TEXAS INSTRUMENTS

Advanced CMOS Logic

SN74ACxxx, SN74ACTxxx, SN74AC16xxx, SN74ACT16xxx

Data Book

1996

Advanced System Logic Products

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Advanced CMOS Logic

SN74ACxxx, SN74ACTxxx, 74AC16xxx, 74ACT16xxx

TEXAS INSTRUMENTS

INTRODUCTION

Texas Instruments places major emphasis on the quality and reliability of semiconductor devices beginning with design and continuing through wafer fabrication, assembly, final test and packaging. Stringent quality, reliability performance and manufacturing standards are defined prior to product design. Several product/process qualifications and evaluations are performed to assure these standards are met for every device released to market.

The AC/ACT end pin family is manufactured with TI's EPIC™ (Enhanced Performance Implanted CMOS) 1µm wafer fabrication process. The EPIC™ process provides proven high volume manufacturability and reliability. This family offers advanced bipolar speeds, 24mA output drive and low CMOS power consumption. Devices are pin-to-pin compatible with currently supplied TI Logic products such as: TTL (SN74xx), Schottky (SN74Sxx), Advanced Schottky (SN74ASxx), Advanced Low-Power Schottky (SN74ALSxx), Low-Power Schottky (SN74LSxx) and Fast (SN74Fxx) devices.

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To support the user in meeting requirements for increasingly compact equipment, Texas Instruments developed several packages including Shrink Small Outline Package (SSOP) and the Thin Shrink Small Outline Package (TSSOP), doubling the number of pins but without requiring more PCB area. Both of these packages are standardized:

- JEDEC standard 48-/56- pin Widebus™ SSOP
- EIAJ standard 48-/56- pin shrink Widebus™ TSSOP

The Widebus™ circuits include16-, 18- and 20 bit versions of the well-known 8-, 9-, and 10-bit bus interface functions.

Most of the products in the databook are available in production quantities. Please contact your local authorized distributor or Texas Instruments representative for details of any of these devices or contact the European Product Information Center (EPIC).

TEXAS INSTRUMENTS

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INTRODUCTION

These symbols, terms, and definitions are in accordance with those currently agreed upon by the JEDEC Council of the Electronic Industries Association (EIA) for use in the USA and by the International Electrotechnical Commission (IEC) for international use.

OPERATING CONDITIONS AND CHARACTERISTICS (IN SEQUENCE BY LETTER SYMBOLS)

C_i **Input capacitance**
The internal capacitance at an input of the device

C_o **Output capacitance**
The internal capacitance at an output of the device

C_{pd} **Power dissipation capacitance**
Used to determine the no-load dynamic power dissipation per logic function (see individual circuit pages):
$P_D = C_{pd} V_{CC}^2 f + I_{CC} V_{CC}$

f_{max} **Maximum clock frequency**
The highest rate at which the clock input of a bistable circuit can be driven through its required sequence while maintaining stable transitions of logic level at the output with input conditions established that should cause changes of output logic level in accordance with the specification.

I_{CC} **Supply current**
The current into* the V_{CC} supply terminal of an integrated circuit

ΔI_{CC} **Supply current change**
The increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

I_{CEX} **Output high leakage current**
The maximum leakage current into the collector of the pulldown output transistor when the output is high and the output forcing condition V_O = 5.5 V.

$I_{I(hold)}$ **Input hold current**
Input current that holds the input at the previous state when the driving device goes to a high-impedance state.

I_{IH} **High-level input current**
The current into* an input when a high-level voltage is applied to that input.

I_{IL} **Low-level input current**
The current into* an input when a low-level voltage is applied to that input.

I_{off} **Input/output power-off leakage current**
The maximum leakage current into/out of the input/output transistors when forcing the input/output to 4.5 V and V_{CC} = 0 V

I_{OH} **High-level output current**
The current into* an output with input conditions applied that, according to the product specification, will establish a high level at the output.

I_{OL} **Low-level output current**
The current into* an output with input conditions applied that, according to the product specification, will establish a low level at the output.

*Current out of a terminal is given as a negative value.

I_{OZ} **Off-state (high-impedance-state) output current (of a 3-state output)**
The current flowing into* an output having 3-state capability with input conditions established that, according to the product specification, will establish the high-impedance state at the output.

t_a **Access time**
The time interval between the application of a specified input pulse and the availability of valid signals at an output

t_{dis} **Disable time (of a 3-state or open-collector output)**
The propagation time between the specified reference points on the input and output voltage waveforms with the output changing from either of the defined active levels (high or low) to a high-impedance (off) state.

NOTE: For 3-state outputs, $t_{dis} = t_{PHZ}$ or t_{PLZ}. Open-collector outputs will change only if they are low at the time of disabling so $t_{dis} = t_{PLH}$.

t_{en} **Enable time (of a 3-state or open-collector output)**
The propagation time between the specified reference points on the input and output voltage waveforms with the output changing from a high-impedance (off) state to either of the defined active levels (high or low).

NOTE: In the case of memories, this is the access time from an enable input (e.g., $\overline{OE}$). For 3-state outputs, $t_{en} = t_{PZH}$ or t_{PZL}. Open-collector outputs will change only if they are responding to data that would cause the output to go low so, for them $t_{en} = t_{PHL}$.

t_h **Hold time**
The time interval during which a signal is retained at a specified input terminal after an active transition occurs at another specified input terminal.

NOTES: 1. The hold time is the actual time interval between two signal events and is determined by the system in which the digital circuit operates. A minimum value is specified that is the shortest interval for which correct operation of the digital circuit is guaranteed.

2. The hold time may have a negative value in which case the minimum limit defines the longest interval (between the release of the signal and the active transition) for which correct operation of the digital circuit is guaranteed.

t_{pd} **Propagation delay time**
The time between the specified reference points on the input and output voltage waveforms with the output changing from one defined level (high or low) to the other defined level. ($t_{pd} = t_{PHL}$ or t_{PLH})

t_{PHL} **Propagation delay time, high-to-low level output**
The time between the specified reference points on the input and output voltage waveforms with the output changing from the defined high level to the defined low level

t_{PHZ} **Disable time (of a 3-state output) from high level**
The time interval between the specified reference points on the input and the output voltage waveforms with the 3-state output changing from the defined high level to a high-impedance (off) state

t_{PLH} **Propagation delay time, low-to-high level output**
The time between the specified reference points on the input and output voltage waveforms with the output changing from the defined low level to the defined high level

t_{PLZ} **Disable time (of a 3-state output) from low level**
The time interval between the specified reference points on the input and the output voltage waveforms with the 3-state output changing from the defined low level to a high-impedance (off) state

t_{PZH} **Enable time (of a 3-state output) to high level**
The time interval between the specified reference points on the input and output voltage waveforms with the 3-state output changing from a high-impedance (off) state to the defined high level

t_{PZL} **Enable time (of a 3-state output) to low level**
The time interval between the specified reference points on the input and output voltage waveforms with the 3-state output changing from a high-impedance (off) state to the defined low level

t_{su} **Setup time**
The time interval between the application of a signal at a specified input terminal and a subsequent active transition at another specified input terminal.

NOTES: 1. The setup time is the actual time interval between two signal events and is determined by the system in which the digital circuit operates. A minimum value is specified that is the shortest interval for which correct operation of the digital circuit is guaranteed.

2. The setup time may have a negative value in which case the minimum limit defines the longest interval (between the active transition and the application of the other signal) for which correct operation of the digital circuit is guaranteed.

t_w **Pulse duration (width)**
The time interval between specified reference points on the leading and trailing edges of the pulse waveform

V_{IH} **High-level input voltage**
An input voltage within the more positive (less negative) of the two ranges of values used to represent the binary variables.

NOTE: A minimum is specified that is the least-positive value of high-level input voltage for which operation of the logic element within specification limits is guaranteed.

V_{IL} **Low-level input voltage**
An input voltage within the less positive (more negative) of the two ranges of values used to represent the binary variables.

NOTE: A maximum is specified that is the most-positive value of low-level input voltage for which operation of the logic element within specification limits is guaranteed.

V_{OH} **High-level output voltage**
The voltage at an output terminal with input conditions applied that, according to product specification, will establish a high level at the output.

V_{OL} **Low-level output voltage**
The voltage at an output terminal with input conditions applied that, according to product specification, will establish a low level at the output.

V_{T+} **Positive-going threshold level**
The voltage level at a transition-operated input that causes operation of the logic element according to specification as the input voltage rises from a level below the negative-going threshold voltage, V_{T-}

V_{T-} **Negative-going threshold level**
The voltage level at a transition-operated input that causes operation of the logic element according to specification as the input voltage falls from a level above the positive-going threshold voltage, V_{T+}.

EXPLANATION OF FUNCTION TABLES

The following symbols are used in function tables on TI data sheets:

H	=	high level (steady state)
L	=	low level (steady state)
↑	=	transition from low to high level
↓	=	transition from high to low level
→	=	value/level or resulting value/level is routed to indicated destination
↶	=	value/level is re-entered
X	=	irrelevant (any input, including transitions)
Z	=	off (high-impedance) state of a 3-state output
a . . . h	=	the level of steady-state inputs A through H respectively
Q_0	=	level of Q before the indicated steady-state input conditions were established
$\overline{Q}_0$	=	complement of Q_0 or level of $\overline{Q}$ before the indicated steady-state input conditions were established
Q_n	=	level of Q before the most recent active transition indicated by ↓ or ↑
⎍	=	one high-level pulse
⎏	=	one low-level pulse
Toggle	=	each output changes to the complement of its previous level on each active transition indicated by ↓ or ↑

If, in the input columns, a row contains only the symbols H, L, and/or X, this means the indicated output is valid whenever the input configuration is achieved and regardless of the sequence in which it is achieved. The output persists so long as the input configuration is maintained.

If, in the input columns, a row contains H, L, and/or X together with ↑ and/or ↓, this means the output is valid whenever the input configuration is achieved but the transition(s) must occur following the achievement of the steady-state levels. If the output is shown as a level (H, L, Q_0, or $\overline{Q}_0$), it persists so long as the steady-state input levels and the levels that terminate indicated transitions are maintained. Unless otherwise indicated, input transitions in the opposite direction to those shown have no effect at the output. (If the output is shown as a pulse, ⎍ or ⎏, the pulse follows the indicated input transition and persists for an interval dependent on the circuit.)

Among the most complex function tables are those of the shift registers. These embody most of the symbols used in any of the function tables, plus more. Below is the function table of a 4-bit bidirectional universal shift register (e.g., type SN74194).

FUNCTION TABLE

INPUTS										OUTPUTS			
CLEAR	MODE		CLOCK	SERIAL		PARALLEL				Q_A	Q_B	Q_C	Q_D
	S1	S0		LEFT	RIGHT	A	B	C	D				
L	X	X	X	X	X	X	X	X	X	L	L	L	L
H	X	X	L	X	X	X	X	X	X	Q_{A_0}	Q_{B_0}	Q_{C_0}	Q_{D_0}
H	H	H	↑	X	X	a	b	c	d	a	b	c	d
H	L	H	↑	X	H	H	H	H	H	H	Q_{A_n}	Q_{B_n}	Q_{C_n}
H	L	H	↑	X	L	L	L	L	L	L	Q_{A_n}	Q_{B_n}	Q_{C_n}
H	H	L	↑	H	X	X	X	X	X	Q_{B_n}	Q_{C_n}	Q_{D_n}	H
H	H	L	↑	L	X	X	X	X	X	Q_{B_n}	Q_{C_n}	Q_{D_n}	L
H	L	L	X	X	X	X	X	X	X	Q_{A_0}	Q_{B_0}	Q_{C_0}	Q_{D_0}

The first line of the table represents a synchronous clearing of the register and says that if clear is low, all four outputs will be reset low regardless of the other inputs. In the following lines, clear is inactive (high) and so has no effect.

The second line shows that so long as the clock input remains low (while clear is high), no other input has any effect and the outputs maintain the levels they assumed before the steady-state combination of clear high and clock low was established. Since on other lines of the table only the rising transition of the clock is shown to be active, the second line implicitly shows that no further change in the outputs will occur while the clock remains high or on the high-to-low transition of the clock.

The third line of the table represents synchronous parallel loading of the register and says that if S1 and S0 are both high then, without regard to the serial input, the data entered at A will be at output Q_A, data entered at B will be at Q_B, and so forth, following a low-to-high clock transition.

The fourth and fifth lines represent the loading of high- and low-level data, respectively, from the shift-right serial input and the shifting of previously entered data one bit; data previously at Q_A is now at Q_B, the previous levels of Q_B and Q_C are now at Q_C and Q_D, respectively, and the data previously at Q_D is no longer in the register. This entry of serial data and shift takes place on the low-to-high transition of the clock when S1 is low and S0 is high and the levels at inputs A through D have no effect.

The sixth and seventh lines represent the loading of high- and low-level data, respectively, from the shift-left serial input and the shifting of previously entered data one bit; data previously at Q_B is now at Q_A, the previous levels of Q_C and Q_D are now at Q_B and Q_C, respectively, and the data previously at Q_A is no longer in the register. This entry of serial data and shift takes place on the low-to-high transition of the clock when S1 is high and S0 is low and the levels at inputs A through D have no effect.

The last line shows that as long as both inputs are low, no other input has any effect and, as in the second line, the outputs maintain the levels they assumed before the steady-state combination of clear high and both mode inputs low was established.

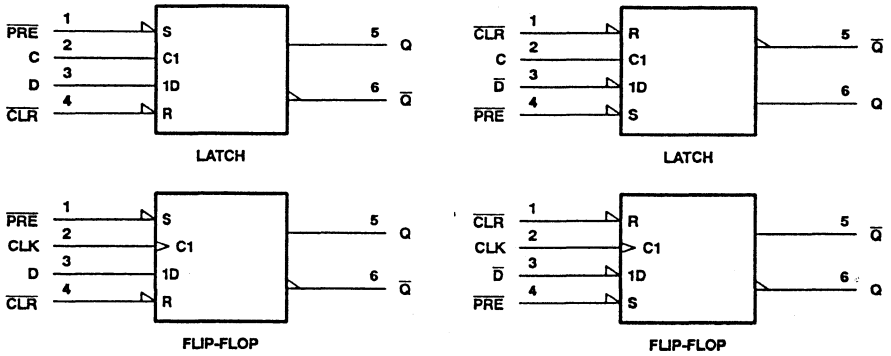
The function table does not reflect all possible combinations or sequential operating modes.

D FLOP AND LATCH SIGNAL CONVENTIONS

It is normal TI practice to name the outputs and other inputs of a D-type flip-flop or latch and to draw its logic symbol based on the assumption of true data (D) inputs. Outputs that produce data in phase with the data inputs are called Q and those producing complementary data are called $\overline{Q}$. An input that causes a Q output to go high or a $\overline{Q}$ output to go low is called preset (PRE). An input that causes a $\overline{Q}$ output to go high or a Q output to go low is called clear (CLR). Bars are used over these pin names (PRE and CLR) if they are active low.

The devices on several data sheets are second-source designs, and the pin name conventions used by the original manufacturers have been retained. That makes it necessary to designate the inputs and outputs of the inverting circuits $\overline{D}$ and Q.

In some applications, it may be advantageous to redesignate the data input from D to $\overline{D}$ or vice versa. In that case, all the other inputs and outputs should be renamed as shown below. Also shown are corresponding changes in the graphical symbols. Arbitrary pin numbers are shown.



The figures show that when Q and $\overline{Q}$ exchange names, the preset and clear pins also exchange names. The polarity indicators (⊳) on $\overline{PRE}$ and $\overline{CLR}$ remain, as these inputs are still active low, but the presence or absence of the polarity indicator changes at D (or $\overline{D}$), Q, and $\overline{Q}$. Pin 5 (Q or $\overline{Q}$) is still in phase with the data input (D or $\overline{D}$); their active levels change together.

In digital system design, consideration must be given to thermal management of components. The small size of the small-outline package makes this even more critical. Figure 1 shows the thermal resistance of these packages for various rates of air flow.

The thermal resistances in Figure 1 can be used to approximate typical and maximum virtual junction temperatures for the EPIC™ ACL family. In general, the junction temperature for any device can be calculated using Equation 1.

$$T_J = R_{\theta JA} \times P_T + T_A \quad (1)$$

where:

- T_J = virtual junction temperature
- $R_{\theta JA}$ = thermal resistance, junction to free air
- P_T = total power dissipation of the device
- T_A = free-air temperature

The total power consumption can be determined from Equation 2 for an AC device and Equation 3 for an ACT device.

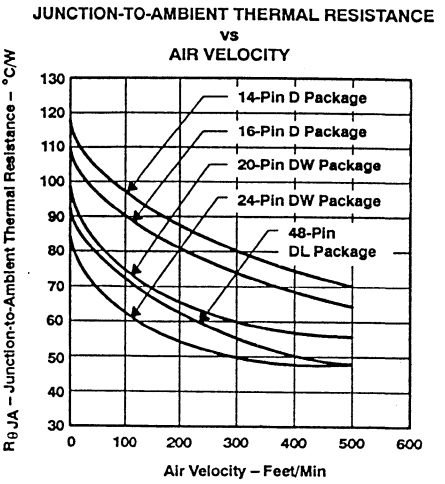


Figure 1

$$P_T = V_{CC} \times I_{CC} + N_{SW}[(C_{pd} \times V_{CC}^2 \times f_i) + (C_L \times V_{CC}^2 \times f_o)] \quad (2)$$

$$P_T = V_{CC} \times [I_{CC} + (N \times \Delta I_{CC} \times dc)] + N_{SW}[(C_{pd} \times V_{CC}^2 \times f_i) + (C_L \times V_{CC}^2 \times f_o)] \quad (3)$$

where:

- V_{CC} = supply voltage (5 V for typical, 5.5 V for maximum) (see Note 1)
- I_{CC} = quiescent supply current (specified on device data sheet)
- C_{pd} = power dissipation capacitance (from the device data sheet)
- f_i = input frequency
- C_L = output load capacitance
- f_o = output frequency
- N = number of inputs driven by a TTL device
- N_{SW} = number of outputs switching
- dc = duty cycle
- ΔI_{CC} = increase in supply current (specified on device data sheet)

NOTE 1: In system applications, I_{CC} can be minimized by keeping input voltage levels less than 1 V for V_{IL} and greater than $V_{CC}-1$ V for V_{IH} and input rise and fall times less than 15 ns.

Positive-NAND Gates

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY													
			ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	HC	HCT	LV	LVC
8 Input		'30	✔	✔	✔	✔	✔	✔								
13 Input		'133	✔				✔									
Dual 4 Input		'20	✔	✔	✔	✔	✔						✔			
Triple 3 Input		'10	✔	✔	✔	✔	✔		✔	✔			✔			✔
Quad 2 Input		'00	✔	✔	✔	✔	✔	✔	✔•	✔	✔	✔	✔	✔	✔	✔
		'37	✔			✔	✔	✔								
	OC	'38	✔		✔	✔	✔	✔								
		'132				✔	✔	✔					✔			
		'1000		✔												
Hex 2 Input		'804	✔	✔												
		'1804		✔												
Quad 2 Input	OC	'03	✔			✔							✔			
Dual 2 Input		'8003	✔													

Positive-AND Gates

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY													
			ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	HC	HCT	LV	LVC
Quad 2 Input	OC	'09	✔			✔	✔									
		'7001											✔			
Dual 4 Input		'21	✔	✔	✔	✔							✔			
Triple 3 Input		'11	✔	✔	✔	✔	✔		✔	✔			✔			
Quad 2 Input		'08	✔	✔	✔	✔	✔		✔•	✔•	✔	✔	✔	✔	✔	✔
		'1008		✔												
Hex 2 Input		'808		✔												
		'1808		✔												

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

Positive-OR/NOR Gates

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY													
			ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	HC	HCT	LV	LVC
Quad 2 Input		'32	✔	✔	✔	✔	✔	✔	✔•	✔•	✔	✔	✔	✔	✔	✔
		'1032		✔												
Hex 2 Input		'832	✔	✔												
		'1832		✔												
Dual 5 Input		'260			✔		✔									
Triple 3 Input		'27	✔	✔	✔	✔							✔			
Quad 2 Input		'02	✔	✔	✔	✔	✔						✔	✔	✔	✔
	OC	'33				✔										
		'7002											✔			
Hex 2 Input		'805	✔	✔												
		'1805		✔												

OR/NOR Gates

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY													
			ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	HC	HCT	LV	LVC
Quad 2-Input Exclusive-OR Gates With Totem-Pole Outputs		'86	✔		✔	✔			✔•	✔	✔	✔	✔			✔
Quad 2-Input Exclusive-NOR Gates	OD	'266				✔							✔			

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

INVERTING/NONINVERTING BUFFERS

Hex Inverters/Noninverters

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY													
			ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	HC	HCT	LV	LVC
Hex Inverters		'04	✔	✔	✔	✔	✔	✔	✔•	✔•	✔	✔	✔	✔	✔	✔
		'U04									✔		✔		✔	✔
	OC	'05	✔			✔	✔	✔					✔			
		'06						✔								
		'14				✔		✔	✔	✔	✔	✔	✔		✔	✔
		'1004	✔	✔												
		'1005	✔													
Hex Noninverters	OC	'35	✔													
		'1034	✔	✔												
	OC	'1035	✔													

BUFFERS/DRIVERS AND BUS TRANSCEIVERS

Buffers/Drivers

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY																	
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	ALVC	HC	HCT	LV	LVC	OTHER
2-Bit Buffers	3S	'306		✔																	
Quad Buffers/Drivers	3S	'125	✔	✔	✔			✔	✔					+	+		✔	✔	✔	✔	
		'126	✔	✔				✔	✔					+	+		✔				
Hex Buffers	OC	'07									✔										
Noninverting Hex Buffers/Drivers	3S	'365							✔								✔				
	3S	'367							✔		✔						✔				
Inverting Hex Buffers/Drivers	3S	'368							✔		✔						✔				

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

BUFFERS/DRIVERS AND BUS TRANSCEIVERS

Buffers/Drivers (Continued)

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY																		
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	ALVC	HC	HCT	LV	LVC	OTHER
Noninverting Octal Buffers/Drivers	3S	'241	✔	✔	✔	✔	✔	✔	✔	✔		✔	✔				✔				
		'244	✔	✔	✔	✔	✔	✔	✔	✔		✔•	✔•	✔	✔		✔	✔	✔	✔	+LVCH
		'1240				✔															
		'1244				✔															
		'25244		✔																	
		'541	✔	✔		✔		✔	✔					✔	✔		✔	✔		✔	
	OC	'757					✔														
		'760		✔		✔	✔														
Inverting Octal Buffers/Drivers	3S	'240	✔	✔	✔	✔	✔	✔	✔	✔		✔•	✔•	✔	✔		✔	✔	✔	✔	
		'540	✔	✔		✔			✔					✔	✔		✔	✔		✔	
	OC	'756		✔			✔														
Inverting and Noninverting Octal Buffers/Drivers	3S	'230					✔														
Noninverting 10-Bit Buffers/Drivers	3S	'827	✔																	✔	
		'29827		✔		✔															
Inverting 10-Bit Buffers/Drivers	3S	'828																		✔	
		'29828		✔		✔															
Noninverting 16-Bit Buffers/Drivers	3S	'16241	✔										✔			✔				✔	
		'16244	✔		✔							✔	✔			✔				✔	
		'16541	✔										✔							✔	
Inverting 16-Bit Buffers/Drivers	3S	'16240	✔									✔	✔			✔				✔	
		'16540	✔										✔							✔	
Noninverting 18-Bit Buffers/Drivers	3S	'16825	✔										✔			✔					
		'16835			✔											✔					
Noninverting 20-Bit Buffers/Drivers	3S	'16827	✔										✔			✔					

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

Universal Bus Transceivers (UBT™)/Universal Bus Exchangers (UBE™)

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY						
			ABT	BCT	LVT	LV	LVC	ALVC	OTHER
Noninverting 9-Bit 4-Port UBE™	3S	'16409						✔	
Noninverting 17-Bit UBT™ With Buffered Clock Outputs and Output Edge Control (OEC™)	OD	'16616							✔GTL
Noninverting 18-Bit UBT™	3S	'16500	✔		✔			✔	
		'16501	✔		✔			✔	
		'16600	✔					✔	
		'16601	✔					✔	
Noninverting 18-Bit UBT™ With Output Edge Control (OEC™)	OD	'16612							✔GTL
Noninverting 18-Bit UBT™	OD	'16622							+GTL
Noninverting 36-Bit UBT™	3S	'32501	✔						
Noninverting 16-Bit Tri-Port UBE™	3S	'32316	✔						
Noninverting 18-Bit Tri-Port UBE™	3S	'32318	✔						
18-Bit UBT™ With Series Resistors on B Port	3S	'162500	✔						
		'162501	✔						
		'162601	✔					✔	
Noninverting 18-Bit UBT™ With Parity Generators /Checkers	3S	'16901						✔	
SCOPE™ 18-Bit UBT™	3S	'18502	✔		✔				
SCOPE™ 20-Bit UBT™	3S	'18504	✔		✔				

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

BUFFERS/DRIVERS AND BUS TRANSCEIVERS

Bus Transceivers

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY																		
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	ALVC	HC	HCT	LV	LVC	OTHER
Inverting Quad Transceivers	OC	'758				✔															
Noninverting Quad Transceivers	3S	'243				✔		✔	✔												
Noninverting Octal Transceivers	3S	'245	✔	✔	✔	✔	✔	✔	✔			✔•	✔•	✔	✔		✔	✔	✔	✔	+LVCH
		'1245				✔															
		'25245	✔	✔																	
		'645				✔	✔		✔								✔	✔			
		'1645				✔															
	OC	'621				✔															
		'641				✔	✔		✔												
	OC/3S	'639				✔	✔														
Inverting Octal Transceivers	3S	'620	✔			✔															
		'623	✔	✔		✔		✔	✔								✔	✔			
		'640	✔	✔		✔	✔		✔								✔				
		'1640				✔															
	OC	'642				✔			✔												
	OC/3S	'638				✔	✔														
Noninverting 9-Bit Transceivers	3S	'863	✔																	✔	
		'29863		✔		✔															
Noninverting 10-Bit Transceivers	3S	'861	✔																	✔	
Noninverting 16-Bit Transceivers	3S	'16245	✔		✔							✔	✔			✔				✔	✔ABTE
		'16623	✔										✔								
Noninverting 16-Bit Transceivers, 3.3-V-to-5-V Level Shifter	3S	'164245														✔					
Inverting 16-Bit Transceivers	3S	'16640	✔									✔	✔								
		'16620										✔	✔								
Noninverting 18-Bit Transceivers	3S	'16863	✔										✔			✔					

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

Bus Transceivers (Continued)

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY																	
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	ALVC	HC	HCT	LV	LVC	OTHER
Inverting 18-Bit Transceivers	3S	'16864											✔								
Noninverting 20-Bit Transceivers	3S	'16861											✔								
Noninverting Octal Registered Transceivers	3S	'543	✔	✔	✔			✔												✔	
		'646	✔	✔	✔	✔	✔		✔								✔	✔		✔	
		'652	✔	✔	✔	✔	✔		✔			•	•				✔	✔		✔	
		'2952	✔		✔															✔	
	OC/3S	'653				✔															
		'654				✔															
Inverting Octal Registered Transceivers	3S	'648				✔	✔		✔												
		'651	✔			✔	✔														
		'2953		✔																	
Noninverting 16-Bit Registered Transceivers	3S	'16470	✔										✔								
		'16543	✔		✔							✔	✔			✔				✔	
		'16646	✔		✔							✔	✔			✔				✔	
		'16652	✔		✔							✔	✔							✔	
		'16952	✔		✔								✔							+	
Inverting 16-Bit Registered Transceivers	3S	'16544											✔								
		'16648											✔								
		'16651											✔								
Noninverting 18-Bit Registered Transceivers	3S	'16474											✔								
		'16500	✔		✔											✔					
		'16501	✔		✔											✔					
		'16600	✔													✔					
		'16601	✔													✔					
Noninverting 36-Bit Transceivers	3S	'32245	✔																		
Noninverting 36-Bit Registered Transceivers	3S	'32501	✔																		
		'32543	✔																		

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

Bus Transceivers (Continued)

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY																	
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	ALVC	HC	HCT	LV	LVC	OTHER
8-/9-Bit Bus Transceivers With Parity Checkers/ Generators	3S	'657	✔																		
		'833	✔																		
		'853	✔																		
	3S/OC	'29833				✔															
		'29834		✔																	
		'29854		✔																	
Dual 8-/9-Bit Bus Transceivers With Parity Checkers/ Generators	3S	'16833	✔										✔								
		'16657	✔										✔								
		'16853	✔																		
Noninverting 16-Bit Tri-Port Registered Bus Exchangers	3S	'32316	✔																		
Noninverting 18-Bit Tri-Port Registered Bus Exchangers	3S	'32318	✔																		
7-Bit TTL/BTL Transceivers	OC	'2041																			✔FB
8-Bit TTL/BTL Transceivers	OC	'2040																			✔FB
8-Bit TTL/BTL Registered Transceivers	OC	'2033																			✔FB
9-Bit TTL/BTL Competition Transceivers	OC	'2032																			+FB
9-Bit TTL/BTL Address/ Data Transceivers	OC	'2031																			✔FB
17-Bit TTL/BTL Universal Storage Transceivers	OC	'1651																			✔FB
18-Bit TTL/BTL Universal Storage Transceivers	OC	'1650																			✔FB

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

MOS Memory Drivers/Transceivers

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY											
			ABT	BCT	LVT	ALS	AS	F	AC	ACT	ALVC	LV	LVC	OTHER
Octal Buffers/Drivers With Series Resistors on Output	3S	'2240	✔	✔		✔								
		'2241	✔											
		'2244	✔	✔				✔						
		'2541				✔								
Octal Transceivers With Series Resistors on B Port	3S	'2245	✔	✔				✔						
10-Bit Buffers/Drivers With Series Resistors	3S	'2827		✔										
		'2828		✔										
10-Bit Flip-Flops With Dual Outputs and Series Resistors	3S	'162820									✔			
11-Bit Buffers/Drivers With Series Resistors	3S	'5400	✔											
		'5401	✔											
12-Bit Buffers/Drivers With Series Resistors	3S	'5402	✔											
		'5403	✔											
16-Bit Buffers/Drivers With Series Resistors	3S	'162244	✔		✔						✔		✔	
16-Bit Transceivers With Series Resistors	3S	'162245	✔		✔						✔			✔LVTH
16-Bit D-Type Latches With Series Resistors	3S	'162373			✔									
16-Bit D-Type Flip-Flops With Series Resistors	3S	'162374			✔									
4-to-1 Multiplexed/Demultiplexed Registered Transceivers With Series Resistors	3S	'162460	✔											
18-Bit UBT™ With Series Resistors on B Port	3S	'162500	✔											
		'162501	✔											
		'162601	✔								✔			
18-Bit Bus-Interface Flip-Flops With Series Resistors	3S	'162823	✔											
18-Bit Buffers/Drivers With Series Resistors	3S	'162825	✔											
20-Bit Buffers/Drivers With Series Resistors	3S	'162827	✔											
12-to-24 Multiplexed D-Type Latches With Series Resistors on B Port	3S	'162260	✔											

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

TESTABILITY BUS-INTERFACE CIRCUITS

IEEE 1149.1 (JTAG) Boundary-Scan Logic

DESCRIPTION	NO. OF BITS	OUTPUT	TYPE	TECHNOLOGY									
				ABT	BCT	LVT	F	LS	S	TTL	AC	ACT	OTHER
Buffers/Drivers	8	3S	'8240	+	✔								
			'8244	+	✔								
Transceivers	8	3S	'8245	✔	✔								
	18	3S	'18245	✔		✔							
Transparent Latches	8	3S	'8373	+	✔								
Flip-Flops	8	3S	'8374	+	✔								
Registered Transceivers	8	3S	'8543	✔									
			'8646	✔									
			'8652	✔									
			'8952	✔									
	18	3S	'18502	✔		✔							
			'18646	✔		✔							
			'18652	✔		✔							
	20	3S	'18504	✔		✔							
Test Bus Controllers		3S	'8990									✔	

FLIP-FLOPS AND LATCHES

Flip-Flops

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY																	
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	ALVC	HC	HCT	LV	LVC	OTHER
Dual J-K Edge Triggered		'109				✔	✔	✔	✔								✔				
		'112				✔		✔	✔	✔							✔			+	+CDC
		'113				✔															
Dual D-Type		'74				✔	✔	✔	✔	✔	✔	✔•	✔•	✔	✔		✔	✔	✔	✔	
Dual 4 Bit D-Type Edge Triggered	3S	'874				✔	✔														
		'876				✔	✔														
Quad D-Type		'175				✔	✔	✔	✔	✔	✔						✔				
Hex D-Type		'174				✔	✔	✔	✔	✔							✔		✔		
		'378						✔													

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

Flip-Flops (Continued)

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY																	
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	ALVC	HC	HCT	LV	LVC	OTHER
Octal D-Type True Data	3S	'374	✔	✔		✔	✔	✔	✔	✔		✔•	✔•	+	+		✔	✔	✔	✔	
		'574	✔		✔	✔	✔	✔				✔	✔	✔	✔		✔	✔	✔	✔	
Octal D-Type True Data With Clear		'273	✔		✔	✔			✔								✔	✔	✔		
	3S	'575				✔	✔														
		'874				✔	✔														
Octal D-Type True Data With Clock Enable		'377	✔					✔	✔								✔	✔			
Octal D-Type Inverting	3S	'534	✔			✔						✔	✔				✔				
		'564				✔						✔	✔								
		'576				✔	✔														
Octal Dual Ranked True Data	3S	'4374					✔														
Octal Inverting With Clear	3S	'577				✔															
Octal Inverting With Preset	3S	'876				✔	✔														
Octal True Data	3S	'825					✔														
9 Bit True Data	3S	'823	✔				✔													✔	
		'29623		✔																	
10 Bit Noninverting	3S	'16820														✔					
10 Bit True Data	3S	'821	✔				✔													+	
		'29821		✔		✔															
16 Bit Noninverting	3S	'16374	✔		✔							✔	✔			✔				✔	
18 Bit Noninverting	3S	'16823	✔									✔	✔			✔					
20 Bit Noninverting	3S	'16721														✔					
		'16821	✔										✔			✔					
20 Bit Noninverting With GTL I/O Levels	OD	'16921																			+GTL

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

FLIP-FLOPS AND LATCHES

Latches

DESCRIPTION	NO. OF BITS	OUTPUT	TYPE	TECHNOLOGY																	
				ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	ALVC	HC	HCT	LV	LVC	OTHER
D-Type Edge Triggered Inverting and Noninverting	8	3S	'996				✔															
D-Type Transparent Readback Latch, True	8	3S	'990				✔															
	9	3S	'992				✔															
	10	3S	'994				✔															
D-Type Transparent With Clear, True Outputs	8	3S	'666				✔															
D-Type Transparent With Clear, Inverting Outputs	8	3S	'667				✔															
D-Type Transparent True	8	3S	'373	✔	✔		✔	✔	✔	✔	✔		✔•	✔•	+	+		✔	✔	✔	✔	
			'573	✔		✔	✔	✔	✔				✔	✔	✔	✔		✔	✔	✔	✔	
	16	3S	'16373	✔		✔							✔	✔			✔				✔	
D-Type Dual 4 Bit Transparent True	8	3S	'873				✔	✔														
D-Type Transparent Inverting	8	3S	'533	✔			✔	✔					✔	✔								
			'563				✔						✔	✔				✔				
			'580				✔															
Addressable	8	2S	'259				✔			✔								✔				
D-Type True Inputs	8	3S	'845				✔															
	9	3S	'843	✔			✔														+	
			'29843		✔																	
	10	3S	'841	✔			✔														✔	
			'29841		✔		✔															
	18	3S	'16843	+													✔					
	20	3S	'16841	✔										✔			✔					
D-Type Inverting Inputs	10	3S	'842				✔															

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

Shift Registers

DESCRIPTION	NO. OF BITS	OUTPUT	TYPE	TECHNOLOGY													
				ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AHC	AHCT	HC	HCT	LV
Parallel In, Parallel Out, Bidirectional	4		'194					✔		✔	✔						
	8		'299				✔		✔	✔	✔						
			'323				✔			✔							
Parallel In, Parallel Out	4		'195							✔	✔						
Serial In, Parallel Out	8		'164				✔			✔					✔		✔
Parallel In, Serial Out	8		'165				✔			✔					✔		
			'166				✔			✔					✔		
Serial In, Parallel Out With Output Latches	8	3S	'594							✔					✔		
			'595							✔					✔		
Noninverting	8	3S	'299				✔		✔	✔	✔						
	9	3S	'29823		✔												

Register Files

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY									
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT
Dual 16 Word × 4 Bits	3S	'870				✔							

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

COUNTERS

Synchronous Counters – Positive Edge Triggered

DESCRIPTION	PARALLEL LOAD	TYPE	TECHNOLOGY												
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AHC	AHCT	HC	HCT
4 Bit Decade Up/Down	Sync	'568				✔									
4 Bit Binary	Sync	'161				✔	✔	✔	✔					✔	
		'163				✔	✔	✔	✔	✔				✔	
		'561				✔									
4 Bit Binary Up/Down	Sync	'169				✔	✔	✔	✔	✔					
		'569				✔									
		'191				✔			✔					✔	
		'193				✔			✔		✔			✔	
8 Bit Up/Down	Sync Clear	'869				✔	✔								
	Async Clear	'867				✔	✔								

Asynchronous Counters (Ripple Clock) – Negative Edge Triggered

DESCRIPTION	PARALLEL LOAD	TYPE	TECHNOLOGY												
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AHC	AHCT	HC	HCT
Dual 4 Bit Binary	None	'393							✔					✔	
12 Bit Binary	Async	'4040												✔	
14 Bit Binary	Async	'4020												✔	
		'4060												✔	

8-Bit Binary Counters With Registers

DESCRIPTION	PARALLEL LOAD	TYPE	TECHNOLOGY												
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AHC	AHCT	HC	HCT
Parallel Register Outputs	3S	'590							✔					✔	
Parallel Register Inputs	3S	'593							✔						

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

Encoders/Data Selectors/Multiplexers

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY																
			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	ALVC	HC	HCT	LV	LVC
Quad 2-to-1		'157				✔	✔	✔	✔	✔	✔			+	+		✔	✔		✔
		'158				✔	✔	✔	✔	✔				+	+		✔			
		'298					✔		✔											
	3S	'257				✔	✔	✔	✔	✔			•	+	+		✔	✔		✔
	3S	'258				✔	✔	✔	✔					+	+					
Hex 2-to-1 Universal Multiplexers	3S	'857				✔														
Dual 4-to-1		'153				✔	✔	✔	✔	✔							✔			
	3S	'253				✔	✔	✔	✔								✔			
	3S	'353					✔													
4-to-1 Registered Transceivers	3S	'16460	✔																	
Cascadable Octals		'148							✔		✔						✔			
8-to-1		'151				✔	✔	✔	✔	✔							✔			
	3S	'251				✔		✔	✔	✔							✔			
16-to-1	3S	'250					✔													
12-to-24 Multiplexed D-Type Latches	3S	'16260	✔													✔				
12-to-24 Registered Bus Exchangers	3S	'16269														✔				
	3S	'16270														✔				

Decoders/Demultiplexers

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY														
			ALS	AS	F	LS	S	TTL	AC	ACT	AHC	AHCT	ALVC	HC	HCT	LV	LVC	OTHER
Dual 2-to-4		'131		✔														
		'139	✔			✔	✔		•	•	+	+		✔	✔			
	OC	'156	✔			✔		✔										
Dual 2-to-4 for Battery Backed-Up Memories		'2414																
3-to-8		'138	✔	✔	✔	✔	✔		•		+	+		✔	✔	✔	✔	
3-to-8 With Address Registers		'137	✔	✔		✔											+	
4-to-10 BCD-to-Decimal		'42				✔								✔				

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

COMPARATORS AND PARITY GENERATORS/CHECKERS

Comparators

DESCRIPTION								TYPE	TECHNOLOGY							
INPUT	P=Q	$\overline{P=Q}$	P>Q	$\overline{P>Q}$	P<Q	OUTPUT	ENABLE		ALS	AS	F	LS	AC	ACT	HC	HCT
8 Bit With 20-kΩ Pullup	No	Yes	No	No	No	2S	Yes	'520	✔				•			
	No	Yes	No	Yes	No	2S	No	'682				✔			✔	
8 Bit Standard	No	Yes	No	No	No	2S	Yes	'521	✔		✔					
	No	Yes	No	Yes	No	2S	No	'684				✔			✔	
	No	Yes	No	No	No	2S	Yes	'688	✔			✔			✔	
8 Bit Latched P	No	No	Yes	No	Yes	2S	Yes	'885		✔						

Parity Generators/Checkers

DESCRIPTION	NO. OF BITS	TYPE	TECHNOLOGY									
			ALS	AS	F	LS	S	TTL	AC	ACT	HC	HCT
Odd/Even	9	'280	✔	✔	✔	✔	✔					
		'286		✔						•		

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

BUS SWITCHES AND 5-V/3-V VOLTAGE TRANSLATORS

Bus Switches

DESCRIPTION	TYPE	TECHNOLOGY			
		CBT	CBTS	CBTD	OTHER
Quad Bus Switches	'3125	✔			
Dual 4-Bit Bus Switches With '244 Pinout	'3244	✔			
8-Bit Bus Switches With '245 Pinout	'3245	✔			
Quad 2-to-1-Bit FET Multiplexers/Demultiplexers	'3257	✔			
Dual Bus Switches	'3306	✔	✔	✔	
8-Bit Bus Switches	'3345	✔			
10-Bit Bus-Exchange Switches	'3383	✔			
Dual 5-Bit Bus Switches	'3384	✔	✔	✔	
10 Bit With Precharged Outputs for Live Insertion	'6800	✔			
18-Bit Bus-Exchange Switches	'16209	✔			
24-Bit Bus-Exchange Switches	'16211	✔			
	'16212	✔			
	'16213	✔			
12-Bit 3-to-1 Bus Select	'16214	✔			
Synchronous 16-Bit-to-32-Bit FET Multiplexers	'16232	✔			
16-Bit-to-32-Bit FET Multiplexers/Demultiplexers	'16233	✔			

ARITHMETIC CIRCUITS

Parallel Binary Adders

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY											
			ALS	AS	F	LS	S	TTL	HC	HCT	AC	ACT	LV	LVC
4 Bit		'283			✔	✔	✔							

Arithmetic Logic Units

DESCRIPTION	OUTPUT	TYPE	TECHNOLOGY											
			ALS	AS	F	LS	S	TTL	HC	HCT	AC	ACT	LV	LVC
4-Bit Arithmetic Logic Units: Function Generator		'181		✔										

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

First-In, First-Out (FIFO) Memories

DESCRIPTION		OUTPUT	TYPE	TECHNOLOGY											
SIZE	TYPE†			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	ALVC
16 Words × 4 Bits	U	3S	'232				✔								
16 Words × 5 Bits	U	3S	'225								✔				
			'233				✔								
32 Words × 9 Bits	B	3S	'2238				✔								
64 Words × 4 Bits	U	3S	'234				✔								
			'236				✔								
64 Words × 5 Bits	U	3S	'235				✔								
64 Words × 8 Bits	U	3S	'2232				✔								
64 Words × 9 Bits	U	3S	'2233				✔								
64-Words × 18 Bits	U, C	3S	'7813											✔	✔
	U	3S	'7814											✔	✔
64 Words × 36 Bits	B, C	3S	'3612	✔											
			'3614	✔											
	U, C	3S	'3611	✔											
			'3613	✔											
Dual 64 × 1	C	3S	'2226											✔	
			'2227											✔	
Dual 256 × 1	C	3S	'2228											✔	
			'2229											✔	
256 Words × 9 Bits	U	3S	'7200L											✔	
256 Words × 18 Bits	U, C	3S	'7805											✔	
	U	3S	'7806											✔	✔
256 × 36 × 2 Bits	B, C	3S	'3622											✔	
512 Words × 9 Bits	U	3S	'7201LA											✔	

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

† U = Unidirectional
B = Bidirectional
C = Clocked
S = Synchronized

First-In, First-Out (FIFO) Memories (Continued)

DESCRIPTION		OUTPUT	TYPE	TECHNOLOGY											
SIZE	TYPE†			ABT	BCT	LVT	ALS	AS	F	LS	S	TTL	AC	ACT	ALVC
512 Words × 18 Bits	U, C	3S	'7803											✔	✔
	U	3S	'7804											✔	✔
	B, C	3S	'7819	✔											
	B	3S	'7820	✔											
512 Words × 32 Bits	B, C	3S	'3638											✔	
512 Words × 36 Bits	U, C	3S	'3631											✔	
	B, C	3S	'3632											✔	
1K Words × 9 Bits	B	3S	'2235											✔	
			'2236											✔	
	U	3S	'7202LA											✔	
1K Words × 18 Bits	U, C	3S	'7811											✔	
			'7881											✔	
	U	3S	'7802											✔	
1K Words × 36 Bits	U, C	3S	'3641											✔	
1K × 36 × 2 Bits	B, C	3S	'3642											+	
2K Words × 9 Bits	U, C	3S	'7807											✔	
	U	3S	'7203L											✔	
			'7808											✔	
2K Words × 18 Bits	U, C	3S	'7882											✔	
2K Words × 36 Bits	U, C	3S	'3651											+	
4K Words × 9 Bits	U	3S	'7204L											✔	
4K Words × 18 Bits	U, C	3S	'7884											✔	

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

† U = Unidirectional
B = Bidirectional
C = Clocked
S = Synchronized

CLOCK-DISTRIBUTION CIRCUITS

3.3-V Clock-Distribution Circuits (CDC)

DESCRIPTION	I/O LEVELS	TYPE	TECHNOLOGY			
			AS	AC	ACT	ABT
3.3-V Hex Inverting Clock Drivers/Buffers	CMOS/CMOS	'203		✔		
1-to-9 Differential LVPECL Buffers	LVPECL/LVPECL	'111				+
1-to-9 Differential LVPECL Buffers With Output Enable	LVPECL/LVPECL	'112				+
1-to-10 Buffers With Output Enable	TTL/TTL	'351				✔
		'2351				✔
1-to-6 PLL Clock Drivers	TTL/TTL	'536				+
		'2536				+
1-to-12 PLL Clock Drivers	TTL/TTL	'586				✔
		'2586				✔
	LVPECL/TTL	'582				+
		'2582				+
Phase-Locked-Loop 1-to-16 Clock Drivers	SSTL/TTL	'587				+
		'2587				+
P5 Motherboard Clock Synthesizers/Drivers	TTL/TTL	'9841				✔
		'9842				✔
		'9843				✔
P6 Motherboard Clock Synthesizers/Drivers	TTL/TTL	'916				+
PC Motherboard Clock Generators With Dual 1-to-4 Buffers	TTL/TTL	'913				+

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

5-V Clock-Distribution Circuits (CDC)

DESCRIPTION	I/O LEVELS	TYPE	TECHNOLOGY			
			AS	AC	ACT	ABT
Hex Inverters	CMOS/CMOS	'204		✔		
		'204-7		✔		
1-to-6 Exclusive ORs	TTL/TTL	'328				✔
	TTL/CMOS	'329				✔
1-to-6 Exclusive ORs With Output Enable	TTL/TTL	'391				✔
	TTL/CMOS	'392				✔
Dual 1-to-4 Buffers (2 inputs, 8 outputs)	TTL/CMOS	'208			✔	
		'208-7			✔	
	CMOS/CMOS	'209		✔		
		'209-7		✔		
1-to-8 Divide-by-2 Flip-Flops (6 inverting, 2 noninverting)	TTL/TTL	'303	✔			
1-to-8 Divide-by-2 Flip-Flops (8 noninverting)	TTL/TTL	'304	✔			
1-to-8 Divide-by-2 Flip-Flops (4 inverting, 4 noninverting)	TTL/TTL	'305	✔			
1-to-8 Fanouts (4 noninverting buffers, 4 divide-by-2 flip-flops)	TTL/CMOS	'337				✔
	TTL/TTL	'339				✔
1-to-8 NANDs	TTL/TTL	'340				✔
1-to-8 ANDs	TTL/TTL	'341				✔
3-Way Fanout Buffers (dual 1-to-3 noninverting buffers, 1-to-4 divide-by-2 flip-flops)	TTL/TTL	'330				✔

✔ Product available in technology indicated • Product available in reduced-noise advanced CMOS (11000 series) + New product planned in technology indicated

2 AC Gates and Octals

- ***EPIC***™ **(Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), DIP (N) Packages, Ceramic Chip Carriers (FK), Flat (W), and DIP (J) Packages**

description

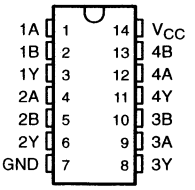
The 'AC00 contain four independent 2-input NAND gates. Each gate performs the Boolean function of $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN54AC00 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AC00 is characterized for operation from –40°C to 85°C.

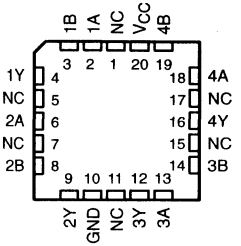
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
H	H	L
L	X	H
X	L	H

SN54AC00 . . . J OR W PACKAGE
SN74AC00 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

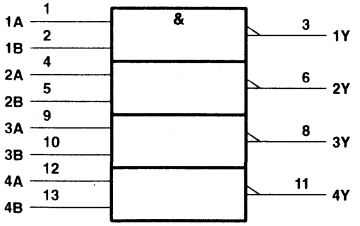


SN54AC00 . . . FK PACKAGE
(TOP VIEW)



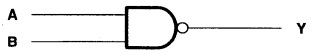
NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each gate (positive logic)



EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC00		SN74AC00		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC00		SN74AC00		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = −12 mA	3 V	2.56			2.4		2.46		
	I_{OH} = −24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = −50 mA†	5.5 V				3.85				
	I_{OH} = −75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	3 V		.002	0.1		0.1		0.1	V
		4.5 V		.001	0.1		0.1		0.1	
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} =12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	μA
C_i	V_I = V_{CC} or GND	5 V		2.6						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC00		SN74AC00		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	2	7	9.5	1	11	2	10	ns
t_{PHL}			1.5	5.5	8	1	9	1	8.5	

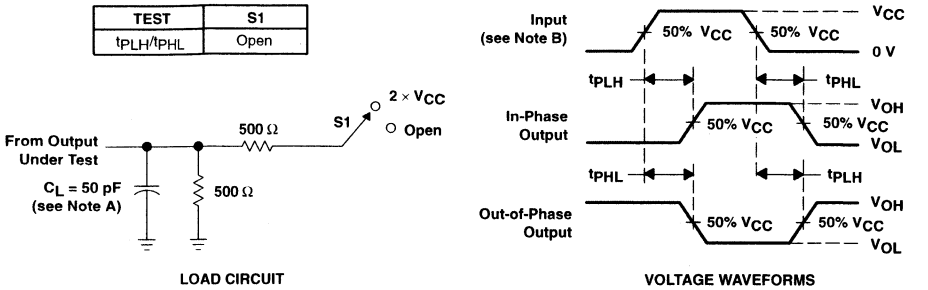
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC00		SN74AC00		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	6	8	1	8.5	1.5	8.5	ns
t_{PHL}			1.5	4.5	6.5	1	7	1	7	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- *EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS

description

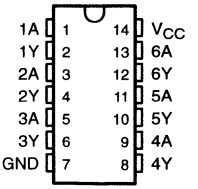
The 'AC04 contain six independent inverters. The devices perform the Boolean function $Y = \overline{A}$.

The SN54AC04 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC04 is characterized for operation from −40°C to 85°C.

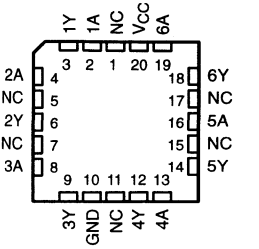
FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H

SN54AC04 . . . J OR W PACKAGE
SN74AC04 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

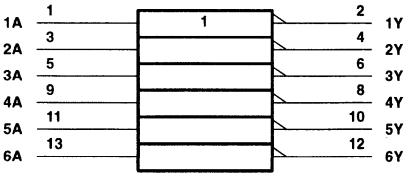


SN54AC04 . . . FK PACKAGE
(TOP VIEW)



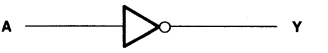
NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each inverter (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC04		SN74AC04		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

TEXAS INSTRUMENTS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC04		SN74AC04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA	3 V	2.9	2.99		2.9		2.9		V
		4.5 V	4.4	4.49		4.4		4.4		
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = −12 mA	3 V	2.56			2.4		2.46		
	I_{OH} = −24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = −50 mA†	5.5 V				3.85				
	I_{OH} = −75 mA†	5.5 V						3.85		
V_{OL}	I_{OH} = 50 μA	3 V		.002	0.1		0.1		0.1	V
		4.5 V		.001	0.1		0.1		0.1	
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} =12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	μA
C_i	V_I = V_{CC} or GND			2.8						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC04		SN74AC04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	4.5	9	1	11	1	10	ns
t_{PHL}			1.5	4.5	8.5	1	10	1	9.5	

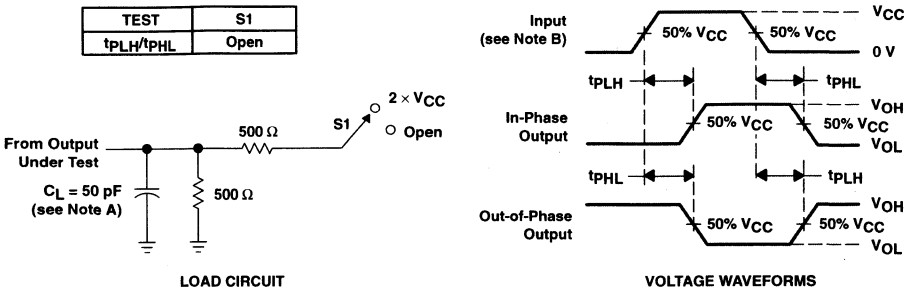
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC04		SN74AC04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	4	7	1	8.5	1	7.5	ns
t_{PHL}			1.5	3.5	6.5	1	7.5	1	7	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

description

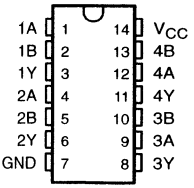
The 'AC08 are quadruple 2-input positive-AND gates. These devices perform the Boolean functions $Y = A \bullet B$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN54AC08 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC08 is characterized for operation from −40°C to 85°C.

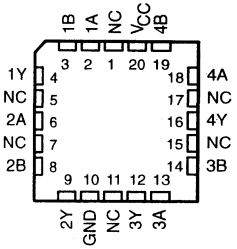
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
H	H	H
L	X	L
X	L	L

SN54AC08 . . . J OR W PACKAGE
SN74AC08 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

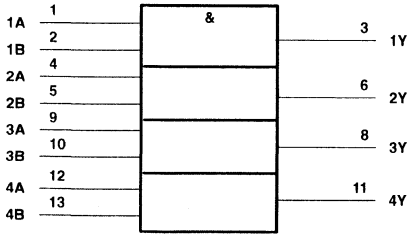


SN54AC08 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each gate (positive logic)

EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC08		SN74AC08		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC08		SN74AC08		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = – 50 μA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = – 12 mA	3 V	2.56			2.4		2.46		
		I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
			5.5 V	4.86			4.7		4.76		
		I_{OH} = – 50 mA†	5.5 V				3.85				
		I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = – 50 μA	3 V		.002	0.1		0.1		0.1	V
			4.5 V		.001	0.1		0.1		0.1	
			5.5 V		.001	0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	A or B ports	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			2		40		20	μA
C_i		VI = V_{CC} or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC08		SN74AC08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	7.5	9.5	1	12.5	1	10	ns
t_{PHL}			1.5	7	8.5	1	11.5	1	9	

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

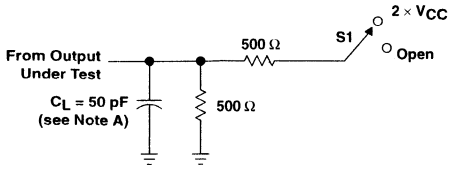
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC08		SN74AC08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	5.5	7.5	1	9	1	8.5	ns
t_{PHL}			1.5	5.5	7	1	8.5	1	7.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

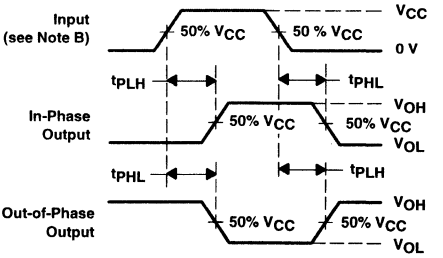
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	20	pF

PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open



LOAD CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- *EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS

description

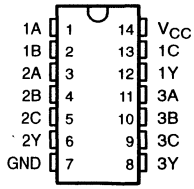
The 'AC10 contain three independent 3-input NAND gates. The devices perform the Boolean functions $Y = \overline{A \bullet B \bullet C}$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

The SN54AC10 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC10 is characterized for operation from −40°C to 85°C.

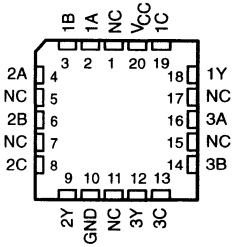
FUNCTION TABLE
(each gate)

INPUTS			OUTPUT
A	B	C	Y
H	H	H	L
L	X	X	H
X	L	X	H
X	X	L	H

SN54AC10 . . . J OR W PACKAGE
SN74AC10 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

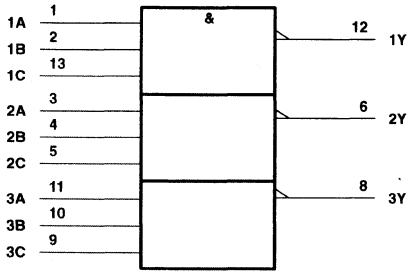


SN54AC10 . . . FK PACKAGE
(TOP VIEW)



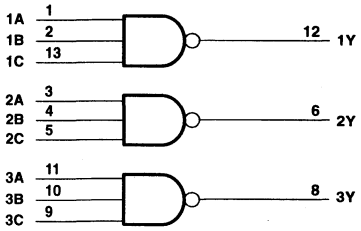
NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each gate (positive logic)



EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC10		SN74AC10		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC10		SN74AC10		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 µA	3 V	2.9	2.99		2.9		2.9		V
		4.5 V	4.4	4.99		4.4		4.4		
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = – 24 mA	3 V	2.56			2.4		2.46		
	I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = – 50 µA	3 V		.002	0.1		0.1		0.1	V
		4.5 V		.001	0.1		0.1		0.1	
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	µA
C_i	VI = V_{CC} or GND	5 V		2.6						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC10		SN74AC10		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	Any	Y	1.5	6	9.5	1	11	1	10.5	ns
t_{PHL}			1.5	5.5	8.5	1	10	1	10	

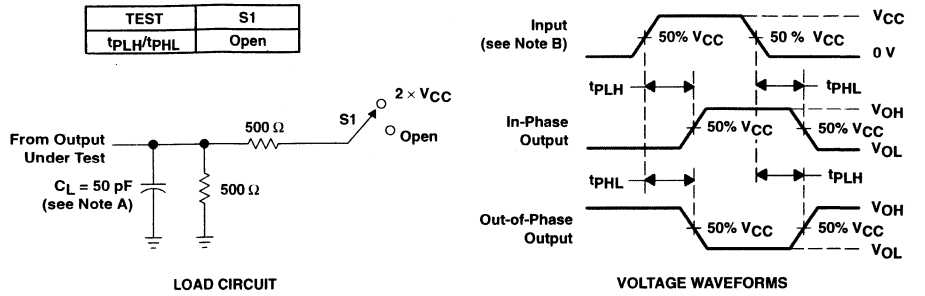
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC10		SN74AC10		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	Any	Y	1.5	4.5	7	1	8.5	1	8	ns
t_{PHL}			1.5	4	6	1	7	1	6.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	25	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

description

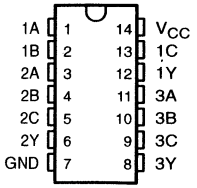
The 'AC11 contain three independent 3-input AND gates. These devices perform the Boolean functions $Y = A \bullet B \bullet C$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

The SN54AC11 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC11 is characterized for operation from −40°C to 85°C.

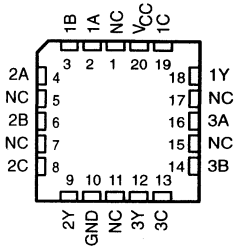
FUNCTION TABLE
(each gate)

INPUTS			OUTPUT
A	B	C	Y
H	H	H	H
L	X	X	L
X	L	X	L
X	X	L	L

SN54AC11 . . . J OR W PACKAGE
SN74AC11 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

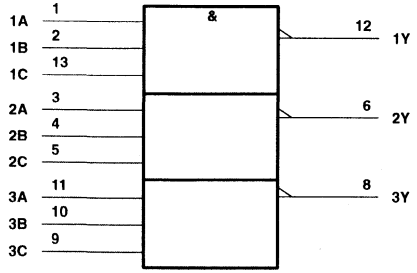


SN54AC11 . . . FK PACKAGE
(TOP VIEW)



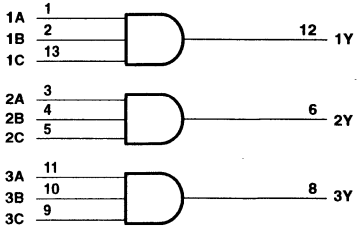
NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each gate (positive logic)



EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC11		SN74AC11		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC11		SN74AC11		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 µA	3 V	2.9	2.99		2.9		2.9		V
		4.5 V	4.4	4.49		4.4		4.4		
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = – 24 mA	3 V	2.56			2.4		2.46		
	I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = – 50 µA	3 V		.002	0.1		0.1		0.1	V
		4.5 V		.001	0.1		0.1		0.1	
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	µA
C_i	VI = V_{CC} or GND	5 V		2.6						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC11		SN74AC11		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	Any	Y	1.5	5.5	9.5	1	11	1	10	ns
t_{PHL}			1.5	5.5	8.5	1	10.5	1	9.5	

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

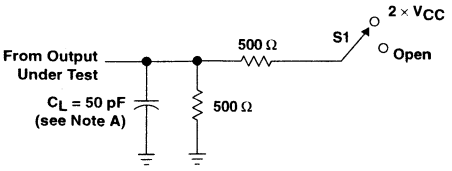
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC11		SN74AC11		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	Any	Y	1.5	4	8	1	8.5	1	8.5	ns
t_{PHL}			1.5	4	7	1	8	1	7.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

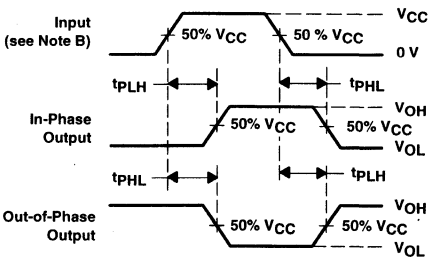
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	20	pF

PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open



LOAD CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- ***EPIC*™ (Enhanced-Performance Implanted CMOS) Submicron Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

description

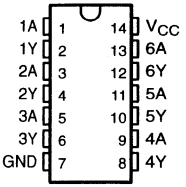
The 'AC14 contain six independent inverters. The devices perform the Boolean function $Y = \overline{A}$.

The SN54AC14 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AC14 is characterized for operation from –40°C to 85°C.

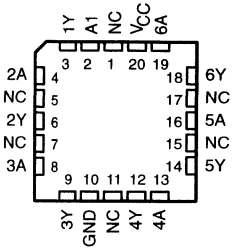
FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H

SN54AC14 . . . J OR W PACKAGE
SN74AC14 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

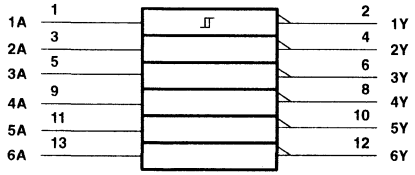


SN54AC14 . . . FK PACKAGE
(TOP VIEW)



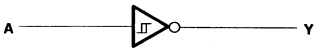
NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, or W packages.

logic diagram, each inverter (positive logic)



EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... – 0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ± 20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ± 20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ± 50 mA
Continuous current through V_{CC} or GND ..... ± 200mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2) D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... – 65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC14		SN74AC14		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		–12		–12	mA
		V_{CC} = 4.5 V		–24		–24	
		V_{CC} = 5.5 V		–24		–24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{T+} Positive-going threshold		3 V			2.2					V
		4.5 V			3.2					
		5.5 V			3.9					
V_{T-} Negative-going threshold		3 V	0.5			0.5		0.5		V
		4.5 V	0.9			0.9		0.9		
		5.5 V	1.1			1.1		1.1		
ΔV_T Hysteresis ($V_{T+} - V_{T-}$)		3 V	0.3		1.2	0.3	1.2	0.3	1.2	V
		4.5 V	0.4		1.4	0.4	1.4	0.4	1.4	
		5.5 V	0.5		1.6	0.5	1.6	0.5	1.6	
V_{OH}	I_{OH} = – 50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = – 4 mA	3 V	2.56			2.4		2.48		
	I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.8		
		5.5 V	4.86			4.7		4.8		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	3 V		.002	0.1		0.1		0.1	V
		4.5 V		.001	0.1		0.1		0.1	
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	μA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	6	13.5	1	16	1.5	15	ns
t_{PHL}			1.5	6	11.5	1	14	1.5	13	

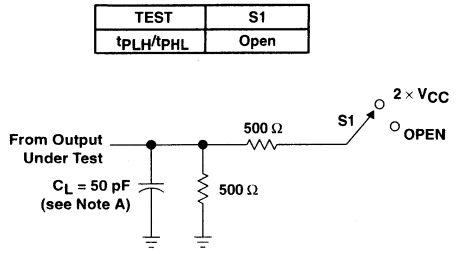
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	5	10	1	12	1.5	11	ns
t_{PHL}			1.5	5	8.5	1	10	1.5	9.5	

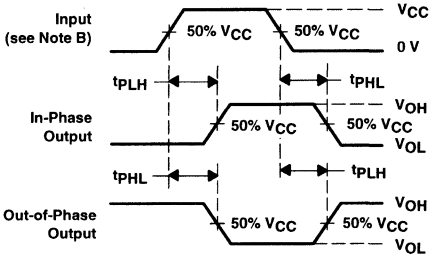
operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	25	pF

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

description

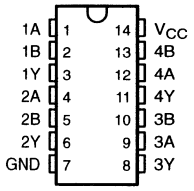
The 'AC32 are quadruple 2-input positive-OR gates. The devices perform the Boolean functions $Y = A + B$ or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

The SN54AC32 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC32 is characterized for operation from −40°C to 85°C.

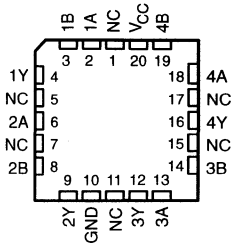
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
H	X	H
X	H	H
L	L	L

SN54AC32 . . . J OR W PACKAGE
SN74AC32 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

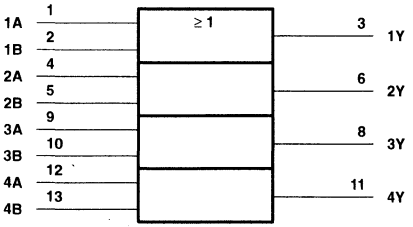


SN54AC32 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each gate (positive logic)

EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC32		SN74AC32		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

TEXAS INSTRUMENTS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC32		SN74AC32		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = –50 µA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = – 12 mA	3 V	2.56			2.4		2.46		
		I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
			5.5 V	4.86			4.7		4.76		
		I_{OH} = – 50 mA†	5.5 V				3.85				
		I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 µA	3 V		.002	0.1		0.1		0.1	V
			4.5 V		.001	0.1		0.1		0.1	
			5.5 V		.001	0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	A or B ports	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			2		40		20	µA
C_i		$V_I = V_{CC}$ or GND	5 V		2.6						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

switching characteristics over recommended operating free-air temperature range V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC32		SN74AC32		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	7	9	1	12	1.5	10	ns
t_{PHL}			1.5	7	8.5	1	11.5	1	9	

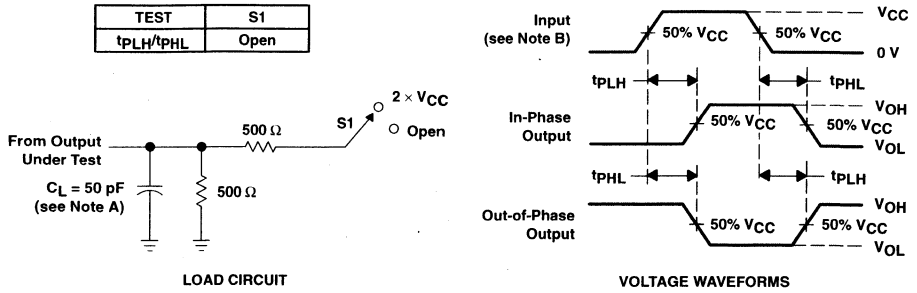
switching characteristics over recommended operating free-air temperature range V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC32		SN74AC32		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	5.5	7.5	1	9	1	8.5	ns
t_{PHL}			1.5	5	7	1	8.5	1	7.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), DIP (N) Packages, Ceramic Chip Carrier (FK), DIP (J), and Flat (W) Packages**

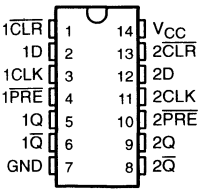
description

The 'AC74 are dual positive-edge-triggered D-type flip-flops.

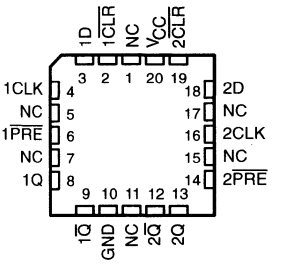
A low level at the preset ($\overline{PRE}$) or clear ($\overline{CLR}$) input sets or resets the outputs regardless of the levels of the other inputs. When $\overline{PRE}$ and $\overline{CLR}$ are inactive (high), data at the data (D) input meeting the setup-time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at D can be changed without affecting the levels at the outputs.

The SN54AC74 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AC74 is characterized for operation from –40°C to 85°C.

SN54AC74 . . . J OR W PACKAGE
SN74AC74 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)



SN54AC74 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

INPUTS				OUTPUTS	
$\overline{PRE}$	$\overline{CLR}$	CLK	D	Q	$\overline{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H†	H†
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q_0	$\overline{Q}_0$

† This configuration is nonstable; that is, it does not persist when either $\overline{PRE}$ or $\overline{CLR}$ returns to its inactive (high) level.

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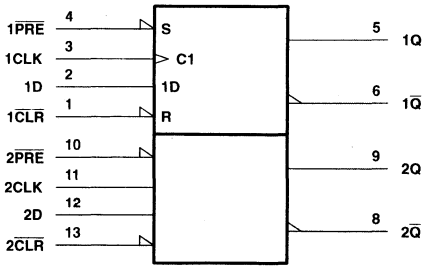
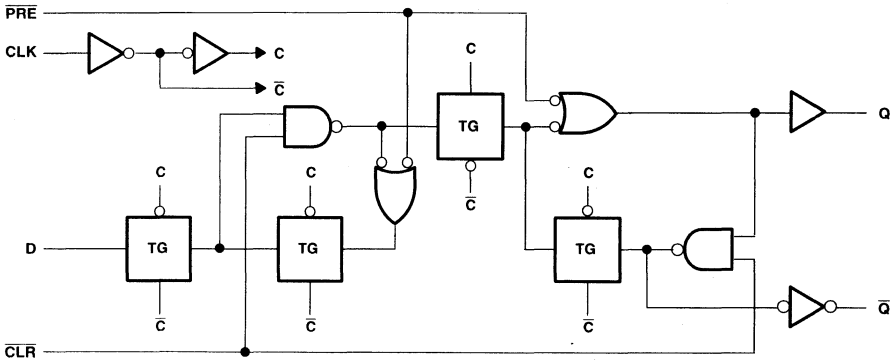
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC74		SN74AC74		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC74		SN74AC74		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = –50 µA	3 V	2.9	4.49		2.9		2.9		V
			4.5 V	4.4	5.49		4.4		4.4		
			5.5 V	5.4	5.49		5.4		5.4		
		I_{OH} = – 12 mA	3 V	2.56			2.4		2.46		
		I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
			5.5 V	4.86			4.7		4.76		
		I_{OH} = – 50 mA†	5.5 V				3.85				
		I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 µA	3 V		.002	0.1		0.1		0.1	V
			4.5 V		.001	0.1		0.1		0.1	
			5.5 V		.001	0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	Data pins	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
	Control pins					±0.1		±1		±1	
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			2		40		20	µA
C_i		$V_I = V_{CC}$ or GND	5 V		3						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54AC74		SN74AC74		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	100	0	100	0	100	MHz
t_w	Pulse duration	$\overline{PRE}$ or $\overline{CLR}$ low	5.5		8		7		ns
		CLK	5.5		8		7		
t_{su}	Setup time, data before CLK↑	Data	4		5		4.5		ns
		$\overline{PRE}$ or $\overline{CLR}$ inactive	0		0.5		0		
t_h	Hold time, data after CLK↑		0.5		0.5		0.5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54AC74		SN74AC74		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	140	0	140	0	140	MHz
t_w	Pulse duration	$\overline{PRE}$ or $\overline{CLR}$ low	4.5		5.5		5		ns
		CLK	4.5		5.5		5		
t_{su}	Setup time, data before CLK↑	Data	3		4		3		ns
		$\overline{PRE}$ or $\overline{CLR}$ inactive	0		0.5		0		
t_h	Hold time, data after CLK↑		0.5		0.5		0.5		ns

TEXAS INSTRUMENTS

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC74		SN74AC74		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			100	125		70		95		MHz
t_{PLH}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	3.5	8	12	1	13	2.5	13	ns
t_{PHL}			4	10.5	12	1	14	3.5	13.5	
t_{PLH}	CLK	Q or $\overline{Q}$	4.5	8	13.5	1	17.5	4	16	ns
t_{PHL}			3.5	8	14	1	13.5	3.5	14.5	

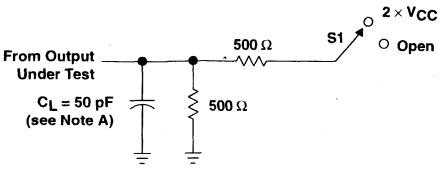
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC74		SN74AC74		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			140	160		95		125		MHz
t_{PLH}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	2.5	6	9	1	9.5	2	10	ns
t_{PHL}			3	8	9.5	1	10.5	2.5	10.5	
t_{PLH}	CLK	Q or $\overline{Q}$	3.5	6	10	1	12	3	10.5	ns
t_{PHL}			2.5	6	10	1	10	2.5	10.5	

operating characteristics, V_{CC} = 3.3 V, T_A = 25°C

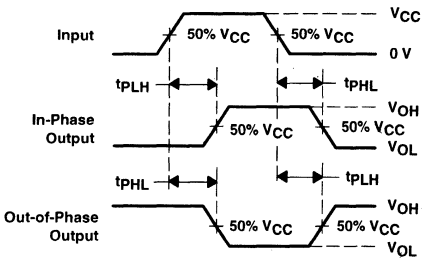
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

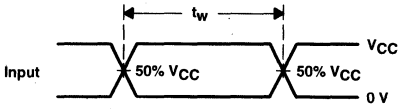


LOAD CIRCUIT

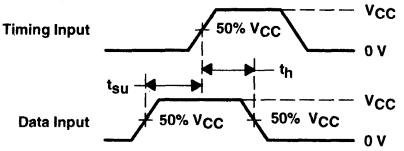
TEST	S1
t_{PLH}/t_{PHL}	Open



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

The 'AC86 are quadruple 2-input exclusive-OR gates. The devices perform the Boolean functions $Y = A \oplus B$ or $Y = \overline{A}B + A\overline{B}$ in positive logic.

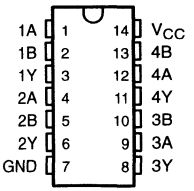
A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

The SN54AC86 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC86 is characterized for operation from −40°C to 85°C.

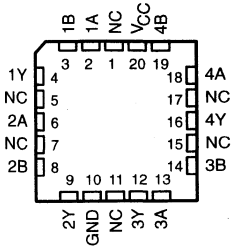
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

SN54AC86 . . . J OR W PACKAGE
SN74AC86 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)



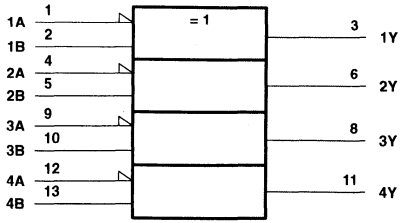
SN54AC86 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

EPIC is a trademark of Texas Instruments Incorporated.

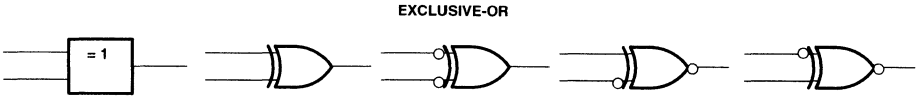
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

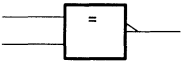
exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



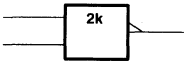
These five equivalent exclusive-OR symbols are valid for an 'AC86 gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



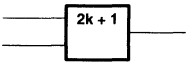
The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC86		SN74AC86		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC86		SN74AC86		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 μA	3 V	4.4			2.9		2.9		V
		4.5 V	5.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = – 12 mA	3 V	2.56			2.4		2.46		
	I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	3 V		.002	0.1		0.1		0.1	V
		4.5 V		.001	0.1		0.1		0.1	
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	μA
C_i	VI = V_{CC} or GND	5 V		2.6						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC86		SN74AC86		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	2	6.5	11.5	1	14	1.5	12.5	ns
t_{PHL}			2	6	11.5	1	14	1.5	12.5	

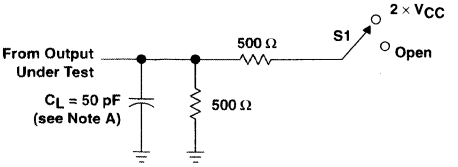
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC86		SN74AC86		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	4.5	8.5	1	10	1	9	ns
t_{PHL}			1.5	4.5	8.5	1	10	1	9.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

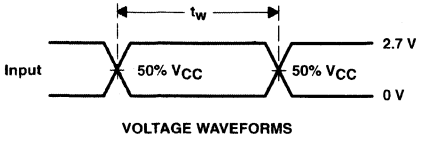
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	25	pF

PARAMETER MEASUREMENT INFORMATION

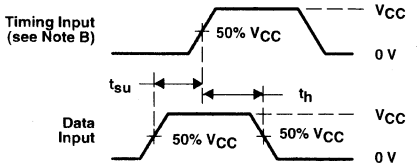


TEST	S1
t_{PLH}/t_{PHL}	Open

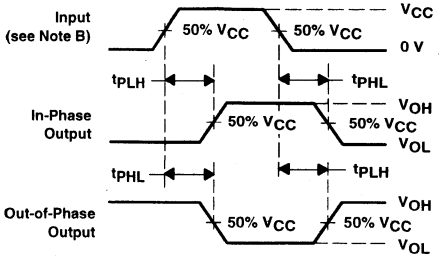
LOAD CIRCUIT



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- ***EPIC***™ **(Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and DIP (N) Packages, Ceramic Chip Carriers (FK), Flat (W), and DIP (J) Packages**

description

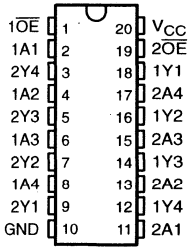
These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 'AC240 are organized as two 4-bit buffers/drivers with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the device passes data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

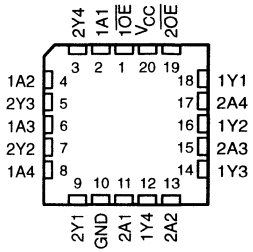
To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54AC240 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC240 is characterized for operation from −40°C to 85°C.

SN54AC240 . . . J OR W PACKAGE
SN74AC240 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC240 . . . FK PACKAGE
(TOP VIEW)

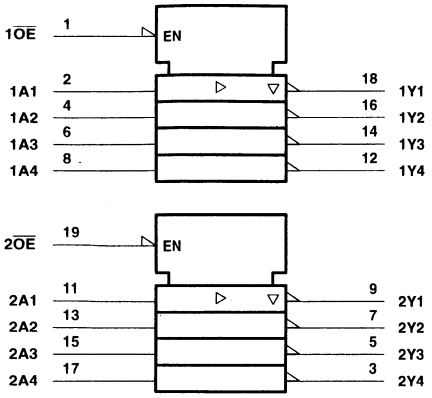


FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z

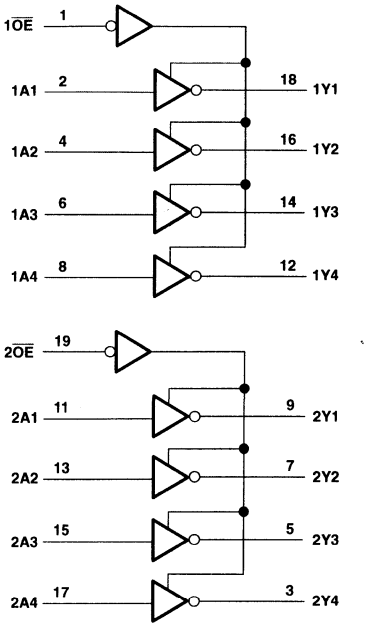
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC240		SN74AC240		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC240		SN74AC240		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = – 50 µA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = – 4 mA	3 V	2.56			2.4		2.46		
		I_{OL} = – 24 mA	4.5 V	3.86			3.7		3.76		
			5.5 V	4.86			4.7		4.76		
		I_{OH} = – 50 mA†	5.5 V				3.85				
		I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	Data inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
	Control inputs	$V_I = V_{CC}$ or GND				±0.1		±1		±1	
I_{OZ}‡		$V_O = V_{CC}$ or GND, $V_{I(OE)} = V_{IL}$ or V_{IH}	5.5 V			±0.25		±5		±2.5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			4		80		40	µA
C_i		$V_I = V_{CC}$ or GND	5 V		2.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC240		SN74AC240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	6	8	1	11	1	9	ns
t_{PHL}			1.5	5.5	8	1	10.5	1	8.5	
t_{PZH}	$\overline{OE}$	Y	1.5	6	10.5	1	11.5	1	11	ns
t_{PZL}			1.5	7	10	1	13	1	11	
t_{PHZ}	$\overline{OE}$	Y	1.5	7	10	1	12.5	1	10.5	ns
t_{PLZ}			1.5	7.5	10.5	1	13.5	1	11.5	

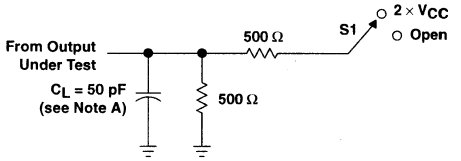
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC240		SN74AC240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	4.5	6.5	1	8.5	1	7	ns
t_{PHL}			1.5	4.5	6	1	8	1	6.5	
t_{PZH}	$\overline{OE}$	Y	1.5	5	7	1	9	1	8	ns
t_{PZL}			1.5	5.5	8	1	10.5	1	8.5	
t_{PHZ}	$\overline{OE}$	Y	2.5	6.5	9	1	10.5	1	9.5	ns
t_{PLZ}			2	6.5	9	1	11	1	9.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

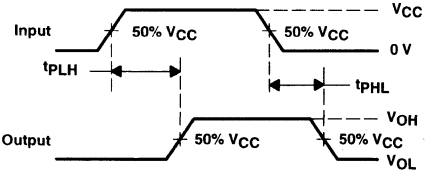
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	C_L = 50 pF, f = 10 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

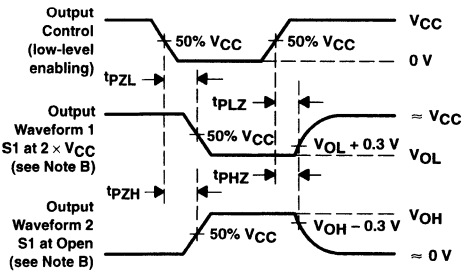


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- ***EPIC***™ **(Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and DIP (N) Packages, Ceramic Chip Carriers (FK), Flat (W), and DIP (J) Packages**

description

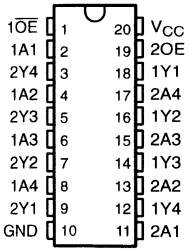
These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 'AC241 are organized as two 4-bit buffers/drivers with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the device passes data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

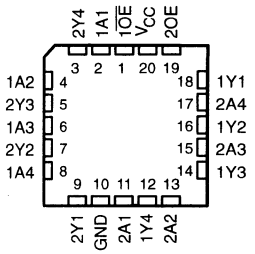
To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54AC241 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC241 is characterized for operation from −40°C to 85°C.

SN54AC241 . . . J OR W PACKAGE
SN74AC241 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC241 . . . FK PACKAGE
(TOP VIEW)



FUNCTION TABLES

INPUTS		OUTPUT
1$\overline{OE}$	1A	1Y
L	H	H
L	L	L
H	X	Z

INPUTS		OUTPUT
2$\overline{OE}$	2A	2Y
H	H	H
H	L	L
L	X	Z

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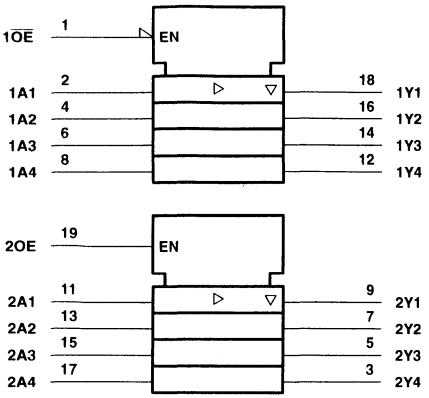
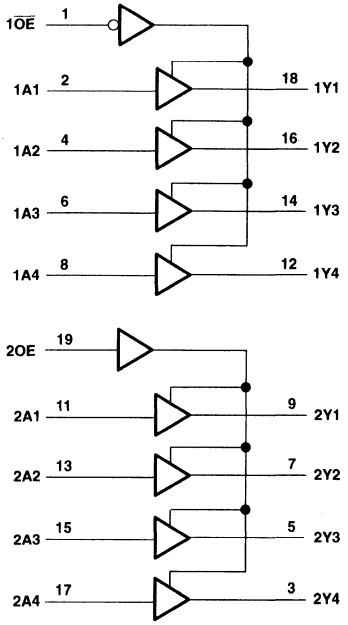
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package	0.6 W
DW package	1.6 W
N package	1.3 W
PW package	0.7 W
Storage temperature range, T_{stg}	−65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC241		SN74AC241		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC241		SN74AC241		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = – 50 µA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = – 4 mA	3 V	2.56			2.4		2.46		
		I_{OL} = – 24 mA	4.5 V	3.86			3.7		3.76		
			5.5 V	4.86			4.7		4.76		
		I_{OH} = – 50 mA†	5.5 V				3.85				
		I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	Data inputs	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
	Control inputs	V_I = V_{CC} or GND				±0.1		±1		±1	
I_{OZ}		V_O = V_{CC} or GND, $V_{I(OE)}$ = V_{IL} or V_{IH}	5.5 V			±0.25		±5		±2.5	µA
I_{CC}		V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	µA
C_i		V_I = V_{CC} or GND	5 V		2.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC241		SN74AC241		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	6	9	1	12	1.5	10	ns
t_{PHL}			1.5	6	9	1	11.5	1	10.5	
t_{PZH}	$\overline{OE}$ or OE	Y	1.5	6.5	12.5	1	13	1	13	ns
t_{PZL}			1.5	7	12	1	13	1.5	13	
t_{PHZ}	$\overline{OE}$ or OE	Y	2	8	12	1	13	2	12.5	ns
t_{PLZ}			1.5	7	12.5	1	13	1	13.5	

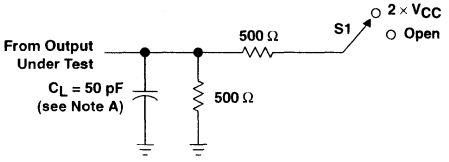
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC241		SN74AC241		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	5	7	1	9.5	1	7.5	ns
t_{PHL}			1.5	4.5	7	1	9	1	7.5	
t_{PZH}	$\overline{OE}$ or OE	Y	1.5	5.5	9	1	10	1	9.5	ns
t_{PZL}			1.5	5.5	9	1	10	1	9.5	
t_{PHZ}	$\overline{OE}$ or OE	Y	1.5	6.5	10	1	11.5	1	10.5	ns
t_{PLZ}			1.5	6	10	1	11.5	1	10.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

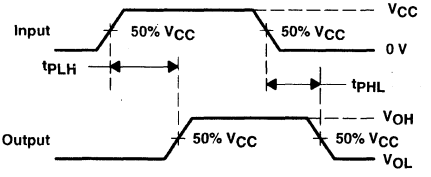
PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	C_L = 50 pF,	f = 1 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

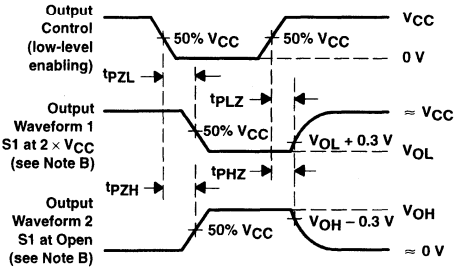


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- ***EPIC***™ **(Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and DIP (N) Packages, Ceramic Chip Carriers (FK), Flat (W), and DIP (J) Packages**

description

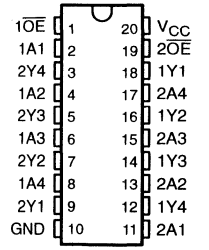
These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 'AC244 are organized as two 4-bit buffers/drivers with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the device passes data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

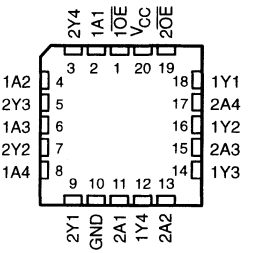
To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54AC244 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AC244 is characterized for operation from –40°C to 85°C.

SN54AC244 . . . J OR W PACKAGE
SN74AC244 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC244 . . . FK PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

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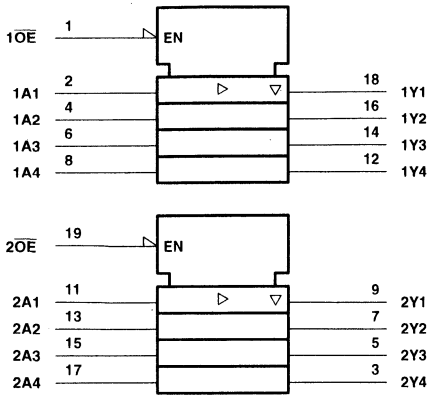
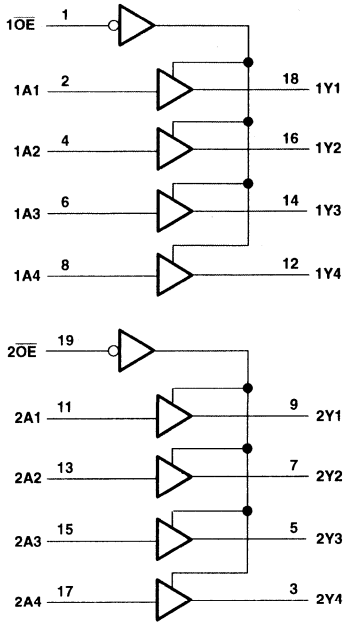
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at $T_A = 55°C$ (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC244		SN74AC244		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC244		SN74AC244		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = – 50 µA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = – 4 mA	3 V	2.56			2.4		2.46		
		I_{OL} = – 24 mA	4.5 V	3.86			3.7		3.76		
			5.5 V	4.86			4.7		4.76		
		I_{OH} = – 50 mA†	5.5 V				3.85				
		I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	Data inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
	Control inputs	$V_I = V_{CC}$ or GND				±0.1		±1		±1	
I_{OZ}		$V_O = V_{CC}$ or GND, $V_{I(OE)} = V_{IL}$ or V_{IH}	5.5 V			±0.25		±5		±2.5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			4		80		40	µA
C_i		$V_I = V_{CC}$ or GND	5 V		2.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC244		SN74AC244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	2	6.5	9	1	12.5	1.5	10	ns
t_{PHL}			2	6.5	9	1	12	2	10	
t_{PZH}	$\overline{OE}$	Y	2	6	10.5	1	11.5	1.5	11	ns
t_{PZL}			2.5	7.5	10	1	13	2	11	
t_{PHZ}	$\overline{OE}$	Y	3	7	10	1	12.5	1.5	10.5	ns
t_{PLZ}			2.5	7.5	10.5	1	13	2.5	11.5	

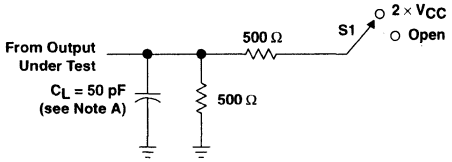
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC244		SN74AC244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	5	7	1	9.5	1	7.5	ns
t_{PHL}			1.5	5	7	1	9	1	7.5	
t_{PZH}	$\overline{OE}$	Y	1.5	5	7	1	9	1.5	8	ns
t_{PZL}			1.5	5.5	8	1	10.5	1.5	8.5	
t_{PHZ}	$\overline{OE}$	Y	2.5	6.5	9	1	10.5	1	9.5	ns
t_{PLZ}			2.0	6.5	9	1	11	2	9.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

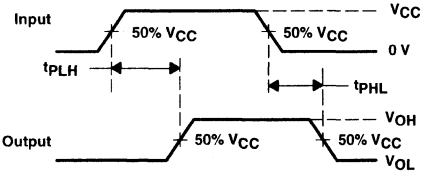
PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	C_L = 50 pF,	f = 10 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

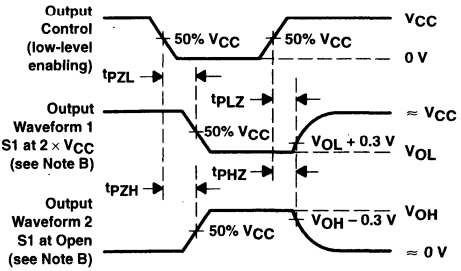


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- ***EPIC***™ **(Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

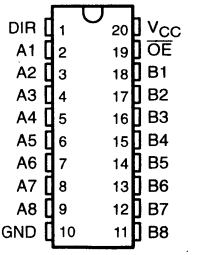
description

The 'AC245 octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

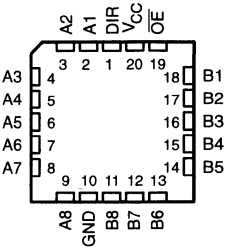
The device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction control (DIR) input. The output enable ($\overline{OE}$) can be used to disable the device so that the buses are effectively isolated.

The SN54AC245 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC245 is characterized for operation from −40°C to 85°C.

SN54AC245 . . . J OR W PACKAGE
SN74AC245 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC245 . . . FK PACKAGE
(TOP VIEW)

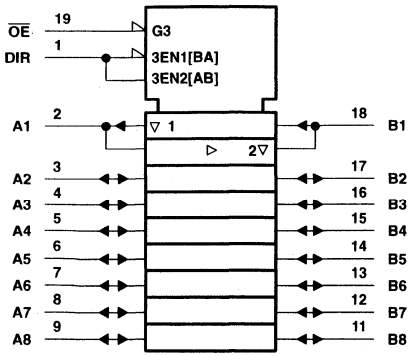


FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

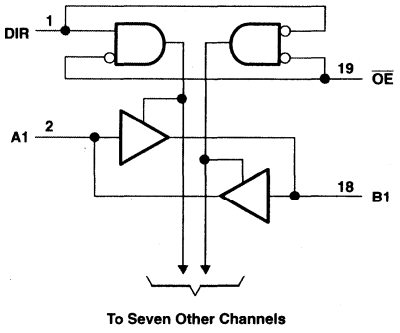
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, J, N, PW, and W packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air)(see Note 2):
DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

			SN54AC245		SN74AC245		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC245		SN74AC245		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = – 50 µA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = – 12 mA	3 V	2.56			2.4		2.46		
		I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
			5.5 V	4.86			4.7		4.76		
		I_{OH} = –50 mA†	5.5 V				3.85				
		I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 µA	3 V		.002	0.1		0.1		0.1	V
			4.5 V		.001	0.1		0.1		0.1	
			5.5 V		.001	0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	A or B ports‡	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
	$\overline{OE}$ or DIR					±0.1		±1		±1	
I_{OZ}		V_O = V_{CC} or GND, V_I(OE) = V_{IL} or V_{IH}	5.5 V			±0.5		±10		±5	µA
I_{CC}		V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	µA
C_i		V_I = V_{CC} or GND	5 V		4.5						pF
C_{io}		V_O = V_{CC} or GND	5 V		15						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC245		SN74AC245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.5	5	8.5	1	11.5	1	9	ns
t_{PHL}			1.5	5	8.5	1	10	1	9	
t_{PZH}	$\overline{OE}$	A or B	2.5	7	11.5	1	13.5	2	12.5	ns
t_{PZL}			2.5	7.5	12	1	14.5	2	13.5	
t_{PHZ}	$\overline{OE}$	A or B	2	6.5	12	1	13.5	1	12.5	ns
t_{PLZ}			2	7	11.5	1	14	1.5	13	

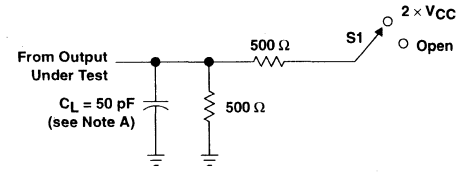
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC245		SN74AC245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.5	3.5	6.5	1	8.5	1	7	ns
t_{PHL}			1.5	3.5	6	1	7.5	1	7	
t_{PZH}	$\overline{OE}$	A or B	1.5	5	8.5	1	10	1	9	ns
t_{PZL}			1.5	5.5	9	1	10.5	1	9.5	
t_{PHZ}	$\overline{OE}$	A or B	1.5	5.5	9	1	10.5	1	10	ns
t_{PLZ}			1.5	5.5	9	1	10.5	1	10	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

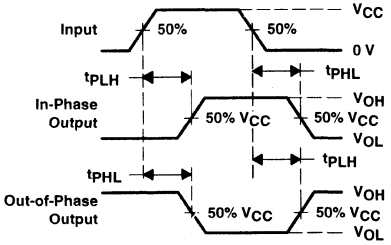
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	C_L = 50 pF, f = 1 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

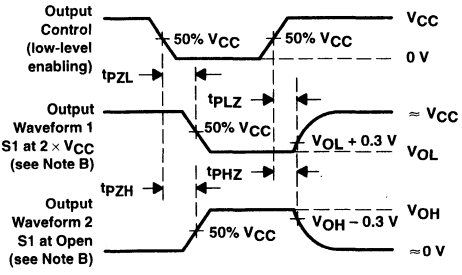


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS



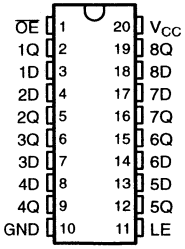
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

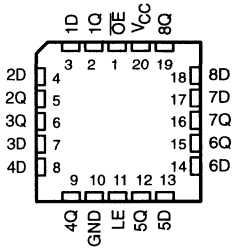
Figure 1. Load Circuit and Voltage Waveforms

- **3-State Noninverting Outputs Drive Bus Lines Directly**
- **Full Parallel Access for Loading**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW) Shrink Small-Outline (DB) and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54AC373 . . . J OR W PACKAGE
SN74AC373 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC373 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches are D-type transparent latches. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines in bus-organized systems without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

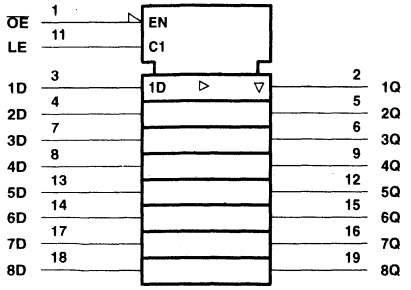
The SN54AC373 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC373 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each latch)

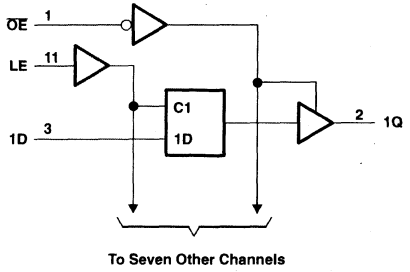
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

			SN54AC373		SN74AC373		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC373		SN74AC373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = −12 mA	3 V	2.56			2.4		2.46		
	I_{OH} = −24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
V_{OL}	I_{OL} = 50 μA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.25		±5		±2.5	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	μA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC373		SN74AC373		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	5.5		6.5		6		ns
t_{su}	Setup time, data before LE↓	5.5		6.5		6		ns
t_h	Hold time, data after LE↓	1		1		1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC373		SN74AC373		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	4		5		4.5		ns
t_{su}	Setup time, data before LE↓	4		5		4.5		ns
t_h	Hold time, data after LE↓	1		1		1		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	TO (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC373		SN74AC373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	1.5	10	13.5	1	16.5	1.5	15	ns
t_{PHL}			1.5	9.5	13.0	1	16	1.5	14.5	
t_{PLH}	LE	Q	1.5	10	13.5	1	16.5	1.5	15	ns
t_{PHL}			1.5	9.5	12.5	1	15	1.5	14	
t_{PZH}	$\overline{OE}$	Q	1.5	9	11.5	1	14	1	13	ns
t_{PZL}			1.5	8.5	11.5	1	13.5	1	13	
t_{PHZ}	$\overline{OE}$	Q	1.5	10	12.5	1	16	1	14.5	ns
t_{PLZ}			1.5	8	11.5	1	13	1	12.5	

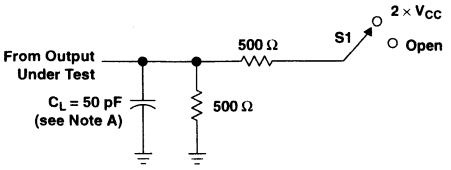
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	TO (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC373		SN74AC373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	1.5	7	9.5	1	11.5	1.5	10.5	ns
t_{PHL}			1.5	7	9.5	1	11.5	1.5	10.5	
t_{PLH}	LE	Q	1.5	7.5	9.5	1	12	1.5	10.5	ns
t_{PHL}			1.5	7	9.5	1	11	1.5	10.5	
t_{PZH}	$\overline{OE}$	Q	1.5	7	8.5	1	10.5	1	9.5	ns
t_{PZL}			1.5	6.5	8.5	1	10	1	9.5	
t_{PHZ}	$\overline{OE}$	Q	1.5	8	11	1	13.5	1	12.5	ns
t_{PLZ}			1.5	6.5	8.5	1	10.5	1	10	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

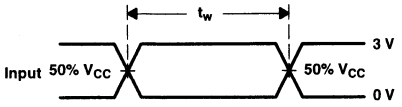
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION

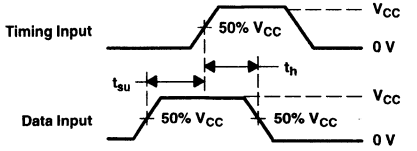


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open

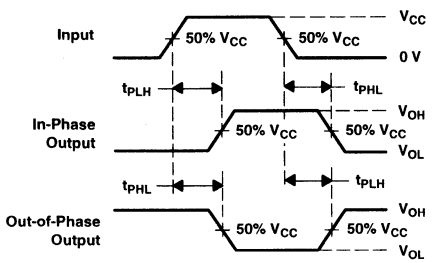
LOAD CIRCUIT



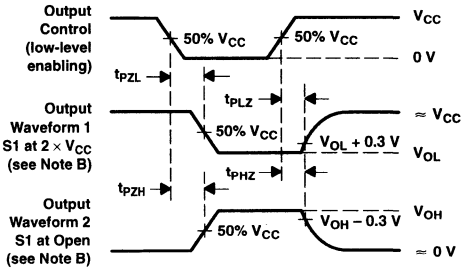
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



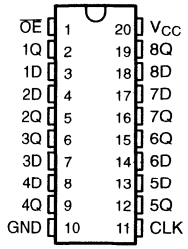
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

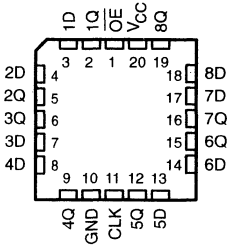
Figure 1. Load Circuit and Voltage Waveforms

- **3-State Non-Inverting Outputs Drive Bus Lines Directly**
- **Full Parallel Access for Loading**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW) Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54AC374 . . . J OR W PACKAGE
SN74AC374 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC374 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the 'AC374 are D-type edge-triggered flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines in bus-organized systems without need for interface or pullup components.

$\overline{OE}$ does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

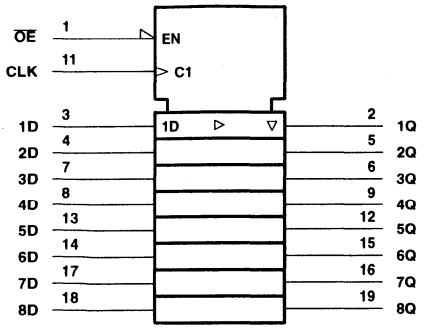
The SN54AC374 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC374 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

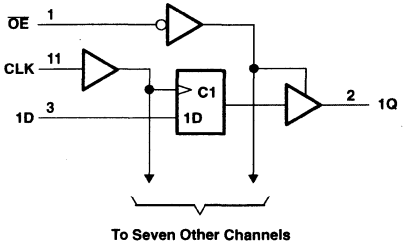
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at $T_A = 55°C$ (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

			SN54AC374		SN74AC374		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC374		SN74AC374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = −12 mA	3 V	2.56			2.4		2.46		
	I_{OH} = −24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
V_{OL}	I_{OL} = 50 μA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.25		±5		±2.5	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	μA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC374		SN74AC374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	5.5		6.5		6		ns
t_{su}	Setup time, data before CLK↑	5.5		6.5		6		ns
t_h	Hold time, data after CLK↑	1				1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC374		SN74AC374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	4		5		4.5		ns
t_{su}	Setup time, data before CLK↑	4		5		4.5		ns
t_h	Hold time, data after CLK↑	1.5		1.5		1.5		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	TO (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC374		SN74AC374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			60	110		60		60		MHz
t_{PLH}	CLK	Q	3	11	13.5	3	16.5	1.5	15.5	ns
t_{PHL}			2.5	10	12.5	3	15	2	14	
t_{PZH}	$\overline{OE}$	Q	3	9.5	11.5	1	14	1.5	13	ns
t_{PZL}			3.5	9	11.5	1	14	1.5	13	
t_{PHZ}	$\overline{OE}$	Q	3	10.5	12.5	1	16	2	14.5	ns
t_{PLZ}			2	8	11.5	1	13	1	12.5	

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

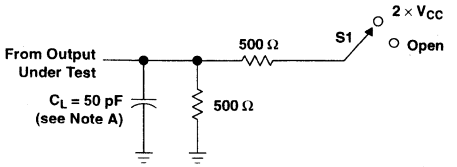
PARAMETER	TO (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC374		SN74AC374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			100	155		95		100		MHz
t_{PLH}	CLK	Q	2.5	8	9.5	3	12	1.5	10.5	ns
t_{PHL}			2	7	9	3	11	1.5	10	
t_{PZH}	$\overline{OE}$	Q	2	7	8.5	1.5	10.5	1	9.5	ns
t_{PZL}			2	6.5	8.5	1.5	10.5	1	9.5	
t_{PHZ}	$\overline{OE}$	Q	2	8	11	1.5	12.5	2	12.5	ns
t_{PLZ}			1.5	6.5	8.5	1.5	10.5	1	10	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	40	pF

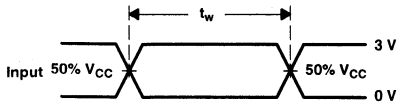
TEXAS INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION

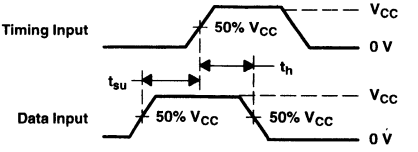


LOAD CIRCUIT

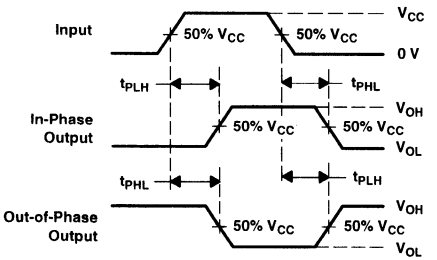
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



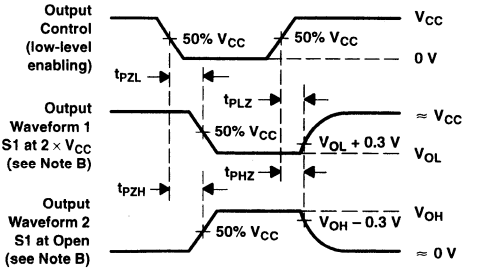
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



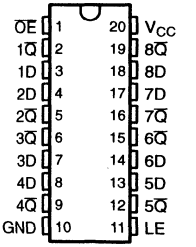
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

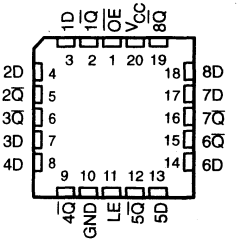
Figure 1. Load Circuit and Voltage Waveforms

- **3-State Inverting Outputs Drive Bus Lines Directly**
- **Full Parallel Access for Loading**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54AC533 . . . J OR W PACKAGE
SN74AC533 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC533 . . . FK PACKAGE
(TOP VIEW)



description

The 'AC533 are octal transparent D-type latches with 3-state outputs. When the latch-enable (LE) input is high, the Q outputs follow the complements of the data (D) inputs. When LE is taken low, the Q outputs are latched at the inverse logic levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

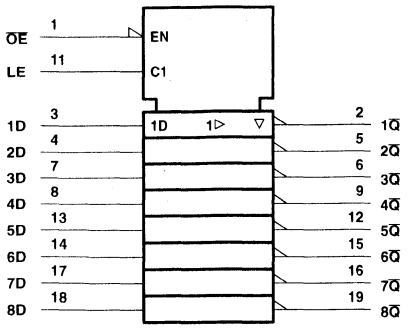
The SN54AC533 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC533 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each latch)

INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	L
L	H	L	H
L	L	X	Q_0
H	X	X	Z

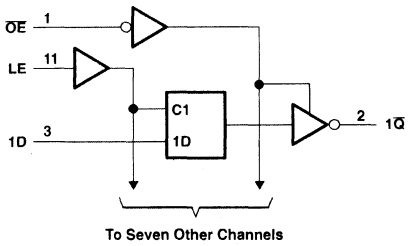
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

			SN54AC533		SN74AC533		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		–12		–12	mA
		V_{CC} = 4.5 V		–24		–24	
		V_{CC} = 5.5 V		–24		–24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC533		SN74AC533		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = –12 mA	3 V	2.56			2.4		2.46		
	I_{OH} = –24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
V_{OL}	I_{OL} = 50 μA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.25		±5		±2.5	μA
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	μA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC533		SN74AC533		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	6		8		6.5		ns
t_{su}	Setup time, data before LE↓	5.5		7.5		6		ns
t_h	Hold time, data after LE↓	1.5		2.5		1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC533		SN74AC533		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	4.5		6.5		5		ns
t_{su}	Setup time, data before LE↓	4		6		4.5		ns
t_h	Hold time, data after LE↓	1.5		2.5		1		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C		SN54AC533		SN74AC533		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	$\overline{Q}$	2	14	1	17.5	1.5	16	ns
t_{PHL}			2	13	1	16	1.5	14.5	
t_{PLH}	LE	$\overline{Q}$	2	14.5	1	18	1.5	16.5	ns
t_{PHL}			2	13	1	16	1.5	14.5	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	2	12.5	1	15.5	1.5	14	ns
t_{PZL}			2	12.5	1	15.5	1.5	14	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	2	13	1	16	1.5	14.5	ns
t_{PLZ}			2	13	1	16	1.5	14.5	

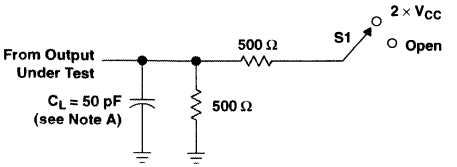
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C		SN54AC533		SN74AC533		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	$\overline{Q}$	2	10	1	12.5	1.5	11	ns
t_{PHL}			2	9.5	1	12	1.5	10.5	
t_{PLH}	LE	$\overline{Q}$	2	10.5	1	13	1.5	11.5	ns
t_{PHL}			2	10	1	13	1.5	11	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	2	9.5	1	12	1.5	10.5	ns
t_{PZL}			2	9.5	1	12	1.5	10.5	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	2	10	1	12.5	1.5	11	ns
t_{PLZ}			2	10	1	12.5	1.5	11	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

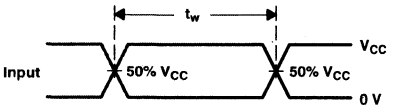
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION

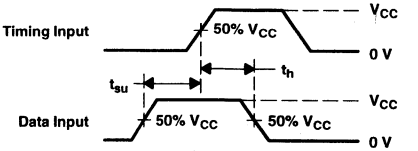


LOAD CIRCUIT

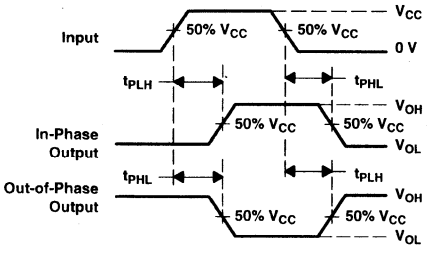
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



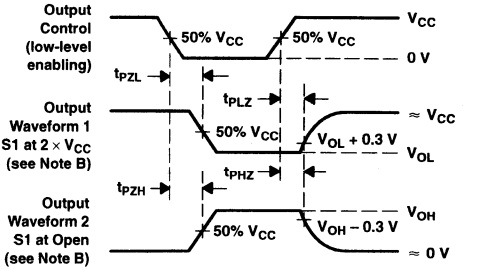
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



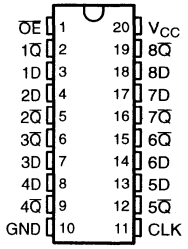
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

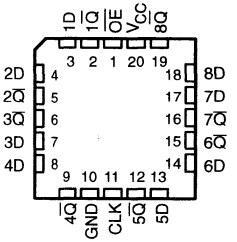
Figure 1. Load Circuit and Voltage Waveforms

- **3-State Inverting Outputs Drive Bus Lines Directly**
- **Full Parallel Access for Loading**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54AC534 . . . J OR W PACKAGE
SN74AC534 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC534 . . . FK PACKAGE
(TOP VIEW)



description

These octal edge-triggered D-type flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the $\overline{Q}$ outputs are set to the complements of the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

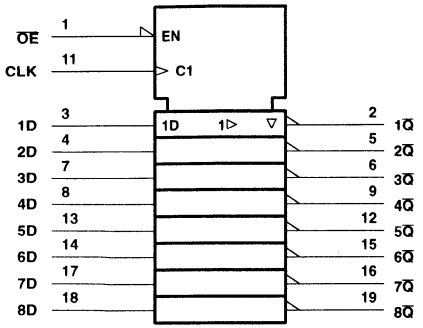
The SN54AC534 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC534 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	$\overline{Q}$
L	↑	H	L
L	↑	L	H
L	H or L	X	$\overline{Q}_0$
H	X	X	Z

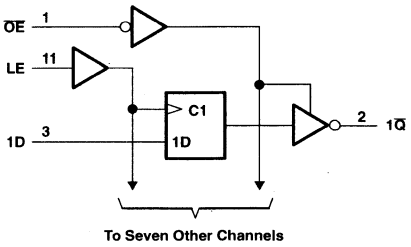
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at $T_A = 55°C$ (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

			SN54AC534		SN74AC534		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		–12		–12	mA
		V_{CC} = 4.5 V		–24		–24	
		V_{CC} = 5.5 V		–24		–24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC534		SN74AC534		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = –12 mA	3 V	2.56			2.4		2.46		
	I_{OH} = –24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
V_{OL}	I_{OL} = 50 μA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.5		±5		±2.5	μA
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	μA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC534		SN74AC534		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	5		8		6.5		ns
t_{su}	Setup time, data before CLK↑	5		8		6.5		ns
t_h	Hold time, data after CLK↑	1		3		1.5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC534		SN74AC534		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	3.5		5.5		4		ns
t_{su}	Setup time, data before CLK↑	3.5		5.5		4		ns
t_h	Hold time, data after CLK↑	1		3		1.5		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C		SN54AC534		SN74AC534		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			70		60		70		MHz
t_{PLH}	CLK	$\overline{Q}$	3	14	2	17.5	2.5	16	ns
t_{PHL}			3	13	2	16.5	2.5	15	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	3	12.5	2	15.5	2.5	14	ns
t_{PZL}			3	12.5	2	15.5	2.5	14	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	2	13.5	1	16.5	1.5	15	ns
t_{PLZ}			2	12	1	15	1.5	13.5	

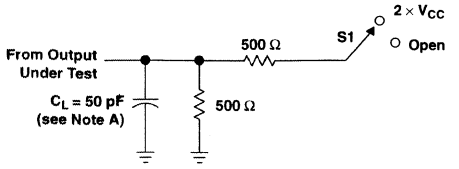
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C		SN54AC534		SN74AC534		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			150		75		140		MHz
t_{PLH}	CLK	$\overline{Q}$	2.5	10.5	1.5	13.5	2	12	ns
t_{PHL}			2.5	9.5	1.5	12.5	2	11	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	2.5	10	1.5	13	2	11.5	ns
t_{PZL}			2.5	10	1.5	13	2	11.5	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	1.5	11.5	1	14	1	12.5	ns
t_{PLZ}			1.5	10	1	12.5	1	11	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

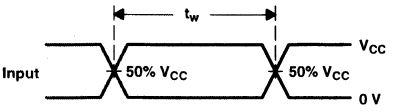
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION

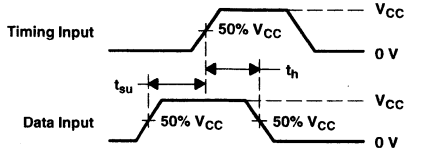


LOAD CIRCUIT

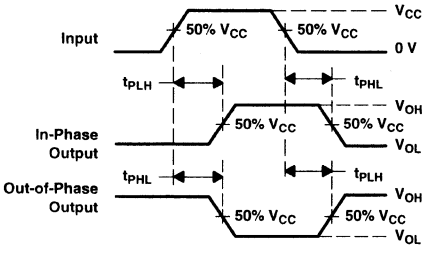
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



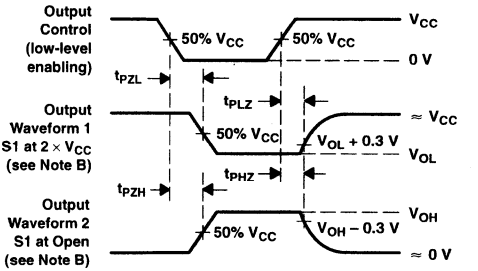
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



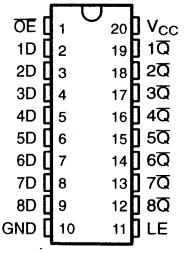
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

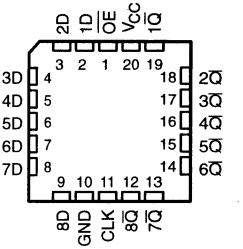
Figure 1. Load Circuit and Voltage Waveforms

- **3-State Inverting Outputs Drive Bus Lines Directly**
- **Full Parallel Access for Loading**
- **Flow-Through Architecture to Optimize PCB Layout**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54AC563 . . . J OR W PACKAGE
SN74AC563 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC563 . . . FK PACKAGE
(TOP VIEW)



description

The 'AC563 are octal D-type transparent latches with 3-state outputs. When the latch-enable (LE) input is high, the $\overline{Q}$ outputs follow the complements of the data (D) inputs. When LE is taken low, the $\overline{Q}$ outputs are latched at the inverse logic levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

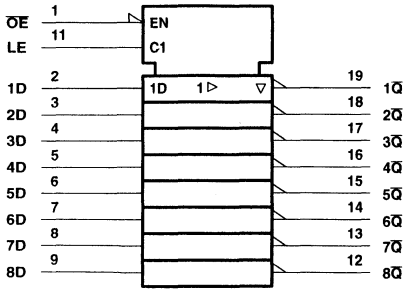
The SN54AC563 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AC563 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each latch)

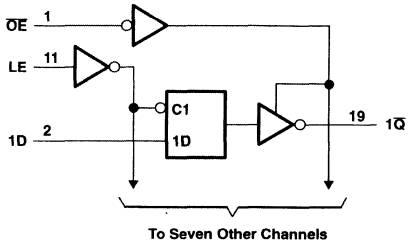
INPUTS			OUTPUT
$\overline{OE}$	LE	D	$\overline{Q}$
L	H	H	L
L	H	L	H
L	L	X	$\overline{Q}_0$
H	X	X	Z

EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, J, N, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

			SN54AC563		SN74AC563		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		–12		–12	mA
		V_{CC} = 4.5 V		–24		–24	
		V_{CC} = 5.5 V		–24		–24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			8		8	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC563		SN74AC563		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	3 V	2.99			2.9		2.9		V
		4.5 V	4.49			4.4		4.4		
		5.5 V	5.49			5.4		5.4		
	I_{OH} = –12 mA	3 V	2.56			2.48		2.46		
	I_{OH} = –24 mA	4.5 V	3.86			3.8		3.76		
		5.5 V	4.86			4.8		4.76		
	I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}	I_{OL} = 50 µA	3 V		0.002	0.1		0.1		0.1	V
		4.5 V		0.001	0.1		0.1		0.1	
		5.5 V		0.001	0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			8				80	µA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC563		SN74AC563		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	6		8		7		ns
t_{su}	Setup time, data before LE↓	2.5		5		3		ns
t_h	Hold time, data after LE↓	2		3		2		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC563		SN74AC563		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	4		6		5		ns
t_{su}	Setup time, data before LE↓	2		4.5		2.5		ns
t_h	Hold time, data after LE↓	2		3		2		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC563		SN74AC563		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	$\overline{Q}$	3.5	5.3	13	1.5	16.5	3.5	15	ns
t_{PHL}			3.5	5.6	12	1.5	15.5	3.5	14	
t_{PLH}	LE	$\overline{Q}$	3.5	4.6	13	1.5	16.5	3.5	15	ns
t_{PHL}			3.5	4.8	12	1.5	15.5	3.5	14	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	2.5	5.3	11	1.5	13.5	2.5	12	ns
t_{PZL}			3	5.4	11	1.5	14	3.5	12.5	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	4	6	12.5	1.5	15	4.5	13.5	ns
t_{PLZ}			2	5.1	9.5	1.5	12	2.5	10.5	

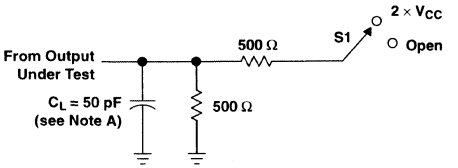
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC563		SN74AC563		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	$\overline{Q}$	2	5.3	10	1.5	13	2	11.5	ns
t_{PHL}			2	5.6	9.5	1.5	12.5	2	11	
t_{PLH}	LE	$\overline{Q}$	2	4.6	9.5	1.5	12.5	2	11	ns
t_{PHL}			2	4.8	8.5	1.5	11.5	2	9.5	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	2	5.3	9	1.5	11.5	2	10	ns
t_{PZL}			1.5	5.4	8.5	1.5	11	2	9.5	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	2	6	11	1.5	13.5	2	12	ns
t_{PLZ}			1.5	5.1	8	1.5	10.5	1.5	9	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

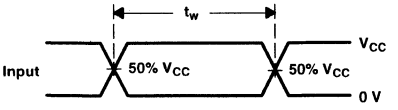
PARAMETER		TEST CONDITIONS	SN54AC563			SN74AC563			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz		25			25		pF

PARAMETER MEASUREMENT INFORMATION

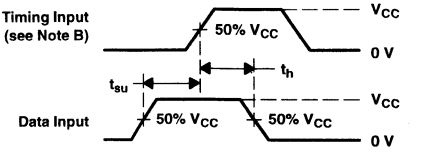


LOAD CIRCUIT

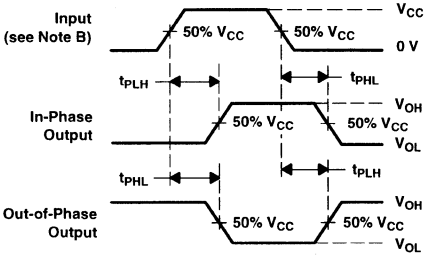
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



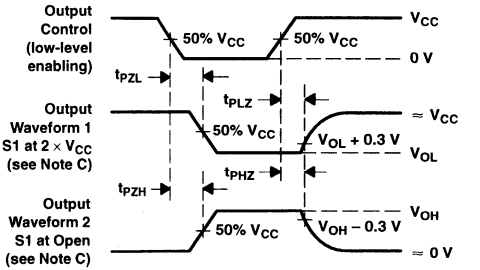
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



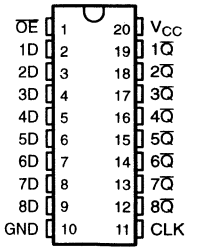
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

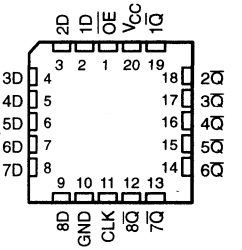
Figure 1. Load Circuit and Voltage Waveforms

- **3-State Inverting Outputs Drive Bus Lines Directly**
- **Full Parallel Access for Loading**
- **Flow-Through Architecture to Optimize PCB Layout**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54AC564 . . . J OR W PACKAGE
SN74AC564 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT564 . . . FK PACKAGE
(TOP VIEW)



description

The 'AC564 are octal D-type edge-triggered flip-flops which feature inverting 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the $\overline{Q}$ outputs are set to the inverse logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

$\overline{OE}$ does not affect internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

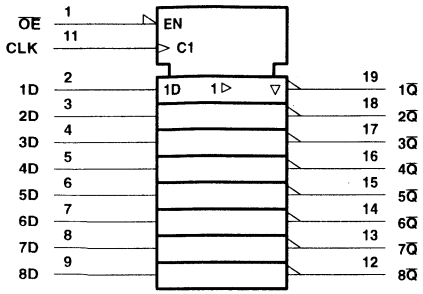
The SN54AC564 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AC564 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each flip-flop)

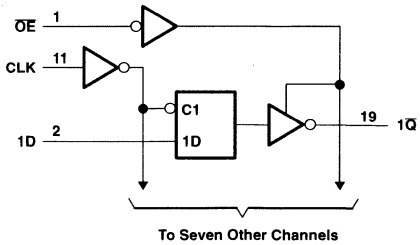
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	$\overline{Q}$
L	↑	H	L
L	↑	L	H
L	H or L	X	$\overline{Q}_0$
H	X	X	Z

EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, J, N, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

			SN54AC564		SN74AC564		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		–12		–12	mA
		V_{CC} = 4.5 V		–24		–24	
		V_{CC} = 5.5 V		–24		–24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C			SN54AC564		SN74AC564		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 μA		3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
	I_{OH} = –12 mA		3 V	2.56			2.4		2.46		
	I_{OH} = –24 mA		4.5 V	3.86			3.7		3.76		
			5.5 V	4.86			4.7		4.76		
V_{OL}	I_{OL} = 50 μA		3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA		3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA		4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
I_I	V_I = V_{CC} or GND		5.5 V			±0.1		±1		±1	μA
I_{OZ}	V_O = V_{CC} or GND		5.5 V			±0.5		±5		±5	μA
I_{CC}	V_I = V_{CC} or GND,	I_O = 0	5.5 V			4		80		40	μA
C_i	V_I = V_{CC} or GND		5 V		4.5						pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC564		SN74AC564		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	6		7.5		7		ns
t_{su}	Setup time, data before CLK↑	2.5		4.5		3		ns
t_h	Hold time, data after CLK↑	2		2.5		2		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC564		SN74AC564		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	4		5		5		ns
t_{su}	Setup time, data before CLK↑	2		3.5		2.5		ns
t_h	Hold time, data after CLK↑	2		2.5		2		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC564		SN74AC564		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			75			55		60		MHz
t_{PLH}	CLK	$\overline{Q}$	3.5	8.1	14	1	16.5	3.5	15.5	ns
t_{PHL}			3.5	8.2	12.5	1	15	3.5	14	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	2.5	7.2	11.5	1	13	2.5	12.5	ns
t_{PZL}			3	7.7	11	1	12.5	3.5	12	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	4	8.6	12.5	1	14	4.5	13.5	ns
t_{PLZ}			2	7.3	9.5	1	10.5	2.5	10.5	

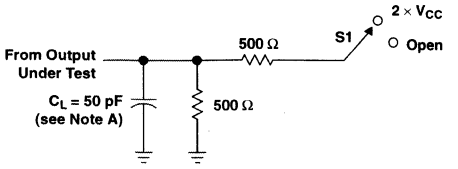
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC564		SN74AC564		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			95			85		85		MHz
t_{PLH}	CLK	$\overline{Q}$	2	4.9	10.5	1.5	11.5	2	11.5	ns
t_{PHL}			2	5	9.5	1.5	10.5	2	10.5	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	2	5.1	9	1.5	9.5	2	9.5	ns
t_{PZL}			1.5	5.2	8.5	1.5	9.5	2	9.5	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	2	5.7	10.5	1.5	11.5	2	11.5	ns
t_{PLZ}			1.5	4.8	8	1.5	9	1.5	9	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

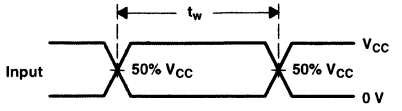
PARAMETER		TEST CONDITIONS	SN54AC564			SN74AC564			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz		50			50		pF

PARAMETER MEASUREMENT INFORMATION

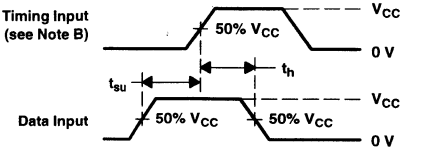


LOAD CIRCUIT

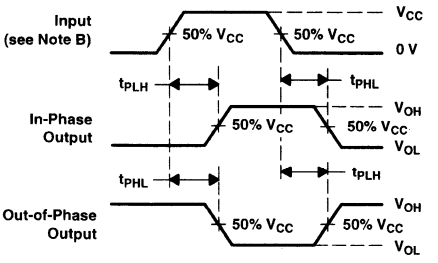
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



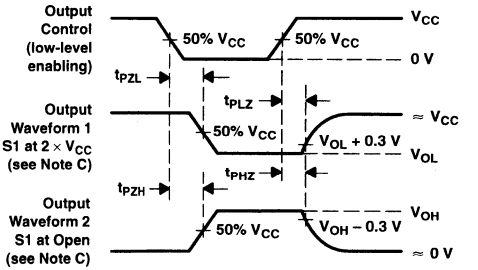
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



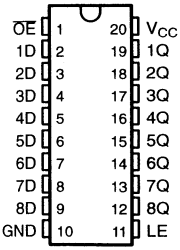
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

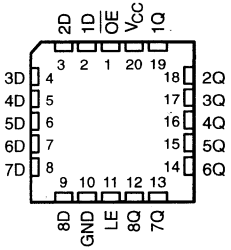
Figure 1. Load Circuit and Voltage Waveforms

- **3-State Outputs Drive Bus Lines Directly**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW) Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54AC573 . . . J OR W PACKAGE
SN74AC573 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC573 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches are D-type transparent latches. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D Inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines in a bus-organized system without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

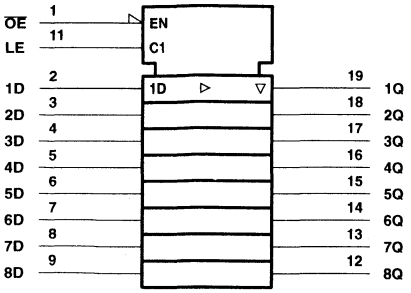
The SN54AC573 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74AC573 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE
(each latch)

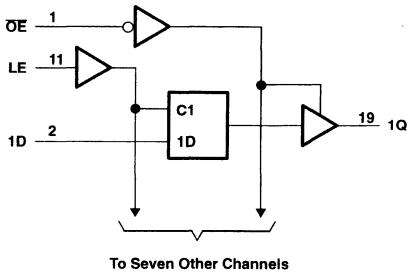
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to + 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ± 20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ± 20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ± 50 mA
Continuous current through, V_{CC} or GND ..... ± 200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... − 65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

			SN54AC573		SN74AC573		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		– 12		– 12	mA
		V_{CC} = 4.5 V		– 24		– 24	
		V_{CC} = 5.5 V		– 24		– 24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		– 55	125	– 40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC573		SN74AC573		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = – 4 mA	3 V	2.58			2.48		2.48		
	I_{OH} = – 24 mA	4.5 V	3.94			3.8		3.8		
		5.5 V	4.94			4.8		4.8		
	I_{OH} = – 75 mA†	5.5 V				3.85		3.85		
V_{OL}	I_{OL} = 50 μA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.44		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.44		0.44	
	I_{OL} = 75 mA	5.5 V					1.65		1.65	
I_I	V_I = V_{CC} or GND	5.5 V			± 0.1		± 1		± 1	μA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			± 0.25		± 5		± 2.5	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	μA
C_i	V_I = V_{CC} or GND	5 V		5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC573		SN74AC573		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	6		8		7		ns
t_{su}	Setup time, data before LE↓	3.5		5		4		ns
t_h	Hold time, data after LE↓	2		3		2		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC573		SN74AC573		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	4		6		5		ns
t_{su}	Setup time, data before LE↓	3		4.5		3.5		ns
t_h	Hold time, data after LE↓	2		3		2		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C		SN54AC573		SN74AC573		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	2.5	13	1.5	16.5	2	15	ns
t_{PHL}			2.5	12	1.5	15.5	2	14	
t_{PLH}	LE	Q	2.5	13	1.5	16.5	2	15	ns
t_{PHL}			2.5	12	1.5	15.5	2	14	
t_{PZH}	$\overline{OE}$	Q	2.5	11	1.5	13.5	2	12	ns
t_{PZL}			2.5	11	1.5	14	2	12.5	
t_{PHZ}	$\overline{OE}$	Q	2.5	12.5	1.5	15	2	13.5	ns
t_{PLZ}			2.5	9.5	1.5	12	2	10.5	

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

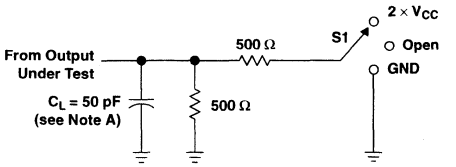
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C		SN54AC573		SN74AC573		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	2.5	10	1.5	13	2	11.5	ns
t_{PHL}			2.5	9.5	1.5	12.5	2	11	
t_{PLH}	LE	Q	2.5	9.5	1.5	12.5	2	11	ns
t_{PHL}			2.5	8.5	1.5	11.5	2	10	
t_{PZH}	$\overline{OE}$	Q	2.5	9	1.5	11.5	2	10	ns
t_{PZL}			2.5	8.5	1.5	11	2	9.5	
t_{PHZ}	$\overline{OE}$	Q	2.5	11	1.5	13.5	2	12	ns
t_{PLZ}			2.5	8	1.5	10.5	2	9	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	25	pF

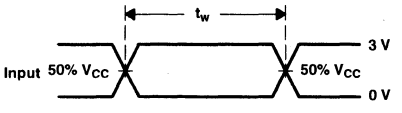
TEXAS INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION

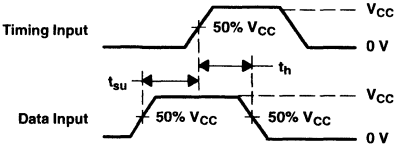


LOAD CIRCUIT

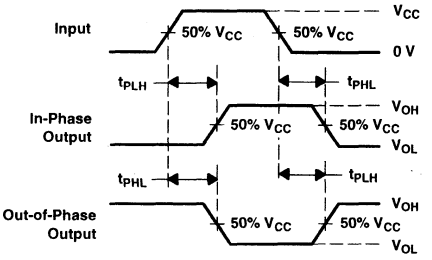
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



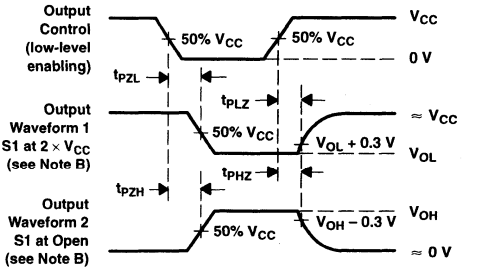
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



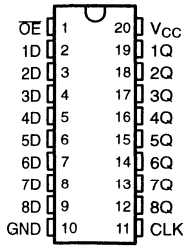
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

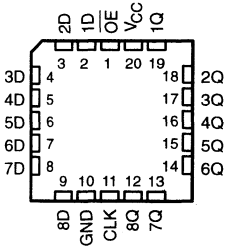
Figure 1. Load Circuit and Voltage Waveforms

- **3-State Outputs Drive Bus Lines Directly**
- ***EPIC***™ **(Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW) Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIP Packages**

SN54AC574 . . . J OR W PACKAGE
SN74AC574 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54AC574 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the 'AC574 are D-type edge-triggered flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines in a bus-organized system without need for interface or pullup components.

$\overline{OE}$ does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

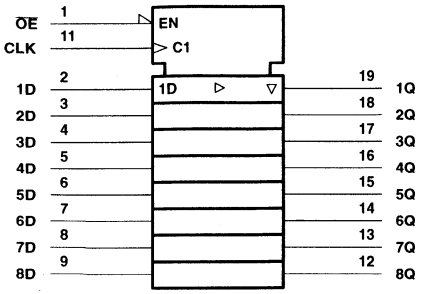
The SN54AC574 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AC574 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each flip-flop)

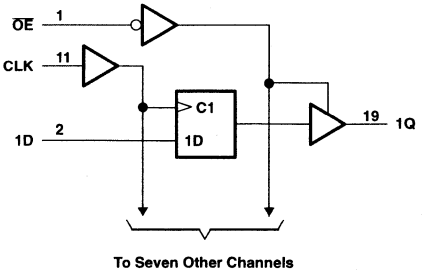
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package	0.6 W
DW package	1.6 W
N package	1.3 W
PW package	0.7 W
Storage temperature range, T_{stg}	−65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

			SN54AC574		SN74AC574		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	8	0	8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC574		SN74AC574		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = −12 mA	3 V	2.56			2.4		2.46		
	I_{OH} = −24 mA	4.5 V	3.94			3.7		3.76		
		5.5 V	4.94			4.7		4.76		
V_{OL}	I_{OL} = 50 μA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.5		±5		±2.5	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	μA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC574		SN74AC574		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	6		7.5		7		ns
t_{su}	Setup time, data before CLK↑	2.5		6.5		3		ns
t_h	Hold time, data after CLK↑	1.5		2.5		1.5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC574		SN74AC574		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	4		5		5		ns
t_{su}	Setup time, data before CLK↑	1.5		3.5		2		ns
t_h	Hold time, data after CLK↑	1.5		2.5		1.5		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	TO (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC574		SN74AC574		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			75	112		55		60		MHz
t_{PLH}	CLK	Q	3.5	8.5	13.5	1	16.5	3.5	15	ns
t_{PHL}			3.5	7.5	12	1	15	3.5	13.5	
t_{PZH}	$\overline{OE}$	Q	2.5	7	11	1	13	2.5	12	ns
t_{PZL}			3	6.5	10.5	1	12.5	3	11.5	
t_{PHZ}	$\overline{OE}$	Q	3.5	7.5	12	1	14	2.5	13	ns
t_{PLZ}			2	5.5	9	1	10.5	1.5	10	

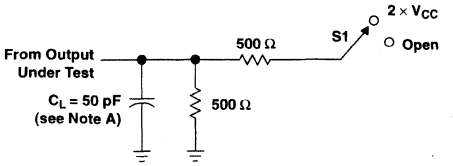
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	TO (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC574		SN74AC574		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			95	153		85		85		MHz
t_{PLH}	CLK	Q	2	6	9.5	1.5	11.5	2	11	ns
t_{PHL}			2	5.5	8.5	1.5	10.5	2	9.5	
t_{PZH}	$\overline{OE}$	Q	2	5	8.5	1.5	9.5	2	9	ns
t_{PZL}			2	5	8	1.5	9.5	1.5	9	
t_{PHZ}	$\overline{OE}$	Q	2	6	9.5	1.5	11.5	1.5	10.5	ns
t_{PLZ}			1	4.5	7.5	1.5	9	1	8.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

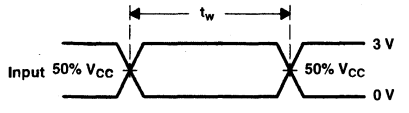
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION

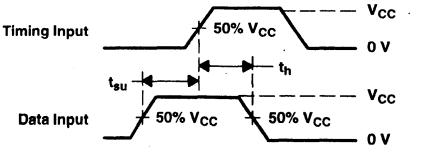


LOAD CIRCUIT

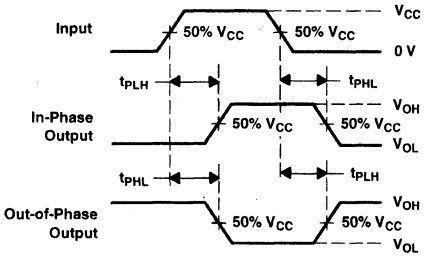
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



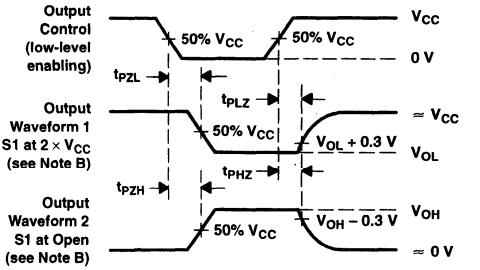
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

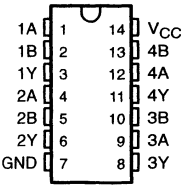
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

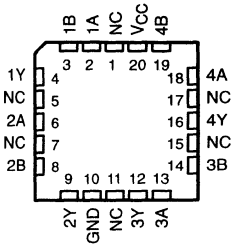
3 ACT Gates and Octals

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), DIP (N) Packages, Ceramic Chip Carriers (FK), Flat (W), and DIP (J) Packages**

SN54ACT00 . . . J OR W PACKAGE
SN74ACT00 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT00 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

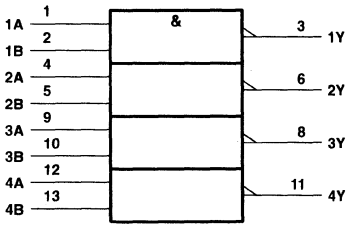
The 'ACT00 contain four independent 2-input NAND gates. Each gate performs the Boolean function of $Y = \overline{A \bullet B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN54ACT00 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT00 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each gate)

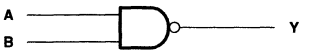
INPUTS		OUTPUT
A	B	Y
H	H	L
L	X	H
X	L	H

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each gate (positive logic)



EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ACT00		SN74ACT00		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

TEXAS INSTRUMENTS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT00		SN74ACT00		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 μA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OL} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	V_I = V_{CC} or GND	5 V		2.6						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

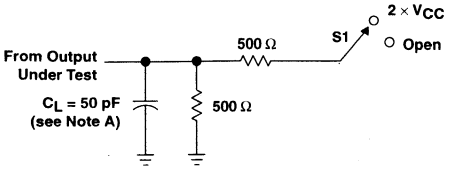
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT00		SN74ACT00		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	5.5	9	1	9.5	1	9.5	ns
t_{PHL}			1.5	4	7	1	8	1	8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

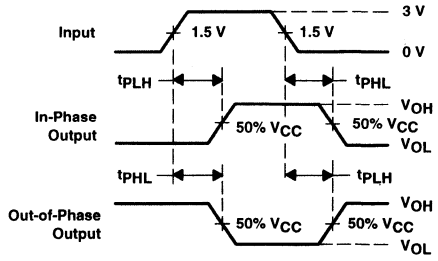
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open



LOAD CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), DIP (N) Packages, Ceramic Chip Carriers (FK), Flat (W), and DIP (J) Packages**

description

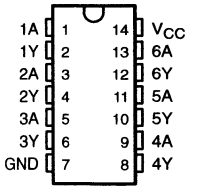
The 'ACT04 contain six independent inverters. The devices perform the Boolean function $Y = \overline{A}$.

The SN54ACT04 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT04 is characterized for operation from −40°C to 85°C.

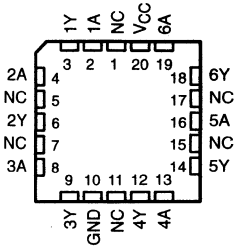
FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H

SN54ACT04 . . . J OR W PACKAGE
SN74ACT04 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

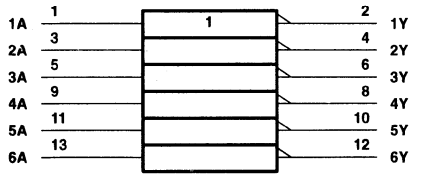


SN54ACT04 . . . FK PACKAGE
(TOP VIEW)



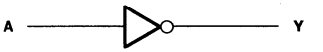
NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each inverter (positive logic)



EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ACT04		SN74ACT04		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT04		SN74ACT04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OL} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

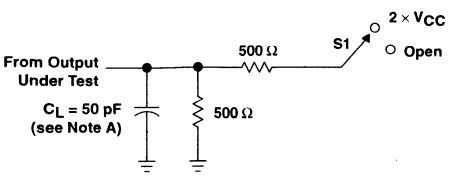
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT04		SN74ACT04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	6	8.5			1	9	ns
t_{PHL}			1	5.5	8			1	8.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

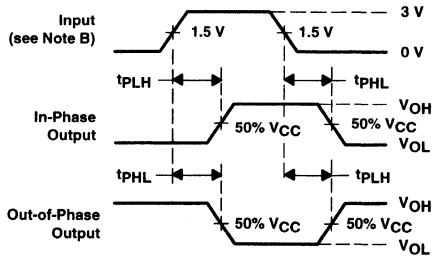
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open



LOAD CIRCUIT



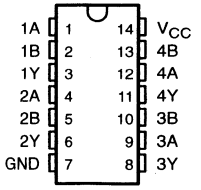
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

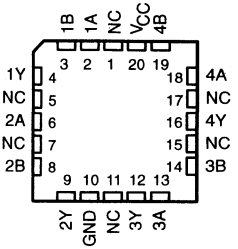
Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

SN54ACT08 . . . J OR W PACKAGE
SN74ACT08 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT08 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

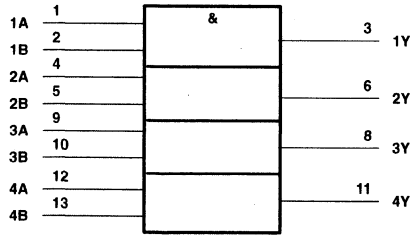
The 'ACT08 are quadruple 2-input positive-AND gates. These devices perform the Boolean functions $Y = A \bullet B$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN54ACT08 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT08 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each gate)

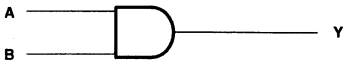
INPUTS		OUTPUT
A	B	Y
H	H	H
L	X	L
X	L	L

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each gate (positive logic)



EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ACT08		SN74ACT08		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT08		SN74ACT08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	VI = V_{CC} or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

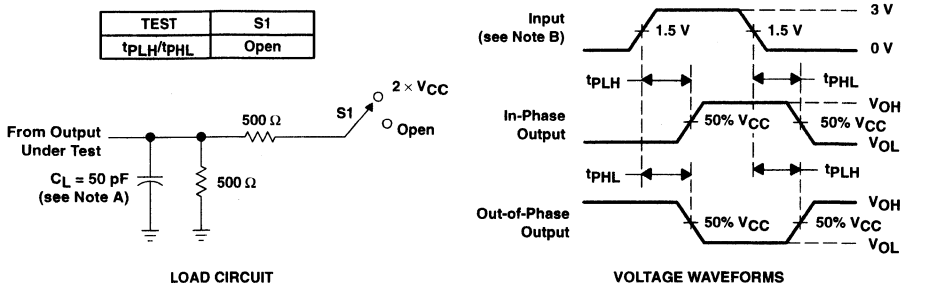
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT08		SN74ACT08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1	6.5	9			1	10	ns
t_{PHL}			1	6.5	9			1	10	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	20	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

description

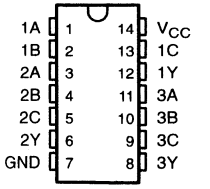
The 'ACT10 contain three independent 3-input NAND gates. The devices perform the Boolean functions $Y = \overline{A \bullet B \bullet C}$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

The SN54ACT10 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT10 is characterized for operation from −40°C to 85°C.

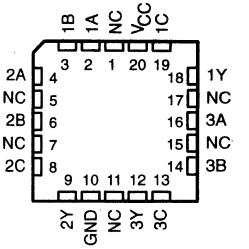
FUNCTION TABLE
(each gate)

INPUTS			OUTPUT
A	B	C	Y
H	H	H	L
L	X	X	H
X	L	X	H
X	X	L	H

SN54ACT10 . . . J OR W PACKAGE
SN74ACT10 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

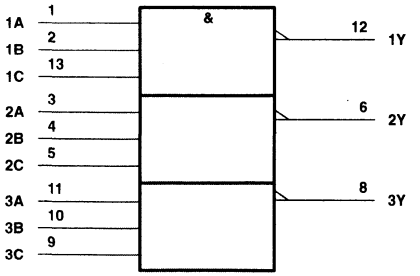


SN54ACT10 . . . FK PACKAGE
(TOP VIEW)



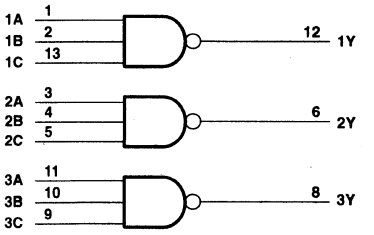
NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each gate (positive logic)



EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ACT10		SN74ACT10		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT10		SN74ACT10		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = – 50 µA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	VI = V_{CC} or GND	5 V		2.6						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

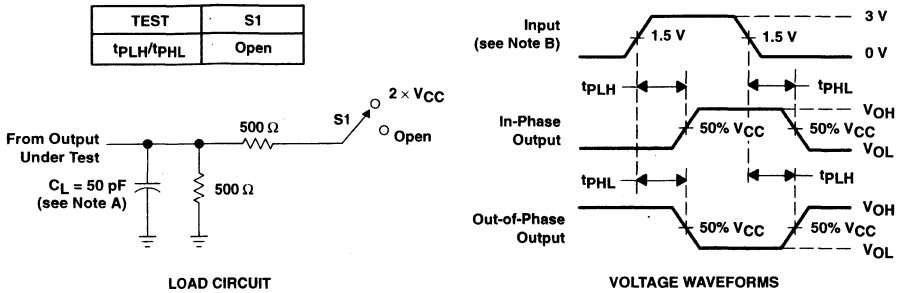
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT10		SN74ACT10		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	Any	Y	1	6.5	9			1	10	ns
t_{PHL}			1	6.5	9			1	9.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	25	pF

PARAMETER MEASUREMENT INFORMATION

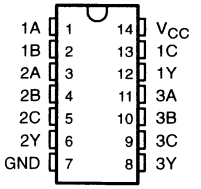


NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

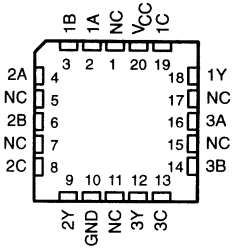
Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

SN54ACT11 . . . J OR W PACKAGE
SN74ACT11 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT11 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

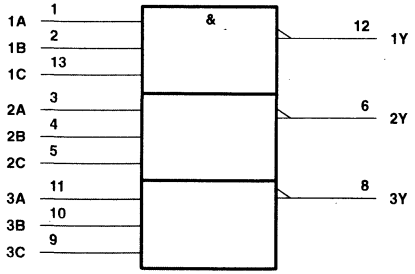
The 'ACT11 contain three independent 3-input AND gates. The devices perform the Boolean functions $Y = A \bullet B \bullet C$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

The SN54ACT11 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT11 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each gate)

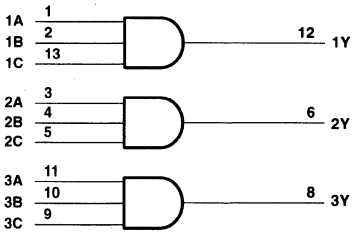
INPUTS			OUTPUT
A	B	C	Y
H	H	H	H
L	X	X	L
X	L	X	L
X	X	L	L

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each gate (positive logic)



EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		MIN	MAX	MIN	MAX	UNIT
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT11		SN74ACT11		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = – 50 µA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			2		40		20	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	VI = V_{CC} or GND	5 V		2.6						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

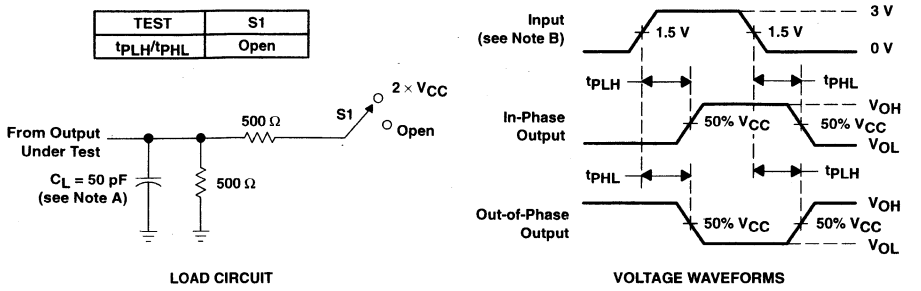
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT11		SN74ACT11		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	Any	Y	1.5	6	9.5			1	10.5	ns
t_{PHL}			1.5	6	9.5			1	10.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	20	pF

PARAMETER MEASUREMENT INFORMATION

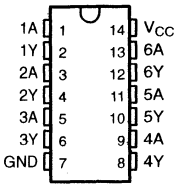


NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

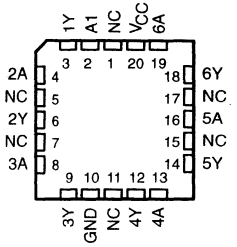
Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin-Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

SN54ACT14 . . . J OR W PACKAGE
SN74ACT14 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT14 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These Schmitt-trigger devices contain six independent inverters. They perform the Boolean function $Y = \overline{A}$. Because of the Schmitt action, they have different input threshold levels for positive-going (V_{T+}) and for negative-going (V_{T-}) signals.

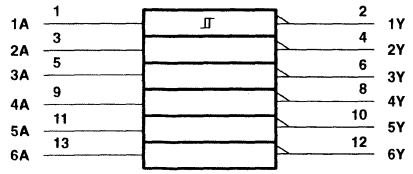
These circuits are temperature compensated and can be triggered from the slowest of input ramps and still give clean, jitter-free output signals. They also have a greater noise margin than conventional inverters.

SN54ACT14 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ACT14 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each inverter)

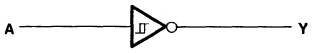
INPUT A	OUTPUT Y
H	L
L	H

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, or W packages.

logic diagram, each inverter (positive logic)



EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ACT14		SN74ACT14		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2.1		2.1		V
V_{IL}	Low-level input voltage		0.5		0.5	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT14		SN74ACT14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{T+} Positive-going threshold		4.5 V	1.2	1.5	1.9	1.2	1.9	1.2	1.9	V
		5.5 V	1.4	1.7	2.1	1.4	2.1	1.4	2.1	
V_{T-} Negative-going threshold		4.5 V	0.5	0.9	1.2	0.5	1.2	0.5	1.2	V
		5.5 V	0.6	1	1.4	0.6	1.4	0.6	1.4	
ΔV_T Hysteresis ($V_{T+} - V_{T-}$)		4.5 V	0.4	0.6	1.4	0.4	1.4	0.4	1.4	V
		5.5 V	0.4	0.6	1.5	0.4	1.5	0.4	1.5	
V_{OH}	I_{OH} = –50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = –24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = –50 mA†	5.5 V				3.85				
	I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			2		40		20	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.6		1.6		1.5	mA
C_i	$V_I = V_{CC}$ or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

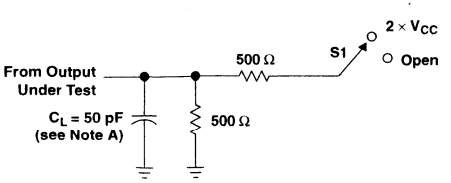
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C		SN54ACT14		SN74ACT14		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	11.5	1	14	1	12.5	ns
t_{PHL}			1.5	10	1	13	1	11	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

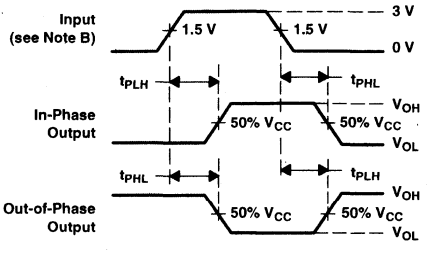
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	20	pF

PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open



LOAD CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

description

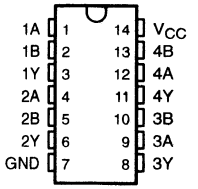
The 'ACT32 are quadruple 2-input positive-OR gates. The devices perform the Boolean functions $Y = A + B$ or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

The SN54ACT32 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT32 is characterized for operation from −40°C to 85°C.

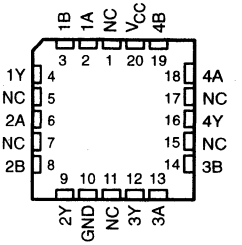
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
H	X	H
X	H	H
L	L	L

SN54ACT32 . . . J OR W PACKAGE
SN74ACT32 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

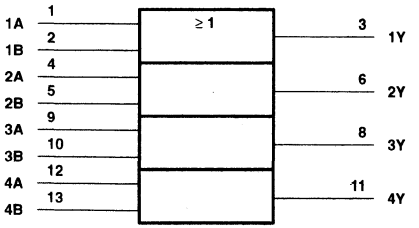


SN54ACT32 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each gate (positive logic)

EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ACT32		SN74ACT32		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT32		SN74ACT32		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	4.5 V	4.4			4.4		4.4		V
		5.5 V	5.4			5.4		5.4		
	I_{OH} = –24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = –50 mA†	5.5 V				3.86				
	I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	5.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V		0.6			1.6		1.5	mA
C_i	V_I = V_{CC} or GND	5 V		2.6						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

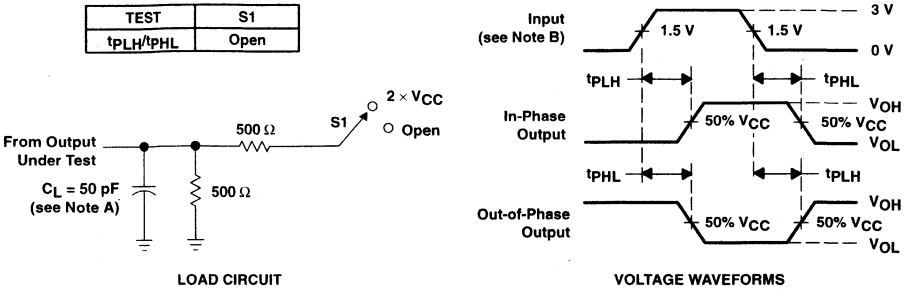
switching characteristics over recommended operating free-air temperature range V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT32		SN74ACT32		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1	6.5	9			1	10	ns
t_{PHL}			1	6.5	9			1	10	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 10 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), DIP (N) Packages, Ceramic Chip Carrier (FK), DIP (J), and Flat (W) Packages**

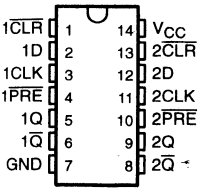
description

The 'ACT74 are dual positive-edge-triggered D-type flip-flops.

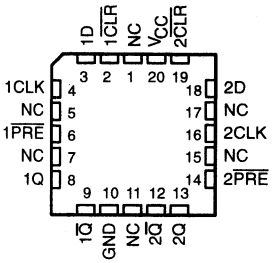
A low level at the preset ($\overline{PRE}$) or clear ($\overline{CLR}$) input sets or resets the outputs regardless of the levels of the other inputs. When $\overline{PRE}$ and $\overline{CLR}$ are inactive (high), data at the data (D) input meeting the setup-time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at D may be changed without affecting the levels at the outputs.

The SN54ACT74 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT74 is characterized for operation from −40°C to 85°C.

SN54ACT74 . . . J OR W PACKAGE
SN74ACT74 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT74 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

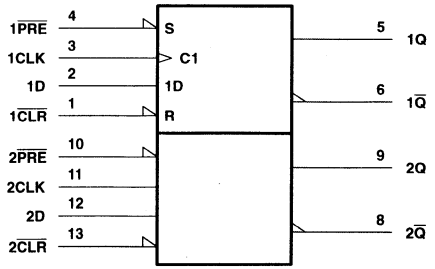
FUNCTION TABLE

INPUTS				OUTPUTS	
$\overline{PRE}$	$\overline{CLR}$	CLK	D	Q	$\overline{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H†	H†
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q_0	$\overline{Q}_0$

† This configuration is nonstable; that is, it does not persist when either $\overline{PRE}$ or $\overline{CLR}$ returns to its inactive (high) level.

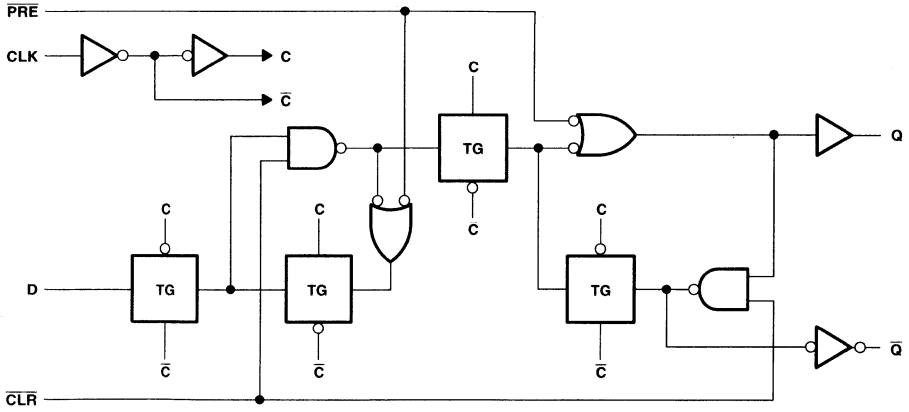
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ACT74		SN74ACT74		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT74		SN74ACT74		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = –24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = –50 mA†	5.5 V				3.86				
	I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	µA
C_i	V_I = V_{CC} or GND	5 V		3						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54ACT74		SN74ACT74		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	145	0	145	0	145	MHz
t_w	Pulse duration	$\overline{PRE}$ or $\overline{CLR}$ low	5		7		6		ns
		CLK	5		7		6		
t_{su}	Setup time, data before CLK↑	Data	3		4		3.5		ns
		$\overline{PRE}$ or $\overline{CLR}$ inactive	0		0.5		0		
t_h	Hold time, data after CLK↑		1		1		1		ns

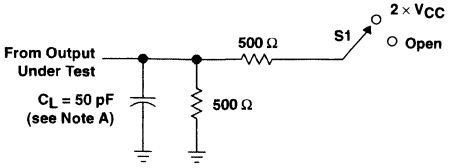
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT74		SN74ACT74		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			145	210		85		125		MHz
t_{PLH}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	3	5.5	9.5	1	11.5	2.5	10.5	ns
t_{PHL}			3	6	10	1	12.5	3	11.5	
t_{PLH}	CLK	Q or $\overline{Q}$	4	7.5	11	1	14	4	13	ns
t_{PHL}			3.5	6	10	1	12	3	11.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

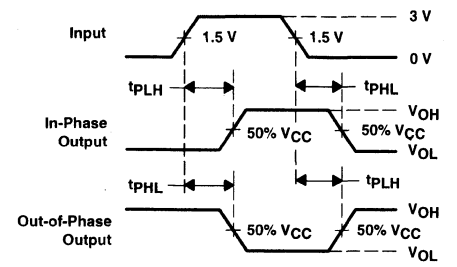
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

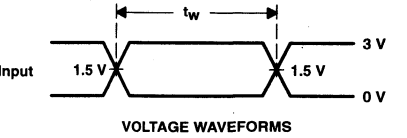


LOAD CIRCUIT

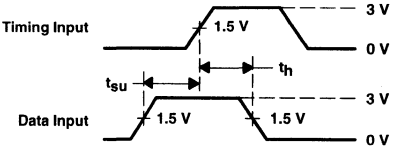
TEST	S1
t_{PLH}/t_{PHL}	Open



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

description

The 'ACT86 are quadruple 2-input exclusive-OR gates. The devices perform the Boolean functions $Y = A \oplus B$ or $Y = \overline{A}B + A\overline{B}$ in positive logic.

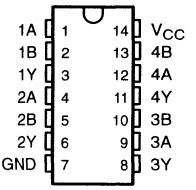
A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

The SN54ACT86 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT86 is characterized for operation from −40°C to 85°C.

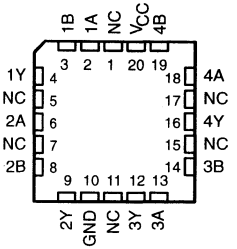
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

SN54ACT86 . . . J OR W PACKAGE
SN74ACT86 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT86 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

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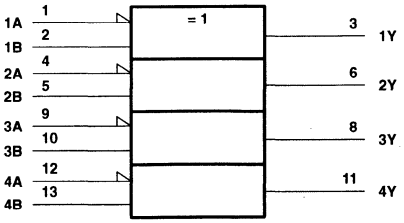
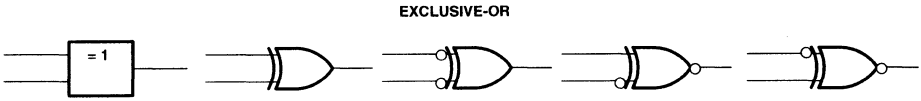
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

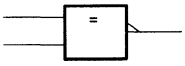
exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



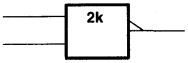
These five equivalent exclusive-OR symbols are valid for an 'ACT86 gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



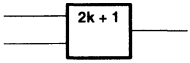
The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package ..... 1.25 W
DB package ..... 0.5 W
N package ..... 1.1 W
PW package ..... 0.5 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		MIN	MAX	MIN	MAX	UNIT
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT86		SN74ACT86		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = – 50 µA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	VI = V_{CC} or GND	5 V		2.6						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

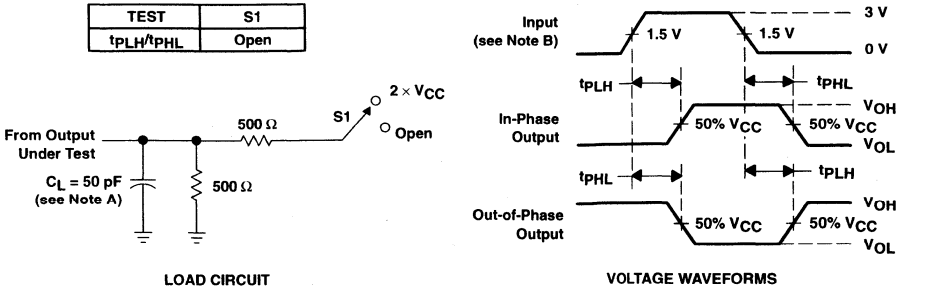
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT86		SN74ACT86		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	8.5	9.5			1	10	ns
t_{PHL}			1.5	7	9.5			1	10.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	25	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and DIP (N) Packages, Ceramic Chip Carriers (FK), Flat (W), and DIP (J) Packages**

description

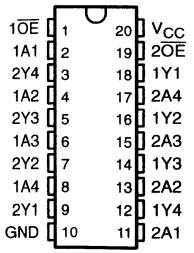
These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 'ACT240 are organized as two 4-bit buffers/drivers with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the device passes data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

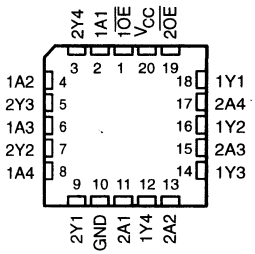
To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ACT240 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ACT240 is characterized for operation from – 40°C to 85°C.

SN54ACT240 . . . J OR W PACKAGE
SN74ACT240 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT240 . . . FK PACKAGE
(TOP VIEW)

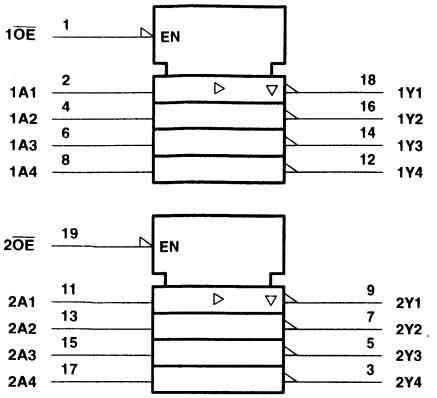


FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z

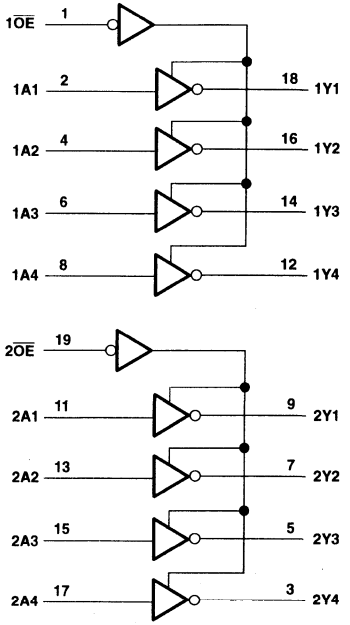
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ACT240		SN74ACT240		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT240		SN74ACT240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OL} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±5		±2.5	µA
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			4		80		40	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	$V_I = V_{CC}$ or GND	5 V		2.5						pF
C_o	$V_I = V_{CC}$ or GND	5 V		8						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

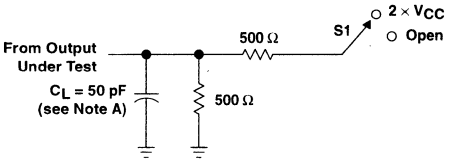
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT240		SN74ACT240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	6	8.5	1	9.5	1.5	9.5	ns
t_{PHL}			1.5	5.5	7.5	1	9	1.5	8.5	
t_{PZH}	$\overline{OE}$	Y	1.5	7	8.5	1	10	1	9.5	ns
t_{PZL}			2	7	9.5	1	11.5	1.5	10.5	
t_{PHZ}	$\overline{OE}$	Y	2	8	9.5	1	11	2	10.5	ns
t_{PLZ}			2.5	6.5	10	1	11.5	2	10.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

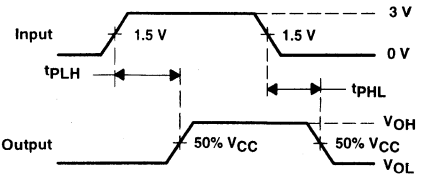
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	C_L = 50 pF, f = 10 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

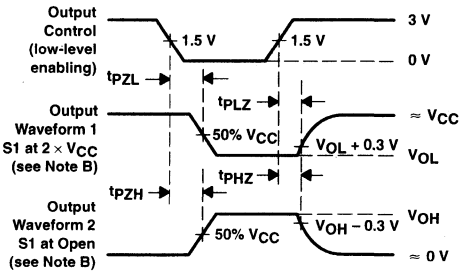


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS



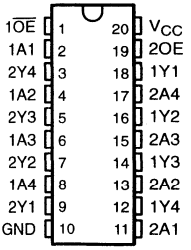
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

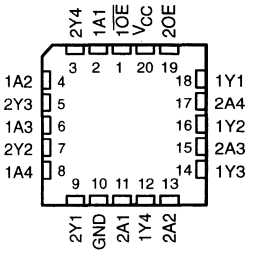
Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and DIP (N) Packages, Ceramic Chip Carriers (FK), Flat (W), and DIP (J) Packages**

SN54ACT241 . . . J OR W PACKAGE
SN74ACT241 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT241 . . . FK PACKAGE
(TOP VIEW)



description

These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 'ACT241 are organized as two 4-bit buffers/drivers with separate complementary output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the device passes data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ACT241 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT241 is characterized for operation from −40°C to 85°C.

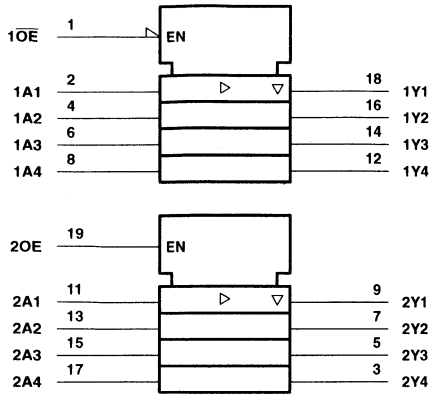
FUNCTION TABLES

INPUTS		OUTPUT
$\overline{1OE}$	1A	1Y
L	H	H
L	L	L
H	X	Z

INPUTS		OUTPUT
2OE	2A	2Y
H	H	H
H	L	L
L	X	Z

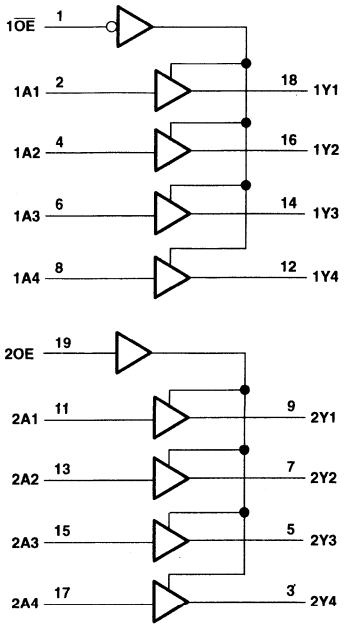
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at $T_A = 55°C$ (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ACT241		SN74ACT241		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT241		SN74ACT241		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 μA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OL} = – 24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±5		±2.5	μA
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			4		80		40	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	$V_I = V_{CC}$ or GND	5 V		2.5						pF
C_o	$V_I = V_{CC}$ or GND	5 V		8						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

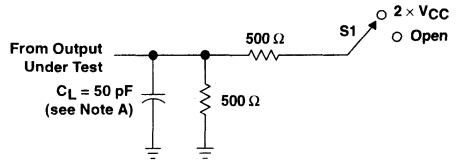
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT241		SN74ACT241		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	6	8.5	1	9.5	1.5	9.5	ns
t_{PHL}			1.5	5.5	7.5	1	9	1.5	8.5	
t_{PZH}	$\overline{OE}$ or OE	Y	1.5	7	8.5	1	10	1	9.5	ns
t_{PZL}			2	7	9.5	1	11.5	1.5	10.5	
t_{PHZ}	$\overline{OE}$ or OE	Y	2	8	9.5	1	11	2	10.5	ns
t_{PLZ}			2.5	6.5	10	1	11.5	2	10.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

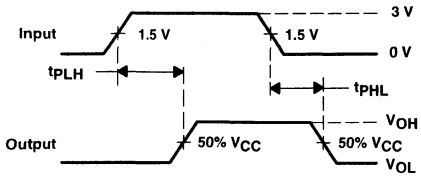
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	C_L = 50 pF, f = 10 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

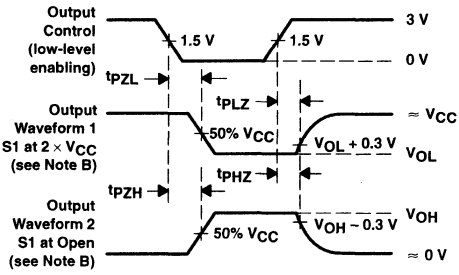


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

TEXAS INSTRUMENTS

- **Inputs Are TTL Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and DIP (N) Packages, Ceramic Chip Carriers (FK), Flat (W), and DIP (J) Packages**

description

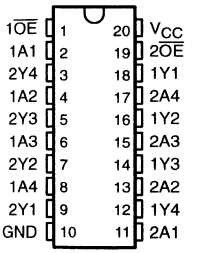
These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 'ACT244 are organized as two 4-bit buffers/drivers with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the device passes data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

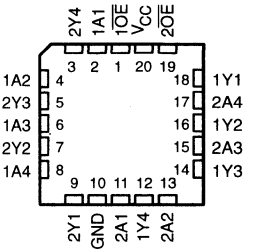
To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ACT244 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT244 is characterized for operation from −40°C to 85°C.

SN54ACT244 . . . J OR W PACKAGE
SN74ACT244 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT244 . . . FK PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

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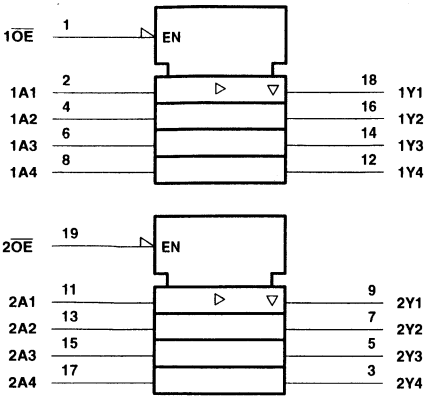
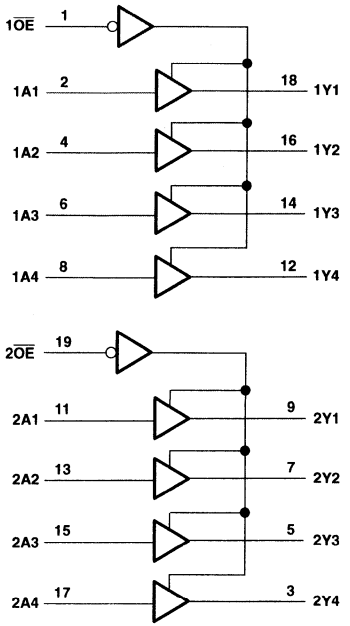
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at $T_A = 55°C$ (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ACT244		SN74ACT244		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT244		SN74ACT244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OL} = −24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = −50 mA†	5.5 V				3.85				
	I_{OH} = −75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V		.001	0.1		0.1		0.1	V
		5.5 V		.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±5		±2.5	μA
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			4		80		40	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	$V_I = V_{CC}$ or GND	5 V		2.5						pF
C_o	$V_I = V_{CC}$ or GND	5 V		8						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

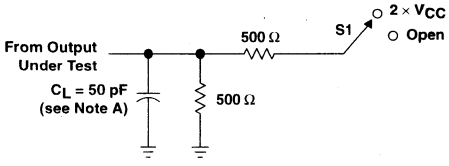
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT244		SN74ACT244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	2	6.5	9	1	10	1.5	10	ns
t_{PHL}			2	7	9	1	10	1.5	10	
t_{PZH}	$\overline{OE}$	Y	1.5	7	8.5	1	9.5	1	9.5	ns
t_{PZL}			2	7	9.5	1	11	1.5	10.5	
t_{PHZ}	$\overline{OE}$	Y	2	8	9.5	1	11	1.5	10.5	ns
t_{PLZ}			2.5	7.5	10	1	11.5	2	10.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

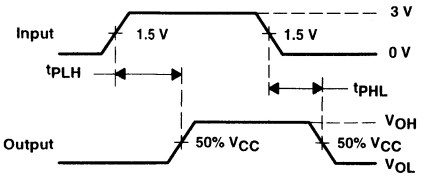
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	C_L = 50 pF, f = 10 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

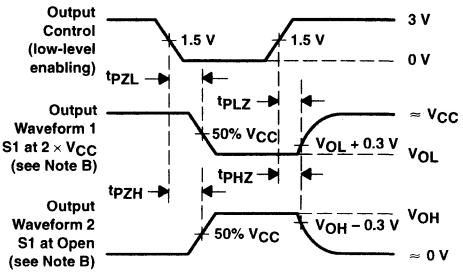


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

TEXAS INSTRUMENTS

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC***™ **(Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and DIP (N), Ceramic Chip Carriers (FK), Flat (W), and DIP (J) Packages**

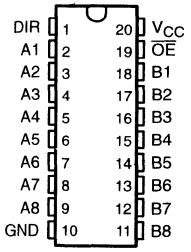
description

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

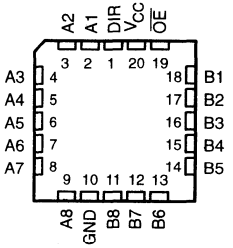
The device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction control (DIR) input. The output enable ($\overline{OE}$) can be used to disable the device so that the buses are effectively isolated.

The SN54ACT245 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT245 is characterized for operation from −40°C to 85°C.

SN54ACT245 . . . J OR W PACKAGE
SN74ACT245 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT245 . . . FK PACKAGE
(TOP VIEW)

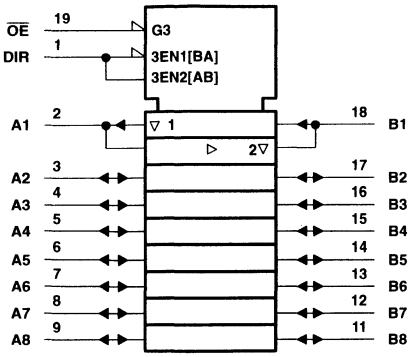


FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

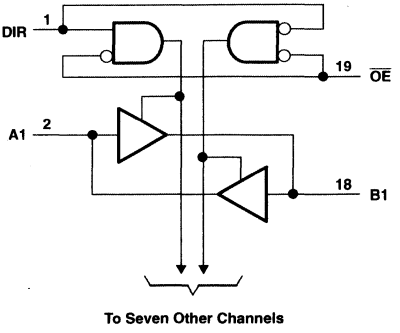
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air)(see Note 2):
DB package ..... 0.6 W
DW package ..... 1.6 W
PW package ..... 0.7 W
N package ..... 1.3 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ACT245		SN74ACT245		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	− 55	125	− 40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT245		SN74ACT245		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = − 50 μA	4.5 V	4.4	4.49		4.4		4.4		V
			5.5 V	5.4	5.49		5.4		5.4		
		I_{OH} = − 24 mA	4.5 V	3.88			3.7		3.76		
			5.5 V	4.86			4.7		4.76		
		I_{OH} = −50 mA†	5.5 V				3.85				
		I_{OH} = −75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 μA	4.5 V		.001	0.1		0.1		0.1	V
			5.5 V		.001	0.1		0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_{OZ}	A or B ports‡	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	μA
I_I	$\overline{OE}$ or DIR	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			4		80		40	μA
ΔI_{CC}§		One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.6		1.6		1.5	mA
C_i		$V_I = V_{CC}$ or GND	5 V		4.5						pF
C_{io}		$V_O = V_{CC}$ or GND	5 V		15						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

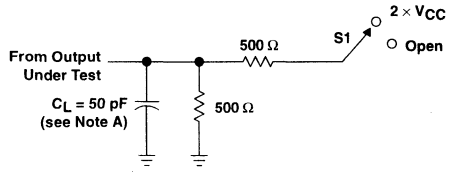
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT245		SN74ACT245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.5	4	7.5	1	9	1.5	8	ns
t_{PHL}			1.5	4	8	1	10	1	9	
t_{PZH}	$\overline{OE}$	A or B	1.5	5	10	1	12	1.5	11	ns
t_{PZL}			1.5	5.5	10	1	13	1.5	12	
t_{PHZ}	$\overline{OE}$	A or B	1.5	5.5	10	1	12	1	11	ns
t_{PLZ}			2	5	10	1	12	1.5	11	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

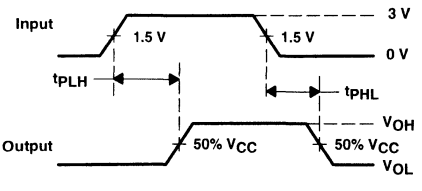
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	C_L = 50 pF, f = 1 MHz	45	pF

PARAMETER MEASUREMENT INFORMATION

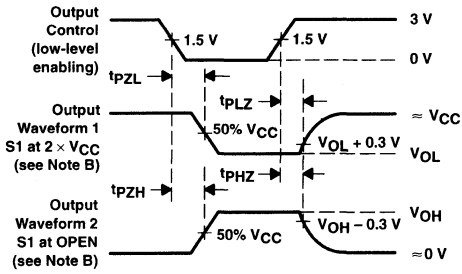


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open

LOAD CIRCUIT



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

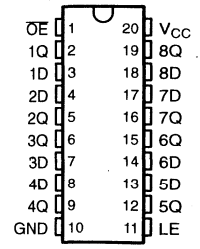
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

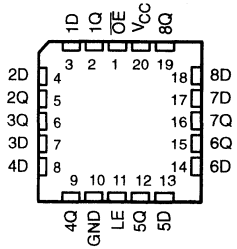
TEXAS INSTRUMENTS

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC***™ **(Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW) Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54ACT373 . . . J OR W PACKAGE
SN74ACT373 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT373 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches are D-type transparent latches. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines in bus-organized systems without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

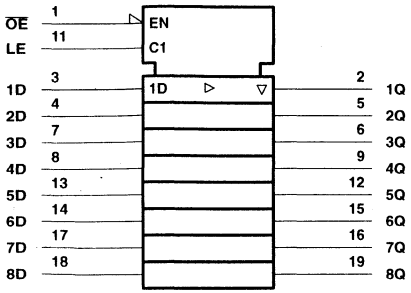
The SN54ACT373 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT373 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each latch)

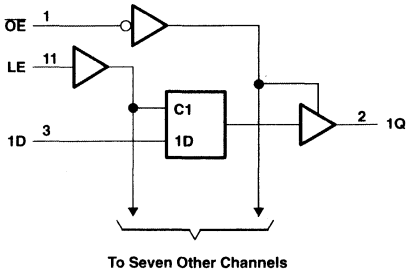
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ACT373		SN74ACT373		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT373		SN74ACT373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = −24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = −50 mA†	5.5 V				3.85				
	I_{OH} = −75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.44		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±5		±2.5	μA
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			4		80		40	μA
ΔI_{CC}‡	One input at 3.4 V, One inputs at GND or V_{CC}	5.5 V			0.6		1.5		1.5	μA
C_i	$V_I = V_{CC}$ or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54AC373		SN74AC373		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	7		8.5		8		ns
t_{su}	Setup time, data before LE↓	7		8.5		8		ns
t_h	Hold time, data after LE↓	0		1		1		ns

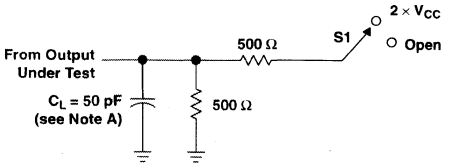
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	TO (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC373		SN74AC373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	2.5	8.5	10	1.5	12.5	1.5	11.5	ns
t_{PHL}			2	8	10	1.5	12.5	1.5	11.5	
t_{PLH}	LE	Q	2.5	8.5	11	1.5	12.5	2	11.5	ns
t_{PHL}			2	8	10	1.5	11.5	1.5	11.5	
t_{PZH}	$\overline{OE}$	Q	2	8	9.5	1.5	11.5	1.5	10.5	ns
t_{PZL}			2	7.5	9	1.5	11	1.5	10.5	
t_{PHZ}	$\overline{OE}$	Q	2.5	9	11	1.5	14	2.5	12.5	ns
t_{PLZ}			1.5	7.5	8.5	1.5	11	1	10	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

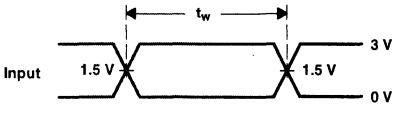
PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF,	f = 1 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION

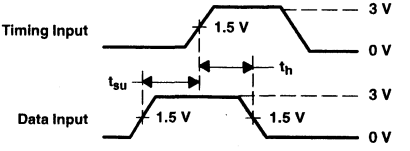


LOAD CIRCUIT

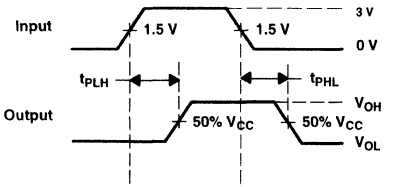
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open

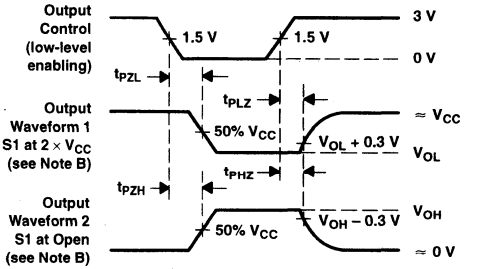


VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS





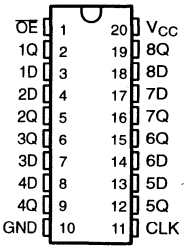
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

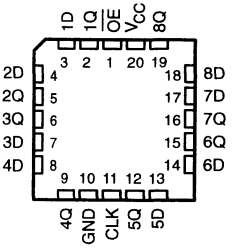
Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW) Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54ACT374 . . . J OR W PACKAGE
SN74ACT374 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT374 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the 'ACT374 are D-type edge-triggered flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines in bus-organized systems without need for interface or pullup components.

$\overline{OE}$ does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

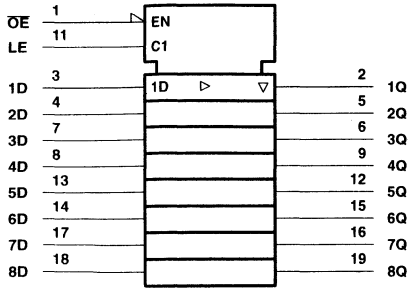
The SN54ACT374 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT374 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each flip-flop)

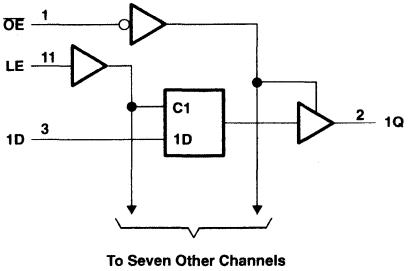
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ACT374		SN74ACT374		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT374		SN74ACT374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = −24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = −50 mA†	5.5 V				3.85				
	I_{OH} = −75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.25		±5		±2.5	μA
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	μA
ΔI_{CC}‡	One input at 3.4 V, One inputs at GND or V_{CC}	5.5 V			0.6		1.6		1.5	μA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54ACT374		SN74ACT374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	5		5		5		ns
t_{su}	Setup time, data before CLK↑	5		5.5		5.5		ns
t_h	Hold time, data after CLK↑	1.5		1.5		1.5		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

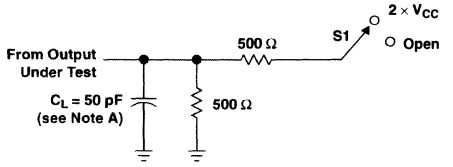
PARAMETER	TO (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT374		SN74ACT374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			100	160		70		90		MHz
t_{PLH}	CLK	Q	2	8.5	10	1.5	12	2	11.5	ns
t_{PHL}			2	8	9.5	1.5	11.5	1.5	11	
t_{PZH}	$\overline{OE}$	Q	2	8	9.5	1.5	11.5	1.5	10.5	ns
t_{PZL}			1.5	8	9	1.5	11.5	1.5	10.5	
t_{PHZ}	$\overline{OE}$	Q	1.5	8.5	11.5	1.5	13	1	12.5	ns
t_{PLZ}			1.5	7	8.5	1.5	11	1	10	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF,	f = 10 MHz	40	pF

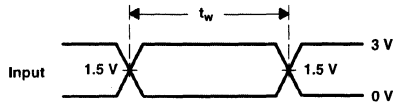
TEXAS INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION

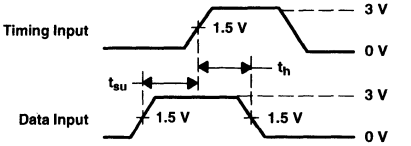


LOAD CIRCUIT

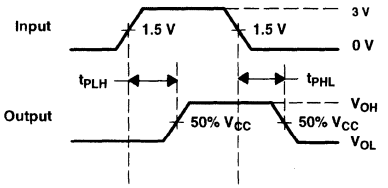
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open

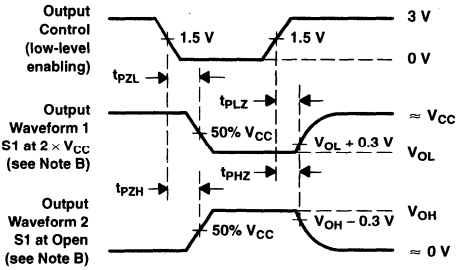


VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS





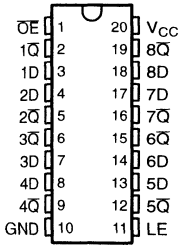
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

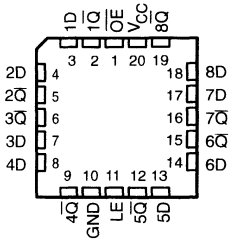
Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- **3-State Inverting Outputs Drive Bus Lines Directly**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54ACT533 . . . J OR W PACKAGE
SN74ACT533 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT533 . . . FK PACKAGE
(TOP VIEW)



description

The 'ACT533 are octal transparent D-type latches with 3-state outputs. When the latch-enable (LE) input is high, the $\overline{Q}$ outputs follow the complements of the data (D) inputs. When LE is taken low, the $\overline{Q}$ outputs are latched at the inverted levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

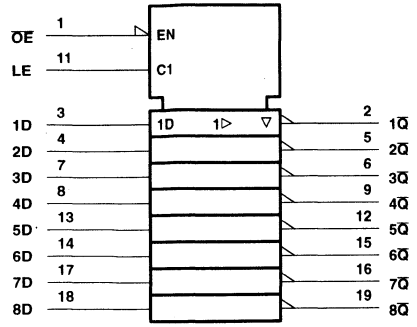
The SN54ACT533 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ACT533 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each latch)

INPUTS			OUTPUT
$\overline{OE}$	LE	D	$\overline{Q}$
L	H	H	L
L	H	L	H
L	L	X	$\overline{Q}_0$
H	X	X	Z

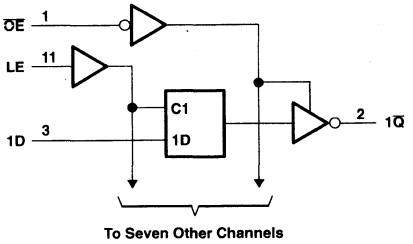
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ACT533		SN74ACT533		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT533		SN74ACT533		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 μA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = –24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = –50 mA†	5.5 V				3.85				
	I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.25		±5		±2.5	μA
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.6		1.6		1.5	mA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54ACT533		SN74ACT533		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	5		7.5		6		ns
t_{su}	Setup time, data before LE↓	3		5.5		4		ns
t_h	Hold time, data after LE↓	2		4		2.5		ns

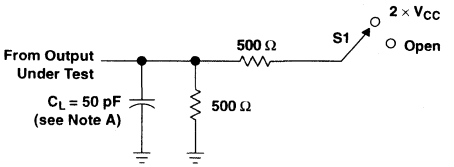
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C		SN54ACT533		SN74ACT533		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	$\overline{Q}$	2.5	10.5	1.5	13	2	11.5	ns
t_{PHL}			2.5	10	1.5	12.5	2	11	
t_{PLH}	LE	$\overline{Q}$	2.5	10.5	1.5	13	2	11.5	ns
t_{PHL}			2.5	10.5	1.5	13	2	11.5	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	2	10	1	12.5	1.5	11	ns
t_{PZL}			2	10	1	12.5	1.5	11	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	2	10	1	12.5	1.5	11	ns
t_{PLZ}			2	10	1	12.5	1.5	11	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

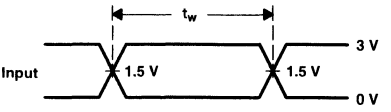
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION

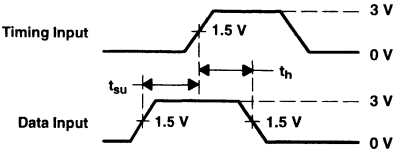


LOAD CIRCUIT

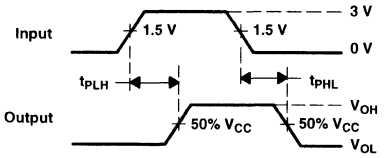
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



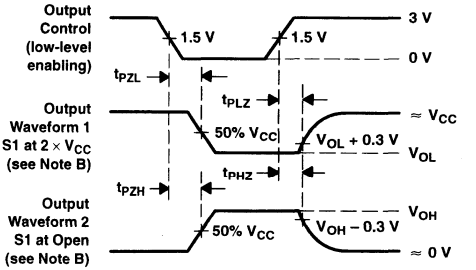
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



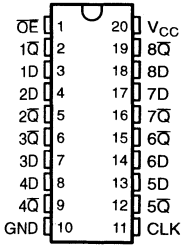
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

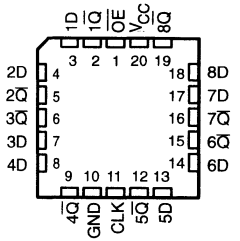
Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- **3-State Inverting Outputs Drive Bus Lines Directly**
- **Full Parallel Access for Loading**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54ACT534 . . . J OR W PACKAGE
SN74ACT534 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT534 . . . FK PACKAGE
(TOP VIEW)



description

These octal edge-triggered D-type flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the $\overline{Q}$ outputs are set to the complements of the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

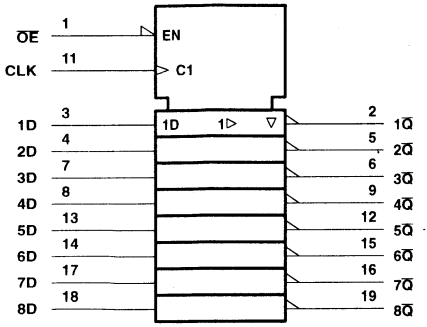
The SN54ACT534 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ACT534 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	$\overline{Q}$
L	↑	H	L
L	↑	L	H
L	H or L	X	$\overline{Q}_0$
H	X	X	Z

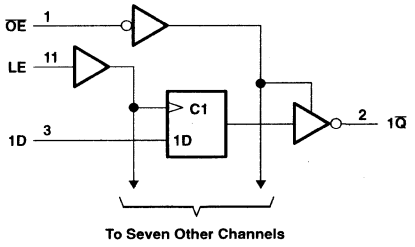
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ACT534		SN74ACT534		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT534		SN74ACT534		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = –24 mA	4.5 V	3.8			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = –50 mA†	5.5 V				3.85				
	I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±5		±2.5	µA
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5,5 V			4		80		40	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.6		1.6		1.5	mA
C_i	$V_I = V_{CC}$ or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54ACT534		SN74ACT534		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	3.5		5		3.5		ns
t_{su}	Setup time, data before CLK↑	3.5		5		4		ns
t_h	Hold time, data after CLK↑	1		3		1.5		ns

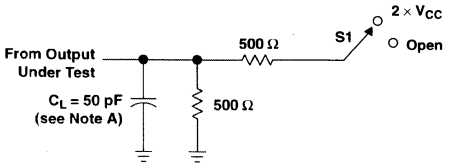
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C		SN54ACT534		SN74ACT534		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			100		85		120		MHz
t_{PLH}	CLK	$\overline{Q}$	2.5	11.5	1.5	14	2	12.5	ns
t_{PHL}			2	10.5	1.5	13	2	12	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	2.5	12	1.5	14	2	12.5	ns
t_{PZL}			2	11	1.5	13	2	11.5	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	1.5	12.5	1.5	14.5	1	13.5	ns
t_{PLZ}			1.5	10.5	1.5	11.5	1	10.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

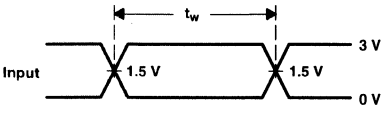
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	40	pF

PARAMETER MEASUREMENT INFORMATION

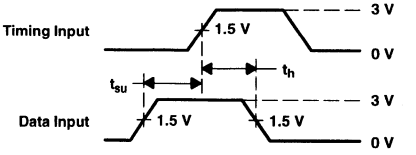


LOAD CIRCUIT

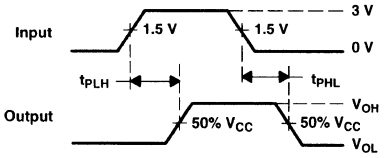
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



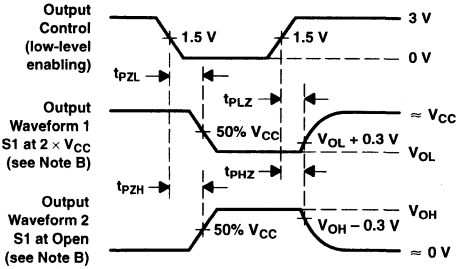
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



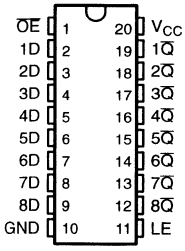
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

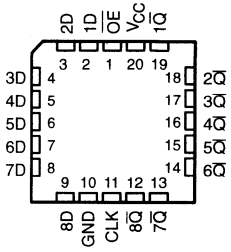
Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- **3-State Inverted Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture to Optimize PCB Layout**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54ACT563 . . . J OR W PACKAGE
SN74ACT563 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT563 . . . FK PACKAGE
(TOP VIEW)



description

The 'ACT563 are octal D-type transparent latches with 3-state outputs. When the latch-enable (LE) input is high, the Q outputs are set to the complements of the data (D) inputs. When LE is taken low, the Q outputs are latched at the inverse logic levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased high logic level provide the capability to drive bus lines without interface or pullup components.

$\overline{OE}$ does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

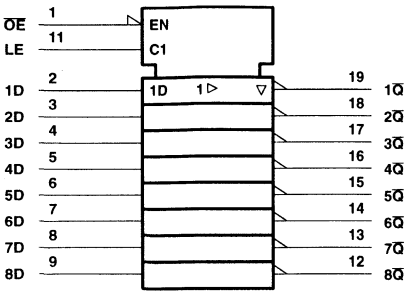
The SN54ACT563 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ACT563 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each latch)

INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	L
L	H	L	H
L	L	X	Q_0
H	X	X	Z

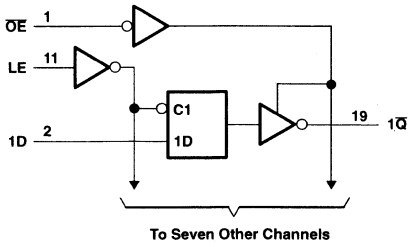
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, J, N, PW, and W packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at $T_A = 55°C$ (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ACT563		SN74ACT563		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		8		8	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT563		SN74ACT563		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = –24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = –50 mA†	5.5 V				3.85				
	I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V		0.001	0.1		0.1		0.1	V
		5.5 V		0.001	0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.25		±5		±2.5	µA
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54ACT563		SN74ACT563		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	3		5		3		ns
t_{su}	Setup time, data before LE↓	4		4.5		4.5		ns
t_h	Hold time, data after LE↓	0		1.5		0		ns

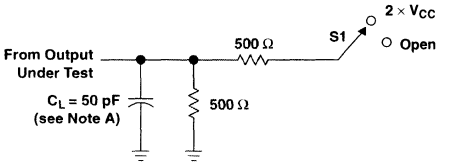
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT563		SN74ACT563		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	$\overline{Q}$	3	7	11.5	1	14.5	2.5	12.5	ns
t_{PHL}			3	6	10	1	12	2.5	11	
t_{PLH}	LE	$\overline{Q}$	3	6.5	10.5	1	12.5	2.5	11.5	ns
t_{PHL}			2.5	5.5	9.5	1	11.5	2	10.5	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	2.5	5.5	9	1	11.5	2	10	ns
t_{PZL}			2	5.5	8.5	1	11	2	9.5	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	3.5	6.5	10.5	1	12	2.5	11.5	ns
t_{PLZ}			2	4.5	8	1	9.5	1	8.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

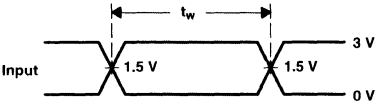
PARAMETER		TEST CONDITIONS	SN54ACT563			SN74ACT563			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz		50			50		pF

PARAMETER MEASUREMENT INFORMATION

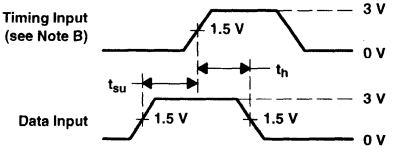


LOAD CIRCUIT

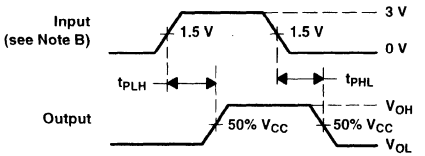
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



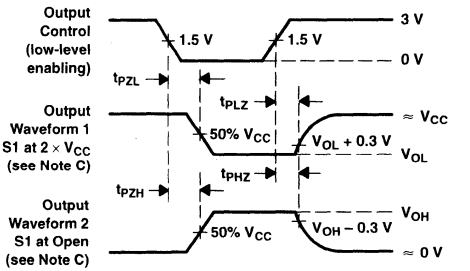
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



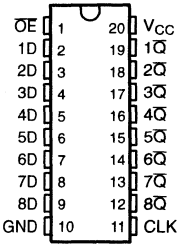
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

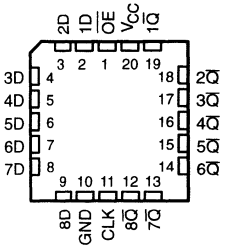
Figure 1. Load Circuit and Voltage Waveforms

- **Inputs Are TTL-Voltage Compatible**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **3-State Inverted Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture to Optimize PCB Layout**
- **Full Parallel Access for Loading**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPs**

SN54ACT564 . . . J OR W PACKAGE
SN74ACT564 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ACT564 . . . FK PACKAGE
(TOP VIEW)



description

The 'ACT564 are octal D-type edge-triggered flip-flops that feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the $\overline{Q}$ outputs are set to the complements of the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

$\overline{OE}$ does not affect internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

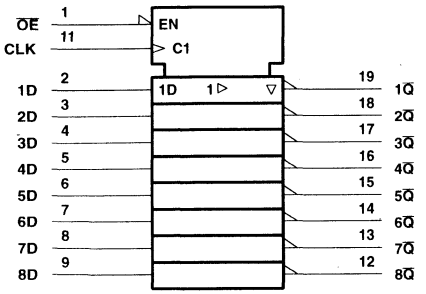
The SN54ACT564 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ACT564 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each flip-flop)

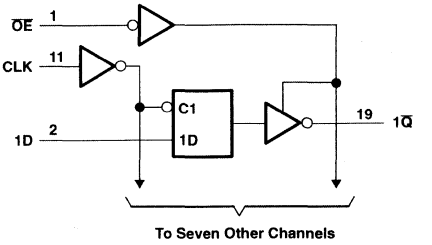
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	$\overline{Q}$
L	↑	H	L
L	↑	L	H
L	H or L	X	$\overline{Q}_0$
H	X	X	Z

EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, J, N, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±200 mA
Maximum power dissipation at $T_A = 55°C$ (in still air) (see Note 2): DB package ..... 0.6 W
DW package ..... 1.6 W
N package ..... 1.3 W
PW package ..... 0.7 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ACT564		SN74ACT564		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	8	0	8	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT564		SN74ACT564		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 μA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I_{OH} = –24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = –50 mA†	5.5 V				3.85				
	I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.25		±5		±2.5	μA
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		80		40	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.6		1.5	mA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF
C_o	V_O = V_{CC} or GND	5 V		15						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		SN54ACT564		SN74ACT564		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	3		5		3.5		ns
t_{su}	Setup time, data before CLK↑	2.5		3.5		3		ns
t_h	Hold time, data after CLK↑	1		2.5		1		ns

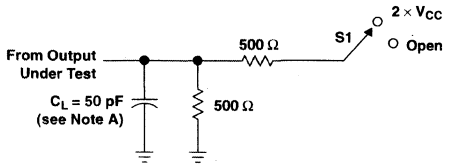
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT564		SN74ACT564		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			85	90		65		75		MHz
t_{PLH}	CLK	$\overline{Q}$	2	6.5	10.5	1	12.5	1.5	11.5	ns
t_{PHL}			1.5	6	9.5	1	11.5	1.5	10.5	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	1.5	5.5	9	1	10.5	1.5	9.5	ns
t_{PZL}			1.5	5.5	8.5	1	10.5	1	9.5	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	1.5	7	10.5	1	12.5	1.5	11.5	ns
t_{PLZ}			1.5	5	8	1	9.5	1	8.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

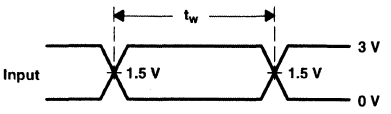
PARAMETER		TEST CONDITIONS	SN54ACT564			SN74ACT564			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz		50			50		pF

PARAMETER MEASUREMENT INFORMATION

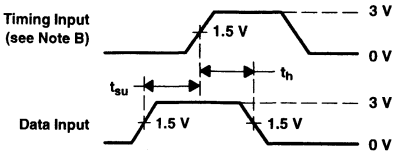


LOAD CIRCUIT

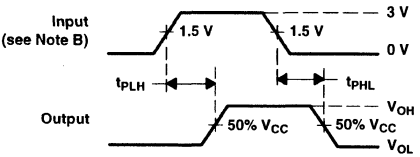
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open



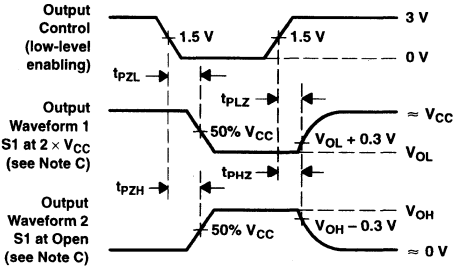
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



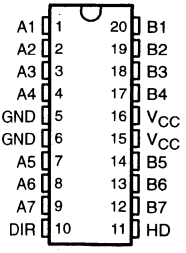
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **3-State Outputs Directly Drive Bus Lines**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Complies With IEEE 1284-I (Level 1 Type) and IEEE 1284-II (Level 2 Type) Electrical Specifications**
- **Package Options Include Plastic Small-Outline (DW) or Shrink Small-Outline (DB) Packages**

DW OR DB PACKAGE
(TOP VIEW)



description

The SN74ACT1284 is designed for asynchronous two-way communication between data buses. The control function minimizes external timing requirements.

The device allows data transmission in either the A-to-B or the B-to-A direction for bits 1, 2, 3, and 4, depending on the logic level at the direction control (DIR) input. Bits 5, 6, and 7, however, always transmit in the A-to-B direction.

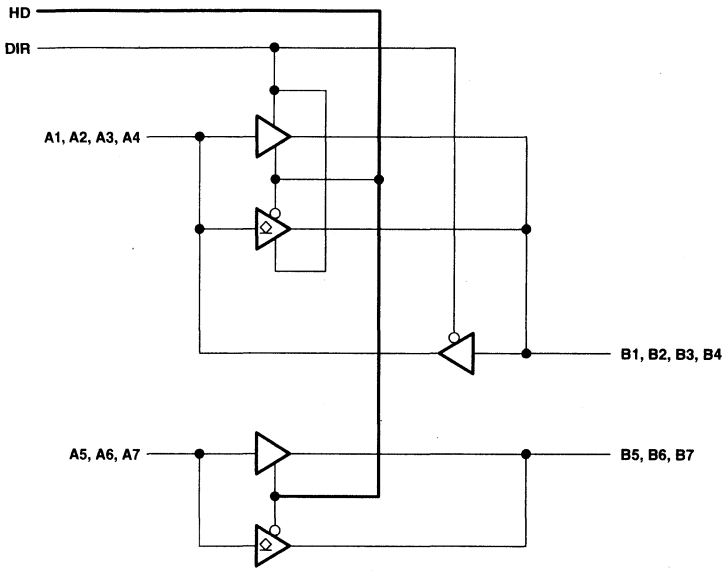
The output drive for each mode is determined by the high drive (HD) control pin. When HD is high, the high drive is delivered by the totem-pole configuration, and when HD is low, the outputs are open drain. This meets the drive requirements as specified in the IEEE 1284-I (level 1 type) and the IEEE 1284-II (level 2 type) parallel peripheral-interface specification.

The SN74ACT1284 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS		OUTPUT	MODE
DIR	HD		
L	L	Open drain	A to B: Bits 5, 6, 7
		Totem pole	B to A: Bits 1, 2, 3, 4
L	H	Totem pole	B to A: Bits 1, 2, 3, 4 and A to B: Bits 5, 6, 7
H	L	Open drain	A to B: Bits 1, 2, 3, 4, 5, 6, 7
H	H	Totem pole	A to B: Bits 1, 2, 3, 4, 5, 6, 7

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
B-port input and output voltage range, V_I and V_O (see Notes 1 and 2) ..... −2 V to 7 V
A-port input and output voltage range, V_I and V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ± 50 mA
Continuous current through V_{CC} or GND ..... ± 200 mA
Maximum power dissipation at $T_A = 55°C$ (in still air): DB package ..... 0.6 W‡
DW package ..... 1.7 W‡
Storage temperature range ..... −65°C to 150°C
Operating free-air temperature range, T_A ..... 0°C to 70°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

‡ The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the "Package Thermal Considerations" application note.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The AC input voltage pulse width is limited to 20 ns if the input voltage goes more negative than −0.5 V.

recommended operating conditions

			MIN	MAX	UNIT
V_{CC}	Supply voltage		4.7	5.5	V
V_{IH}	High-level input voltage		2		V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage		0	V_{CC}	V
V_O	Open drain output voltage	HD low	0	5.5	V
I_{OH}	High-level output current	B port, HD high		−14	mA
		A port		−4	mA
I_{OL}	Low-level output current	B port		14	mA
		A port		4	mA
T_A	Operating free-air temperature		0	70	°C

electrical characteristics over recommended ranges of operating free-air temperature and supply voltage (unless otherwise noted)

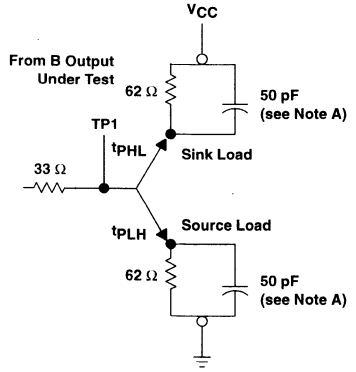
PARAMETER		TEST CONDITIONS	V_{CC}†	MIN	TYP	MAX	UNIT
V_{hys}	Input hysteresis	$V_{IT+} - V_{IT-}$ for all inputs	5 V	0.4			V
			4.7 V	0.2			
V_{OH}	B port	$I_{OH} = -14$ mA	4.7 V	2.4			V
	A port	$I_{OH} = -50$ µA	MIN to MAX	$V_{CC}-0.2$			
		$I_{OH} = -4$ mA	4.7	3.7			
V_{OL}	B port	$I_{OL} = 14$ mA	4.7 V			0.4	V
	A port	$I_{OL} = 50$ µA				0.2	
		$I_{OL} = 4$ mA				0.4	
I_I		$V_I = V_{CC}$ or GND	5.5 V			±1	µA
I_{OZ}	A or B ports‡	$V_O = V_{CC}$ or GND	5.5 V			±20	µA
I_{OFF}	B port	V_I or $V_O \leq 7$ V	0 V			±100	µA
I_{CC}		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			1.5	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4		pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12		pF
Z_O	B port	$I_{OH} = -20$ mA, $I_{OH} = -50$mA	5 V	8		30	Ω

† For I/O ports, the parameter I_{OZ} includes the input leakage current I_I.
‡ For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

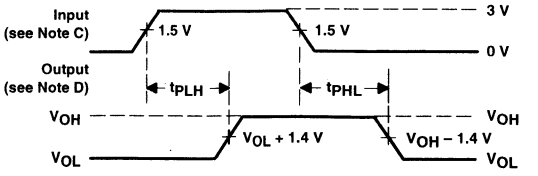
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t_{PLH}	Totem pole	A or B	B or A	1	20	ns
t_{PHL}				1	20	
SR		B output		0.05	0.4	V/ns
t_{pd}(EN)		HD	B	1	20	ns
t_{pd}(DIS)				1	20	
t_r, t_f	Open drain	A	B		120	ns

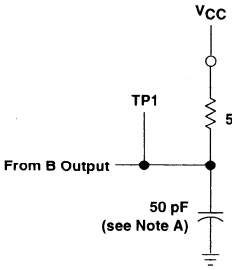
PARAMETER MEASUREMENT INFORMATION



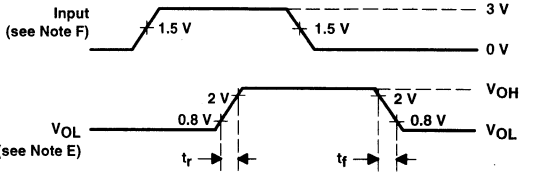
A-TO-B LOAD (totem pole)



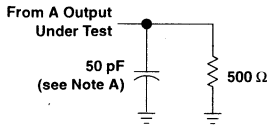
VOLTAGE WAVEFORMS MEASURED AT TP1
PROPAGATION DELAY TIMES (A to B)



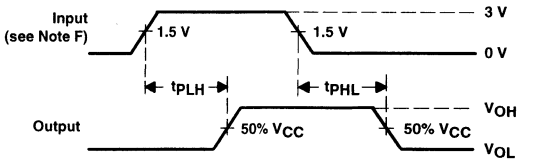
A-TO-B LOAD (open drain)



VOLTAGE WAVEFORMS MEASURED AT TP1, B SIDE



B-TO-A LOAD (totem pole)



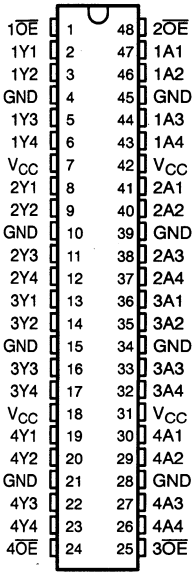
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (B to A)

NOTES: A. CL includes probe and jig capacitance.
B. The outputs are measured one at a time with one transition per measurement.
C. Input rise and fall times are 3 ns, 150 ns < pulse width < 10 µs for both low-to-high and high-to-low transitions.
D. Slew rate is defined as 10% and 90% of the transition times.
E. Rise and fall times, open drain, are < 120 ns.
F. Input rise and fall times are 3 ns.

Figure 1. Load Circuits and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **3-State Outputs Drive Bus Lines or Buffer Memory Address Registers**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Pin Spacings**

54AC16240 . . . WD PACKAGE
74AC16240 . . . DL PACKAGE
(TOP VIEW)



description

The 'AC16240 are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

They can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide inverting outputs and symmetrical active-low output-enable ($\overline{OE}$) inputs.

The 74AC16240 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16240 is characterized for operation over the full military temperature range of –55°C to 125°C.

The 74AC16240 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 4-bit buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z

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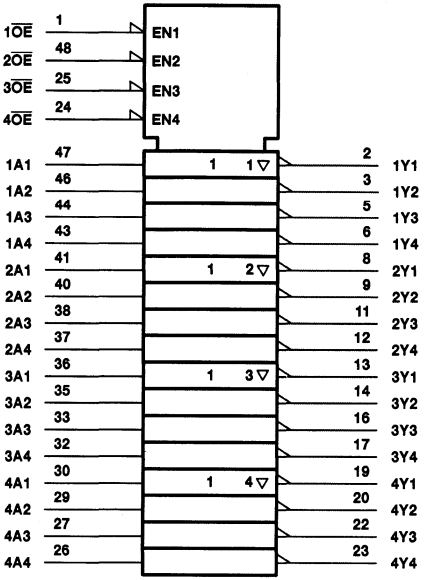
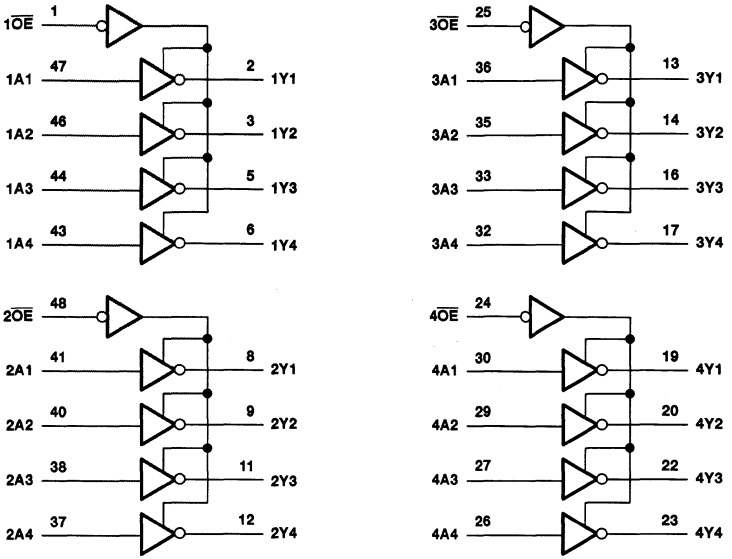
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum power dissipation at T_A = 55°C (in still air)(see Note 2): DL package ..... 1.2 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

			54AC16240			74AC16240			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		3	5	5.5	3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			2.1			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 5.5 V	3.85			3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9			0.9	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 5.5 V			1.65			1.65	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4			–4	mA
		V_{CC} = 4.5 V			–24			–24	
		V_{CC} = 5.5 V			–24			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12			12	mA
		V_{CC} = 4.5 V			24			24	
		V_{CC} = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54AC16240		74AC16240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = –4 mA	3 V	2.58			2.48		2.48		
	I_{OH} = –24 mA	4.5 V	3.94			3.8		3.8		
		5.5 V	4.94			4.8		4.8		
	I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}	I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.44		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.44		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80		80	µA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF
C_o	V_O = V_{CC} or GND	5 V		12						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16240		74AC16240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.8	5.4	7.5	1.8	8.3	1.8	8.3	ns
t_{PHL}			2.5	7	9.3	2.5	10.2	2.5	10.2	
t_{PZH}	$\overline{OE}$	Y	2.1	6.1	8.5	2.1	9.5	2.1	9.5	ns
t_{PZL}			2.9	8.4	11.3	2.9	12.6	2.9	12.6	
t_{PHZ}	$\overline{OE}$	Y	4.3	6.2	8.3	4.3	8.7	4.3	8.7	ns
t_{PLZ}			3.6	6	7.8	3.6	8.4	3.6	8.4	

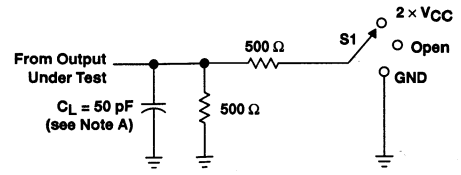
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16240		74AC16240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.3	3.3	5.3	1.3	5.8	1.3	5.8	ns
t_{PHL}			1.9	4.3	6.5	1.9	7.1	1.9	7.1	
t_{PZH}	$\overline{OE}$	Y	1.6	3.8	5.9	1.6	6.6	1.6	6.6	ns
t_{PZL}			3.2	4.7	7.2	3.2	8.1	3.2	8.1	
t_{PHZ}	$\overline{OE}$	Y	4.2	6	7.7	4.2	8.1	4.2	8.1	ns
t_{PLZ}			3.4	5.1	6.9	3.4	7.3	3.4	7.3	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

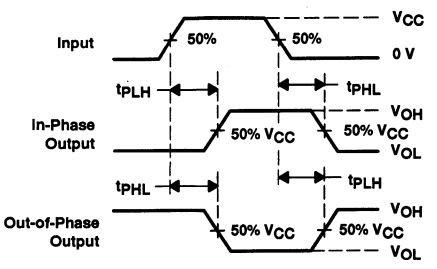
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per latch	Outputs enabled	C_L = 50 pF, f = 1 MHz	42	pF
		Outputs disabled		6	

PARAMETER MEASUREMENT INFORMATION

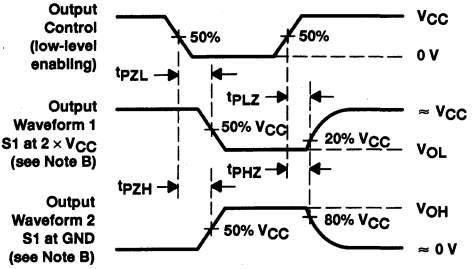


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



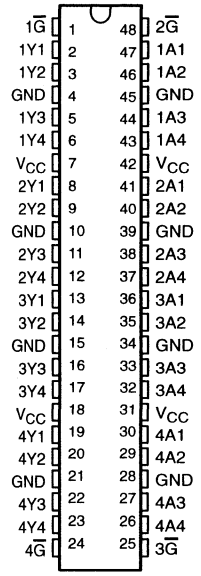
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Shrink Small-Outline 300-mil Package Using 25-mil Center-to-Center Pin Spacings**
- **3-State Outputs Drive Bus Lines or Buffer Memory Address Registers**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Packaged in Plastic Shrink and Plastic Thin Shrink Small-Outline Packages Using 25-mil Center-to-Center Pin Spacings**

DGG OR DL PACKAGE
(TOP VIEW)



description

The 74AC16244 is a 16-bit buffer/line driver designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. This device provides true outputs and symmetrical $\overline{G}$ (active-low) output-enable inputs.

The 74AC16244 is packaged in the TI's shrink small-outline package (SSOP), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

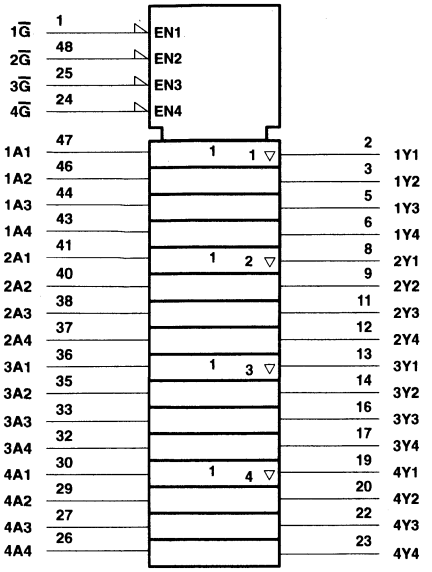
The 74AC16244 is characterized for operation from – 40°C to 85°C.

FUNCTION TABLE
(each driver)

INPUTS		OUTPUT
$\overline{G}$	A	Y
L	H	H
L	L	L
H	X	Z

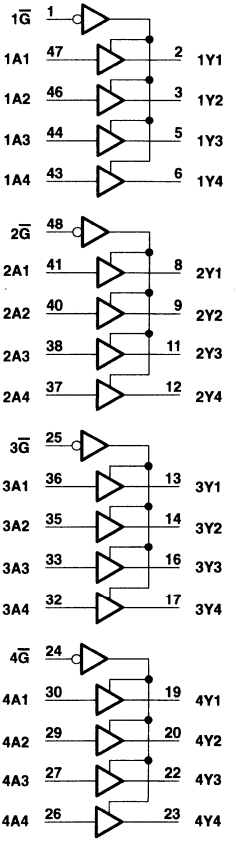
Widebus and EPIC are trademarks of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... – 0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... – 0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... – 0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ± 50 mA
Continuous current through V_{CC} or GND ..... ± 400 mA
Storage temperature range ..... – 65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage (see Note 3)		3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			V
		V_{CC} = 4.5 V	3.15			
		V_{CC} = 5.5 V	3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9	V
		V_{CC} = 4.5 V			1.35	
		V_{CC} = 5.5 V			1.65	
V_I	Input voltage		0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4	mA
		V_{CC} = 4.5 V			–24	
		V_{CC} = 5.5 V			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12	mA
		V_{CC} = 4.5 V			24	
		V_{CC} = 5.5 V			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	ns/V
T_A	Operating free-air temperature		–40		85	°C

NOTES: 2. Unused or floating inputs should be tied to V_{CC} through a pullup resistor of approximately 5 kΩ or greater.
3. All V_{CC} and GND pins must be connected to the proper voltage supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	I_{OH} = −50 μA	3 V	2.9			2.9		V
		4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
	I_{OH} = −4 mA	3 V	2.58			2.48		
	I_{OH} = −24 mA	4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}	I_{OL} = −50 μA	3 V			0.1		0.1	V
		4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1	μA
I_{OZ}	V_I = V_{CC} or GND	5.5 V			±0.5		±5	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80	μA
C_i	V_I = V_{CC} or GND	5 V		4.5				pF
C_o	V_I = V_{CC} or GND	5 V		12				

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	Y	2	7.1	9.4	2	10.8	ns
t_{PHL}			2.4	8.3	10.7	2.4	11.8	
t_{PZH}	$\overline{G}$	Y	2.2	7.5	10	2.2	11.5	ns
t_{PZL}			2.9	10.4	13	2.9	14.6	
t_{PHZ}	$\overline{G}$	Y	4.1	6.8	8.4	4.1	9.1	ns
t_{PLZ}			3.7	6.5	8.1	3.7	8.8	

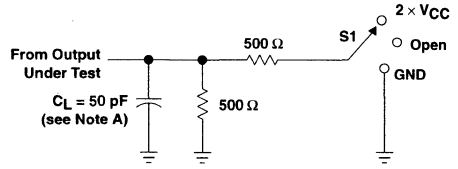
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	Y	1.6	4.6	6.3	1.6	7.1	ns
t_{PHL}			2	5.3	7	2	7.9	
t_{PZH}	$\overline{G}$	Y	1.7	4.8	6.7	1.7	7.5	ns
t_{PZL}			2.2	6.1	8.1	2.2	9	
t_{PHZ}	$\overline{G}$	Y	4	6.4	7.8	4	8.4	ns
t_{PLZ}			3.5	5.5	7.2	3.5	7.6	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

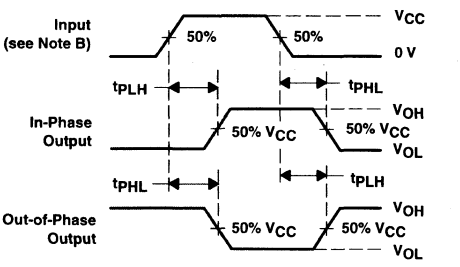
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per latch	Outputs enabled	C_L = 50 pF, f = 1 MHz	43	pF
		Outputs disabled		7	

PARAMETER MEASUREMENT INFORMATION

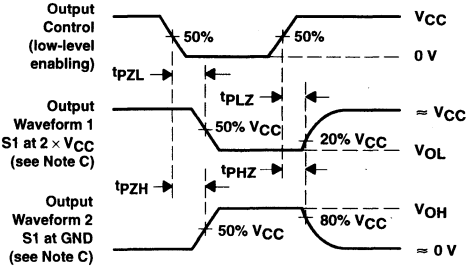


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



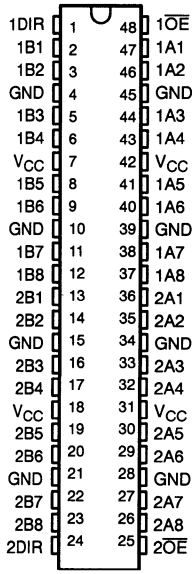
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **3-State Outputs Drive Bus Lines or Buffer Memory Address Registers**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic Thin Shrink Small-Outline (DGG) Package, 300-mil Shrink Small-Outline (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Pin Spacings**

54AC16245 . . . WD PACKAGE
74AC16245 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'AC16245 are 16-bit bus transceivers organized as dual-octal noninverting 3-state transceivers designed for asynchronous two-way communication between data buses. The control function implementation minimizes external timing requirements

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction control (DIR) input. The output-enable input ($\overline{OE}$) can be used to disable the devices so that the buses are effectively isolated.

The 74AC16245 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

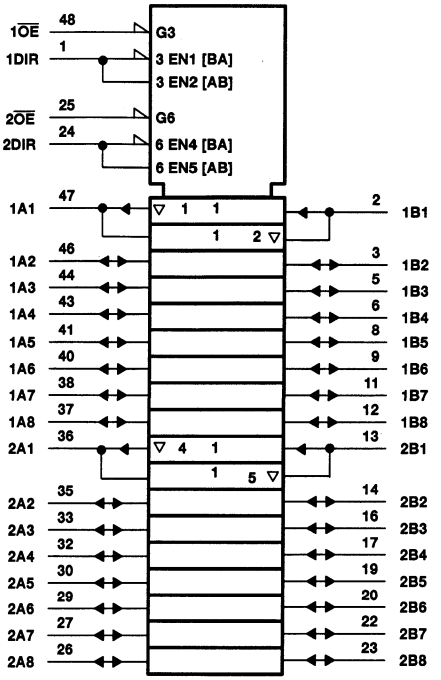
The 54AC16245 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16245 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

CONTROL INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to bus
H	X	Isolation

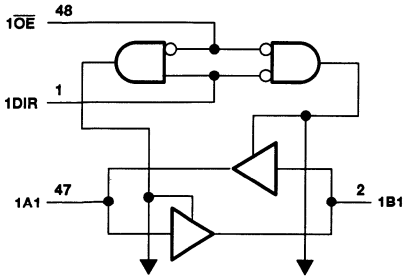
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

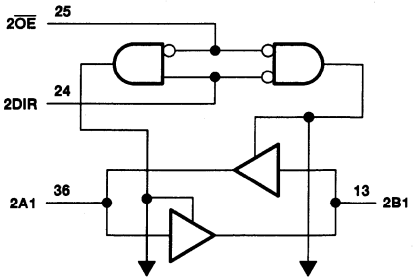
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DGG package ..... 0.85 W
DL package ..... 1.2 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

			54AC16245			74AC16245			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage (see Note 4)		3	5	5.5	3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			2.1			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 5.5 V	3.85			3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9			0.9	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 5.5 V			1.65			1.65	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4			–4	mA
		V_{CC} = 4.5 V			–24			–24	
		V_{CC} = 5.5 V			–24			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12			12	mA
		V_{CC} = 4.5 V			24			24	
		V_{CC} = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTES: 3. All unused pins (input and I/O) must be held high or low to prevent them from floating.
4. All V_{CC} and GND pins must be connected to the proper voltage power supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54AC16245		74AC16245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = –4 mA	3 V	2.58			2.48		2.48		
	I_{OH} = –24 mA	4.5 V	3.94			3.8		3.8		
		5.5 V	4.94			4.8		4.8		
	I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}	I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.44		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.44		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}	V_I = V_{CC} or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80		80	µA
C_i	V_I = V_{CC} or GND	5 V		4.5						pF
C_o	V_I = V_{CC} or GND	5 V		16						

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16245		74AC16245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	2.5	7.6	10.4	2.5	11.9	2.5	11.9	ns
t_{PHL}			3.1	9	12.3	3.1	13.5	3.1	13.5	
t_{PZH}	$\overline{OE}$	A or B	2.8	8.6	11.8	2.8	13.2	2.8	13.2	ns
t_{PZL}			3.9	12	16.2	3.9	18	3.9	18	
t_{PHZ}	$\overline{OE}$	A or B	5.3	8.4	10.4	5.3	11.2	5.3	11.2	ns
t_{PLZ}			4.4	7.7	9.7	4.4	10.3	4.4	10.3	

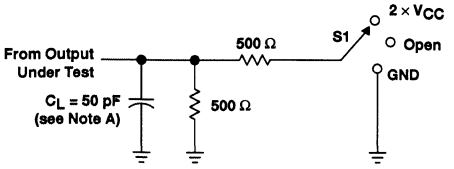
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16245		74AC16245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	2	4.6	6.9	2	7.9	2	7.9	ns
t_{PHL}			2.5	5.2	7.9	2.5	8.9	2.5	8.9	
t_{PZH}	$\overline{OE}$	A or B	2.3	4.9	7.5	2.3	8.6	2.3	8.6	ns
t_{PZL}			3	6.2	9.5	3	10.7	3	10.7	
t_{PHZ}	$\overline{OE}$	A or B	5	7.2	9.1	5	9.8	5	9.8	ns
t_{PLZ}			4.2	6.2	8.1	4.2	8.7	4.2	8.7	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

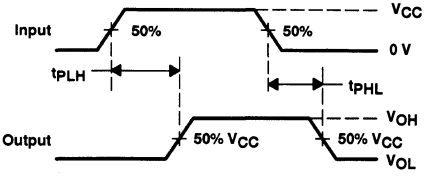
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per latch	Outputs enabled	C_L = 50 pF, f = 1 MHz	43	pF
		Outputs disabled		8	

PARAMETER MEASUREMENT INFORMATION

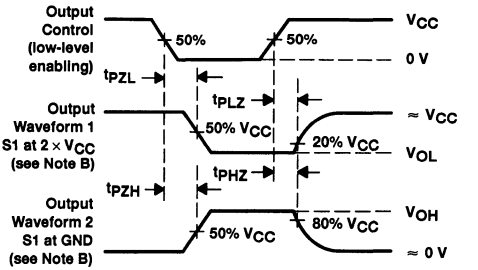


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

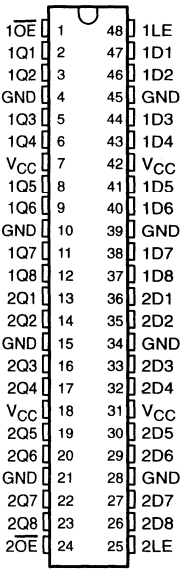
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

SCAS121A – D3467, MARCH 1990 – REVISED APRIL 1993

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Packages Using 25-mil Center-to-Center Pin Spacings**
- **3-State True Outputs**
- **Full Parallel Access for Loading**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74AC16373 is a 16-bit transparent D-type latch with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. The device can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components. The output enable ($\overline{OE}$) does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74AC16373 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

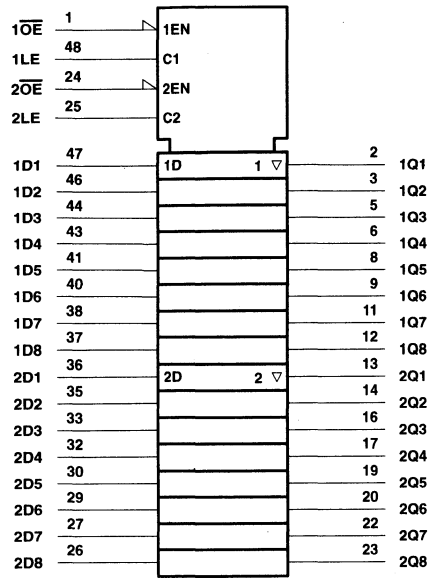
The 74AC16373 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE

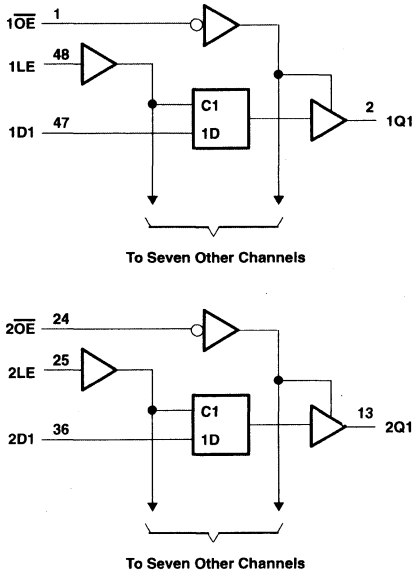
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

EPIC and Widebus are trademarks of Texas Instruments Incorporated.

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum power dissipation at $T_A = 55°C$ (in still air) ..... 0.85 W
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			V
		V_{CC} = 4.5 V	3.15			
		V_{CC} = 5.5 V	3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9	V
		V_{CC} = 4.5 V			1.35	
		V_{CC} = 5.5 V			1.65	
V_I	Input voltage		0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4	mA
		V_{CC} = 4.5 V			–24	
		V_{CC} = 5.5 V			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12	mA
		V_{CC} = 4.5 V			24	
		V_{CC} = 5.5 V			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	ns/V
T_A	Operating free-air temperature		–40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	TA = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	I_{OH} = – 50 µA	3 V	2.9			2.9		V
		4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
	I_{OH} = – 4 mA	3 V	2.58			2.48		
	I_{OL} = – 24 mA	4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	I_{OH} = –75 mA†	5.5 V				3.85		
V_{OL}	I_{OL} = 50 µA	3 V			0.1		0.1	V
		4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1	µA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.5		±5	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80	µA
C_i	V_I = V_{CC} or GND	5 V		4.5				pF
C_o	V_O = V_{CC} or GND	5 V		12				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		MIN	MAX	UNIT
		MIN	MAX			
t_w	Pulse duration, LE high	5		5		ns
t_{su}	Setup time, data before LE↓	1.5		1.5		ns
t_h	Hold time, data after LE↓	3		3		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		MIN	MAX	UNIT
		MIN	MAX			
t_w	Pulse duration, LE high	4		4		ns
t_{su}	Setup time, data before LE↓	1.5		1.5		ns
t_h	Hold time, data after LE↓	2.5		2.5		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	D	Q	3.7	10.6	13.4	3.7	15.1	ns
t_{PHL}			4.3	11.3	14	4.3	14.8	
t_{PLH}	LE	Q	4.6	12.9	15.8	4.6	18.6	ns
t_{PHL}			4.5	12.1	14.6	4.5	16.4	
t_{PZH}	$\overline{OE}$	Q	4.2	11.8	14.8	4.2	17.5	ns
t_{PZL}			5.4	16.3	19.8	5.4	22.3	
t_{PHZ}	$\overline{OE}$	Q	4.2	7.9	9.5	4.2	10.2	ns
t_{PLZ}			3.8	7.1	8.9	3.8	9.8	

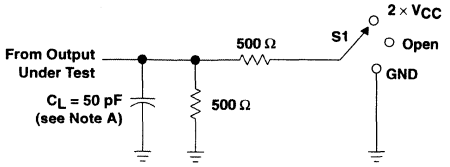
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	D	Q	3.1	6.7	8.5	3.1	9.7	ns
t_{PHL}			3.5	7.3	9.1	3.5	10.1	
t_{PLH}	LE	Q	3.8	8.2	10.2	3.8	11.9	ns
t_{PHL}			3.6	7.8	9.7	3.6	10.9	
t_{PZH}	$\overline{OE}$	Q	3.5	7.4	9.4	3.5	10.8	ns
t_{PZL}			4.3	9.1	11.3	4.3	12.8	
t_{PHZ}	$\overline{OE}$	Q	3.9	6.6	8	3.9	8.8	ns
t_{PLZ}			3.7	5.9	7.4	3.7	8.1	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

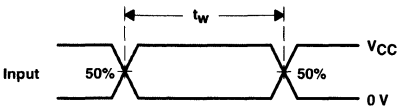
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per latch	Outputs enabled	C_L = 50 pF, f = 1 MHz	43	pF
		Outputs disabled		5	

PARAMETER MEASUREMENT INFORMATION

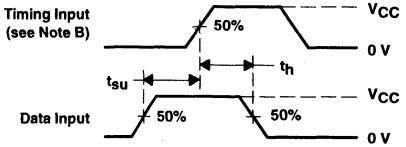


LOAD CIRCUIT

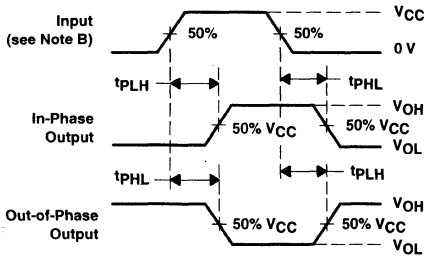
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × VCC
t_{PHZ}/t_{PZH}	GND



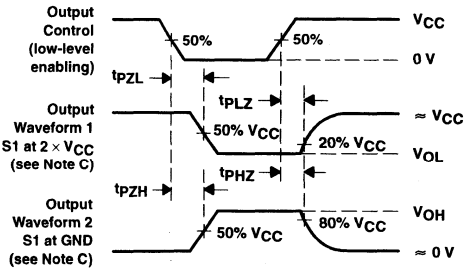
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



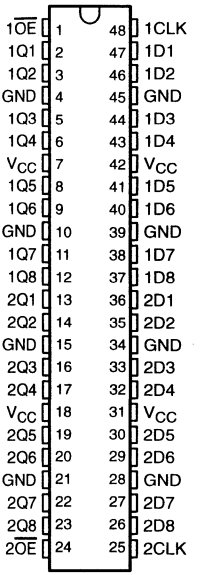
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **3-State True Outputs**
- **Full Parallel Access for Loading**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74AC16374 is a 16-bit edge-triggered D-type flip-flop with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The 74AC16374 can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

The output enable ($\overline{OE}$) does not affect the internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74AC16374 is packaged in TI's shrink small-outline package (SSOP), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

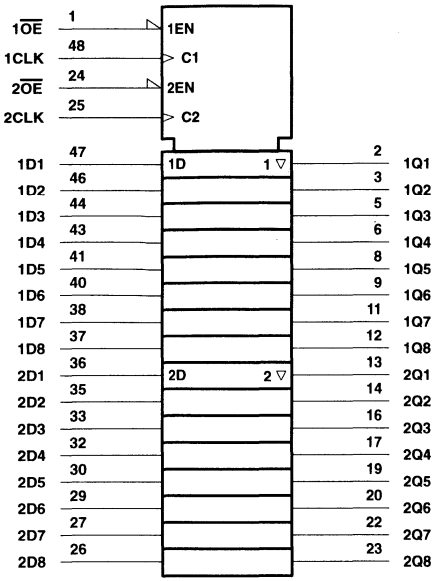
The 74AC16374 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	X	X	Q_0
L	↓	X	Q_0
H	X	X	Z

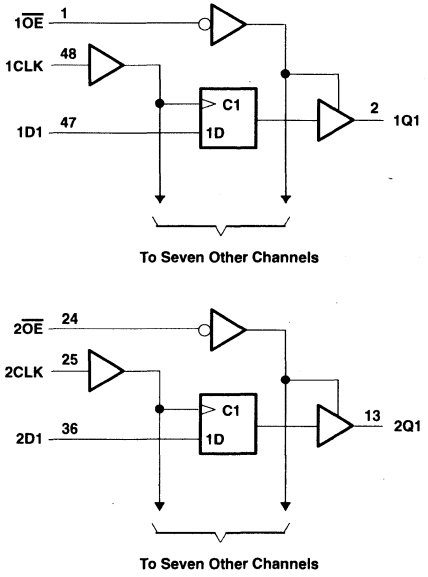
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum power package dissipation at T_A = 55°C (in still air) ..... 0.85 W
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			V
		V_{CC} = 4.5 V	3.15			
		V_{CC} = 5.5 V	3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9	V
		V_{CC} = 4.5 V			1.35	
		V_{CC} = 5.5 V			1.65	
V_I	Input voltage		0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			−4	mA
		V_{CC} = 4.5 V			−24	
		V_{CC} = 5.5 V			−24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12	mA
		V_{CC} = 4.5 V			24	
		V_{CC} = 5.5 V			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	ns/V
T_A	Operating free-air temperature		−40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	TA = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	I_{OH} = − 50 µA	3 V	2.9			2.9		V
		4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
	I_{OH} = − 4 mA	3 V	2.58			2.48		
	I_{OL} = −24 mA	4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}	I_{OL} = 50 µA	3 V			0.1		0.1	V
		4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1	µA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.5		±5	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80	µA
C_i	V_I = V_{CC} or GND	5 V		3				pF
C_o	V_O = V_{CC} or GND	5 V		11				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
f_{clock}	Clock frequency		0	60	0	60	MHz
t_w	Pulse duration	CLK high or low	8.3		8.3		ns
t_{su}	Setup time, data before CLK↑		7.5		7.5		ns
t_h	Hold time, data after CLK↑		0		0		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
f_{clock}	Clock frequency		0	100	0	100	MHz
t_w	Pulse duration	CLK high or low	5		5		ns
t_{su}	Setup time, data before CLK↑		5		5		ns
t_h	Hold time, data after CLK↑		0		0		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f_{max}			60			60		MHz
t_{PLH}	CLK	Q	4.9	12.2	15	4.9	17	ns
t_{PHL}			4.8	11.9	14.3	4.8	15.7	
t_{PZH}	$\overline{OE}$	Q	4.3	11.9	14.7	4.3	16.8	ns
t_{PZL}			5.3	15.5	18.7	5.3	21.2	
t_{PHZ}	$\overline{OE}$	Q	4	7.3	9	4	9.8	ns
t_{PLZ}			3.8	7.1	8.8	3.8	9.4	

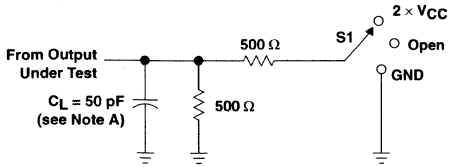
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f_{max}			100			100		MHz
t_{PLH}	CLK	Q	3.8	7.6	9.5	3.8	10.8	ns
t_{PHL}			3.8	7.6	9.5	3.8	10.6	
t_{PZH}	$\overline{OE}$	Q	3.2	7.2	9	3.2	10.2	ns
t_{PZL}			3.8	8.7	10.7	3.8	12.1	
t_{PHZ}	$\overline{OE}$	Q	3.7	6	7.5	3.7	8.2	ns
t_{PLZ}			3.5	5.8	7.3	3.5	7.9	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

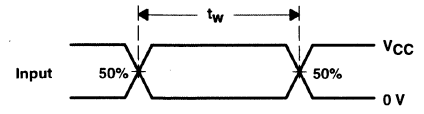
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per flip-flop	Outputs enabled	C_L = 50 pF, f = 1 MHz	49	pF
		Outputs disabled		32	

PARAMETER MEASUREMENT INFORMATION

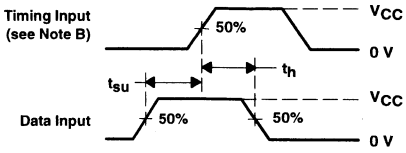


LOAD CIRCUIT

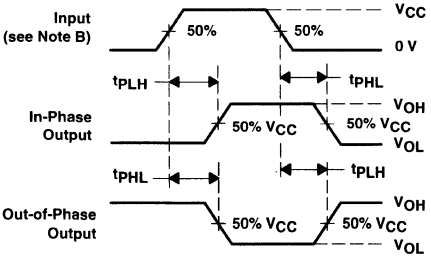
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



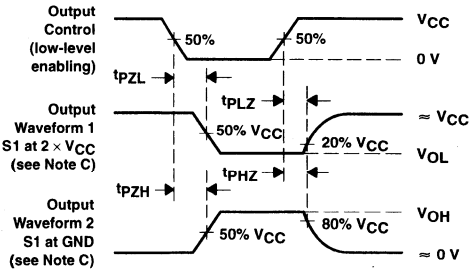
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



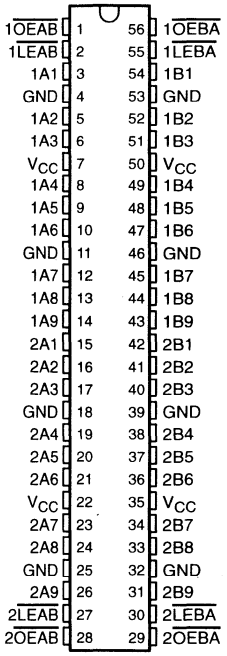
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **3-State True Outputs**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Pin Spacings**

54AC16472 . . . WD PACKAGE
74AC16472 . . . DL PACKAGE
(TOP VIEW)



description

The 'AC16472 are 18-bit registered transceivers that contain two sets of D-type latches for temporary storage of data flowing in either direction. They can be used as two 9-bit transceivers or one 18-bit transceiver. Separate latch-enable ($\overline{LEAB}$ or $\overline{LEBA}$) and output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

When $\overline{OEAB}$ and $\overline{LEAB}$ are both low, the A-to-B latches are transparent; a subsequent low-to-high transition of $\overline{LEAB}$ puts the A latches in the storage mode. With $\overline{OEAB}$ low, the B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires the use of the $\overline{LEBA}$ and $\overline{OEBA}$ inputs.

The 74AC16472 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16472 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16472 is characterized for operation from –40°C to 85°C.

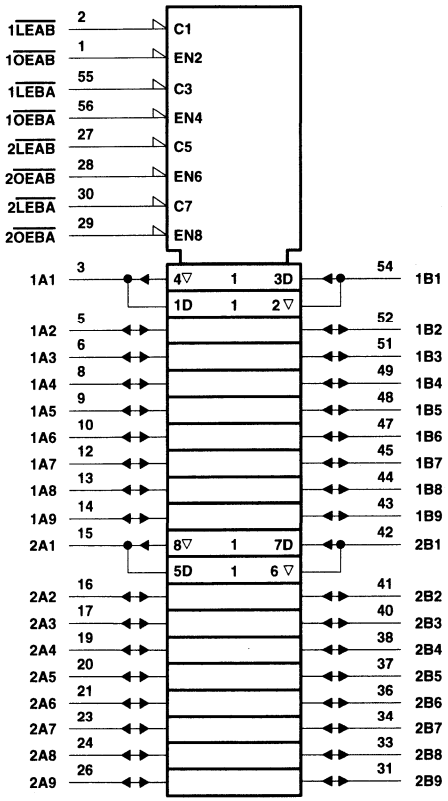
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

FUNCTION TABLE†

INPUTS			OUTPUT
$\overline{LEAB}$	OEAB	A	B
X	H	X	Z
H	L	X	B_0‡
L	L	H	H
L	L	L	L

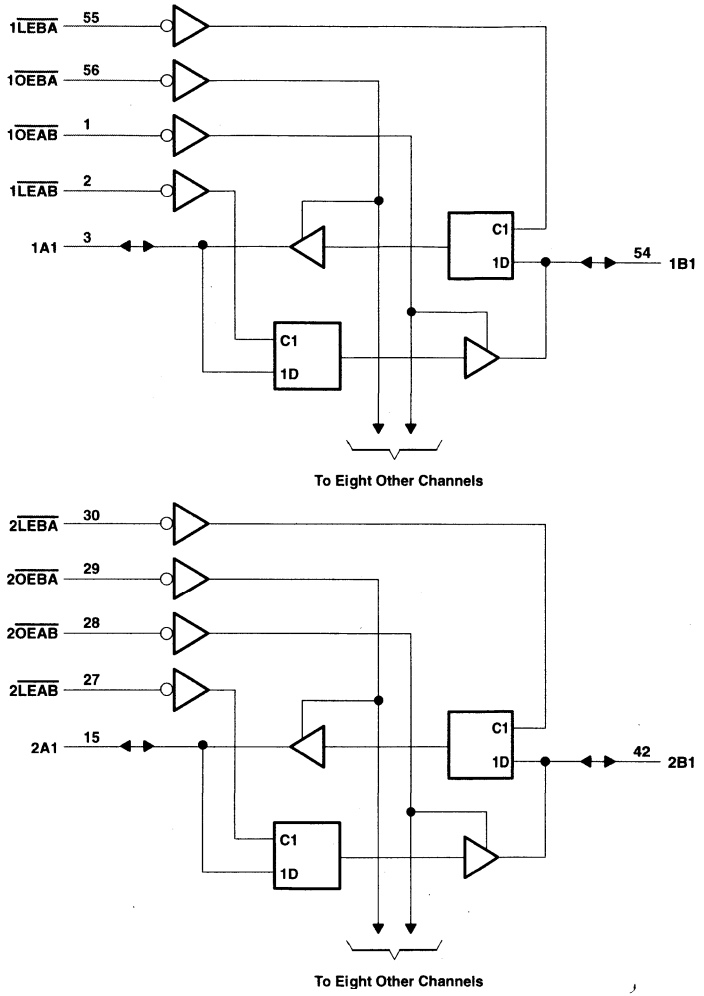
† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{LEBA}$ and $\overline{OEBA}$.
‡ Output level before the indicated steady-state input conditions were established

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±450 mA
Maximum power package dissipation at T_A = 55°C (in still air) (see Note 2): DL package ..... 1.4 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

			54AC16472			74AC16472			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		3	5	5.5	3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			2.1			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 5.5 V	3.85			3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9			0.9	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 5.5 V			1.65			1.65	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4			–4	mA
		V_{CC} = 4.5 V			–24			–24	
		V_{CC} = 5.5 V			–24			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12			12	mA
		V_{CC} = 4.5 V			24			24	
		V_{CC} = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54AC16472		74AC16472		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = –50 µA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = –4 mA	3 V	2.58			2.48		2.48		
		I_{OL} = –24 mA	4.5 V	3.94			3.8		3.8		
			5.5 V	4.94			4.8		4.8		
		I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}		I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.44		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
			5.5 V			0.36		0.44		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80		80	µA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		3						pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		11.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		54AC16472		74AC16472		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low	4		4		4		ns
t_{su}	Setup time, data before $\overline{LEAB}$ or $\overline{LEBA}$ ↑	0.5		0.5		0.5		ns
t_h	Hold time, data after $\overline{LEAB}$ or $\overline{LEBA}$ ↑	3.5		3.5		3.5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		54AC16472		74AC16472		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low	4		4		4		ns
t_{su}	Setup time, data before $\overline{LEAB}$ or $\overline{LEBA}$ ↑	0.5		0.5		0.5		ns
t_h	Hold time, data after $\overline{LEAB}$ or $\overline{LEBA}$ ↑	2.5		2.5		2.5		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16472		74AC16472		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	3.5	8	12.5	3.5	14.2	3.5	14.2	ns
t_{PHL}			3.9	8.4	12.8	3.9	13.9	3.9	13.9	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	4.8	10.3	15.6	4.8	17.9	4.8	17.9	ns
t_{PHL}			4.7	9.7	14.7	4.7	16.3	4.7	16.3	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	3.9	8.9	14	3.9	15.9	3.9	15.9	ns
t_{PZL}			5	11.2	17.6	5	19.7	5	19.7	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	4.4	7	9.4	4.4	10	4.4	10	ns
t_{PLZ}			4	6.4	8.7	4	9.4	4	9.4	

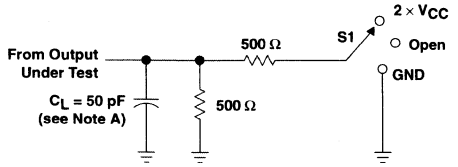
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16472		74AC16472		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	2.9	5.6	8.4	2.9	9.5	2.9	9.5	ns
t_{PHL}			3.1	6	8.7	3.1	9.6	3.1	9.6	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	3.9	7.3	10.3	3.9	11.7	3.9	11.7	ns
t_{PHL}			3.7	6.9	9.7	3.7	10.9	3.7	10.9	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	3.1	6.2	8.9	3.1	10.2	3.1	10.2	ns
t_{PZL}			3.9	7.3	10.4	3.9	11.6	3.9	11.6	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	4.3	6.2	8.1	4.3	8.6	4.3	8.6	ns
t_{PLZ}			3.8	5.7	7.4	3.8	8	3.8	8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

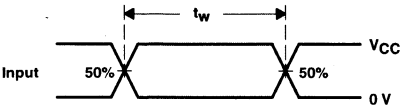
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	59	pF
		Outputs disabled		6	

PARAMETER MEASUREMENT INFORMATION

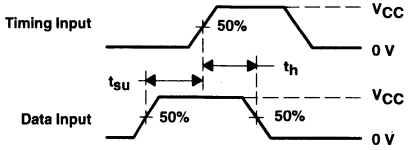


LOAD CIRCUIT

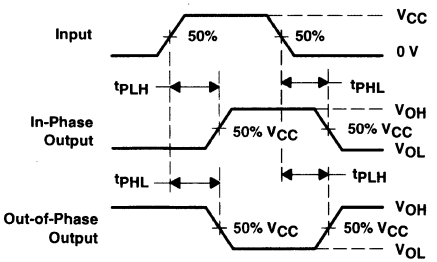
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × VCC
t_{PHZ}/t_{PZH}	GND



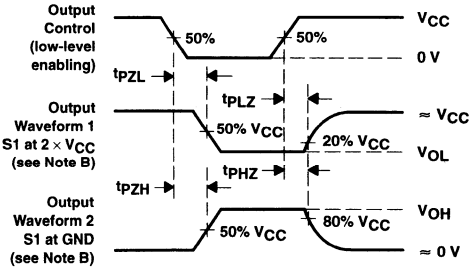
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



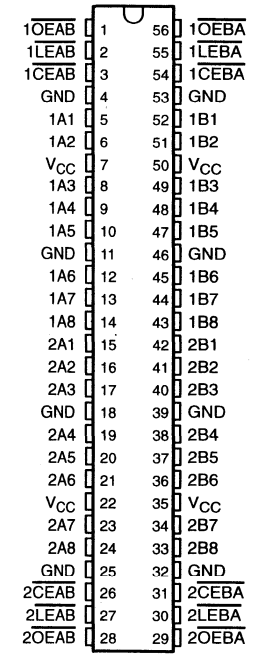
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **3-State True Outputs**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Pin Spacings**

54AC16543 . . . WD PACKAGE
74AC16543 . . . DL PACKAGE
(TOP VIEW)



description

The 'AC16543 are 16-bit registered transceivers that contain two sets of D-type latches for temporary storage of data flowing in either direction. They can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable ($\overline{LEAB}$ or $\overline{LEBA}$) and output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable ($\overline{CEAB}$) input must be low to enter data from A or to output data to B. Having $\overline{CEAB}$ low and $\overline{LEAB}$ low makes the A-to-B latches transparent; a subsequent low-to-high transition at $\overline{LEAB}$ puts the A latches in the storage mode. Data flow from B to A is similar, but requires using the $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$ inputs.

The 74AC16543 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16543 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16543 is characterized for operation from –40°C to 85°C.

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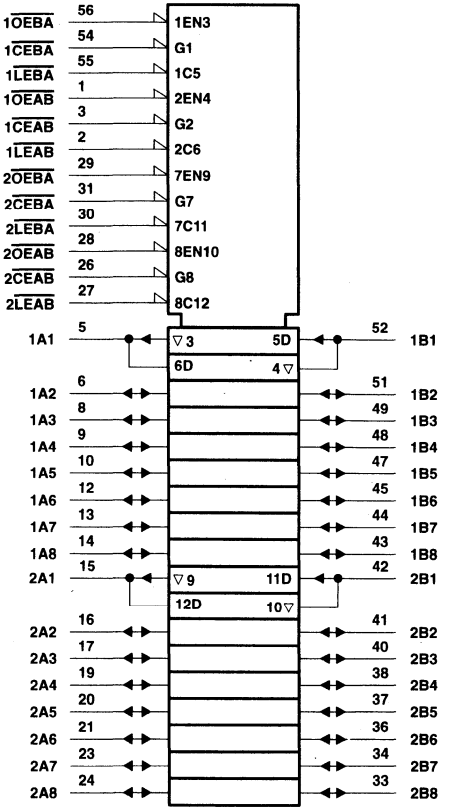
FUNCTION TABLE† (each 8-bit section)

INPUTS				OUTPUT
$\overline{CEAB}$	$\overline{LEAB}$	$\overline{OEAB}$	A	B
H	X	X	X	Z
X	X	H	X	Z
L	H	L	X	B_0‡
L	L	L	L	L
L	L	L	H	H

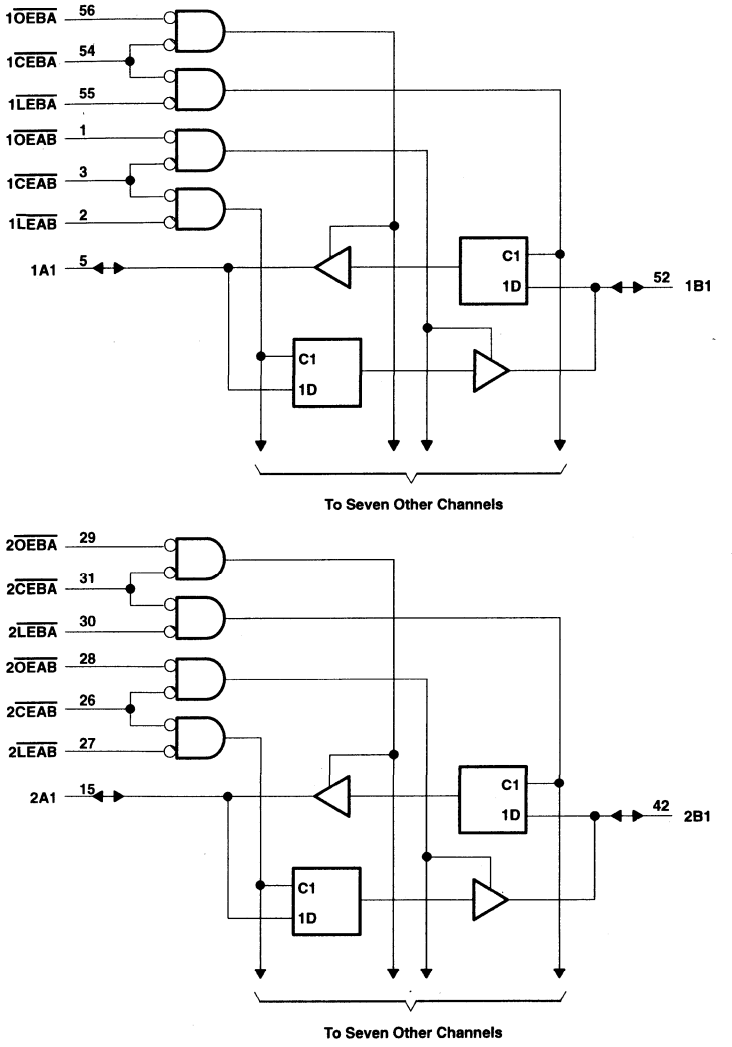
† A-to-B data flow is shown; B-to-A flow control is the same except that it uses $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$.
‡ Output level before the indicated steady-state input conditions were established

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum power package dissipation at T_A = 55°C (in still air)(see Note 2): DL package ..... 1.4 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

			54AC16543			74AC16543			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		3	5	5.5	3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			2.1			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 5.5 V	3.85			3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9			0.9	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 5.5 V			1.65			1.65	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4			–4	mA
		V_{CC} = 4.5 V			–24			–24	
		V_{CC} = 5.5 V			–24			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12			12	mA
		V_{CC} = 4.5 V			24			24	
		V_{CC} = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54AC16543		74AC16543		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = –50 µA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = –4 mA	3 V	2.58			2.48		2.48		
		I_{OL} = –24 mA	4.5 V	3.94			3.8		3.8		
			5.5 V	4.94			4.8		4.8		
		I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}		I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.44		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
			5.5 V			0.36		0.44		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80		80	µA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		3						pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		11.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		54AC16543		74AC16543		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low	5		5		5		ns
t_{su}	Setup time, data before $\overline{LEAB}$ or $\overline{LEBA}$ ↑	1		1		1		ns
t_h	Hold time, data after $\overline{LEAB}$ or $\overline{LEBA}$ ↑	3.5		3.5		3.5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		54AC16543		74AC16543		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low	4		4		4		ns
t_{su}	Setup time, data before $\overline{LEAB}$ or $\overline{LEBA}$ ↑	1		1		1		ns
t_h	Hold time, data after $\overline{LEAB}$ or $\overline{LEBA}$ ↑	3		3		3		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16543		74AC16543		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	3.2	8.6	12.5	3.2	13.9	3.2	13.9	ns
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	4.6	11.8	16	4.6	18	4.6	18	ns
t_{PHL}			4.6	11.3	15.4	4.6	16.8	4.6	16.8	
t_{PZH}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	3.7	10	14	3.7	15.8	3.7	15.8	ns
t_{PZL}			4.6	12.7	17.7	4.6	19.8	4.6	19.8	
t_{PHZ}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	4.7	7.8	10.1	4.7	10.8	4.7	10.8	ns
t_{PLZ}			4.3	7.3	9.7	4.3	10.4	4.3	10.4	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	3.5	9.7	13.9	3.5	15.7	3.5	15.7	ns
t_{PZL}			4.5	12.5	17.6	4.5	19.7	4.5	19.7	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	4.8	7.5	9.6	4.8	10.2	4.8	10.2	ns
t_{PLZ}			4.1	6.8	9.2	4.1	9.8	4.1	9.8	

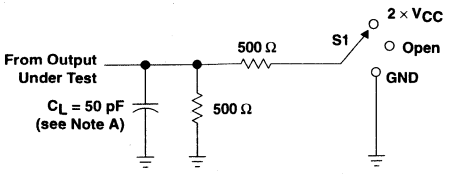
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16543		74AC16543		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	2.7	5.2	7.8	2.7	8.8	2.7	8.8	ns
t_{PHL}			2.9	5.5	8.3	2.9	9.2	2.9	9.2	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	3.9	7	10.2	3.9	11.5	3.9	11.5	ns
t_{PHL}			3.7	6.7	9.9	3.7	10.9	3.7	10.9	
t_{PZH}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	3	5.8	8.7	3	9.8	3	9.8	ns
t_{PZL}			3.6	6.7	10.3	3.6	11.5	3.6	11.5	
t_{PHZ}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	4.2	6.5	8.7	4.2	9.3	4.2	9.3	ns
t_{PLZ}			4	5.9	8.2	4	8.8	4	8.8	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	2.9	5.6	8.5	2.9	9.6	2.9	9.6	ns
t_{PZL}			3.5	6.6	10.2	3.5	11.3	3.5	11.3	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	4.2	6.3	8.4	4.2	8.9	4.2	8.9	ns
t_{PLZ}			3.7	5.6	7.9	3.7	8.4	3.7	8.4	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

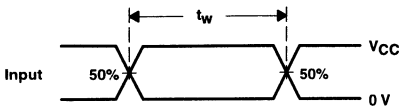
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	53	pF
		Outputs disabled		11	

PARAMETER MEASUREMENT INFORMATION

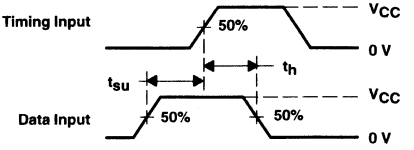


LOAD CIRCUIT

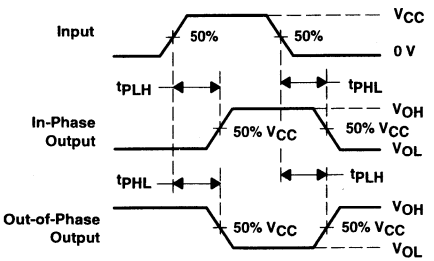
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



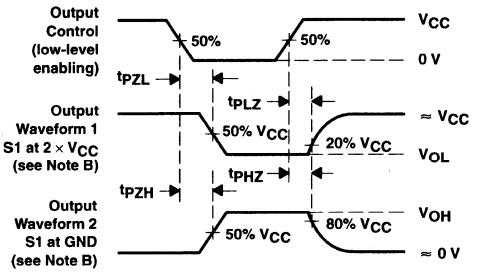
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



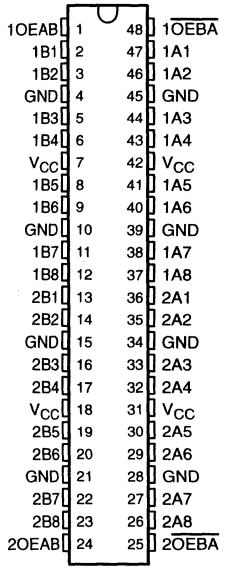
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Packaged in Plastic 300-mil Shrink Small-Outline Packages Using 25-mil Center-to-Center Pin Spacings**

DL PACKAGE
(TOP VIEW)



description

The 74AC16620 is an inverting 16-bit transceiver designed for asynchronous communication between data buses. The control function implementation allows for maximum flexibility in timing.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the complementary output-enable (OEAB or $\overline{OEBA}$) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives the transceiver the capability to store data by simultaneous enabling of OEAB and $\overline{OEBA}$. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, the bus lines remain at their last states.

The 74AC16620 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74AC16620 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

INPUTS		OPERATION
$\overline{OEBA}$	OEAB	
L	L	$\overline{B}$ data to A bus
L	H	$\overline{B}$ data to A bus, $\overline{A}$ data to B bus
H	L	Isolation
H	H	$\overline{A}$ data to B bus

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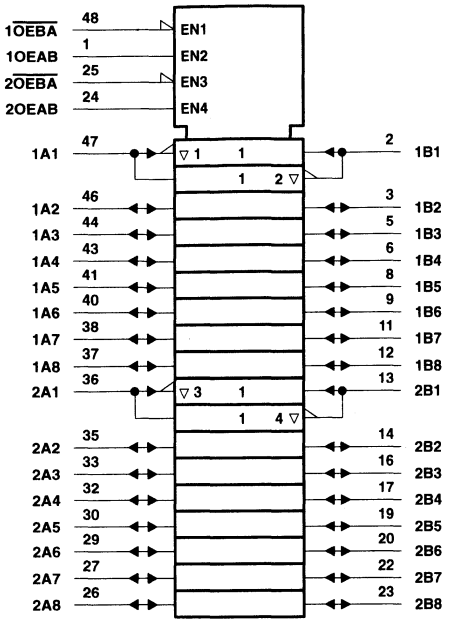
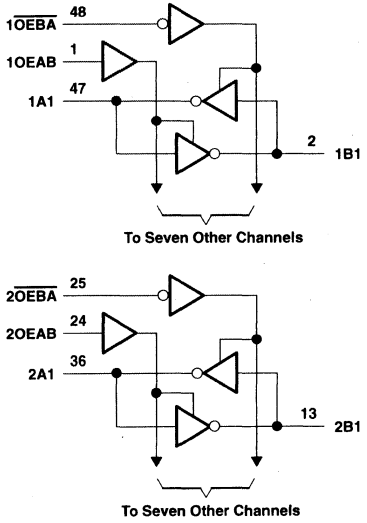
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum power dissipation at T_A = 55°C (in still air) ..... 0.85 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			V
		V_{CC} = 4.5 V	3.15			
		V_{CC} = 5.5 V	3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9	V
		V_{CC} = 4.5 V			1.35	
		V_{CC} = 5.5 V			1.65	
V_I	Input voltage		0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			−4	mA
		V_{CC} = 4.5 V			−24	
		V_{CC} = 5.5 V			−24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12	mA
		V_{CC} = 4.5 V			24	
		V_{CC} = 5.5 V			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	ns/V
T_A	Operating free-air temperature		−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = – 50 μA	3 V	2.9			2.9		V
			4.5 V	4.4			4.4		
			5.5 V	5.4			5.4		
		I_{OH} = – 4 mA	3 V	2.58			2.48		
		I_{OH} = – 24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = –75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 μA	3 V			0.1		0.1	V
			4.5 V			0.1		0.1	
			5.5 V			0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	V_I = V_{CC} or GND	5.5 V			±0.1		±1	μA
I_{OZ}‡	A or B ports	V_O = V_{CC} or GND	5.5 V			±0.5		±5	μA
I_{CC}		V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80	μA
C_i	Control inputs	V_I = V_{CC} or GND	5 V		4.5				pF
C_{io}	A or B ports	V_O = V_{CC} or GND	5 V		16				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	2.7	6.1	8.7	2.7	9.7	ns
t_{PHL}			3.9	7.9	10.6	3.9	11.7	
t_{PZH}	$\overline{OEBA}$	A	3.2	7.1	10	3.2	11.2	ns
t_{PZL}			4.5	11.1	13.5	4.5	15	
t_{PHZ}	$\overline{OEBA}$	A	5.3	7.4	9.5	5.3	10.2	ns
t_{PLZ}			4.6	7	9.2	4.6	9.8	
t_{PZH}	OEAB	B	3.1	6.7	9.5	3.1	10.7	ns
t_{PZL}			4.4	9.6	13	4.4	14.5	
t_{PHZ}	OEAB	B	5	7.1	9.3	5	9.8	ns
t_{PLZ}			4.4	6.8	8.9	4.4	9.4	

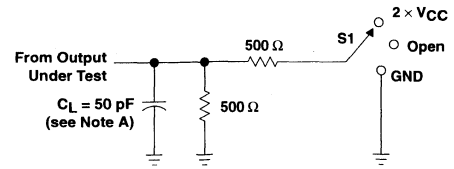
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	2.1	3.9	6.1	2.1	6.8	ns
t_{PHL}			3.1	4.9	7.3	3.1	8.2	
t_{PZH}	$\overline{OEBA}$	A	2.2	4.3	6.8	2.2	7.6	ns
t_{PZL}			3.3	5.5	8.4	3.3	9.4	
t_{PHZ}	$\overline{OEBA}$	A	4.9	6.6	8.6	4.9	9.2	ns
t_{PLZ}			4.1	5.8	7.8	4.1	8.3	
t_{PZH}	OEAB	B	2.2	4.2	6.5	2.2	7.3	ns
t_{PZL}			3.4	5.4	8.1	3.4	9.1	
t_{PHZ}	OEAB	B	4.6	6.4	8.5	4.6	9	ns
t_{PLZ}			4.1	5.6	7.6	4.1	8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

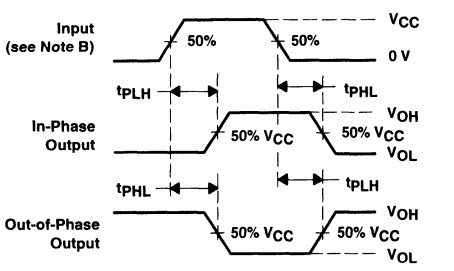
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	49	pF
		Outputs disabled		6	

PARAMETER MEASUREMENT INFORMATION

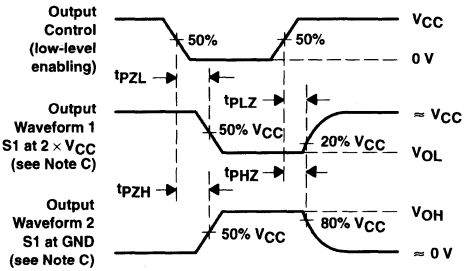


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



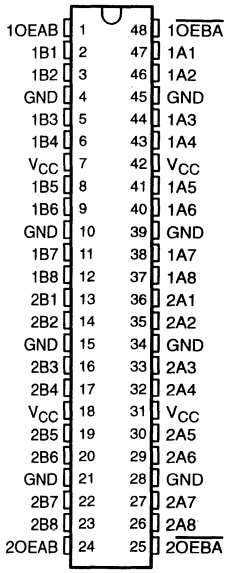
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74AC16623 is a 16-bit transceiver designed for asynchronous communication between data buses. The control function implementation allows for maximum flexibility in timing.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the output-enable ($\overline{OEBA}$ and OEAB) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives the bus transceiver the capability to store data by simultaneous enabling of $\overline{OEBA}$ and OEAB. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, the bus lines will remain at their last states.

The 74AC16623 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74AC16623 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

INPUTS		OPERATION
$\overline{OEBA}$	OEAB	
L	L	B data to A bus
H	H	A data to B bus
H	L	Isolation
L	H	B data to A bus, A data to B bus

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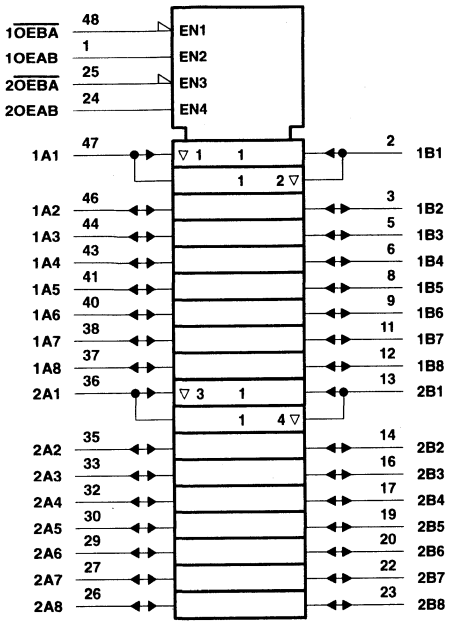
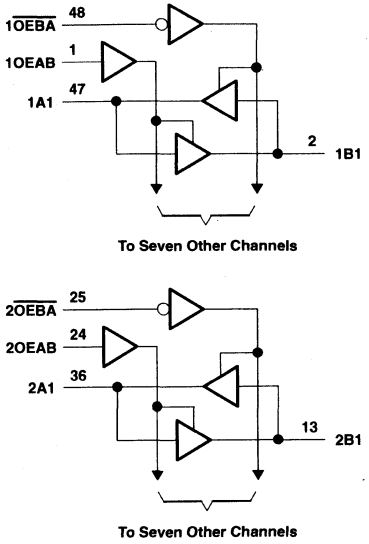
logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC})	±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC})	±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±400 mA
Maximum power package dissipation at T_A = 55°C (in still air)	0.85 W
Storage temperature range	−65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			V
		V_{CC} = 4.5 V	3.15			
		V_{CC} = 5.5 V	3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9	V
		V_{CC} = 4.5 V			1.35	
		V_{CC} = 5.5 V			1.65	
V_I	Input voltage		0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			−4	mA
		V_{CC} = 4.5 V			−24	
		V_{CC} = 5.5 V			−24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12	mA
		V_{CC} = 4.5 V			24	
		V_{CC} = 5.5 V			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	ns/V
T_A	Operating free-air temperature		−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	TA = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = − 50 µA	3 V	2.9			2.9		V
			4.5 V	4.4			4.4		
			5.5 V	5.4			5.4		
		I_{OH} = − 4 mA	3 V	2.58			2.48		
		I_{OL} = − 24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 µA	3 V			0.1		0.1	V
			4.5 V			0.1		0.1	
			5.5 V			0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	V_I = V_{CC} or GND	5.5 V			±0.1		±1	µA
I_{OZ}‡	A or B ports	V_O = V_{CC} or GND	5.5 V			±0.5		±5	µA
I_{CC}		V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80	µA
C_i	Control inputs	V_I = V_{CC} or GND	5 V		4.5				pF
C_{io}	A or B ports	V_O = V_{CC} or GND	5 V		16				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	2.7	8.1	10	2.7	11.2	ns
t_{PHL}			3.1	9.3	11.4	3.1	12.5	
t_{PZH}	$\overline{OEBA}$	A	2.7	8.3	10.3	2.7	11.5	ns
t_{PZL}			3.5	11.8	14.2	3.5	15.6	
t_{PHZ}	$\overline{OEBA}$	A	4.8	7.7	9.3	4.8	9.9	ns
t_{PLZ}			4.1	7.5	9.2	4.1	9.8	
t_{PZH}	OEAB	B	2.8	8.1	9.9	2.8	11.1	ns
t_{PZL}			3.8	10.7	14.1	3.8	15.1	
t_{PHZ}	OEAB	B	4.7	7.5	9.1	4.7	9.5	ns
t_{PLZ}			4.3	7.3	8.9	4.3	9.3	

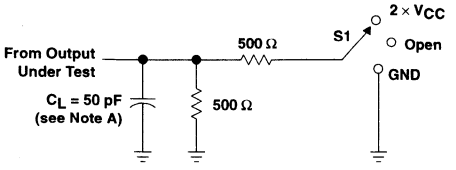
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	2.3	5.1	6.9	2.3	7.7	ns
t_{PHL}			2.6	6	7.8	2.6	8.6	
t_{PZH}	$\overline{OEBA}$	A	2.1	5.3	6.8	2.1	7.6	ns
t_{PZL}			2.8	6.9	8.5	2.8	9.4	
t_{PHZ}	$\overline{OEBA}$	A	4.7	6.9	8.4	4.7	8.9	ns
t_{PLZ}			4	6.3	7.7	4	8.2	
t_{PZH}	OEAB	B	2.3	5.2	6.7	2.3	7.5	ns
t_{PZL}			3	6.7	8.4	3	9.3	
t_{PHZ}	OEAB	B	4.5	6.9	8.4	4.5	8.9	ns
t_{PLZ}			4	6.2	7.6	4	7.9	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

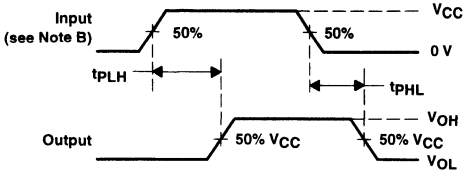
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	47	pF
		Outputs disabled		8	

PARAMETER MEASUREMENT INFORMATION

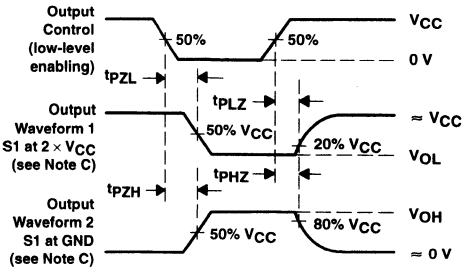


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



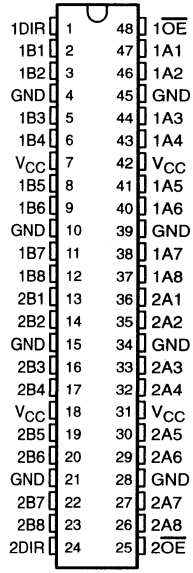
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Packaged in Plastic 300-mil Shrink Small-Outline Packages Using 25-mil Center-to-Center Pin Spacings**

DL PACKAGE
(TOP VIEW)



description

The 74AC16640 is an inverting 16-bit transceiver designed for asynchronous communication between data buses.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction-control (1DIR and 2DIR) inputs. The output-enable (1$\overline{OE}$ and 2$\overline{OE}$) inputs can be used to disable the device so that the buses are effectively isolated.

The 74AC16640 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74AC16640 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each section)

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	$\overline{B}$ data to A bus
L	H	$\overline{A}$ data to B bus
H	X	Isolation

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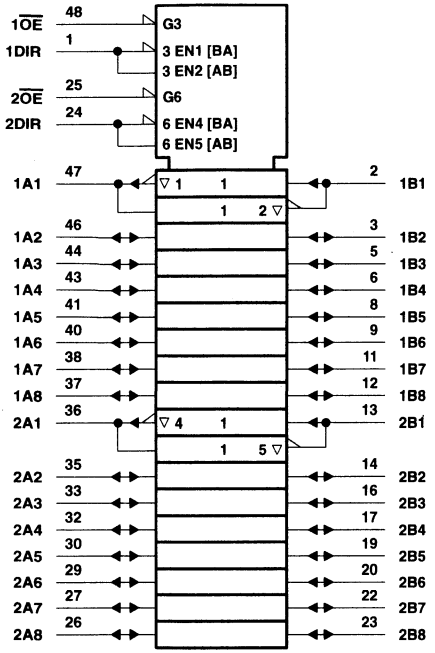
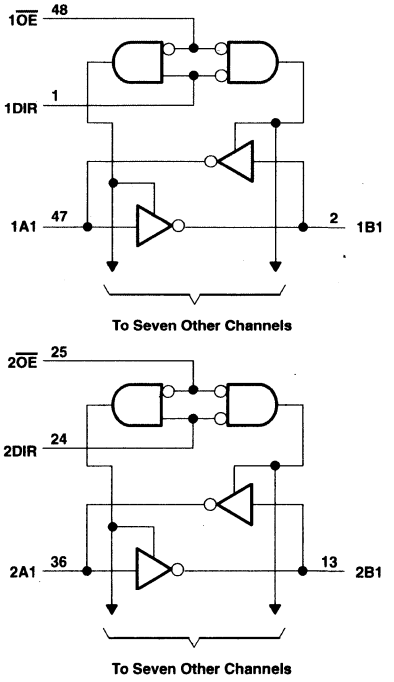
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum power dissipation at T_A = 55°C (in still air) ..... 0.85 W
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			V
		V_{CC} = 4.5 V	3.15			
		V_{CC} = 5.5 V	3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9	V
		V_{CC} = 4.5 V			1.35	
		V_{CC} = 5.5 V			1.65	
V_I	Input voltage		0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			−4	mA
		V_{CC} = 4.5 V			−24	
		V_{CC} = 5.5 V			−24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12	mA
		V_{CC} = 4.5 V			24	
		V_{CC} = 5.5 V			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	ns/V
T_A	Operating free-air temperature		−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = −50 μA	3 V	2.9			2.9		V
			4.5 V	4.4			4.4		
			5.5 V	5.4			5.4		
		I_{OH} = −4 mA	3 V	2.58			2.48		
		I_{OH} = −24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 μA	3 V			0.1		0.1	V
			4.5 V			0.1		0.1	
			5.5 V			0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	V_I = V_{CC} or GND	5.5 V			±0.1		±1	μA
I_{OZ}‡	A or B ports	V_O = V_{CC} or GND	5.5 V			±0.5		±5	μA
I_{CC}		V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80	μA
C_i	Control inputs	V_I = V_{CC} or GND	5 V		4.5				pF
C_{io}	A or B ports	V_O = V_{CC} or GND	5 V		16				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	2.2	6.9	9.1	2.2	10	ns
t_{PHL}			3	8.5	11	3	11.9	
t_{PZH}	$\overline{OE}$	A or B	3	8.2	11	3	12.3	ns
t_{PZL}			3.9	10.9	14	3.9	15.5	
t_{PHZ}	$\overline{OE}$	A or B	5.1	8.3	10.6	5.1	11.2	ns
t_{PLZ}			4.3	7.8	10.1	4.3	10.6	

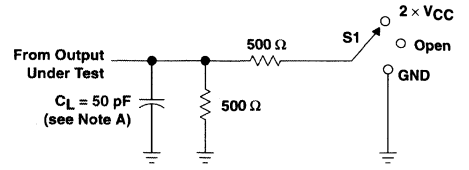
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1.8	4.7		1.8	7.3	ns
t_{PHL}			2.6	5.7		2.6	8.6	
t_{PZH}	$\overline{OE}$	A or B	2.4	5.6		2.4	8	ns
t_{PZL}			3	6.6		3	9.9	
t_{PHZ}	$\overline{OE}$	A or B	5	7.5		5	9.9	ns
t_{PLZ}			4.1	6.5		4.1	9	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

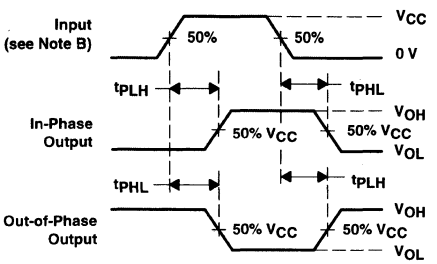
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	55	pF
		Outputs disabled		8	

PARAMETER MEASUREMENT INFORMATION

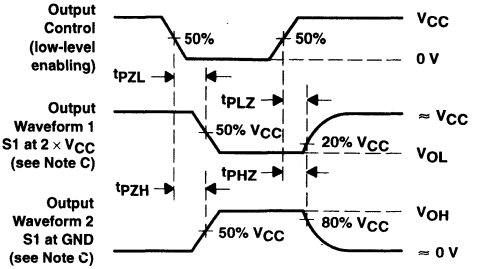


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × VCC
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



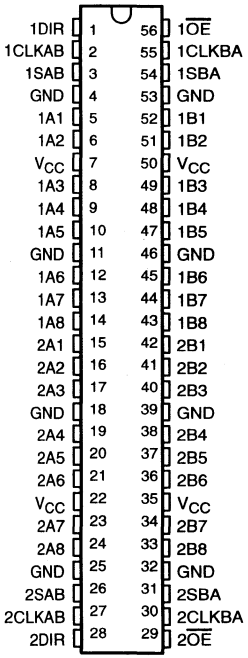
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Packaged in Shrink Small-Outline 300-mil Packages (SSOP) and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings**
- **Independent Registers for A and B Buses**
- **Multiplexed Real-Time and Stored Data**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

54ACT16646 . . . WD PACKAGE
74ACT16646 . . . DL PACKAGE
(TOP VIEW)



description

The 'AC16646 is a 16-bit bus transceiver, which consists of D-type flip-flops and control circuitry with 3-state outputs arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The device can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock input (CLKAB or CLKBA). Figure 1 illustrates the four fundamental bus-management functions that can be performed with the octal bus transceivers and registers.

Output enable ($\overline{OE}$) and direction (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select controls (SAB and SBA) can multiplex stored and real-time (transparent mode) data. The circuitry used for select control will eliminate the typical decoding glitch which occurs in a multiplexer during the transition between stored and real-time data. The direction control determines which bus receives data when $\overline{OE}$ is active (low). In the isolation mode ($\overline{OE}$ high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

The 74AC16646 is packaged in the TI shrink small-outline package (SSOP), which provides twice the functionality of standard small-outline packages in the same PCB area.

The 54AC16646 is characterized for operation over the full military temperature range of −55°C to 125°C. The 74AC16646 is characterized for operation from −40°C to 85°C.

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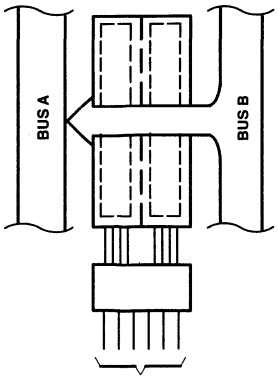
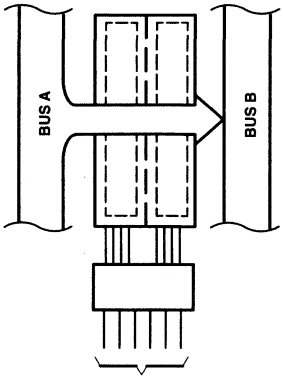


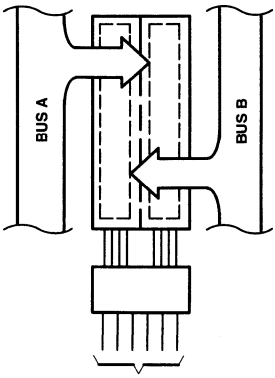
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER BUS B TO BUS A



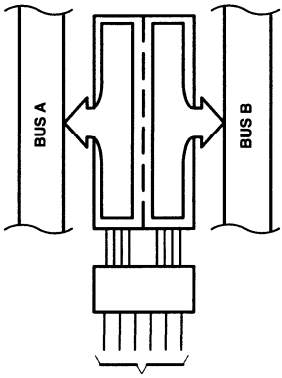
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
L	H	X	X	L	X

REAL-TIME TRANSFER BUS A TO BUS B



$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
X	X	↑	X	X	X
X	X	X	↑	X	X
H	X	↑	↑	X	X

STORAGE FROM A, B OR A AND B



$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
L	L	X	H or L	X	H
L	H	H or L	X	H	X

TRANSFER STORED DATA TO A OR B

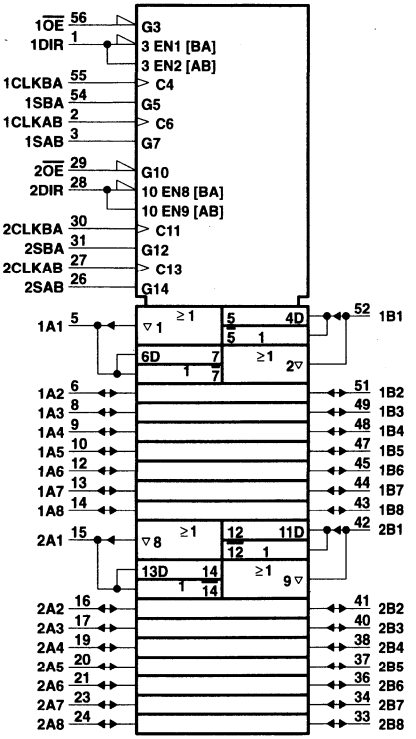
Figure 1. Bus-Management Functions

FUNCTION TABLE

INPUTS						DATA I/O†		OPERATION OR FUNCTION
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	
X	X	↑	X	X	X	Input	Unspecified	Store A, B unspecified†
X	X	X	↑	X	X	Unspecified	Input	Store B, A unspecified†
H	X	↑	↑	X	X	Input	Input	Store A and B Data
H	X	H or L	H or L	X	X	Input	Input	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-Time B Data to A Bus
L	L	X	H or L	X	H	Output	Input	Stored B Data to A Bus
L	H	X	X	L	X	Input	Output	Real-Time A Data to B Bus
L	H	H or L	X	H	X	Input	Output	Stored A Data to B Bus

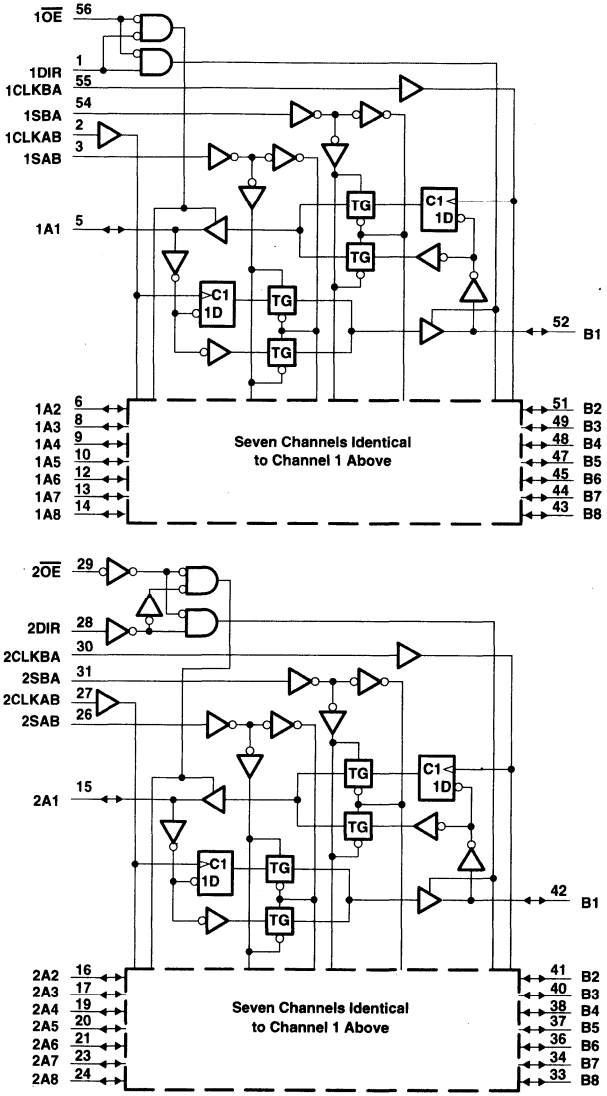
† The data output functions may be enabled or disabled by various signals at the $\overline{OE}$ or DIR inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... – 0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... – 0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... – 0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Storage temperature range ..... – 65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

			54AC16646			74AC16646			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage (see Note 2)		3	5	5.5	3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			2.1			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 5.5 V	3.85			3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9			0.9	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 5.5 V			1.65			1.65	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4			–4	mA
		V_{CC} = 4.5 V			–24			–24	
		V_{CC} = 5.5 V			–24			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12			12	mA
		V_{CC} = 4.5 V			24			24	
		V_{CC} = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTE 2: All V_{CC} and GND pins must be connected to the proper voltage power supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54AC16646		74AC16646		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 µA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = −4 mA	3 V	2.58			2.4		2.48		
		4.5 V	3.94			3.7		3.8		
		5.5 V	4.94			4.7		4.8		
	I_{OH} = −50 mA†	5.5 V				3.85				
	I_{OH} = −75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
		4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}	$V_I = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		160		80	µA
C_i	$V_I = V_{CC}$ or GND	5 V		4.5						pF
C_o	$V_I = V_{CC}$ or GND	5 V		16						

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 2)

		T_A = 25°C		54AC16646		74AC16646		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	65	0	65	0	65	MHz
t_w	Pulse duration, CLKAB or CLKBA high or low	7		7		7		ns
t_{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	6.5		6.5		6.5		ns
t_h	Hold time, A after CLKAB↑ or B after CLKBA↑	1		1		1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 2)

		T_A = 25°C		54AC16646		74AC16646		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	75	0	75	0	75	MHz
t_w	Pulse duration, CLKAB or CLkBA high or low	6.5		6.5		6.5		ns
t_{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	5		5		5		ns
t_h	Hold time, A after CLKAB↑ or B after CLKBA↑	1		1		1		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16646		74AC16646		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			65			65		65		MHz
t_{PLH}	A or B	B or A	3.4	9.3	13.2	3.4	15.7	3.4	14.8	ns
t_{PHL}			3.6	10	13.4	3.6	15.1	3.6	4.5	
t_{PZH}	$\overline{OE}$	A or B	3.8	10.5		3.8	17.6	3.8	16.4	ns
t_{PZL}			4.8	13.9		4.8	22.1	4.8	20.9	
t_{PHZ}	$\overline{OE}$	A or B	4.4	7.6		4.4	11	4.4	10.7	ns
t_{PLZ}			4	7		4	10.4	4	10.1	
t_{PLH}	CLKBA or CLKAB	A or B	4.7	12.1		4.7	19.9	4.7	18.7	ns
t_{PHL}			4.8	12.2		4.8	18.8	4.8	18	
t_{PLH}	SAB or SBA† (with A or B high)	A or B	4.7	12		4.7	19.9	4.7	18.5	ns
t_{PHL}			4.5	11.4		4.5	17.2	4.5	16.4	
t_{PLH}	SBA or SAB† (with A or B low)	A or B	4	10.5		4	17.3	4	16.3	ns
t_{PHL}			5.2	13.3		5.2	20.3	5.2	19.3	
t_{PZH}	DIR	A or B	3.6	10.3		3.6	17.9	3.6	16.8	ns
t_{PZL}			4.7	13.5		4.7	22.1	4.7	20.8	
t_{PHZ}	DIR	A or B	4.6	7.8		4.6	11.6	4.6	11.2	ns
t_{PLZ}			3.9	7		3.9	11	3.9	10.6	

† These parameters are measured with the internal output state of the storage register opposite to that of the bus input.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 2)

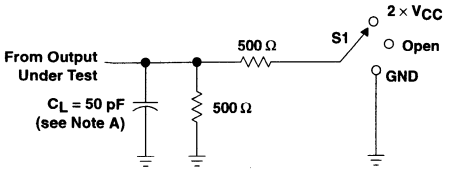
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16646		74AC16646		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			75			75		75		MHz
t_{PLH}	A or B	B or A	2.9	5.5	8.5	2.9	10.1	2.9	9.5	ns
t_{PHL}			2.9	5.7	8.9	2.9	10.1	2.9	9.7	
t_{PZH}	$\overline{OE}$	A or B	3.1	6.1	9.4	3.1	11.1	3.1	10.5	ns
t_{PZL}			4.1	7.3	11	4.1	12.9	4.1	12.2	
t_{PHZ}	$\overline{OE}$	A or B	4	6.1	8.4	4	9.1	4	8.9	ns
t_{PLZ}			3.8	5.7	8	3.8	8.9	3.8	8.6	
t_{PLH}	CLKBA or CLKAB	A or B	3.9	7	10.8	3.9	12.8	3.9	12.1	ns
t_{PHL}			3.9	7.1	10.8	3.9	12.5	3.9	11.9	
t_{PLH}	SAB or SBA† (with A or B high)	A or B	4	7.4	11.1	4	13.4	4	12.5	ns
t_{PHL}			3.6	6.7	10.2	3.6	11.8	3.6	11.2	
t_{PLH}	SBA or SAB† (with A or B low)	A or B	3.3	6.1	9.5	3.3	11.2	3.3	10.6	ns
t_{PHL}			4.3	8	11.7	4.3	13.9	4.3	13.1	
t_{PZH}	DIR	A or B	3	5.9	9.6	3	11.6	3	10.9	ns
t_{PZL}			3.6	7	11.1	3.6	12.9	3.6	12.2	
t_{PHZ}	DIR	A or B	4	6.2	8.8	4	9.6	3	9.4	ns
t_{PLZ}			3.7	5.7	8.2	3.7	9	3.7	8.8	

† These parameters are measured with the internal output state of the storage register opposite to that of the bus input.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

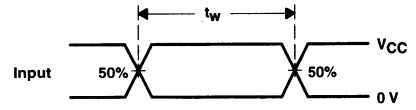
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per latch	Outputs enabled	C_L = 50 pF, f = 1 MHz	62	pF
		Outputs disabled		14	

PARAMETER MEASUREMENT INFORMATION

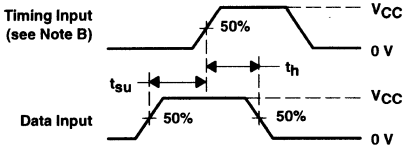


LOAD CIRCUIT

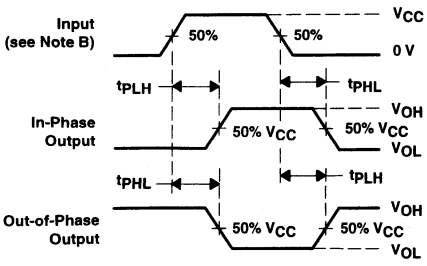
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



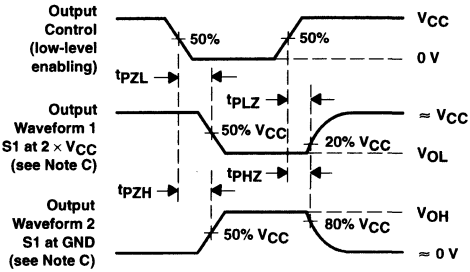
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



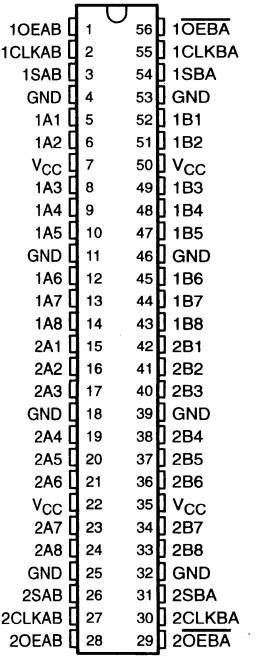
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings**
- **Independent Registers and Enables for A and B Buses**
- **Multiplexed Real-Time and Stored Data**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

54AC16652 . . . WD PACKAGE
74AC16652 . . . DL PACKAGE
(TOP VIEW)



description

The 'AC16652 is a 16-bit bus transceiver that consists of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The device can be used as two 8-bit transceivers or one 16-bit transceiver.

Complementary output-enable (OEAB and $\overline{\text{OEBA}}$) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'AC16652.

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the levels on the select-control or output-enable inputs. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and $\overline{\text{OEBA}}$. In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus line are at high impedance, each set of bus lines remains at its last state.

The 74AC16652 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16652 is characterized for operation over the full military temperature range of −55°C to 125°C. The 74AC16652 is characterized for operation from −40°C to 85°C.

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FUNCTION TABLE

INPUTS						DATA I/O†		OPERATION OR FUNCTION
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	
L	H	L	L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	L	X	X	Input	Unspecified‡	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	L	↑	X	X	Unspecified‡	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	L	X	H	X	Input	Output	Stored A data to B bus
H	L	L	L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

† The data output functions may be enabled or disabled by a variety of level combinations at the OEAB or $\overline{OEBA}$ inputs. Data input functions are always enabled; i.e., data at the bus pins is stored on every low-to-high transition on the clock inputs.

‡ Select control = L; clocks can occur simultaneously.
Select control = H; clocks must be staggered in order to load both registers.

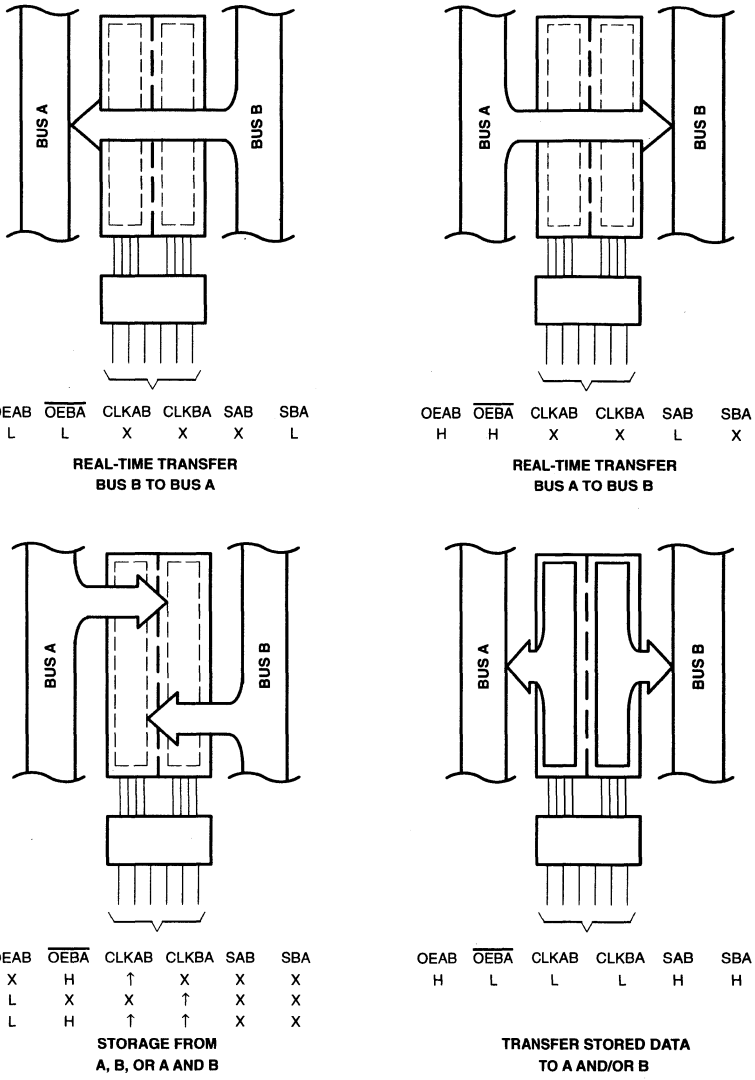
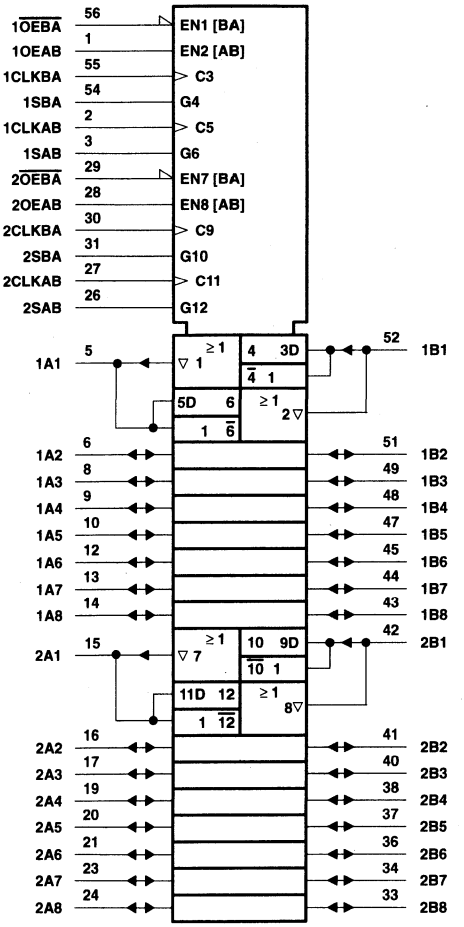


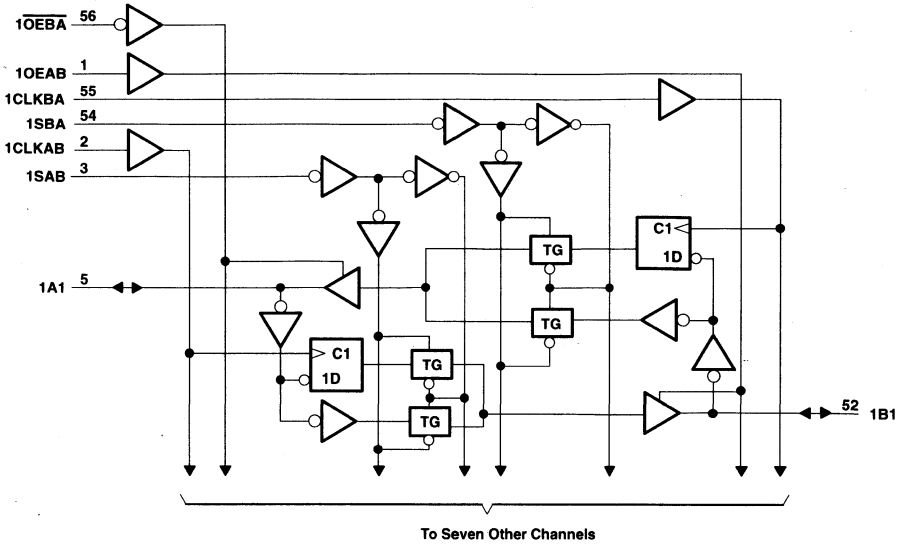
Figure 1. Bus-Management Functions

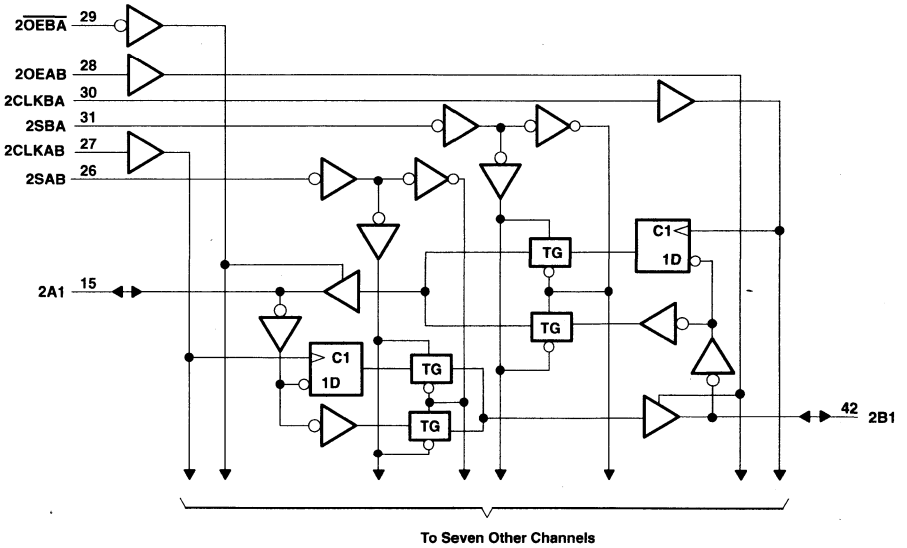
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagrams (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum package power dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			54AC16652			74AC16652			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage (see Note 2)		3	5	5.5	3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			2.1			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 5.5 V	3.85			3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9			0.9	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 5.5 V			1.65			1.65	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			−4			−4	mA
		V_{CC} = 4.5 V			−24			−24	
		V_{CC} = 5.5 V			−24			−24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12			12	mA
		V_{CC} = 4.5 V			24			24	
		V_{CC} = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
T_A	Operating free-air temperature		−55		125	−40		85	°C

NOTE 2: All V_{CC} and GND pins must be connected to the proper voltage power supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54AC16652		74AC16652		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = −50 μA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = −4 mA	3 V	2.58			2.4		2.48		
		I_{OH} = − 24 mA	4.5 V	3.94			3.7		3.8		
			5.5 V	4.94			4.7		4.8		
		I_{OH} = −50 mA†	5.5 V				3.85				
		I_{OH} = −75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 μA	3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA
I_{OZ}	A or B ports‡	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	μA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		160		80	μA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4						pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 2)

		T_A = 25°C		54AC16652		74AC16652		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	55	0	55	0	55	MHz
t_w	Pulse duration, CLKAB or CLKBA high or low	9		9		9		ns
t_{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	7		7		7		ns
t_h	Hold time, A after CLKAB↑ or B after CLKBA↑	0		0		0		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 2)

		T_A = 25°C		54AC16652		74AC16652		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	95	0	95	0	95	MHz
t_w	Pulse duration, CLKAB or CLKBA high or low	5		5		5		ns
t_{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5		4.5		4.5		ns
t_h	Hold time, A after CLKAB↑ or B after CLKBA↑	0		0		0		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16652		74AC16652		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			55			55		55		MHz
t_{PLH}	A or B	B or A	3.6	10.4	13.7	3.6	17.1	3.6	15.6	ns
t_{PHL}			4.1	10.9	14.3	4.1	16.3	4.1	15.4	
t_{PLH}	CLKBA or CLKAB	A or B	5.1	13.6	17.3	5.1	21.2	5.1	19.5	ns
t_{PHL}			5.4	13.5	17.2	5.4	19.9	5.4	18.8	
t_{PLH}	SBA or SAB (with A or B high)	A or B	5.8	15.0	18.7	5.8	23.3	5.8	21.4	ns
t_{PHL}			5.4	13.1	16.7	5.4	19.1	5.4	18.1	
t_{PLH}	SBA or SAB (with A or B low)	A or B	4.2	11.8	15.2	4.2	18.9	4.2	17.4	ns
t_{PHL}			5.9	14.4	18.3	5.9	21.7	5.9	20.3	
t_{PZH}	$\overline{OEBA}$	A	4.2	11.8	15.1	4.2	18.8	4.2	17.2	ns
t_{PZL}			6	16.2	20.6	6	25.3	6	23.5	
t_{PHZ}	$\overline{OEBA}$	A	4.6	8.1	10	4.6	10.9	4.6	10.6	ns
t_{PLZ}			4.4	7.6	9.6	4.4	10.6	4.4	10.3	
t_{PZH}	OEAB	B	4.1	11.5	14.6	4.1	18.1	4.1	16.6	ns
t_{PZL}			6	16.0	20	6	24.6	6	22.7	
t_{PHZ}	OEAB	B	4.3	7.2	9	4.3	9.7	4.3	9.5	ns
t_{PLZ}			3.9	6.7	8.6	3.9	9.2	3.9	9.1	

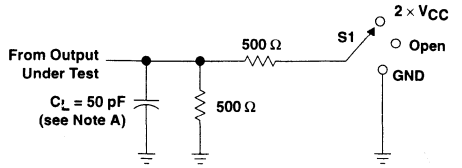
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16652		74AC16652		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			95			95		95		MHz
t_{PLH}	A or B	B or A	2.7	6.1	8.8	2.7	10.7	2.7	9.9	ns
t_{PHL}			3	6.3	9.2	3	10.8	3	10.2	
t_{PLH}	CLKBA or CLKAB	A or B	3.9	7.8	10.9	3.9	13.3	3.9	12.2	ns
t_{PHL}			4.2	7.8	11.1	4.2	13.2	4.2	12.3	
t_{PLH}	SBA or SAB (with A or B high)	A or B	4.5	8.8	12.1	4.5	15	4.5	13.8	ns
t_{PHL}			4.1	7.7	11	4.1	12.9	4.1	12.1	
t_{PLH}	SBA or SAB (with A or B low)	A or B	3.1	6.7	9.7	3.1	11.9	3.1	11	ns
t_{PHL}			4.6	8.8	12.2	4.6	14.9	4.6	13.8	
t_{PZH}	$\overline{OEBA}$	A	3.1	6.7	9.5	3.1	11.6	3.1	10.7	ns
t_{PZL}			4.5	8.3	11.8	4.5	14.4	4.5	13.2	
t_{PHZ}	$\overline{OEBA}$	A	4.6	6.5	8.3	4.6	9	4.6	8.8	ns
t_{PLZ}			4.1	6.1	8.1	4.1	9.1	4.1	8.7	
t_{PZH}	OEAB	B	3.1	6.6	9.3	3.1	11.3	3.1	10.5	ns
t_{PZL}			4.6	8.2	11.6	4.6	14.1	4.6	13	
t_{PHZ}	OEAB	B	4.2	5.9	7.7	4.2	8.3	4.2	8	ns
t_{PLZ}			3.7	5.5	7.4	3.7	8.3	3.7	7.8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

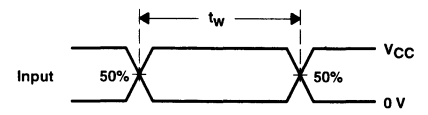
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	57	pF
		Outputs disabled		13	

PARAMETER MEASUREMENT INFORMATION

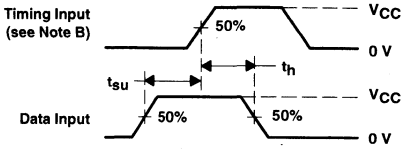


LOAD CIRCUIT

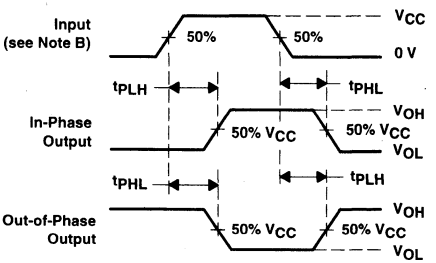
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × VCC
t_{PHZ}/t_{PZH}	GND



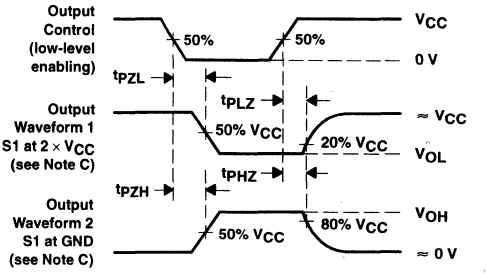
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



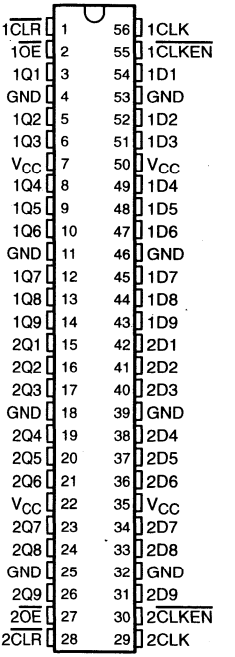
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Provides Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Pin Spacings**

54AC16823 . . . WD PACKAGE
74AC16823 . . . DL PACKAGE
(TOP VIEW)



description

These 18-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, parity bus interfacing, and working registers.

The 'AC16823 can be used as two 9-bit flip-flops or one 18-bit flip-flop. With the clock-enable ($\overline{CLKEN}$) input low, the D-type flip-flops enter data on the low-to-high transitions of the clock. Taking $\overline{CLKEN}$ high disables the clock buffer, thus latching the outputs. Taking the clear ($\overline{CLR}$) input low causes the Q outputs to go low independently of the clock.

The output enable ($\overline{OE}$) input can be used to place the outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

$\overline{OE}$ does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74AC16823 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16374 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16823 is characterized for operation from –40°C to 85°C.

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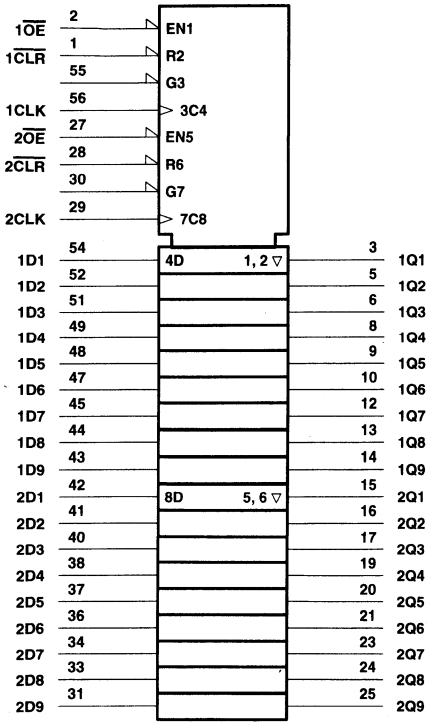
FUNCTION TABLE
(each 9-bit stage)

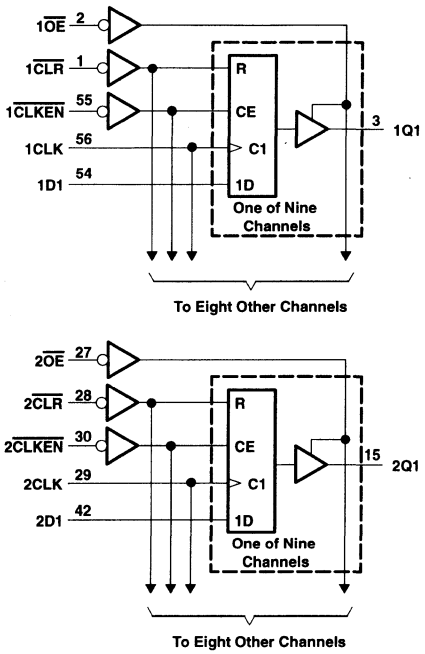
INPUTS					OUTPUT
$\overline{OE}$	$\overline{CLR}$	$\overline{CLKEN}$	CLK	D	Q
L	L	X	X	X	L
L	H	L	↑	H	H
L	H	L	↑	L	L
L	H	L	L	X	Q_0
L	H	H	X	X	Q_0
H	X	X	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±450 mA
Maximum power package dissipation at T_A = 55°C (in still air)(see Note 2): DL package ..... 1.4 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

			54AC16823			74AC16823			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		3	5	5.5	3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			2.1			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 5.5 V	3.85			3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9			0.9	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 5.5 V			1.65			1.65	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4			–4	mA
		V_{CC} = 4.5 V			–24			–24	
		V_{CC} = 5.5 V			–24			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12			12	mA
		V_{CC} = 4.5 V			24			24	
		V_{CC} = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	TA = 25°C			54AC16823		74AC16823		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = –4 mA	3 V	2.58			2.48		2.48		
	I_{OL} = –24 mA	4.5 V	3.94			3.8		3.8		
		5.5 V	4.94			4.8		4.8		
	I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}	I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.44		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.44		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80		80	µA
C_i	$V_I = V_{CC}$ or GND	5 V		3						pF
C_o	$V_O = V_{CC}$ or GND	5 V		11						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		54AC16823		74AC16823		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	60	0	60	0	60	MHz
t_w	Pulse duration	$\overline{CLR}$ low	3.3		3.3		3.3		ns
		CLK high or low	8.4		8.4		8.4		
t_{su}	Setup time before CLK↑	$\overline{CLR}$ inactive	0.5		0.5		0.5		ns
		Data	7.2		7.2		7.2		
		$\overline{CLKEN}$ low	5.8		5.8		5.8		
t_h	Hold time after CLK↑	Data	0		0		0		ns
		$\overline{CLKEN}$ high or low	1		1		1		

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		54AC16823		74AC16823		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	115	0	115	0	115	MHz
t_w	Pulse duration	$\overline{CLR}$ low	3.3		3.3		3.3		ns
		CLK high or low	4.4		4.4		4.4		
t_{su}	Setup time before CLK↑	$\overline{CLR}$ inactive	0.6		0.6		0.6		ns
		Data	5		5		5		
		$\overline{CLKEN}$ low	4.2		4.2		4.2		
t_h	Hold time after CLK↑	Data	1.3		1.3		1.3		ns
		$\overline{CLKEN}$ high or low	1.4		1.4		1.4		

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16823		74AC16823		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			60			60		60		MHz
t_{PLH}	CLK	Q	3.9	13.8	16.8	3.9	18.8	3.9	18.8	ns
t_{PHL}			4.7	14.5	17.3	4.7	18.9	4.7	18.9	
t_{PHL}	$\overline{CLR}$	Q	4	12.4	14.9	4	16.2	4	16.2	ns
t_{PZH}	$\overline{OE}$	Q	3	11.1	14	3	15.4	3	15.4	ns
t_{PZL}			4.3	15	18.7	4.3	20.8	4.3	20.8	
t_{PHZ}	$\overline{OE}$	Q	4.5	8.5	10.4	4.5	11.2	4.5	11.2	ns
t_{PLZ}			3.9	7.7	9.3	3.9	10.3	3.9	10.3	

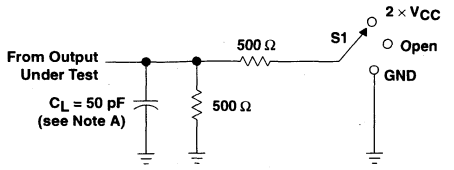
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16823		74AC16823		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			115			115		115		MHz
t_{PLH}	CLK	Q	3.1	7.8	10.6	3.1	12	3.1	12	ns
t_{PHL}			3.9	8.6	11.4	3.9	12.7	3.9	12.7	
t_{PHL}	$\overline{CLR}$	Q	3.2	7.4	9.9	3.2	11	3.2	11	ns
t_{PZH}	$\overline{OE}$	Q	2.2	6.1	8.6	2.2	9.7	2.2	9.7	ns
t_{PZL}			3	7.4	10.6	3	11.8	3	11.8	
t_{PHZ}	$\overline{OE}$	Q	4.2	6.8	8.7	4.2	9.3	4.2	9.3	ns
t_{PLZ}			3.7	6.2	7.8	3.7	8.6	3.7	8.6	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

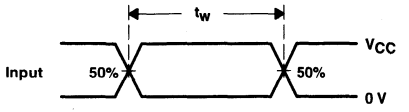
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per flip-flop	Outputs enabled	C_L = 50 pF, f = 1 MHz	36	pF
		Outputs disabled		18	

PARAMETER MEASUREMENT INFORMATION

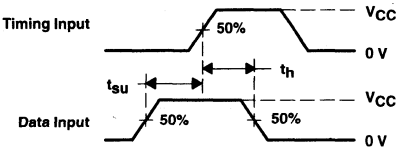


LOAD CIRCUIT

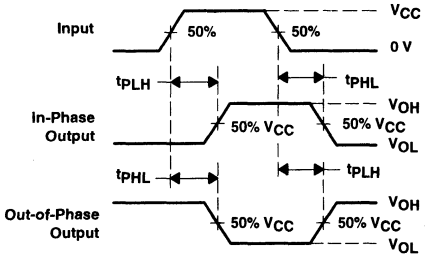
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × VCC
t_{PHZ}/t_{PZH}	GND



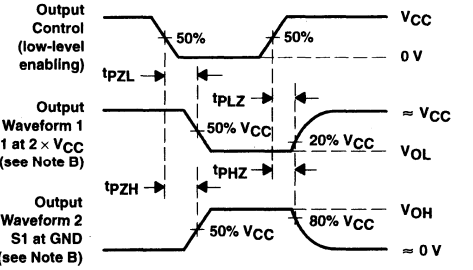
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

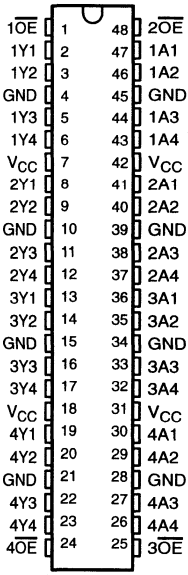
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

5 ACT Widebus™

- **Members of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines or Buffer Memory Address Registers**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

54ACT16240 . . . WD PACKAGE
74ACT16240 . . . DL PACKAGE
(TOP VIEW)



description

The 'ACT16240 is a 16-bit buffer or line driver designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. This device provides inverting outputs and symmetrical active-low output-enable ($\overline{OE}$) inputs.

The 74ACT16240 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

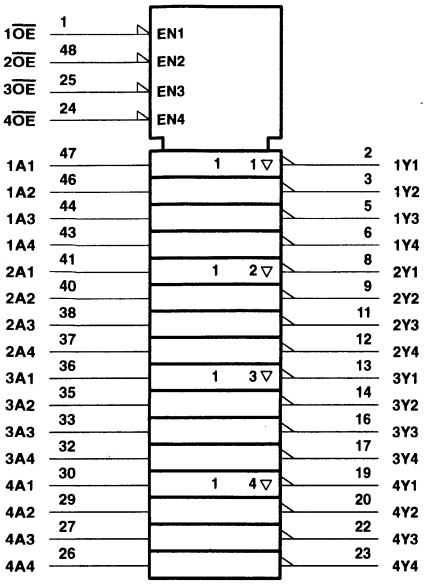
The 54ACT16240 is characterized for operation over the full military temperature range of −55°C to 125°C. The 74ACT16240 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each section)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z

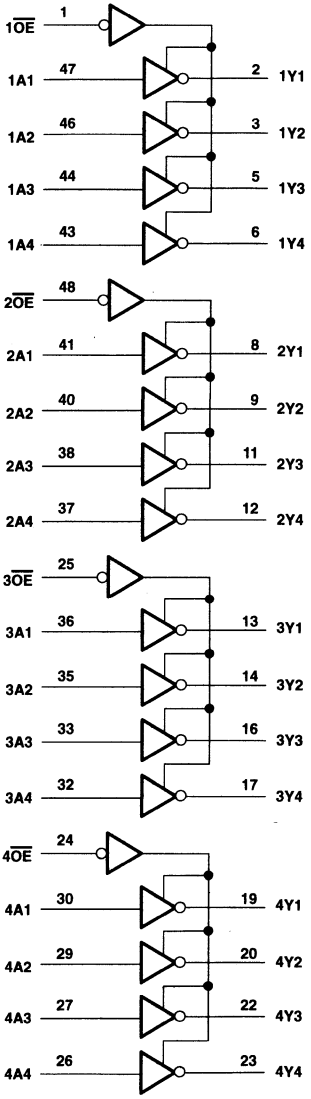
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



TEXAS INSTRUMENTS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum package power dissipation at $T_A = 55°C$ (in still air) ..... 0.85 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		54ACT16240			74ACT16240			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current			−24			−24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
T_A	Operating free-air temperature	−55		125	−40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16240		74ACT16240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA	4.5 V	4.4			4.4		4.4		V
		5.5 V	5.4			5.4		5.4		
	I_{OH} = −24 mA	4.5 V	3.94			3.7		3.8		
		5.5 V	4.94			4.7		4.8		
	I_{OH} = −50 mA†	5.5 V				3.85				
	I_{OH} = −75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.5		±10		±5	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			8		160		80	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at VCC or GND	5.5 V			0.9		1		1	mA
C_i	V_I = V_{CC} or GND	5.5 V		4.5						pF
C_o	V_O = V_{CC} or GND	5 V		12						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

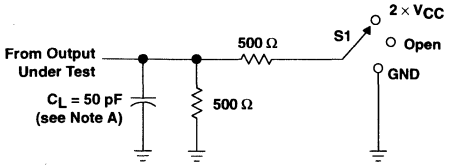
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ±0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16240		74ACT16240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	2.3	5	7.7	2	9.5	2.3	8.5	ns
t_{PHL}			4.1	6.7	9.2	3	11.5	4.1	10.2	
t_{PZH}	$\overline{OE}$	Y	2.6	5.6	8.5	2	10.1	2.6	9.4	ns
t_{PZL}			3.3	6.7	10.2	2.5	12.2	3.3	11.4	
t_{PHZ}	$\overline{OE}$	Y	5.9	8.3	11	4.5	12.7	5.9	12	ns
t_{PLZ}			5.1	7.4	9.9	4	12	5.1	10.7	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

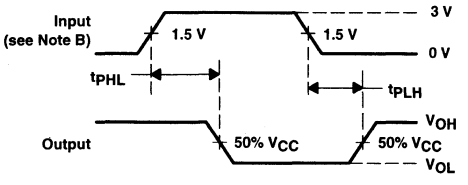
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per driver	Outputs enabled	C_L = 50 pF, f = 1 MHz	38	pF
		Outputs disabled		9	

PARAMETER MEASUREMENT INFORMATION

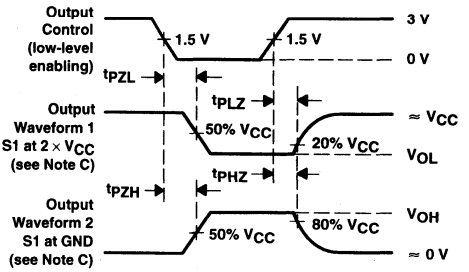


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

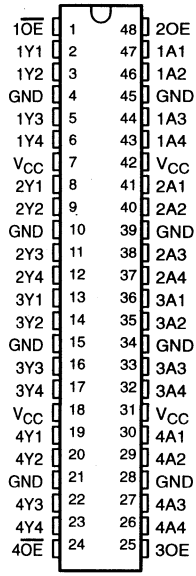
NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

SCAS189 – D3465, MARCH 1990 – REVISED APRIL 1993

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines or Buffer Memory Address Registers**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16241 is a 16-bit buffer or line driver designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. This device provides true outputs and complementary output-enable (OE and $\overline{OE}$) inputs.

The 74ACT16241 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16241 is characterized for operation from −40°C to 85°C.

FUNCTION TABLES

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

INPUTS		OUTPUT
OE	A	Y
H	H	H
H	L	L
L	X	Z

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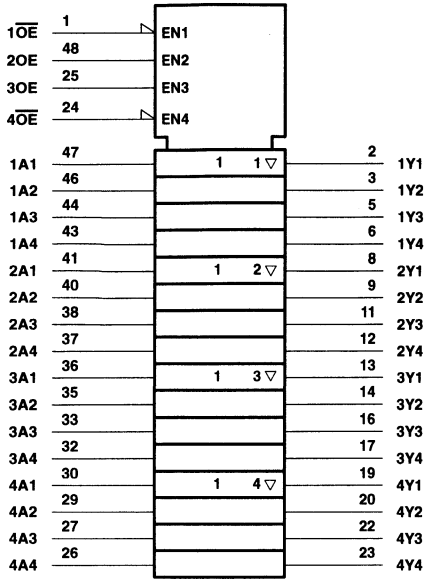
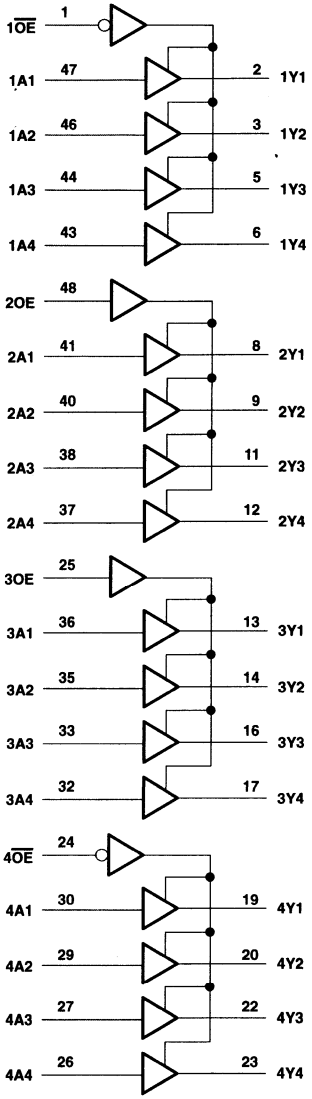
logic symbol†



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum package power dissipation at T_A = 55°C (in still air) ..... 0.85 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note NO TAG)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	I_{OH} = −50 μA	4.5 V	4.4			4.4		V
		5.5 V	5.4			5.4		
	I_{OH} = −24 mA	4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1	V
		5.5 V			0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	$V_I = V_{CC}$ or GND	5 V		4.5				pF
C_o	$V_O = V_{CC}$ or GND	5 V		13				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

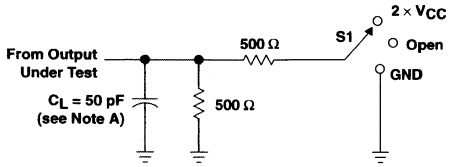
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	Y	3.3	6.5	8.4	3.3	9.5	ns
t_{PHL}			2.3	6.3	8.2	2.3	9.1	
t_{PZH}	$\overline{OE}$ or OE	Y	2.3	6.5	8.3	2.3	9.4	ns
t_{PZL}			2.9	7.3	9.3	2.9	10.5	
t_{PHZ}	$\overline{OE}$ or OE	Y	4.3	8.9	10.6	4.3	11.6	ns
t_{PLZ}			4	8.1	9.8	4	10.7	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

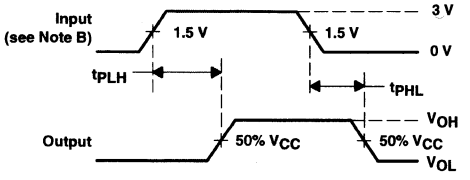
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	C_L = 50 pF, f = 1 MHz	43	pF
		Outputs disabled		10	

PARAMETER MEASUREMENT INFORMATION

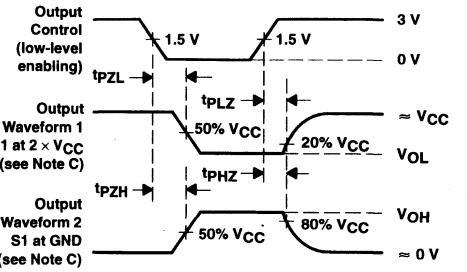


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT



VOLTAGE WAVEFORMS



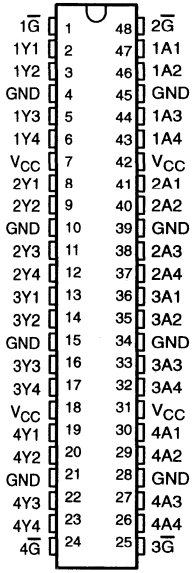
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Shrink Small-Outline 300-mil Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines or Buffer Memory Address Registers**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Packaged in Plastic Shrink and Plastic Thin Shrink Small-Outline Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings**

54ACT16244 . . . WD PACKAGE
74ACT16244 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ACT16244 is a 16-bit buffer or line driver designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. This device provides true outputs and symmetrical $\overline{G}$ (active-low) output-enable inputs.

The 'ACT16244 is packaged in the TI's shrink small-outline package (SSOP), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16244 is characterized for operation over the full military temperature range of – 55°C to 125°C. The 74ACT16244 is characterized for operation from – 40°C to 85°C.

FUNCTION TABLE
(each driver)

INPUTS		OUTPUT
$\overline{G}$	A	Y
L	H	H
L	L	L
H	X	Z

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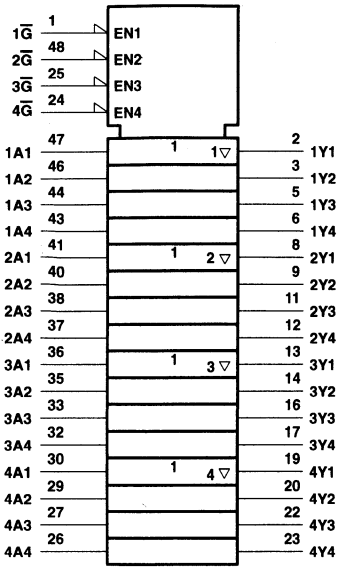
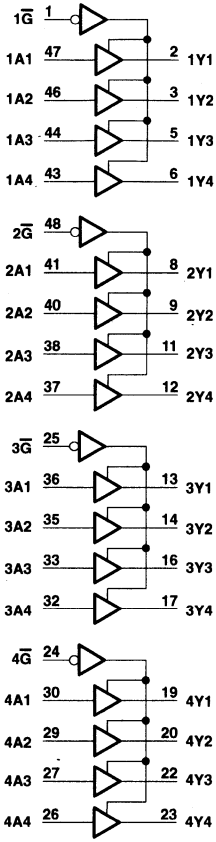
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... – 0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... – 0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... – 0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Storage temperature range ..... – 65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions (see Note 2)

		54ACT16244		74ACT16244		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage (see Note 3)	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	0	10	ns/V
T_A	Operating free-air temperature	–55	125	– 40	85	°C

NOTES: 2. Unused or floating inputs should be tied to V_{CC} through a pullup resistor of approximately 5 kΩ or greater.
3. All V_{CC} and GND pins must be connected to the proper voltage supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16244		74ACT16244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 μA	4.5 V	4.4			4.4		4.4		V
		5.5 V	5.4			5.4		5.4		
	I_{OH} = – 24 mA	4.5 V	3.94			3.7		3.8		
		5.5 V	4.94			4.7		4.8		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		160		80	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.9		1		1	mA
C_i	$V_I = V_{CC}$ or GND	5 V		4.5						pF
C_o	$V_O = V_{CC}$ or GND	5 V		13.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

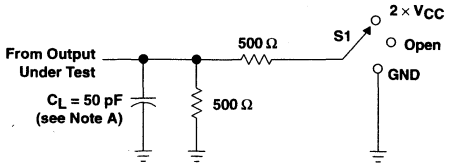
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16244		74ACT16244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	4	6.5	8.5	4	10.3	4	9.4	ns
t_{PHL}			3.4	6.3	8.7	3.4	10.1	3.4	9.5	
t_{PZH}	$\overline{G}$	Y	3	5.8	8.1	3	9.5	3	8.9	ns
t_{PZL}			3.7	6.7	9.3	3.7	11	3.7	10.3	
t_{PHZ}	$\overline{G}$	Y	5.4	8.1	10.3	5.4	12	5.4	11.3	ns
t_{PLZ}			5	7.5	9.5	5	10.9	5	10.3	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

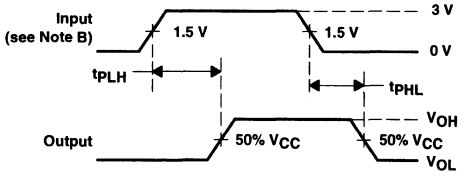
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per latch	Outputs enabled	C_L = 50 pF, f = 1 MHz	39	pF
		Outputs disabled		11	

PARAMETER MEASUREMENT INFORMATION

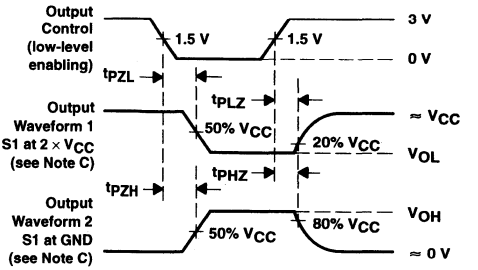


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

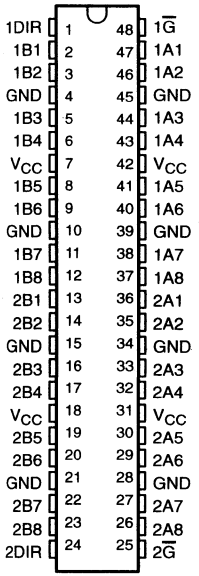
NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

SCAS097A – D3402, DECEMBER 1989 – REVISED APRIL 1993

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Shrink Small-Outline 300-mil Package and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture to Optimize PCB Layout**
- **Distributed V_{CC} and GND Configuration to Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Packaged in Plastic Shrink and Plastic Thin Shrink Small-Outline Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings**

54ACT16245 . . . WD PACKAGE
74ACT16245 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ACT16245 is a 16-bit bus transceiver organized as a dual-octal noninverting 3-state transceiver and is designed for asynchronous two-way communication between data buses. The control function implementation minimizes external timing requirements

The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction control (DIR) input. The enable input ($\overline{G}$) can be used to disable the devices so that the buses are effectively isolated.

The 54ACT16245 is characterized over the full military temperature range of – 55°C to 125°C. The 74ACT16245 is characterized for operation from – 40°C to 85°C.

FUNCTION TABLE

CONTROL INPUTS		OPERATION
$\overline{G}$	DIR	
L	L	B data to A Bus
L	H	A data to B Bus
H	X	Isolation

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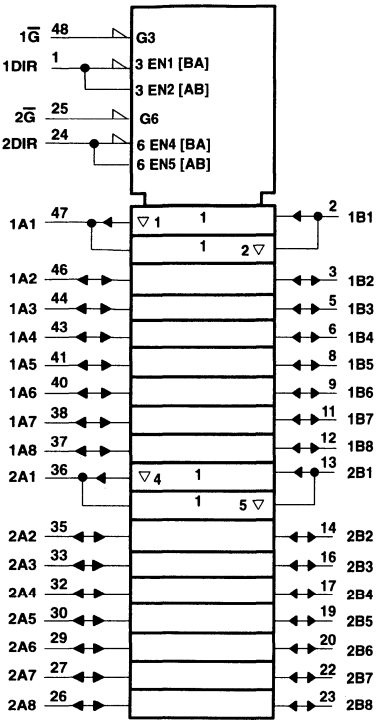
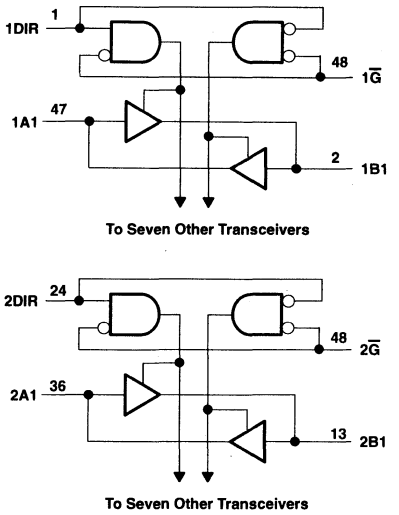
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} ..... – 0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... – 0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... – 0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ± 50 mA
Continuous current through V_{CC} or GND ..... ± 400 mA
Storage temperature range ..... – 65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions (see Note 2)

		54ACT16245		74ACT16245		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage (see Note 3)	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	0	10	ns/V
T_A	Operating free-air temperature	–55	125	– 40	85	°C

NOTES: 2. Unused or floating inputs should be tied to V_{CC} through a pullup resistor of approximately 5 kΩ or greater.
3. All V_{CC} and GND pins must be connected to the proper voltage power supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16245		74ACT16245		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = – 50 μA	4.5 V	4.4			4.4		4.4		V
			5.5 V	5.4			5.4		5.4		
		I_{OH} = – 24 mA	4.5 V	3.94			3.94		3.8		
			5.5 V	4.94			4.94		4.8		
		I_{OH} = – 50 mA†	5.5 V				3.85				
		I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		± 1		± 1	μA
I_{OZ}	A or B ports‡	$V_O = V_{CC}$ or GND	5.5 V			± 0.5		± 10		± 5	μA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		160		80	μA
ΔI_{CC}§		One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.9		1		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4.5						pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		16						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current I_I.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

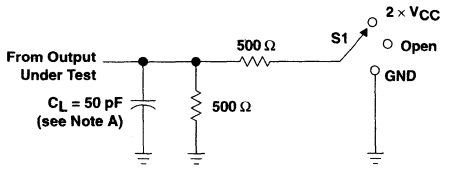
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16245		74ACT16245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	nA or nB	nB or nA	3.2	6.9	9.3	3.2	11.5	3.2	10.5	ns
t_{PHL}			2.6	6.4	9.2	2.6	11.1	2.6	10.2	
t_{PZH}	$n\overline{G}$	nB or nA	2.7	6.4	9.1	2.7	10.9	2.7	10	ns
t_{PZL}			3.4	7.4	10.5	3.4	12.6	3.4	11.6	
t_{PHZ}	$\overline{G}$	nB or nA	5.8	9.2	11.6	5.8	13.4	5.8	12.6	ns
t_{PLZ}			5.5	8.5	10.8	5.5	12.7	5.5	11.8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

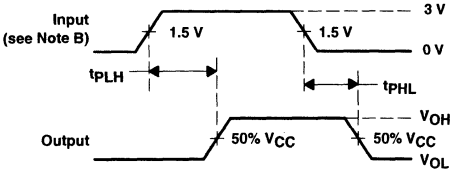
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	52	pF
		Outputs disabled		10	

PARAMETER MEASUREMENT INFORMATION

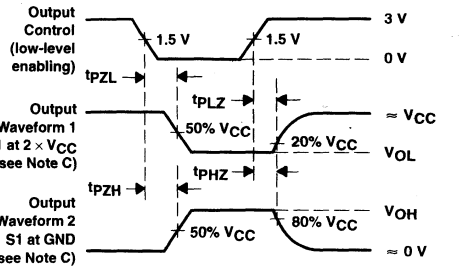


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



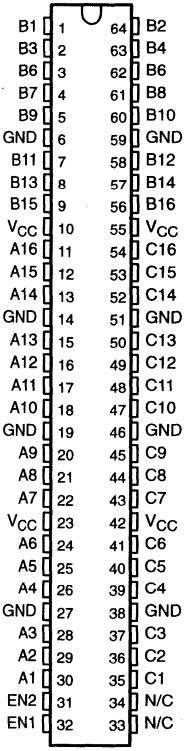
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Bus-Hold Inputs Eliminate the Need for External Pullup Resistors**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Packaged in Plastic Thin Shrink Small-Outline (DGG) Package**

DGG PACKAGE
(TOP VIEW)



description

The 74ACT16254 is a dual 16-bit, noninverting bus-interface device. The A and C ports perform a transceiver function, like that of the 74ACT245. The B and C ports perform the buffer/driver function of the 74ACT244. The A and C port outputs are designed to sink up to 12 mA.

The 74ACT16254 is designed for asynchronous communication between data buses. The control function implementation minimizes external timing requirements.

Data transmission from the A port to the C port, C port to A port, or B port to C port is accomplished by setting the appropriate logic levels on the bus enable (EN1 and EN2) inputs.

All outputs are disabled when logic highs are placed on both EN1 and EN2; the buses are effectively isolated.

The 74ACT16254 is packaged in TI's thin shrink small-outline package (DGG), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

Active bus-hold circuitry is provided to hold unused or floating data and I/O pins at a valid logic level.

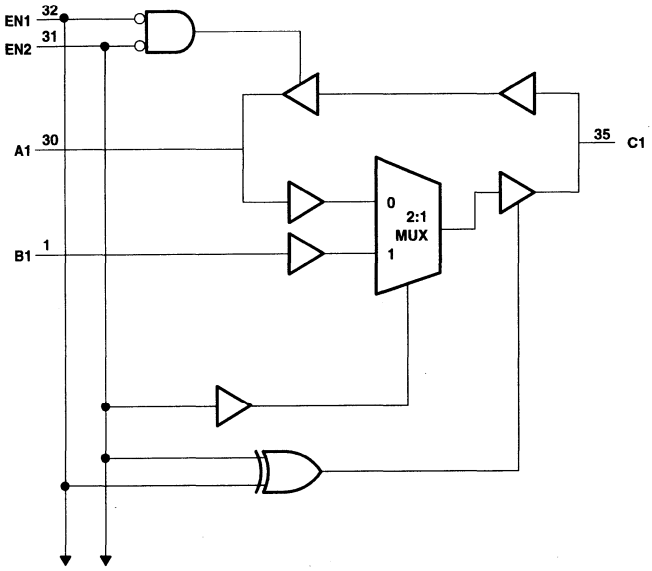
The 74ACT16254 is characterized for operation from –40°C to 85°C.

Widebus is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE

INPUTS		OPERATION
EN2	EN1	
H	H	Isolation
H	L	B data to C bus
L	H	A data to C bus
L	L	C data to A bus

logic diagram, each port (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Current into any output in the low state, I_O ..... 50 mA
Input clamp current, I_{IK} (V_I < 0) ..... −50 mA
Output clamp current, I_{OK} (V_O < 0) ..... −50mA
Continuous current through V_{CC} or GND ..... ±100 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2) ..... 1 W
Storage temperature range, T_{stg} ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	4.5	5.5	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage	0	V_{CC}	V
I_{OH}	High-level output current		−12	mA
I_{OL}	Low-level output current		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10	ns/V
T_A	Operating free-air temperature	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA				−1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = −100 μA		3			V
	V_{CC} = 5.5 V,	I_{OH} = −100 μA		4.2			
	V_{CC} = 4.5 V,	I_{OH} = −12 mA		3			
V_{OL}	V_{CC} = 4.5 V to 5.5 V,	I_{OL} = 100 μA				0.1	V
	V_{CC} = 4.5 V,	I_{OL} = 12 mA				0.4	
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND	Inputs only			±10	μA
I_{hold}	V_{CC}= 4.5 V,	V_I = 2 V	A, B, or C port	−100			μA
	V_{CC} = 4.5 V,	V_I = 0.8 V		100			
I_{OZ}‡	V_{CC} = 5.5 V,	V_O = V_{CC} or GND				±20	μA
I_{CC}	V_{CC} = 5.5 V, I_O = 0,	V_I = V_{CC} or GND				50	μA
ΔI_{CC}§	V_{CC} = 5.5 V, Other inputs at V_{CC} or GND	One input at 3.4 V,				500	μA
C_i	V_{CC} = 5 V,	V_I = V_{CC} or GND			3.5		pF
C_{io}	V_{CC} = 5 V,	V_O = V_{CC} or GND			5		pF

† All typical values are at T_A = 25°C.
‡ The parameter I_{OZ} includes the input-leakage current.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

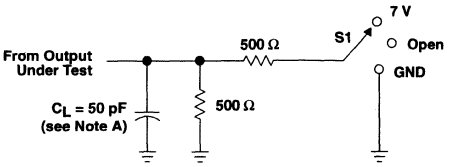
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			UNIT
			MIN	TYP	MAX	
t_{pd}	A or B	C	1.5	3.7	6.2	ns
t_{pd}	C	A	1.5	3.3	5.5	ns
t_{en}	EN1 or EN2	C	1.5	5.3	9.5	ns
t_{dis}	EN1 or EN2	C	1.5	4.4	8	ns
t_{en}	EN2	A	1.5	6.2	10.5	ns
t_{dis}	EN2	A	1.5	4.8	8	ns

operating characteristics, T_A = 25°C

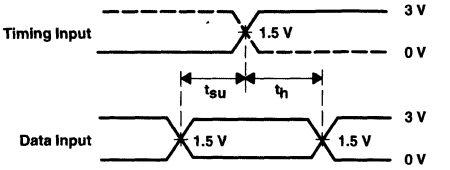
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	C_L = 50 pF, f = 10 MHz	16	pF
		Outputs disabled		2	pF

PARAMETER MEASUREMENT INFORMATION

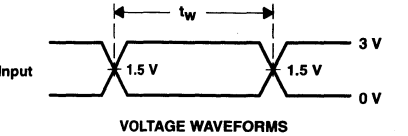


TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	GND

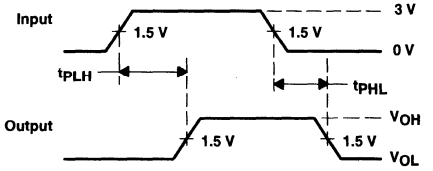
LOAD CIRCUIT



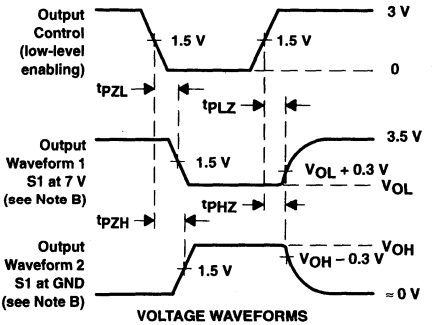
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



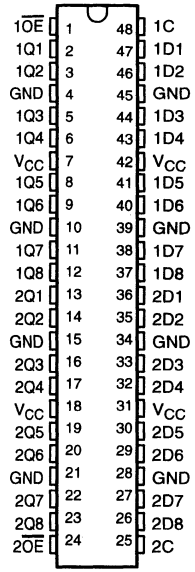
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PHL} and t_{PLH} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Shrink Small-Outline 300-mil Package and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Bus-Driving True Outputs**
- **Full Parallel Access for Loading**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed Center-Pin V_{CC} and GND Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

54ACT16373 . . . WD PACKAGE
74ACT16373 . . . DL PACKAGE
(TOP VIEW)



description

The 'ACT16373 is a 16-bit D-type transparent latch with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. The device can be used as two 8-bit latches or one 16-bit latch. The Q outputs of the latches will follow the D inputs if enable C is taken high. When C is taken low, the Q outputs will be latched at the levels set up at the D inputs.

A buffered output-enable input $\overline{OE}$ can be used to place the outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive the bus lines in a bus-organized system without need for interface or pullup components. The output enable $\overline{OE}$ does not affect the internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74ACT16373 is packaged in TI's shrink small-outline package (SSOP), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

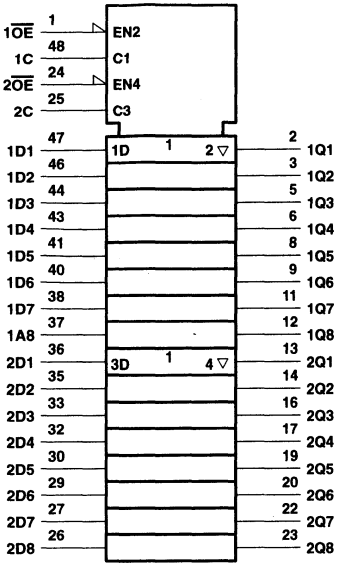
The 54ACT16373 is characterized over the full military temperature range of – 55°C to 125°C. The 74ACT16373 is characterized for operation from – 40°C to 85°C.

FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE}$	C	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

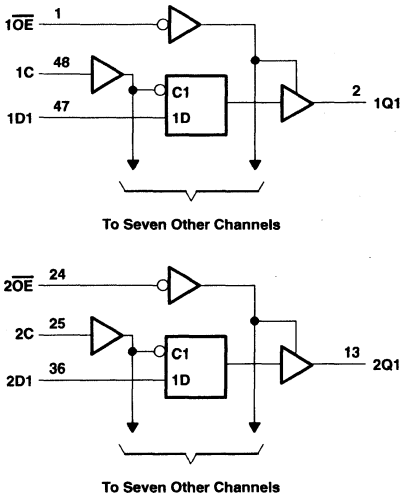
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ± 50 mA
Continuous current through V_{CC} or GND ..... ± 400 mA
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions (see Note 2)

		54ACT16373		74ACT16373		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage (see Note 3)	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	0	10	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTES: 2. Unused or floating inputs should be tied to V_{CC} through a pullup resistor of approximately 5 kΩ or greater.
3. All V_{CC} and GND pins must be connected to the proper voltage supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16373		74ACT16373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = − 50 μA	4.5 V	4.4			4.4		4.4		V
		5.5 V	5.4			5.4		5.4		
	I_{OH} = − 24 mA	4.5 V	3.94			3.7		3.8		
		5.5 V	4.94			4.7		4.8		
	I_{OH} = − 50 mA†	5.5 V				3.85				
	I_{OH} = − 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		± 1		± 1	μA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			± 0.5		± 10		± 5	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		160		80	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.9		1		1	mA
C_i	$V_I = V_{CC}$ or GND	5 V		4.5						pF
C_o	$V_I = V_{CC}$ or GND	5 V		12						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V to V_{CC}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		T_A = 25°C		54ACT16373		74ACT16373		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, C high	4		4		1		ns
t_{su}	Setup time, data before C↓	1		1		1		ns
t_h	Hold time, data after C↓	5		5		5		ns

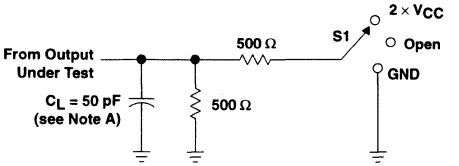
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16373		74ACT16373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	3.8	7.9	9.4	3.8	11.8	3.8	11.1	ns
t_{PHL}			3.1	8.2	9.7	3.1	13	3.1	12.3	
t_{PLH}	C	Q	4.6	9.3	10.8	4.6	13.7	4.6	12.8	ns
t_{PHL}			4.5	9.1	10.5	4.5	13	4.5	12.2	
t_{PZH}	$\overline{OE}$	Q	3.1	8	9.5	3.1	13	3.1	12.1	ns
t_{PZL}			3.8	9.4	11.1	3.8	15.1	3.8	14.2	
t_{PHZ}	$\overline{OE}$	Q	5.3	8.6	9.9	5.3	11	5.3	10.7	ns
t_{PLZ}			4.3	7.4	8.7	4.3	9.8	4.3	9.4	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

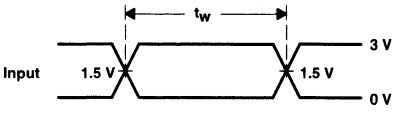
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per latch	Outputs enabled	C_L = 50 pF, f = 1 MHz	43	pF
		Outputs disabled		4.5	

PARAMETER MEASUREMENT INFORMATION

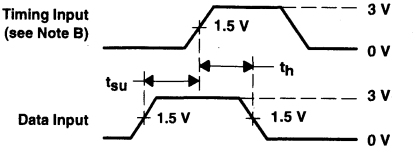


LOAD CIRCUIT

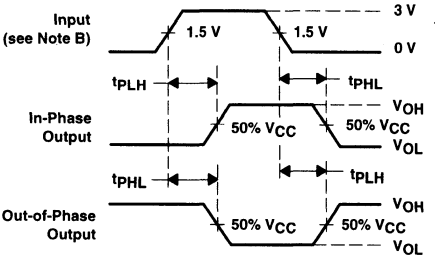
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × VCC
t_{PHZ}/t_{PZH}	GND



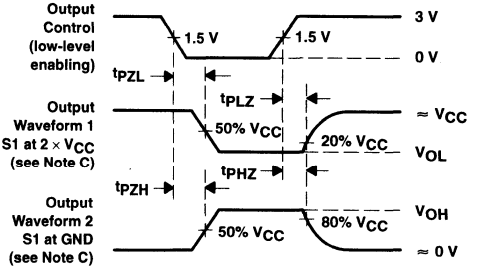
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



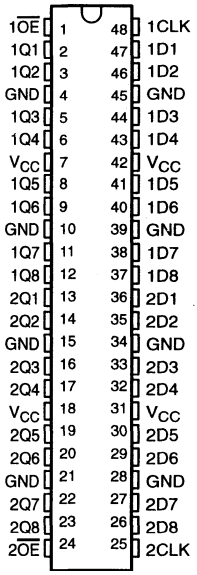
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Packaged in Shrink Small-Outline 300-mil Package and 380-mil Fine-Pitch Ceramic Flat Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Bus-Driving True Outputs**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

54ACT16374 . . . WD PACKAGE
74ACT16374 . . . DL PACKAGE
(TOP VIEW)



description

The 'ACT16374 is a 16-bit edge-triggered D-type flip-flop with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The device can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of CLK, the Q outputs of the flip-flop take on the logic levels set up at the D inputs.

An output-enable input $\overline{OE}$ can be used to place the outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state provides the capability to drive the bus lines in a bus-organized system without need for interface or pullup components. The output-enable $\overline{OE}$ does not affect the internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74ACT16374 is packaged in TI's shrink small-outline package (SSOP), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit board area.

The 54ACT16374 is characterized over the full military temperature range of – 55°C to 125°C. The 74ACT16374 is characterized for operation from – 40°C to 85°C.

FUNCTION TABLE
(each section)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	K
L	L	X	Q_0
H	X	X	Z

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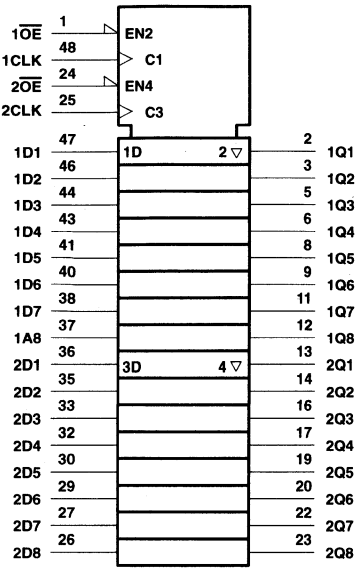
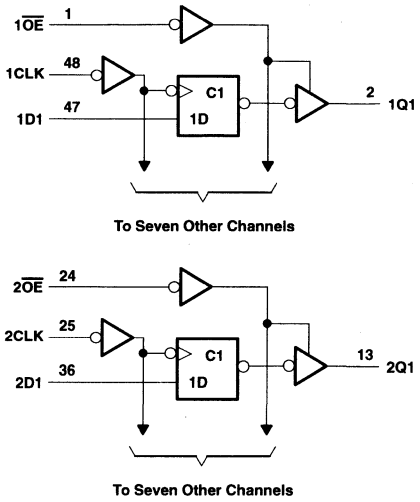
logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

		54ACT16374			74ACT16374			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage (see Note 2)	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current			−24			−24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
T_A	Operating free-air temperature	−55		125	−40		85	°C

NOTE 2: All V_{CC} and GND pins must be connected to the proper voltage supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16374		74ACT16374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = – 50 μA	4.5 V	4.4			4.4		4.4		V
		5.5 V	5.4			5.4		5.4		
	I_{OH} = – 24 mA	4.5 V	3.94			3.7		3.8		
		5.5 V	4.94			4.7		4.8		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		± 1		± 1	μA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			± 0.5		± 10		± 5	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		160		80	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.9		1		1	mA
C_i	$V_I = V_{CC}$ or GND	5 V		4.5						pF
C_o	$V_O = V_{CC}$ or GND	5 V		12						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V to V_{CC}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			T_A = 25°C		54ACT16374		74ACT16374		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	65	0	65	0	65	MHz
t_w	Pulse duration	CLK low	7.5		7.5		7.5		ns
		CLK high	4.5		4.5		4.5		
t_{su}	Setup time, data before C↑		6.5		6.5		6.5		ns
t_h	Hold time, data after C↑		1		1		1		ns

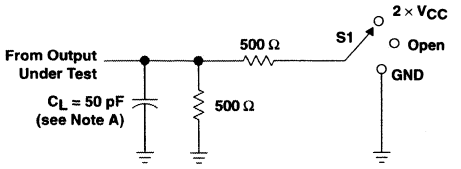
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16374		74ACT16374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			65			65		65		MHz
t_{PLH}	CLK	Q	5.1	8.8	10.9	5.1	13.2	5.1	12.4	ns
t_{PHL}			5.3	8.8	10.9	5.3	13.1	5.3	12.2	
t_{PZH}	$\overline{OE}$	Q	3.7	8.4	10.5	3.7	12.7	3.7	11.9	ns
t_{PZL}			4.4	9.7	11.9	4.4	14.3	4.4	13.4	
t_{PHZ}	$\overline{OE}$	Q	5.4	7.9	9.8	5.4	10.9	5.4	10.4	ns
t_{PLZ}			4.9	7.2	9.1	4.9	10.2	4.9	9.8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

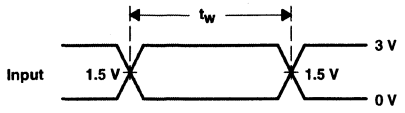
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per flip-flop	Outputs enabled	C_L = 50 pF, f = 1 MHz	52	pF
		Outputs disabled		38	

PARAMETER MEASUREMENT INFORMATION

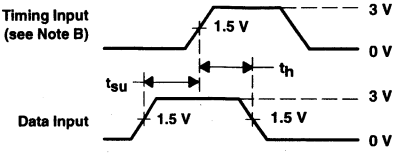


LOAD CIRCUIT

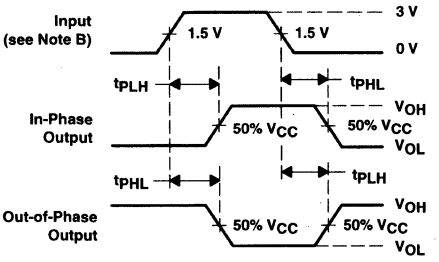
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



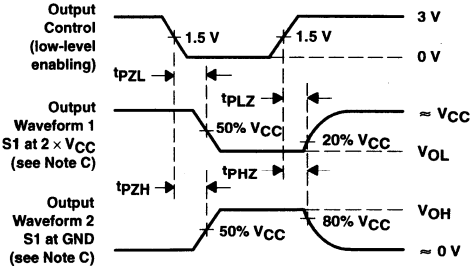
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



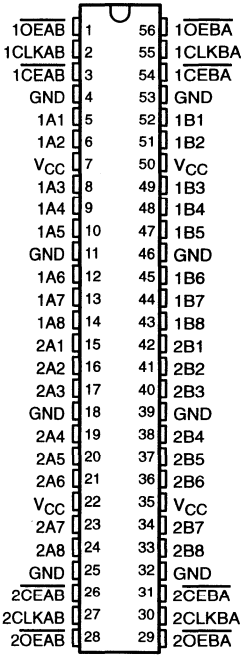
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16470 is a 16-bit registered transceiver that contains two sets of D-type flip-flops for temporary storage of data flowing in either direction. The device can be used as two 8-bit transceivers or one 16-bit transceiver. Separate clock (CLKAB or CLKBA) and output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable ($\overline{CEAB}$) input must be low in order to enter data from A or to output data to B. If both $\overline{CEAB}$ and CLKAB are low, then B port will have the level of A port prior to the most recent low-to-high transition of CLKAB. Data flow from B to A is similar, but requires the use of $\overline{CEBA}$, CLKBA, and $\overline{OEBA}$ inputs.

To avoid false clocking of the flip-flops, $\overline{CE}$ should not be switched from high to low while CLK is high.

The 74ACT16470 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16470 is characterized for operation from −40°C to 85°C.

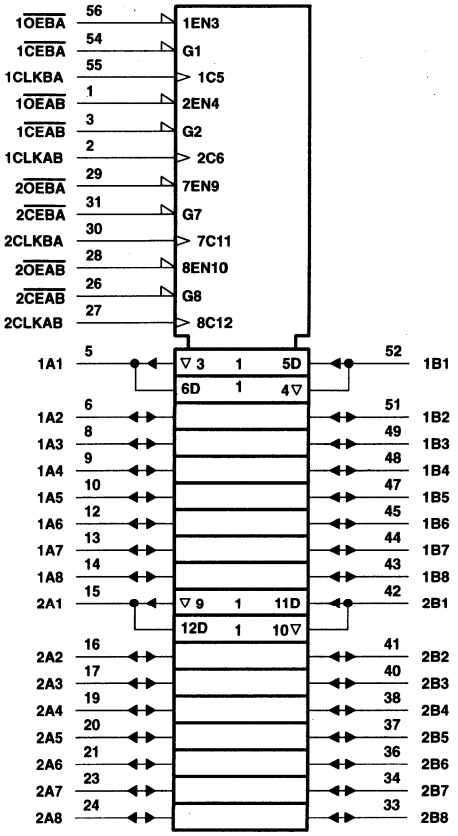
FUNCTION TABLE†

INPUTS				OUTPUT
$\overline{CEAB}$	CLKAB	$\overline{OEAB}$	A	B
H	X	X	X	Z
X	X	H	X	Z
L	L	L	X	B_0‡
L	↑	L	L	L
L	↑	L	H	H

† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{CEBA}$, CLKBA, and $\overline{OEBA}$.
‡ Output level before the indicated steady-state input conditions were established.

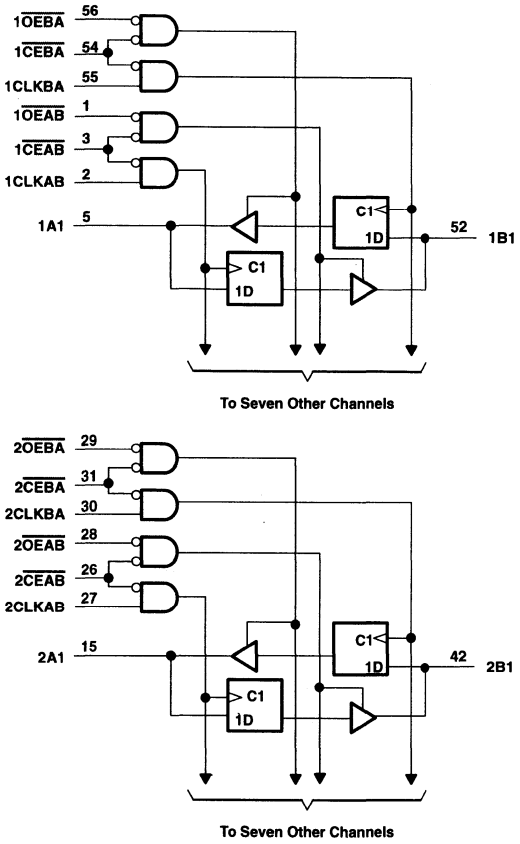
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)§

Supply voltage range, V_{CC} ..... −0.5 to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 to V_{CC} + 0.5 V
Input voltage range, V_O (see Note 1) ..... −0.5 to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum power package dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

§ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note NO TAG)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = – 50 μA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = – 24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = – 75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 μA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		± 5	μA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	μA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		3				pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		11.5				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
f_{clock}	Clock frequency		0	55	0	55	MHz
t_w	Pulse duration	CLK high	4		4		ns
		CLK low	8.5		8.5		
t_{su}	Setup time	Data before CLK↑	6		6		ns
t_h	Hold time	Data after CLK↑	1		1		ns

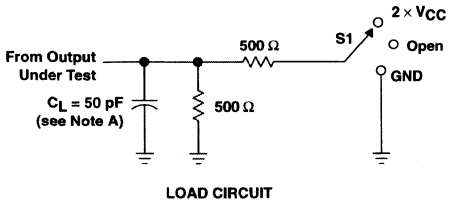
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see NO TAG)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f_{max}			55			55		MHz
t_{PLH}	CLK	A or B	3.9	8.3	10.3	3.9	11.8	ns
t_{PHL}			3.8	8.4	10.3	3.8	11.7	
t_{PZH}	$\overline{OE}$	A or B	3.2	8.3	10.5	3.2	11.9	ns
t_{PZL}			3.6	9.5	11.8	3.6	13.4	
t_{PHZ}	$\overline{OE}$	A or B	4.6	7.4	9.3	4.6	9.9	ns
t_{PLZ}			4.6	7	8.8	4.6	9.5	
t_{PZH}	$\overline{CE}$	A or B	3.5	8.8	10.9	3.5	12.5	ns
t_{PZL}			4.2	10.1	12.4	4.2	14.3	
t_{PHZ}	$\overline{CE}$	A or B	5.2	8.3	10.3	5.2	11.2	ns
t_{PLZ}			5.2	7.9	10	5.2	10.9	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

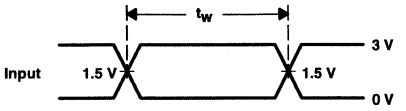
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	59	pF
		Outputs disabled		39	

PARAMETER MEASUREMENT INFORMATION

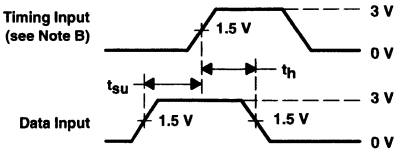


LOAD CIRCUIT

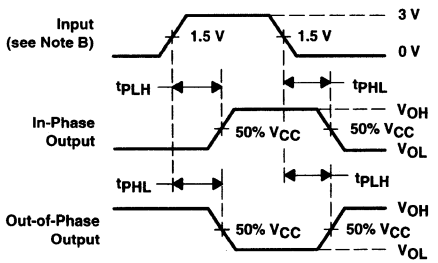
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



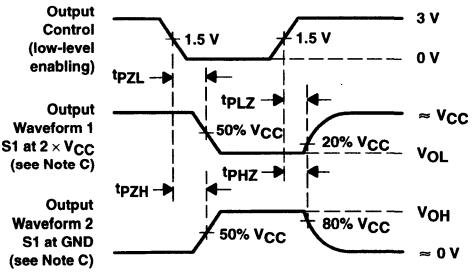
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



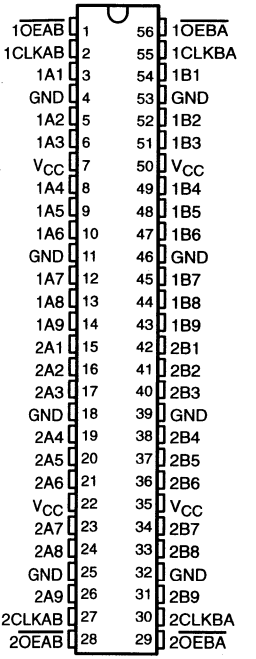
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings**

54ACT16474 . . . WD PACKAGE
74ACT16474 . . . DL PACKAGE
(TOP VIEW)



description

The 'ACT16474 are noninverting 18-bit registered bus transceivers composed of two 9-bit sections with separate control signals. For either 9-bit transceiver section, data flow in the A-to-B mode is controlled by output-enable ($1\overline{OEAB}$ or $2\overline{OEAB}$) and clock (1CLKAB or 2CLKAB) inputs. When $1\overline{OEAB}$ or $2\overline{OEAB}$ is low, the corresponding outputs are active (high or low) and take on either the current data on low-to-high transition of 1CLKAB or 2CLKAB or the previously stored data if 1CLKAB or 2CLKAB is low.

When $1\overline{OEAB}$ or $2\overline{OEAB}$ is high, the corresponding outputs are in the high-impedance state. $1\overline{OEAB}$ or $2\overline{OEAB}$ does not affect the operation on the internal registers. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

Data flow from B to A is similar, but uses $1\overline{OEBA}$ and/or $2\overline{OEBA}$ and 1CLKBA and/or 2CLKBA.

The 74ACT16474 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16474 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16474 is characterized for operation from –40°C to 85°C.

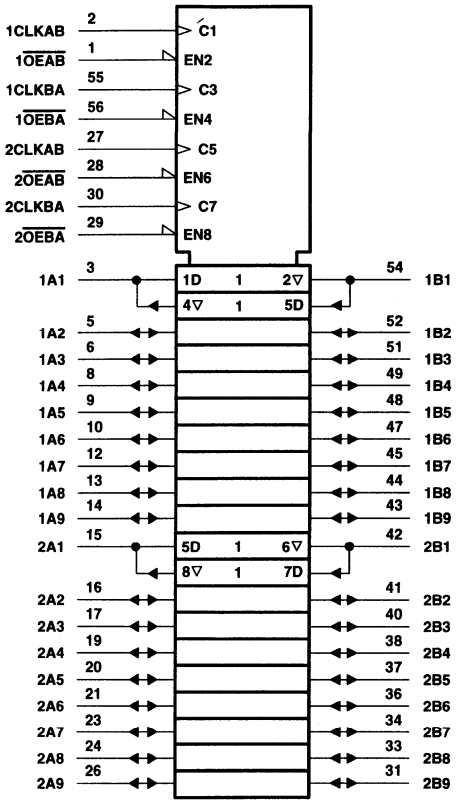
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

FUNCTION TABLE†

INPUTS			OUTPUT
CLKAB	OEAB	A	B
X	H	X	Z
L	L	X	B_0‡
↑	L	H	H
↑	L	L	L

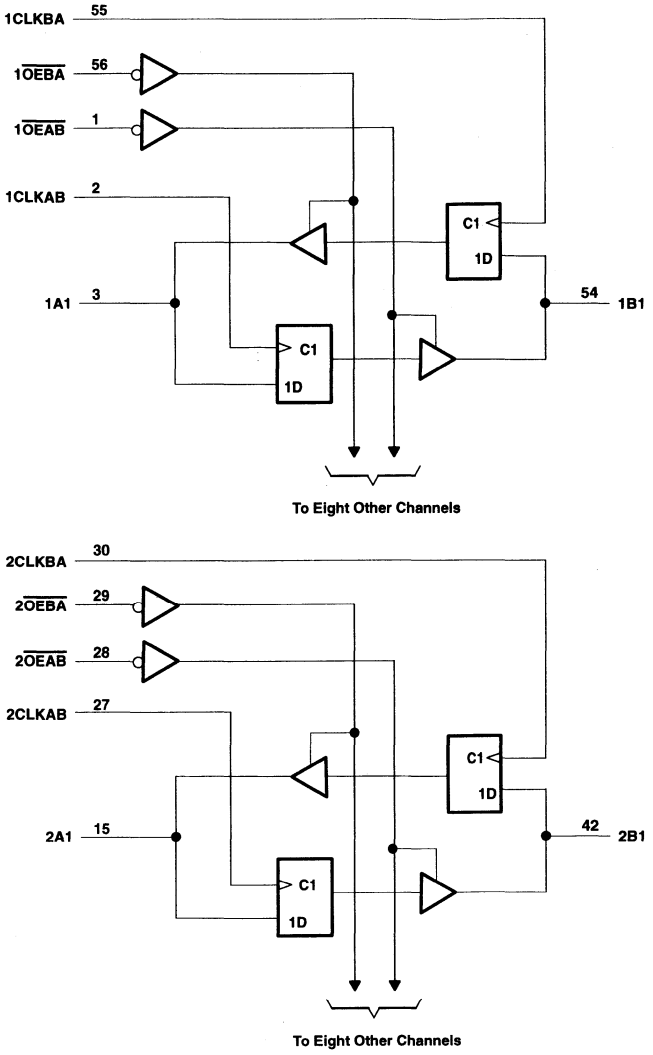
† A-to-B data flow is shown: B-to-A flow is similar but uses CLKBA, and $\overline{OEBA}$.
‡ Output level before the indicated steady-state input conditions were established

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 to V_{CC} + 0.5 V
Input voltage range, V_O (see Note 1) ..... –0.5 to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±450 mA
Maximum package power dissipation at T_A = 55°C (in still air) (see Note 2): DL package ..... 1.4 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		54ACT16474			74ACT16474			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current			–24			–24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
T_A	Operating free-air temperature	–55		125	–40		85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16474		74ACT16474		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = –50 µA	4.5 V	4.4			4.4		4.4		V
			5.5 V	5.4			5.4		5.4		
		I_{OH} = –24 mA	4.5 V	3.94			3.8		3.8		
			5.5 V	4.94			4.8		4.8		
		I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1		0.1	V
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
			5.5 V			0.36		0.44		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		3						pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		11.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		54ACT16474		74ACT16474		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	75	0	75	0	75	MHz
t_w	Pulse duration	CLK high	4		4		4		ns
		CLK low	6.6		6.6		6.6		
t_{su}	Setup time	Data before CLK↑	5.5		5.5		5.5		ns
t_h	Hold time	Data after CLK↑	1		1		1		ns

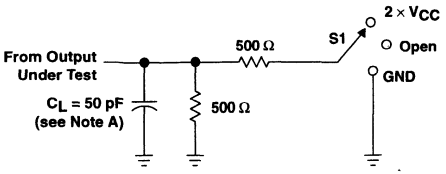
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16474		74ACT16474		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			75			75		75		MHz
t_{PLH}	CLK	A or B	4	8	10.2	4	11.5	4	11.5	ns
t_{PHL}			4.2	8	10.2	4.2	11.4	4.2	11.4	
t_{PZH}	$\overline{OE}$	A or B	3	7.8	10.3	3	11.7	3	11.7	ns
t_{PZL}			3.7	9.2	11.6	3.7	13.1	3.7	13.1	
t_{PHZ}	$\overline{OE}$	A or B	4.8	7.1	8.8	4.8	9.5	4.8	9.5	ns
t_{PLZ}			4.4	6.6	8.4	4.4	9	4.4	9	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

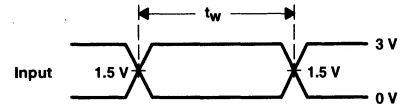
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	61	pF
		Outputs disabled		37	

PARAMETER MEASUREMENT INFORMATION

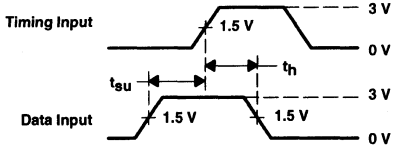


LOAD CIRCUIT

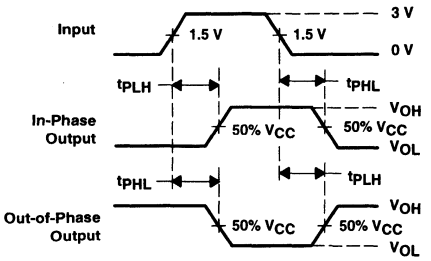
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



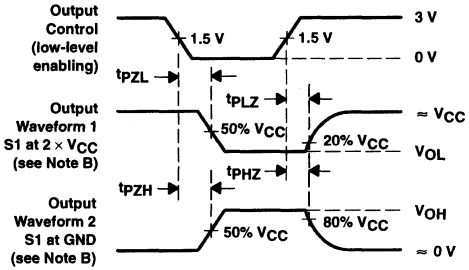
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



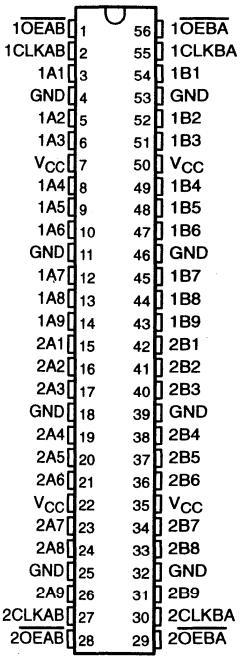
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Inverting Outputs**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16475 is an 18-bit registered transceiver that contains two sets of D-type flip-flops for temporary storage of data flowing in either direction. It can be used as two 9-bit transceivers or one 18-bit transceiver. Separate clock (CLKAB and CLKBA) and output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

Data at the A inputs meeting the setup time requirements is transferred to the B outputs on the positive-going edge of CLKAB. With $\overline{OEAB}$ low, the 3-state B outputs are enabled and reflect the inverted A data. Data flow from B to A is similar but requires the use of the CLKAB and $\overline{OEBA}$ inputs.

The 74ACT16475 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16475 is characterized for operation from –40°C to 85°C.

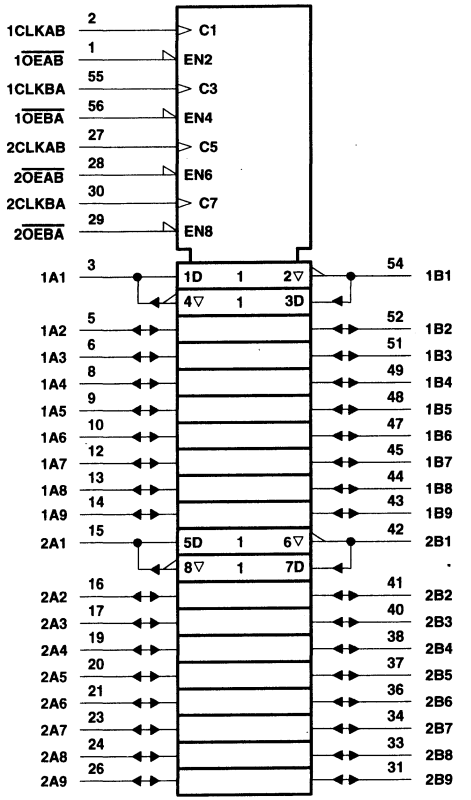
FUNCTION TABLE†

INPUTS			OUTPUT
$\overline{OEAB}$	CLKAB	A	B
H	X	X	Z
L	L	X	B_0‡
L	↑	L	H
L	↑	H	L

† A-to-B data flow is shown: B-to-A flow is similar but uses CLKBA and $\overline{OEBA}$.
‡ Output level before the indicated steady-state input conditions were established.

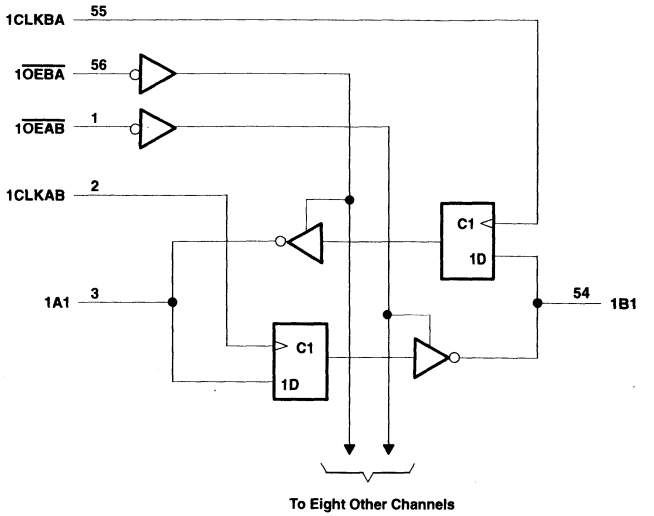
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

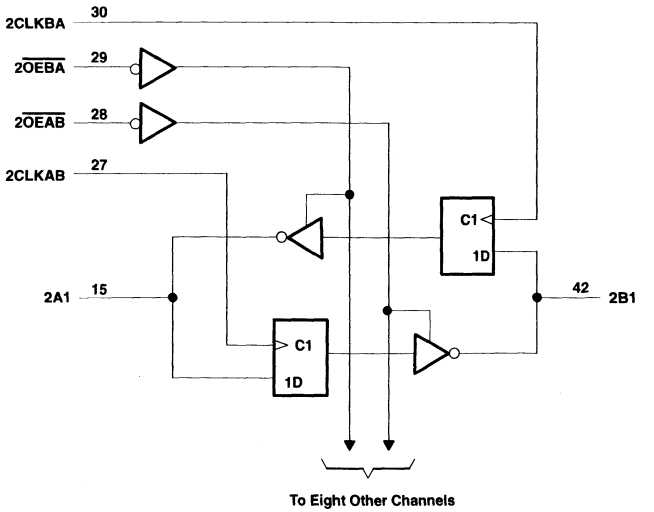
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±450 mA
Maximum power package dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = −50 μA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = −24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 μA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	μA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4.5				pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
f_{clock}	Clock frequency		0	75	0	75	MHz
t_w	Pulse duration	CLK high or low	6.5		6.5		ns
t_{su}	Setup time	Data before CLK↑	5.5		5.5		ns
t_h	Hold time	Data after CLK↑	1.5		1.5		ns

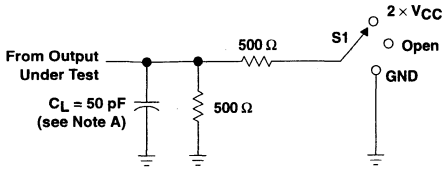
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f_{max}			75			75		MHz
t_{PLH}	CLKAB or CLKBA	B or A	3.8	7.9	11.1	3.8	12.5	ns
t_{PHL}			4.2	8.1	11.4	4.2	12.6	
t_{PZH}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	2.8	7.3	11.4	2.8	12.8	ns
t_{PZL}			3.4	7.4	13.1	3.4	14.8	
t_{PHZ}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	5.2	6.5	9.8	5.2	10.5	ns
t_{PLZ}			4.5	6.6	9.1	4.5	9.8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

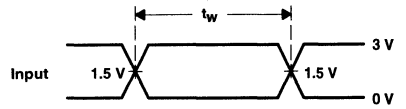
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	27	pF
		Outputs disabled		9	

PARAMETER MEASUREMENT INFORMATION

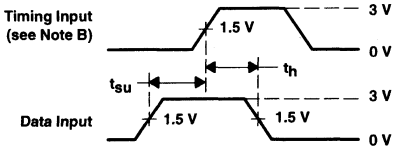


LOAD CIRCUIT

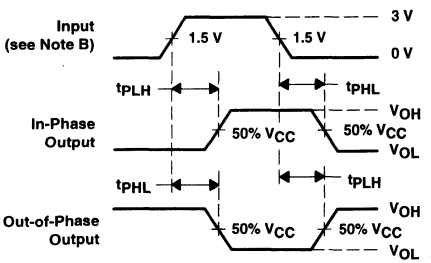
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



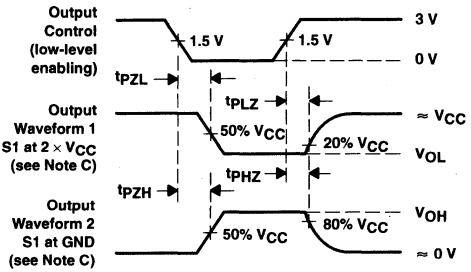
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



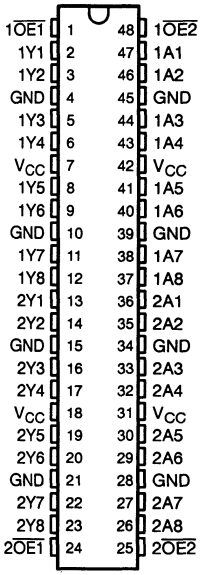
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Inputs Are TTL-Voltage Compatible**
- **Provide Extra Data Width Necessary for Wider Address/Data Paths**
- **Provide Inverted Data**
- **3-State Outputs Drive Bus Lines or Buffer Memory Address Registers**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Shrink Small-Outline 300-mil (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings**

54ACT16540 . . . WD PACKAGE
74ACT16540 . . . DL PACKAGE
(TOP VIEW)



description

These 16-bit buffers/bus drivers provide a high-performance bus interface for wide data paths.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all corresponding outputs are in the high-impedance state.

The 74ACT16540 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16540 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16540 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	H
L	L	H	L
H	X	X	Z
X	H	X	Z

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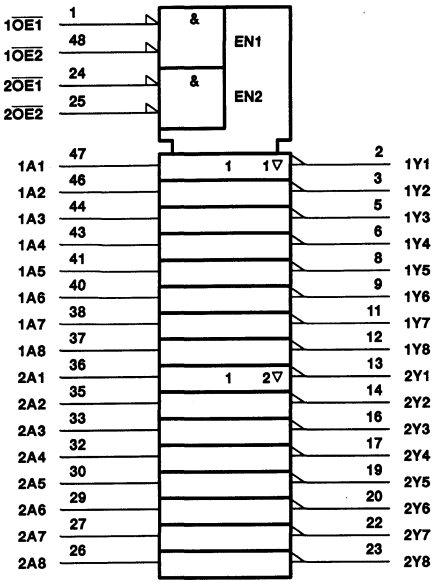
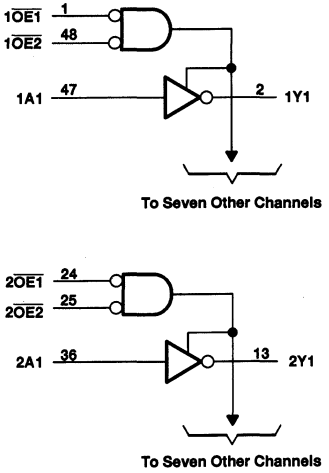
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum power package dissipation at T_A = 55°C (in still air) (see Note 2): DL package ..... 1.2 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		54ACT16540			74ACT16540			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current			−24			−24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
T_A	Operating free-air temperature	−55		125	−40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16540		74ACT16540		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA	4.5 V	4.4			4.4		4.4		V
		5.5 V	5.4			5.4		5.4		
	I_{OH} = −24 mA	4.5 V	3.94			3.8		3.8		
		5.5 V	4.94			4.8		4.8		
	I_{OH} = −75 mA†	5.5 V				3.85		3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.44		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80		80	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1		1	mA
C_i	$V_I = V_{CC}$ or GND	5 V		4						pF
C_o	$V_O = V_{CC}$ or GND	5 V		13						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

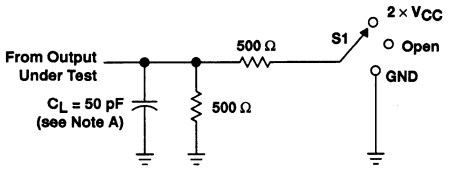
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16540		74ACT16540		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	2.1	5.1	6.8	2.1	7.5	2.1	7.5	ns
t_{PHL}			3.9	6.8	8.5	3.9	9.5	3.9	9.5	
t_{PZH}	$\overline{OE}$	Y	2.7	6.2	8	2.7	8.9	2.7	8.9	ns
t_{PZL}			3.6	7.5	9.5	3.6	10.5	3.6	10.5	
t_{PHZ}	$\overline{OE}$	Y	5.4	9.2	10.9	5.4	11.9	5.4	11.9	ns
t_{PLZ}			5.4	8.6	10.3	5.4	11.1	5.4	11.1	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

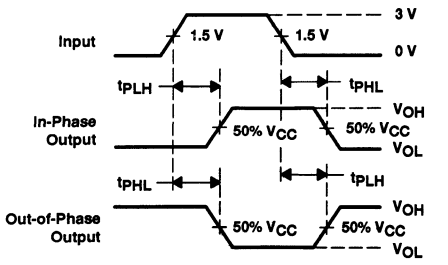
PARAMETER			TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer	Outputs enabled	C_L = 50 pF,	f = 1 MHz	42	pF
		Outputs disabled			8.5	

PARAMETER MEASUREMENT INFORMATION

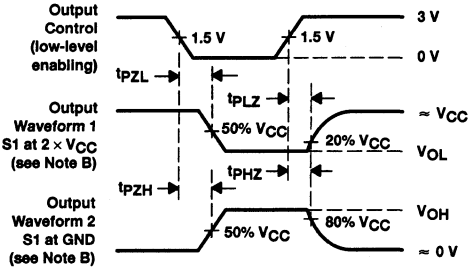


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



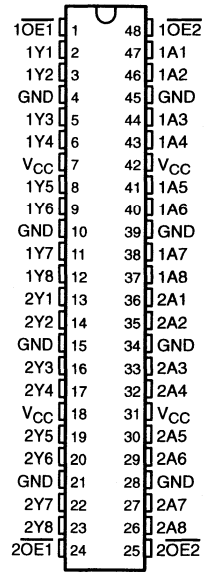
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL- or CMOS-Voltage Compatible**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16541 is a noninverting 16-bit buffer composed of two 8-bit sections with separate output-enable signals. For either 8-bit buffer section, the two output-enable (1$\overline{OE1}$ and 1$\overline{OE2}$ or 2$\overline{OE1}$ and 2$\overline{OE2}$) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 8-bit buffer section are in the high-impedance state.

The 74ACT16541 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16541 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

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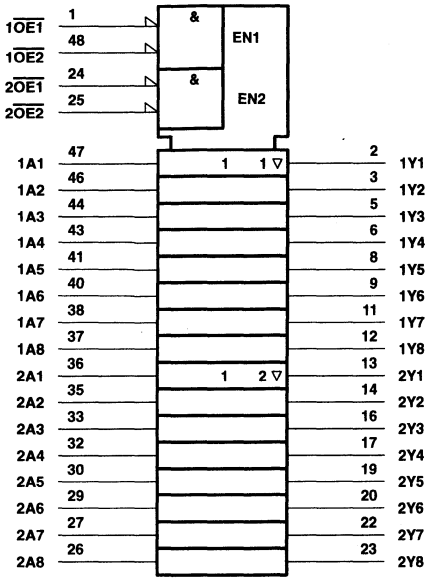
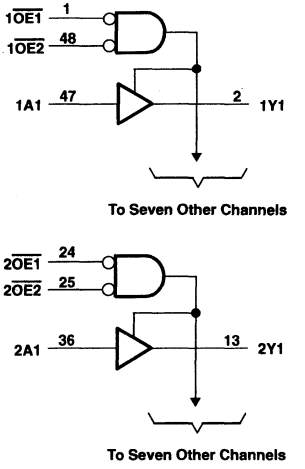
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum package power dissipation at T_A = 55°C (in still air) ..... 0.85 W
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	I_{OH} = −50 μA	4.5 V	4.4			4.4		V
		5.5 V	5.4			5.4		
	I_{OH} = −24 mA	4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1	V
		5.5 V			0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	$V_I = V_{CC}$ or GND	5.5 V		4				pF
C_o	$V_O = V_{CC}$ or GND	5 V		13				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

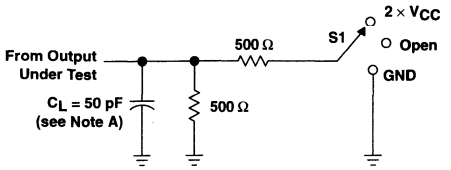
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	Y	3.1	5.9	7.9	3.1	9	ns
t_{PHL}			2.7	6.3	8.3	2.7	9.2	
t_{PZH}	$\overline{OE}$	Y	2.8	6.5	8.9	2.8	9.7	ns
t_{PZL}			3.5	7.5	9.9	3.5	11	
t_{PHZ}	$\overline{OE}$	Y	4.5	8.5	10.3	4.5	11.3	ns
t_{PLZ}			4.9	8	9.9	4.9	10.7	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

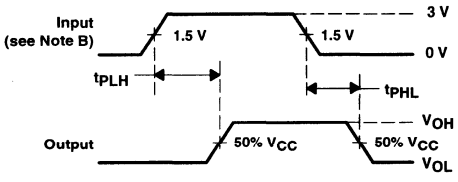
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	Outputs enabled	C_L = 50 pF, f = 1 MHz	40	pF
		Outputs disabled		9.5	

PARAMETER MEASUREMENT INFORMATION

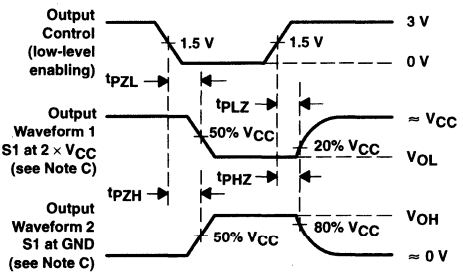


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



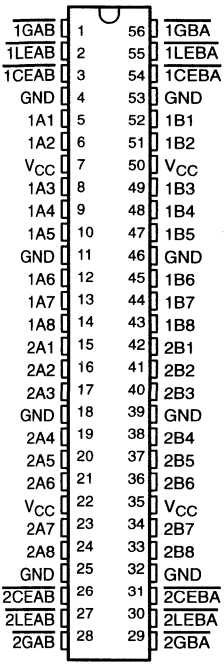
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Shrink Small-Outline 300-mil Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State True Outputs**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16543 is a 16-bit registered transceiver that contains two sets of D-type latches for temporary storage of data flowing in either direction. The 74ACT16543 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch enable ($\overline{LEAB}$ or $\overline{LEBA}$) and output enable ($\overline{GAB}$ or $\overline{GBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable ($\overline{CEAB}$) input must be low in order to enter data from A or to output data to B Having $\overline{CEAB}$ low and $\overline{LEAB}$ low makes the A-to-B latches transparent; a subsequent low-to-high-transition at $\overline{LEAB}$ puts the A latches in the storage mode. Data flow from B to A is similar, but requires using the $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{GBA}$ inputs.

The 74ACT16543 is packaged in TI's shrink small-outline package (SSOP), which provides twice the functionality of standard small-outline packages in the same PCB area.

The 74ACT16543 is characterized for operation from – 40°C to 85°C.

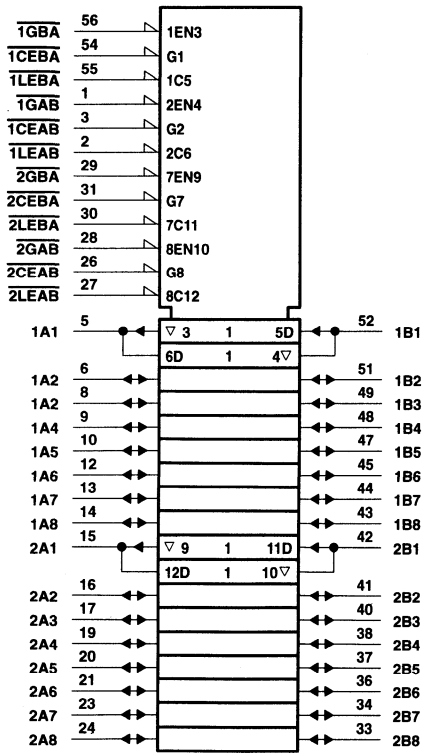
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

FUNCTION TABLE
(each octal register)

INPUTS			LATCH STATUS A TO B†	OUTPUT BUFFERS B1 THRU B8
$\overline{CEAB}$	$\overline{LEAB}$	$\overline{GAB}$		
H	X	X	Storing	Z
X	H	X	Storing	
X	X	H		Z
L	L	L	Transparent	Current A Data
L	H	L	Storing	Previous‡ A Data

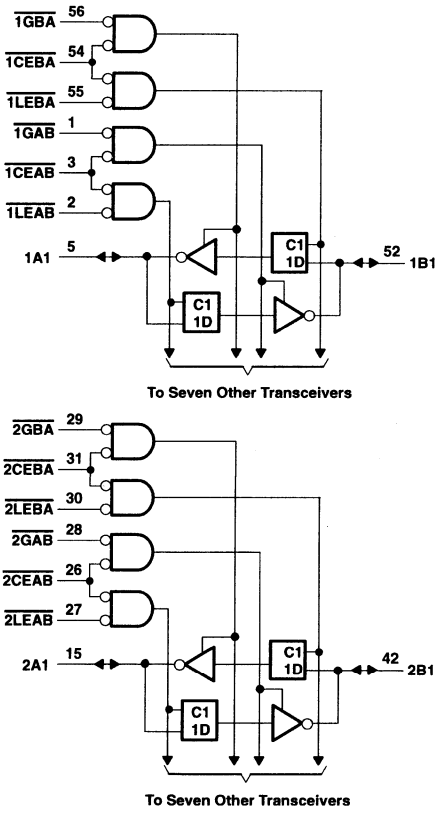
† A-to-B data flow is shown: B-to-A flow control is the same except uses $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{GBA}$ are used.
‡ Data present before low-to-high transition of $\overline{LEAB}$ occurring while $\overline{CEAB}$ is low.

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage (see Note 2)	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: All V_{CC} and GND pins must be connected to the proper voltage power supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = – 50 µA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = – 24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = – 75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		± 1	µA
I_{OZ}	A or B ports‡	$V_O = V_{CC}$ or GND	5.5 V			± 0.5		± 5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.9		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4.5				pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12				

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		T_A = 25°C		MIN	MAX	UNIT
		MIN	MAX			
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low	7.5		7.5		ns
t_{su}	Setup time, data before $\overline{LEAB}$ or $\overline{LEBA}$↑	2.5		2.5		ns
t_h	Hold time, data after $\overline{LEAB}$ or $\overline{LEBA}$↑	4		4		ns

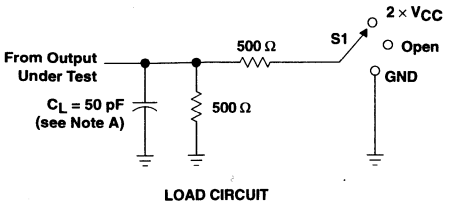
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	3.5	6.9	9.5	3.5	10.5	ns
t_{PHL}			3.1	7.3	10.7	3.1	11.6	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	3.9	8.6	12.3	3.9	13.8	ns
t_{PHL}			3.9	8.7	12.2	3.9	13.5	
t_{PZH}	$\overline{GBA}$ or $\overline{GAB}$	A or B	2.6	7.1	10.3	2.6	11.4	ns
t_{PZL}			3.5	8.3	11.9	3.5	13.2	
t_{PHZ}	$\overline{GBA}$ or $\overline{GAB}$	A or B	4.1	8.2	10.5	4.1	11.1	ns
t_{PLZ}			5	7.3	9.3	5	9.6	
t_{PZH}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	3.1	7.3	10.7	3.1	11.7	ns
t_{PZL}			3.9	8.5	12.2	3.9	13.5	
t_{PHZ}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	4.6	8.5	11	4.6	11.6	ns
t_{PLZ}			5.2	7.4	9.7	5.2	10.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

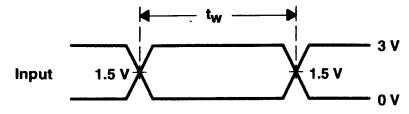
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	45	pF
		Outputs disabled		12	

PARAMETER MEASUREMENT INFORMATION

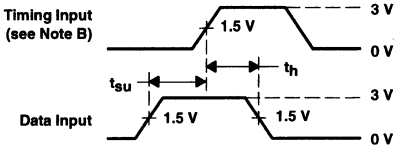


LOAD CIRCUIT

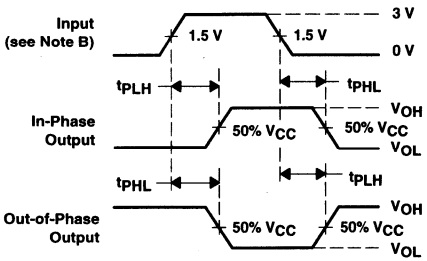
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



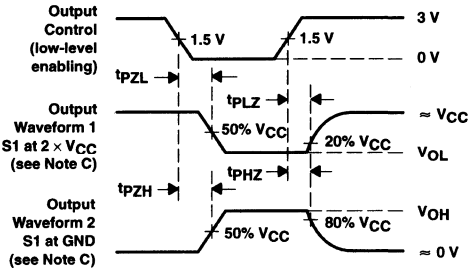
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



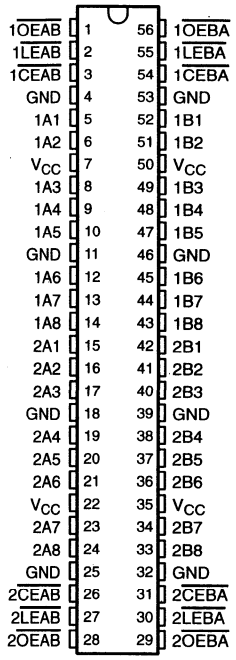
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-Mil Shrink Small-Outline Package Using 25-Mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Inverted Outputs**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PPACKAGE
(TOP VIEW)



description

The 74ACT16544 is a 16-bit registered transceiver that contains two sets of D-type latches for temporary storage of data flowing in either direction. It can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable ($\overline{LEAB}$ or $\overline{LEBA}$) and output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable ($\overline{CEAB}$) input must be low in order to enter data from A or to output data to B. Having $\overline{CEAB}$ low and $\overline{LEAB}$ low makes the A-to-B latches transparent; a subsequent low-to-high transition at $\overline{LEAB}$ puts the A latches in the storage mode. Data flow from B to A is similar, but requires using the $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$ inputs.

The 74ACT16544 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16544 is characterized for operation from −40°C to 85°C.

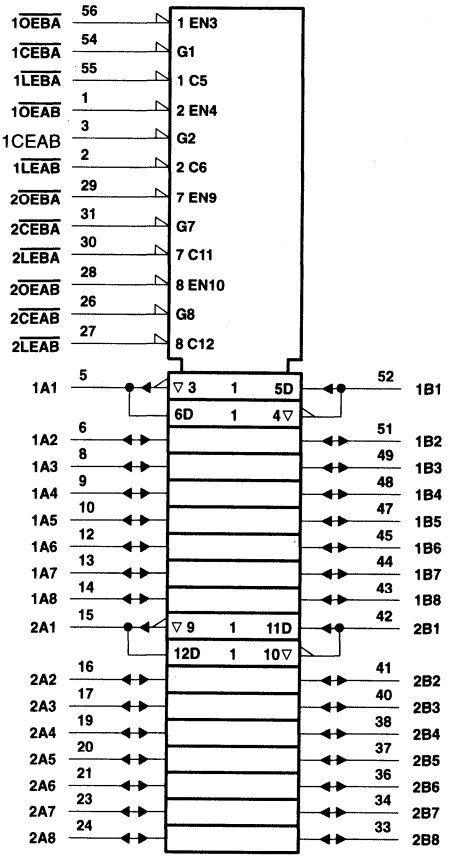
FUNCTION TABLE†

INPUTS				OUTPUT
$\overline{CEAB}$	$\overline{LEAB}$	$\overline{OEAB}$	A	B
H	X	X	X	Z
L	X	H	X	Z
L	H	L	X	B_0‡
L	L	L	L	H
L	L	L	H	L

† A-to-B data flow is shown; B-to-A flow control is the same except that it uses $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$.
‡ Output level before the indicated steady-state input conditions were established.

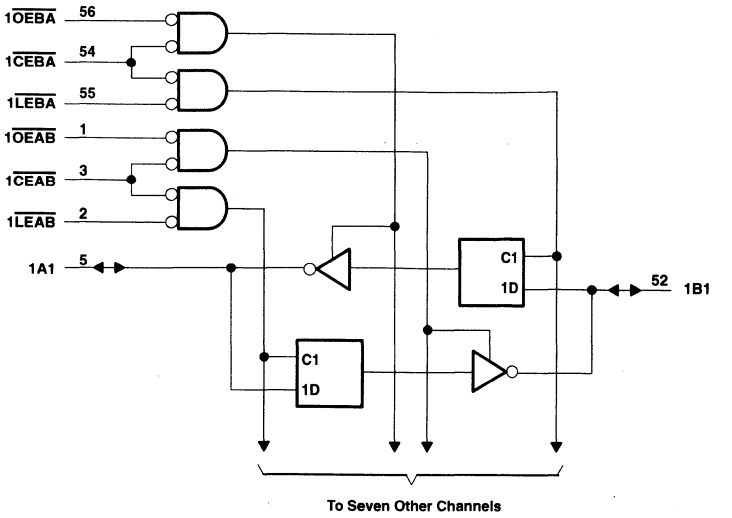
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

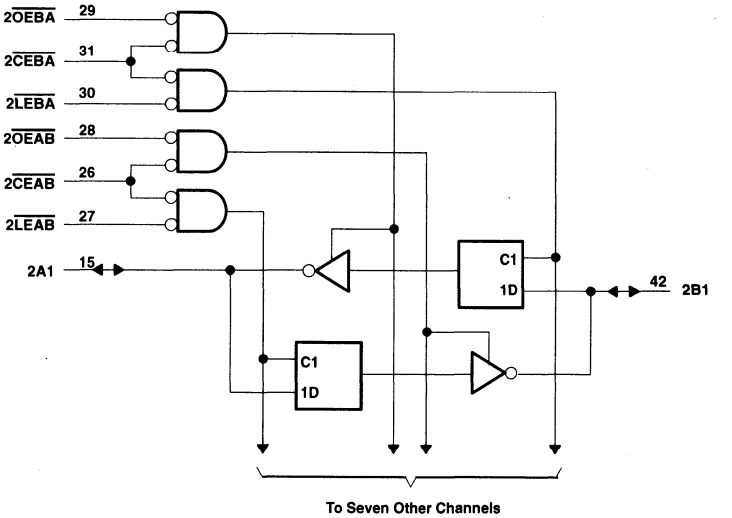
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)§

Supply voltage range, V_{CC} ..... −0.5 to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 to V_{CC} + 0.5 V
Input voltage range, V_O (see Note 1) ..... −0.5 to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum power package dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

§ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = – 50 µA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = – 24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = –75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	µA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4.5				pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (NO TAG)

			T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
t_w	Pulse duration	$\overline{LEAB}$ or $\overline{LEBA}$ low	5.5		5.5		ns
t_{su}	Setup time	Data before $\overline{LEAB}$ or $\overline{LEBA}$ ↑	1.5		1.5		ns
		Data before $\overline{CEAB}$ or $\overline{CEBA}$ ↑	1.5		1.5		
t_h	Hold time	Data after $\overline{LEAB}$ or $\overline{LEBA}$ ↑	3		3		ns
		Data after $\overline{CEAB}$ or $\overline{CEBA}$ ↑	3		3		

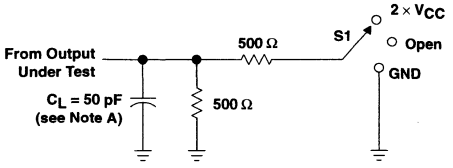
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see NO TAG)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	2.8	6.7	10	2.8	11.2	ns
t_{PHL}			4	7.5	10	4	11.2	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	2.7	9	13.3	2.7	14	ns
t_{PHL}			2.8	8.5	12.1	2.8	13.5	
t_{PZH}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	3.2	7.2	10.5	3.2	11.7	ns
t_{PZL}			3.8	8.2	12	3.8	13.6	
t_{PHZ}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	5.8	8.2	10.3	5.8	11.1	ns
t_{PLZ}			5	7.4	9.4	5	10.2	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	2.8	6.9	10.2	2.8	11.4	ns
t_{PZL}			3.6	7.9	11.7	3.6	13.3	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	5.2	7.7	9.8	5.2	10.5	ns
t_{PLZ}			3.4	6.8	8.8	3.4	9.6	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

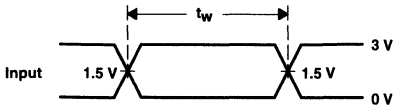
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	60	pF
		Outputs disabled		13	

PARAMETER MEASUREMENT INFORMATION

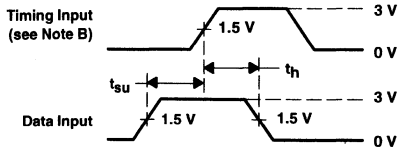


LOAD CIRCUIT

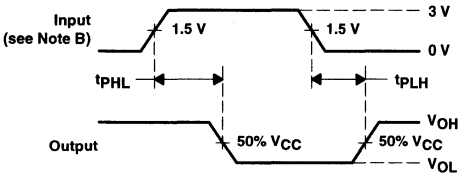
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



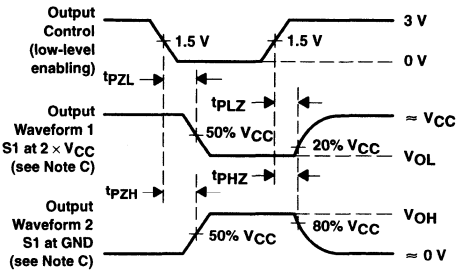
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



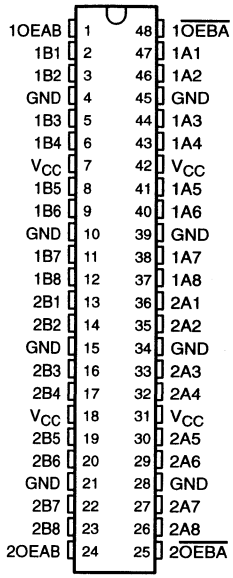
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **Inverting Logic**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16620 is an inverting 16-bit transceiver designed for asynchronous communication between data buses. The control function implementation allows for maximum flexibility in timing.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the output-enable (OEAB or $\overline{OEBA}$) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives the transceiver the capability to store data by simultaneous enabling of OEAB and $\overline{OEBA}$. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, the bus lines remain at their last states.

The 74ACT16620 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16620 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

INPUTS		OPERATION
$\overline{OEBA}$	OEAB	
L	L	$\overline{B}$ data to A bus
L	H	$\overline{B}$ data to A bus, $\overline{A}$ data to B bus
H	L	Isolation
H	H	$\overline{A}$ data to B bus

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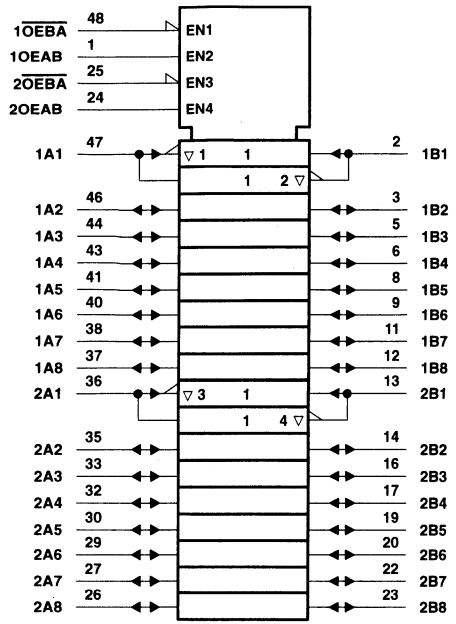
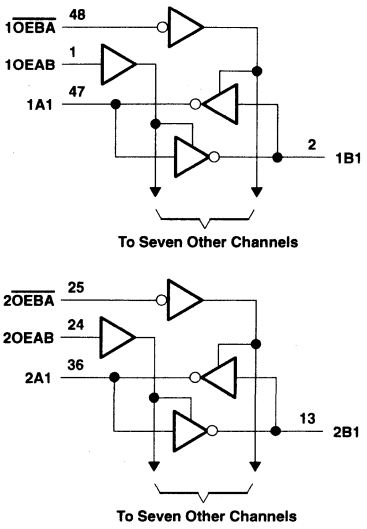
logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC})	±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC})	±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±400 mA
Maximum package power dissipation at T_A = 55°C (in still air)	0.85 W
Storage temperature range	−65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = −50 µA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = −24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	µA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4				pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		15				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

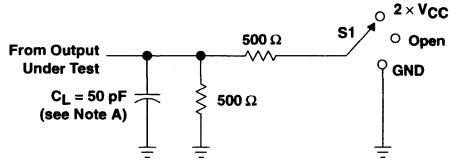
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	2	5	7.7	2	8.5	ns
t_{PHL}			4	7	9.3	4	10.5	
t_{PZH}	$\overline{OEBA}$	A	2.2	5.5	8.3	2.2	9.1	ns
t_{PZL}			2.8	6.4	10	2.8	10.9	
t_{PHZ}	$\overline{OEBA}$	A	6	8.8	11	6	11.9	ns
t_{PLZ}			5.1	7.9	10	5.1	10.6	
t_{PZH}	OEAB	B	3.6	6.2	7.9	3.6	8.9	ns
t_{PZL}			4.4	7.1	9.4	4.4	10.5	
t_{PHZ}	OEAB	B	5	7.8	10.1	5	10.8	ns
t_{PLZ}			4.1	6.7	9.1	4.1	9.6	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

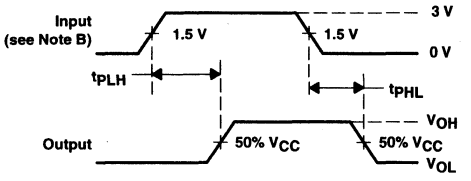
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	57	pF
		Outputs disabled		10	

PARAMETER MEASUREMENT INFORMATION

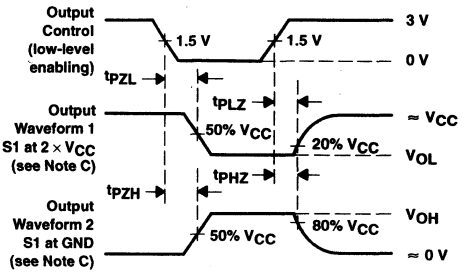


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



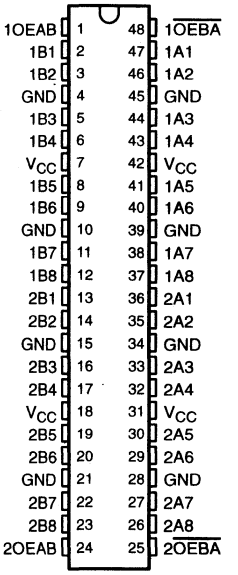
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Shrink Small-Outline 300-mil Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs are TTL-Voltage Compatible**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16623 is a 16-bit transceiver designed for asynchronous two-way communication between data buses. The control function implementation allows for maximum flexibility in timing.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the enable inputs ($\overline{OEBA}$ and OEAB) The enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives the bus transceiver the capability to store data by simultaneous enabling of $\overline{OEBA}$ and OEAB. Each output reinforces its input in this transceiver configuration. When both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, the bus lines remain at their last states.

The 74ACT16623 is packaged in TI's shrink small-outline package (SSOP), which provides twice the functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16623 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

INPUTS		OPERATION
$\overline{OEBA}$	OEAB	
L	L	B data to A bus
H	H	A data to B bus
H	L	Isolation
L	H	B data to A bus, A data to B bus

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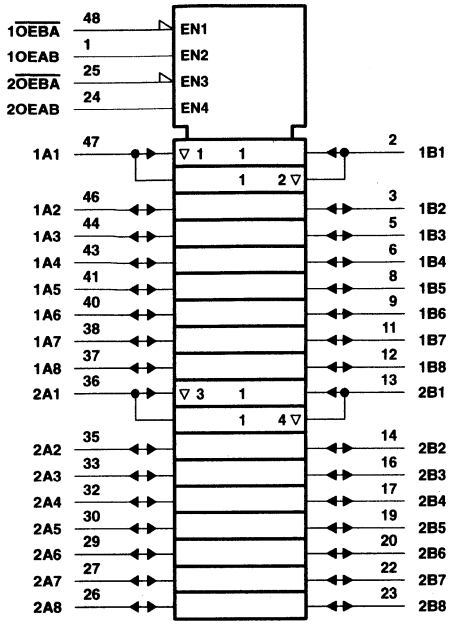
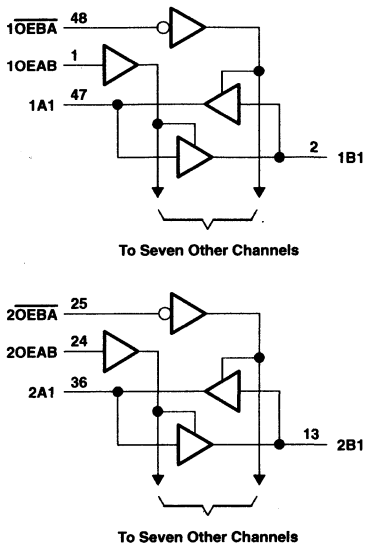
logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage (see Note 3)	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTES: 2. Unused or floating inputs should be connected to V_{CC} through a pullup resistor of approximately 5 kΩ or greater.
3. All V_{CC} and GND pins must be connected to the proper supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	TA = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = −50 µA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = −24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = −50 mA†	5.5 V						
		I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 50 mA†	5.5 V						
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	µA
I_{OZ}	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	µA
ΔI_{CC}‡		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4.5				pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		16				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

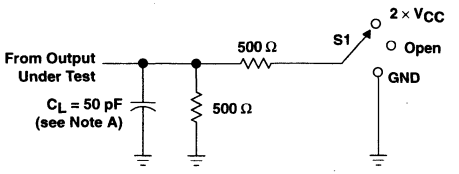
switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	4.2	7.3	9.5	4.2	10.4	ns
t_{PHL}			3.1	7.3	9.5	3.1	10.3	
t_{PZH}	$\overline{OEBA}$	A	2.7	6.8	8.8	2.7	9.5	ns
t_{PZL}			3.5	8.2	10.2	3.5	11.1	
t_{PHZ}	$\overline{OEBA}$	A	6	9.6	11.3	6	12	ns
t_{PLZ}			5.3	8.6	10.3	5.3	10.7	
t_{PZH}	OEAB	B	4.1	6.9	8.7	4.1	9.3	ns
t_{PZL}			5.1	7.9	9.7	5.1	10.6	
t_{PHZ}	OEAB	B	5.1	8.2	10.2	5.1	10.4	ns
t_{PLZ}			4.4	7.4	9.3	4.4	9.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

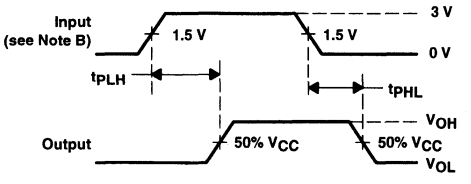
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	56	pF
		Outputs disabled		11	

PARAMETER MEASUREMENT INFORMATION

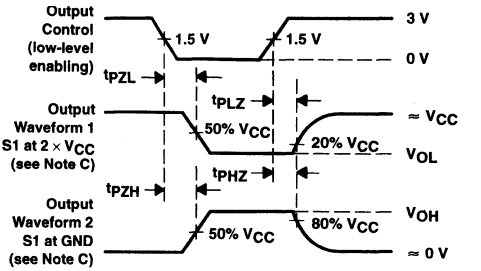


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



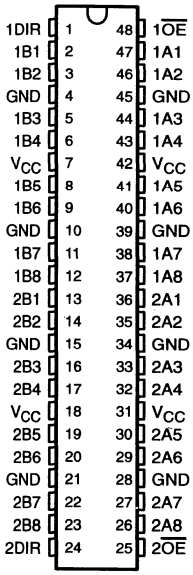
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16640 is an inverting 16-bit transceiver designed for asynchronous communication between data buses.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction-control (1DIR and 2DIR) inputs. The output-enable (1$\overline{OE}$ and 2$\overline{OE}$) inputs can be used to disable the device so that the buses are effectively isolated.

The 74ACT16640 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16640 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each section)

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	$\overline{B}$ data to A bus
L	H	$\overline{A}$ data to B bus
H	X	Isolation

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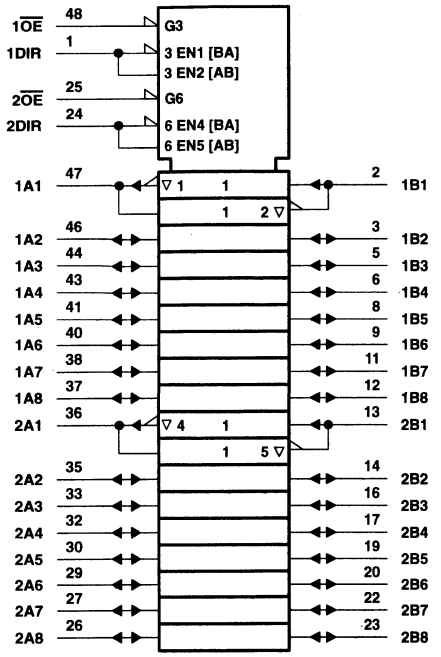
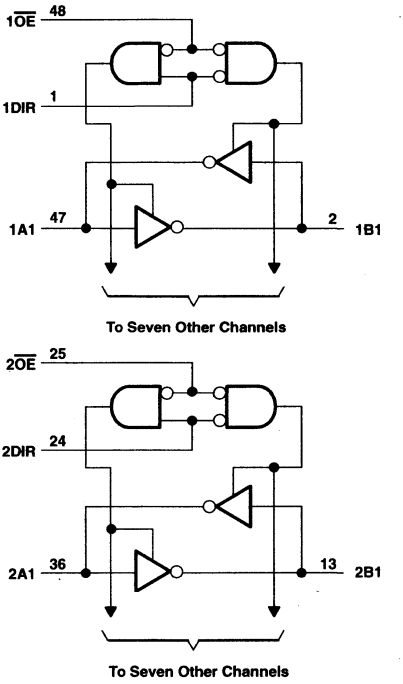
logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±400 mA
Maximum package power dissipation at T_A = 55°C (in still air)	0.85 W
Storage temperature range	−65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = −50 μA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = −24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 μA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±1		±1	μA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	μA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4.5				pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		16				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

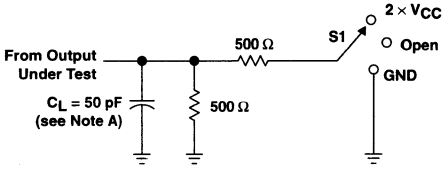
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see NO TAG)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	2.2	6	8.3	2.2	9.1	ns
t_{PHL}			4.1	7.6	9.3	4.1	10.5	
t_{PZH}	$\overline{OE}$	A or B	2.7	6.9	8.9	2.7	9.8	ns
t_{PZL}			3.5	8.2	10.4	3.5	11.5	
t_{PHZ}	$\overline{OE}$	A or B	6.1	9.4	11.4	6.1	12.5	ns
t_{PLZ}			5.5	8.7	10.3	5.5	11	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

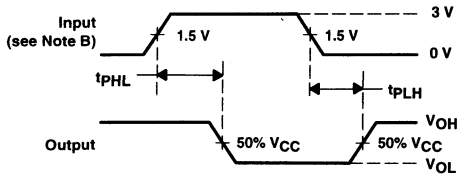
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	52	pF
		Outputs disabled		9	

PARAMETER MEASUREMENT INFORMATION

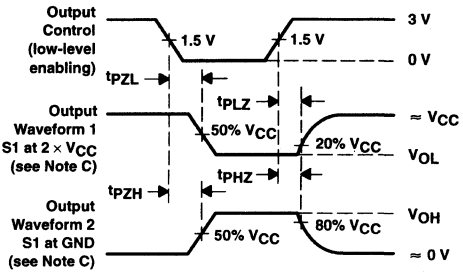


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



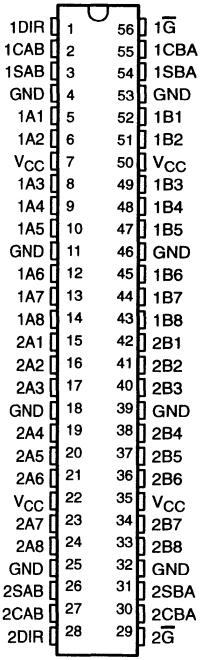
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Packaged in Shrink Small-Outline 300-mil Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **Independent Registers for A and B Buses**
- **Multiplexed Real-Time and Stored Data**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

54ACT16646 . . . WD PACKAGE
74ACT16646 . . . DL PACKAGE
(TOP VIEW)



description

The 'ACT16646 is a 16-bit bus transceiver which consists of D-type flip-flops and control circuitry with 3-state outputs arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The device can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock input (CAB or CBA). Figure 1 illustrates the four fundamental bus-management functions that can be performed with the bus transceivers and registers.

Output enable ($\overline{G}$) and direction (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select controls (SAB and SBA) can multiplex stored and real-time (transparent mode) data. The circuitry used for select control eliminates the typical decoding glitch which occurs in a multiplexer during the transition between stored and real-time data. The direction control determines which bus receives data when $\overline{G}$ is low. In the isolation mode ($\overline{G}$ high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

The 74ACT16646 is packaged in TI's shrink small-outline package (SSOP), which provides twice the functionality of standard small-outline packages in the same PCB area.

The 54ACT16646 is characterized for operation over the full military temperature range of – 55°C to 125°C. The 74ACT16646 is characterized for operation from – 40°C to 85°C.

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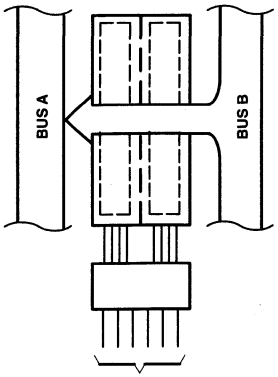
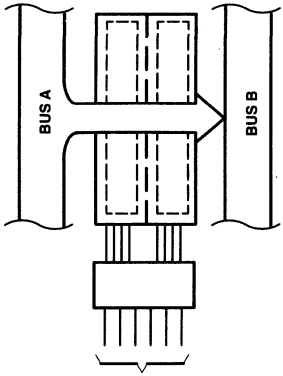


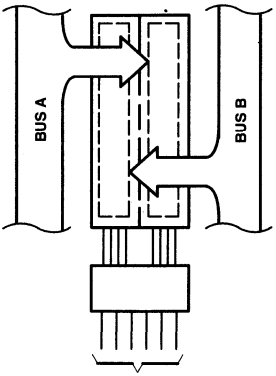
$\overline{G}$	$\overline{DIR}$	CAB	CBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER BUS B TO BUS A



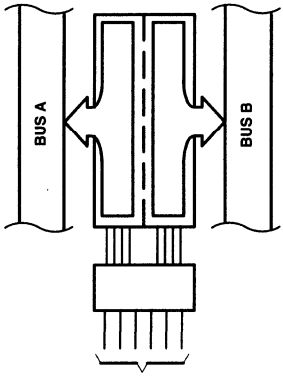
$\overline{G}$	$\overline{DIR}$	CAB	CBA	SAB	SBA
L	H	X	X	L	X

REAL-TIME TRANSFER BUS A TO BUS B



$\overline{G}$	DIR	CAB	CBA	SAB	SBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

STORAGE FROM A AND/OR B



$\overline{G}$	DIR	CAB	CBA	SAB	SBA
L	L	X	H or L	X	H
L	H	H or L	X	H	X

TRANSFER STORED DATA TO A AND/OR B

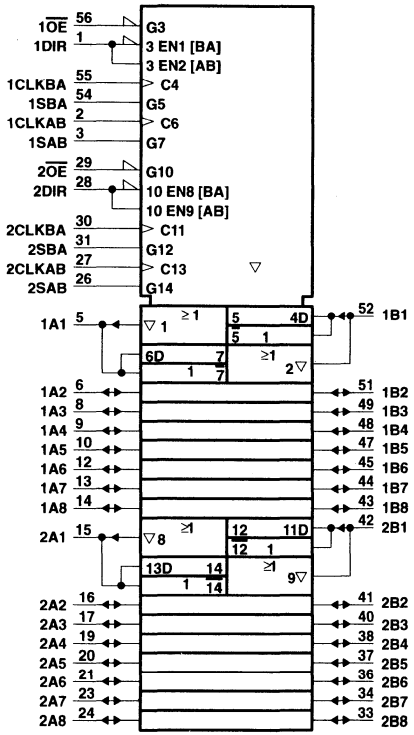
Figure 1. Bus-Management Functions

FUNCTION TABLE

INPUTS						DATA I/O		OPERATION OR FUNCTION
$\overline{G}$	DIR	CAB	CBA	SAB	SBA	A1 THRU A8	B1 THRU B8	
X	X	↑	X	X	X	Input	Unspecified†	Store A, B unspecified†
X	X	X	↑	X	X	Unspecified†	Input	Store B, A unspecified†
H	X	↑	↑	X	X	Input	Input	Store A and B Data
H	X	H or L	H or L	X	X	Input	Input	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-Time B Data to A Bus
L	L	X	H or L	X	H	Output	Input	Stored B Data to A Bus
L	H	X	X	L	X	Input	Output	Real-Time A Data to B Bus
L	H	H or L	X	H	X	Input	Output	Stored A Data to B Bus

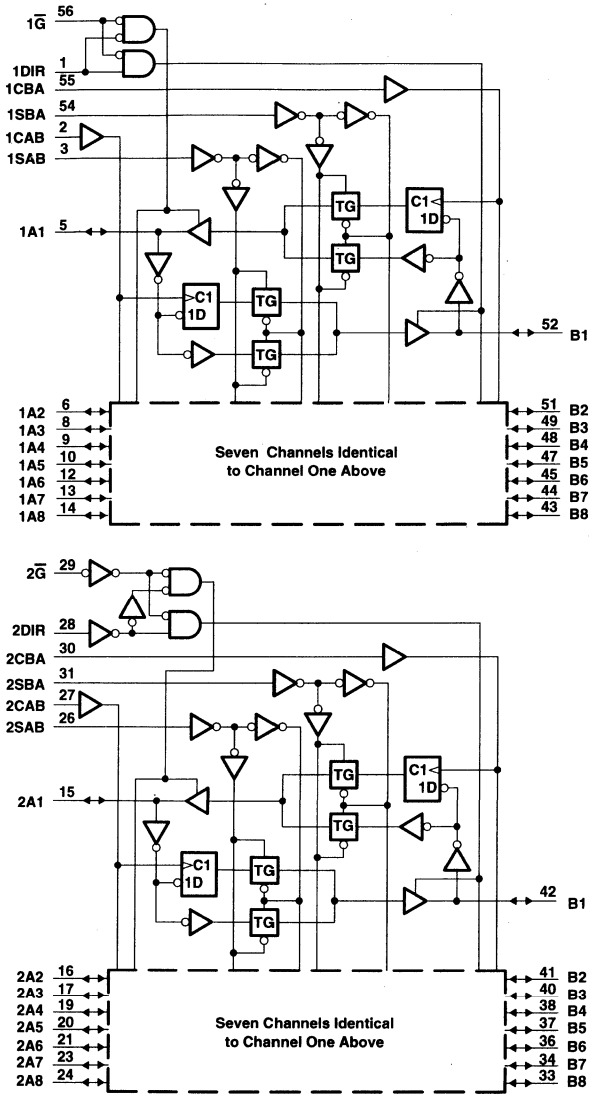
† The data output functions may be enabled or disabled by various signals at the $\overline{G}$ or DIR inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ± 20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ± 50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ± 50 mA
Continuous current through V_{CC} or GND ..... ± 400 mA
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

		54ACT16646		74ACT16646		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage (see Note 2)	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		−24		−24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	0	10	ns/V
T_A	Operating free-air temperature	−55	125	−40	85	°C

NOTE 2: All V_{CC} and GND pins must be connected to the proper voltage power supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16646		74ACT16646		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = – 50 µA	4.5 V	4.4			4.4		4.4		V
			5.5 V	5.4			5.4		5.4		
		I_{OH} = – 24 mA	4.5 V	3.94			3.7		3.8		
			5.5 V	4.94			4.7		4.8		
		I_{OH} = – 50 mA†	5.5 V				3.85				
		I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1		0.1	V
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		± 1		± 1	µA
I_{OZ}	A or B ports‡	$V_O = V_{CC}$ or GND	5.5 V			± 0.5		± 10		± 5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		160		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.9		1		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4						pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

			T_A = 25°C		54ACT16646		74ACT16646		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	90	0	90	0	90	MHz
t_w	Pulse duration, CAB or CBA high or low		5.5		5.5		5.5		ns
t_{su}	Setup time, A before CAB↑ or B before CBA↑	Data high	4		4		4		ns
		Data low	6		6		6		
t_h	Hold time, A before CAB↑ or B before CBA↑		1.5		1.5		1.5		ns

TEXAS INSTRUMENTS

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

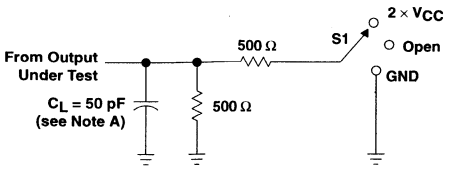
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16646		74ACT16646		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			90			90		90		MHz
t_{PLH}	A or B	B or A	3.9	7.5	9.4	3.9	11.5	3.9	10.6	ns
t_{PHL}			3.4	7.6	10.6	3.4	12.2	3.4	11.4	
t_{PZH}	$\overline{G}$	A or B	3.2	7.7	10.8	3.2	12.9	3.2	11.9	ns
t_{PZL}			4.2	9	12.2	4.2	14.6	4.2	13.5	
t_{PHZ}	$\overline{G}$	A or B	5.3	7.7	9.6	5.3	10.4	5.3	10.2	ns
t_{PLZL}			4.9	7.3	9.2	4.9	10.3	4.9	9.9	
t_{PLH}	CBA or CAB	A or B	4.9	8.9	11.1	4.9	13.1	4.9	12.2	ns
t_{PHL}			5.1	9	11	5.1	13.1	5.1	12.3	
t_{PLH}	SAB or SBA† (with A or B high)	A or B	5.2	10.3	13.8	5.2	17.2	5.2	15.6	ns
t_{PHL}			4.9	8.2	10.6	4.9	12.5	4.9	11.7	
t_{PLH}	SBA or SAB† (with A or B high)	A or B	4.3	7.8	9.9	4.3	12.1	4.3	11.1	ns
t_{PHL}			5.9	11.2	14.9	5.9	18.2	5.9	16.7	
t_{PZH}	DIR	A or B	4.5	9.5	13.6	4.5	16.2	4.5	15.2	ns
t_{PZL}			4.3	9.2	11.8	4.3	14.2	4.3	13.1	
t_{PHZ}	DIR	A or B	4.5	7.9	10.2	4.5	11.2	4.5	10.8	ns
t_{PLZ}			4.4	7.5	9.8	4.4	10.8	4.4	10.4	

† These parameters are measured with the internal output state of the storage register opposite to that of the bus input.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

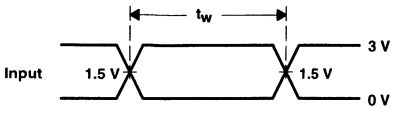
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	58	pF
		Outputs disabled		13	

PARAMETER MEASUREMENT INFORMATION

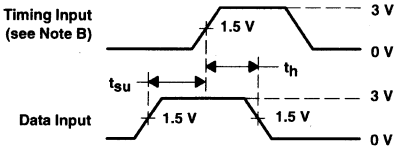


LOAD CIRCUIT

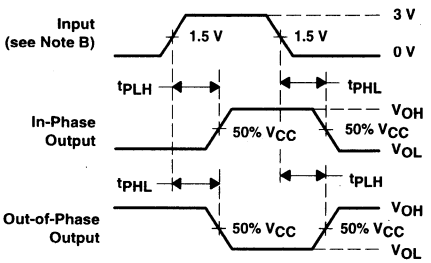
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



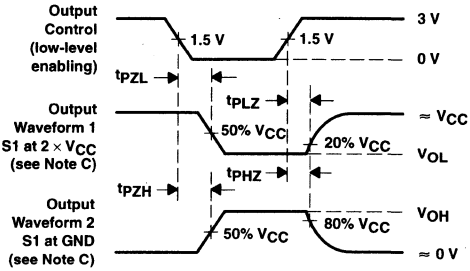
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



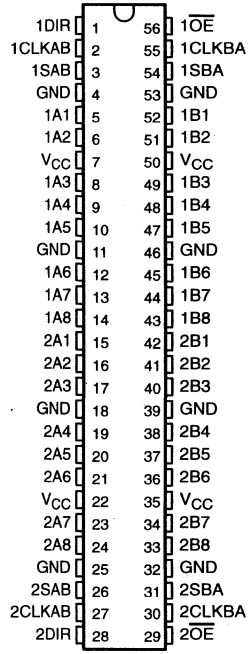
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Packages Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **Independent Registers for A and B Buses**
- **Inverting Data Path**
- **Multiplexed Real-Time and Stored Data**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16648 is a 16-bit bus transceiver that consists of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The device can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus will be clocked into the registers on the low-to-high transition of the appropriate clock pin (CLKAB or CLKBA). Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 74ACT16648.

Output-enable ($\overline{OE}$) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The circuitry used for select control will eliminate the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. The direction control (DIR) determines which bus will receive data when $\overline{OE}$ is low. In the isolation mode ($\overline{OE}$ high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

The 74ACT16648 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16648 is characterized for operation from –40°C to 85°C.

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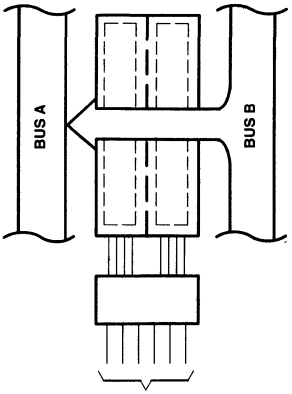
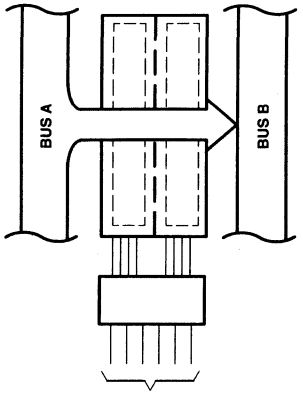


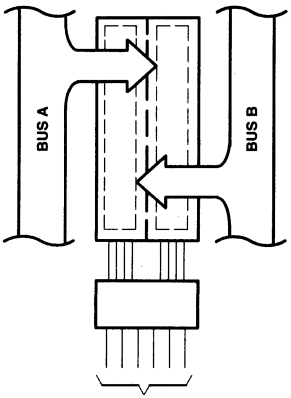
56 $\overline{OE}$	1 DIR	2 CLKAB	55 CLKBA	3 SAB	54 SBA
L	L	X	X	X	L

REAL-TIME TRANSFER
BUS B TO BUS A



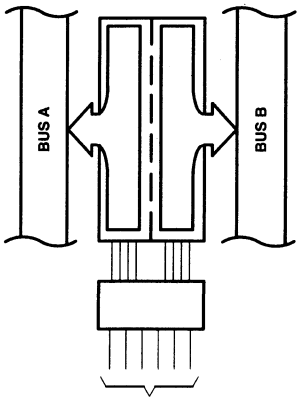
56 $\overline{OE}$	1 DIR	2 CLKAB	55 CLKBA	3 SAB	54 SBA
L	H	X	X	L	X

REAL-TIME TRANSFER
BUS A TO BUS B



56 $\overline{OE}$	1 DIR	2 CLKAB	55 CLKBA	3 SAB	54 SBA
X	X	↑	X	X	X
X	X	X	↑	X	X
H	X	↑	↑	X	X

STORAGE FROM
A, B, OR A AND B

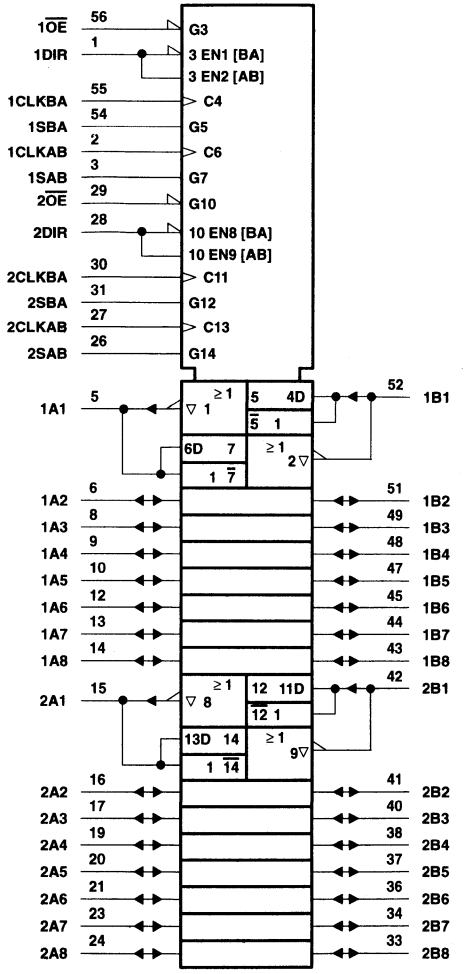


56 $\overline{OE}$	1 DIR	2 CLKAB	55 CLKBA	3 SAB	54 SBA
L	L	X	L	X	H
L	H	L	X	H	X

TRANSFER STORED DATA
TO A AND/OR B

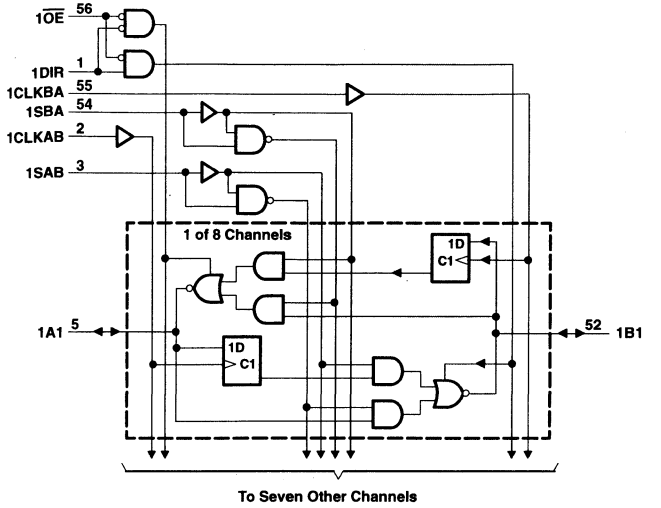
Figure 1. Bus-Management Functions

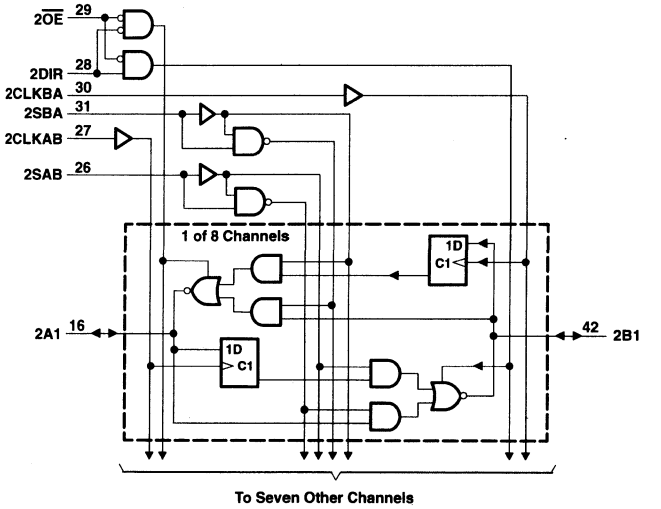
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





FUNCTION TABLE
(each 8-bit section)

INPUTS						DATA I/O		OPERATION OR FUNCTION
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	
X	X	↑	X	X	X	Input	Unspecified†	Store A, B unspecified†
X	X	X	↑	X	X	Unspecified†	Input	Store B, A unspecified†
H	X	↑	↑	X	X	Input	Input	Store A and B data
H	X	L	L	X	X	Input disabled	Input disabled	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-time $\overline{B}$ data to A bus
L	L	X	L	X	H	Output	Input	Stored $\overline{B}$ data to A bus
L	H	X	X	L	X	Input	Output	Real-time $\overline{A}$ data to B bus
L	H	L	X	H	X	Input	Output	Stored $\overline{A}$ data to B bus

† The data output functions may be enabled or disabled by a variety of level combinations at the $\overline{OE}$ and DIR inputs. Data input functions are always enabled; i.e., data at the bus pins is stored on every low-to-high transition on the clock inputs.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum package power dissipation at $T_A = 55°C$ (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = – 50 µA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = – 24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = –75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	µA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4				pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 2)

		T_A = 25°C		MIN	MAX	UNIT
		MIN	MAX			
f_{clock}	Clock frequency	0	75	0	75	MHz
t_w	Pulse duration, CLKAB or CLKBA high or low	6.5		6.5		ns
t_{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5		4.5		ns
t_h	Hold time, A after CLKAB↑ or B after CLKBA↑	1		1		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 2)

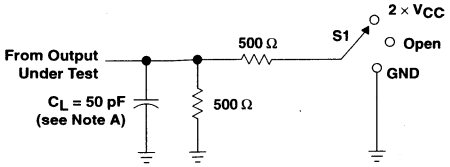
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f_{max}			75			75		MHz
t_{PLH}	A or B	B or A	2.4	7.2	9.8	2.4	11	ns
t_{PHL}			3.8	7.7	10.1	3.8	11.2	
t_{PZH}	$\overline{OE}$	A or B	2.9	7.9	10.7	2.9	12	ns
t_{PZL}			3.6	9.1	12.1	3.6	13.7	
t_{PHZ}			5.2	8.1	9.7	5.2	10.4	
t_{PLZ}			4.7	7.3	9.1	4.7	9.9	
t_{PLH}	CLKBA or CLKAB	A or B	4.4	8.5	11.3	4.4	12.7	ns
t_{PHL}			4.6	8.8	11.4	4.6	12.7	
t_{PLH}	SBA or SAB† (with A or B high)	A or B	3.8	7.5	10	3.8	11.3	ns
t_{PHL}			5.1	11.4	12.7	5.1	16.6	
t_{PLH}	SBA or SAB† (with A or B low)	A or B	4.5	10.6	13.9	4.5	15.8	ns
t_{PHL}			4.3	8.3	10.8	4.3	11.9	
t_{PZH}	DIR	A or B	2.8	7.8	10.7	2.8	11.9	ns
t_{PZL}			3.7	9.3	12.2	3.7	13.7	
t_{PHZ}			4.6	8.6	10.9	4.6	11.5	
t_{PLZ}			4	7.4	9.7	4	10.4	

† These parameters are measured with the internal output state of the storage registers opposite to that of the bus input.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

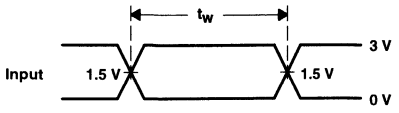
PARAMETER			TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF,	f = 1 MHz	63	pF
		Outputs disabled			14	

PARAMETER MEASUREMENT INFORMATION

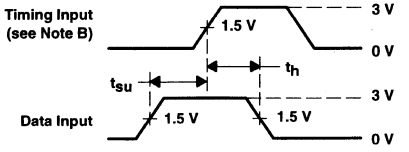


LOAD CIRCUIT

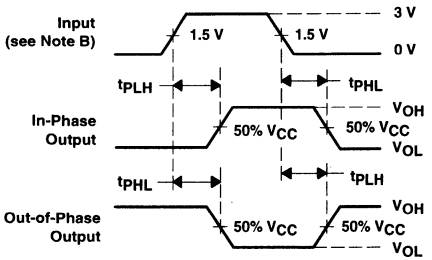
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



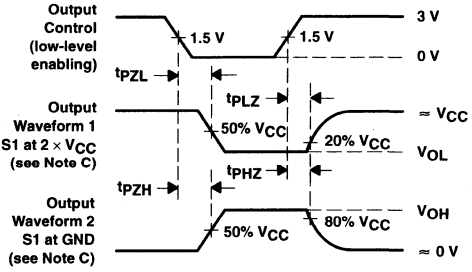
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

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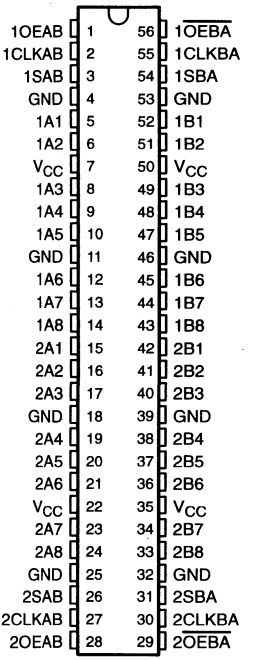
- **500-mA Typical Latch-Up Immunity at 125°C**

54ACT16651 . . . WD PACKAGE
74ACT16651 . . . DL PACKAGE
(TOP VIEW)



description

The 'ACT16651 is a 16-bit bus transceiver that consists of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The device can be used as two 8-bit transceivers or one 16-bit transceiver.

Complementary output-enable (OEAB and $\overline{\text{OEBA}}$) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ACT16651.

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the levels on the select-control or output-enable inputs. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and $\overline{\text{OEBA}}$. In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus line are at high impedance, each set of bus lines remains at its last state.

The 74ACT16651 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16651 is characterized for operation over the full military temperature range of −55°C to 125°C. The 74ACT16651 is characterized fro operation from −40°C to 85°C.

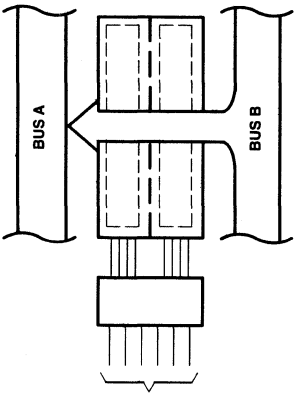
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

FUNCTION TABLE

INPUTS						DATA I/O†		OPERATION OR FUNCTION
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	
L	H	L	L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	L	X	X	Input	Unspecified‡	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	L	↑	X	X	Unspecified‡	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time $\overline{B}$ data to A bus
L	L	X	L	X	H	Output	Input	Stored $\overline{B}$ data to A bus
H	H	X	X	L	X	Input	Output	Real-time $\overline{A}$ data to B bus
H	H	L	X	H	X	Input	Output	Stored $\overline{A}$ data to B bus
H	L	L	L	H	H	Output	Output	Stored $\overline{A}$ data to B bus and stored $\overline{B}$ data to A bus

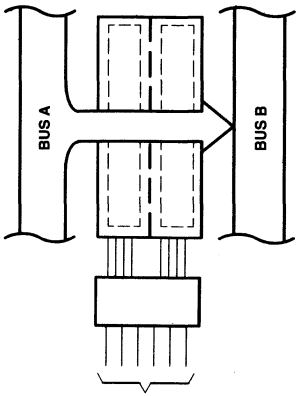
† The data output functions may be enabled or disabled by a variety of level combinations at the OEAB or $\overline{OEBA}$ inputs. Data input functions are always enabled; i.e., data at the bus pins is stored on every low-to-high transition on the clock inputs.

‡ Select control = L; clocks can occur simultaneously.
Select control = H; clocks must be staggered in order to load both registers.



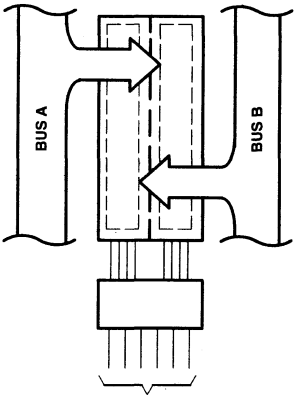
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER
BUS B TO BUS A



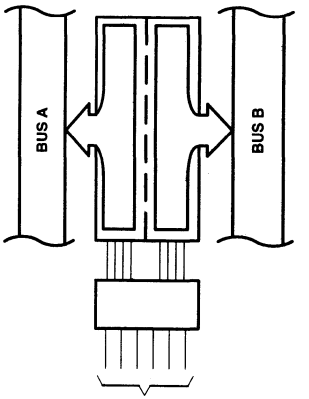
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	H	X	X	L	X

REAL-TIME TRANSFER
BUS A TO BUS B



OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

STORAGE FROM
A, B, OR A AND B

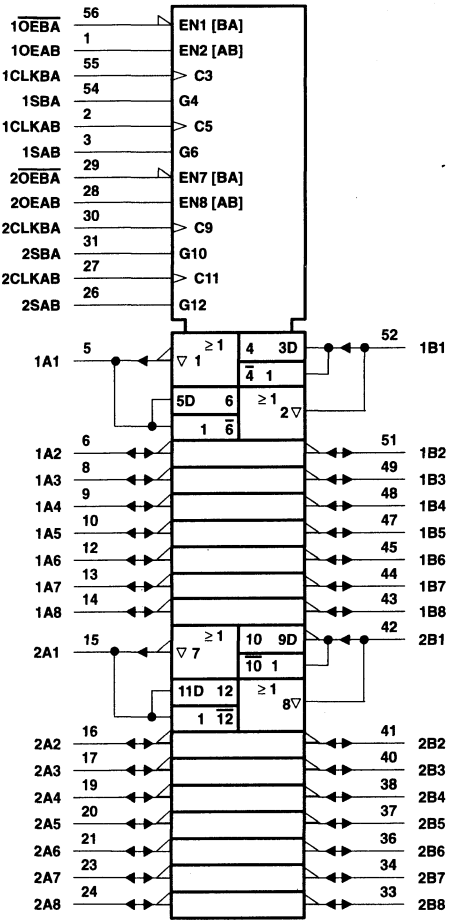


OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	L	L	L	H	H

TRANSFER STORED DATA
TO A AND/OR B

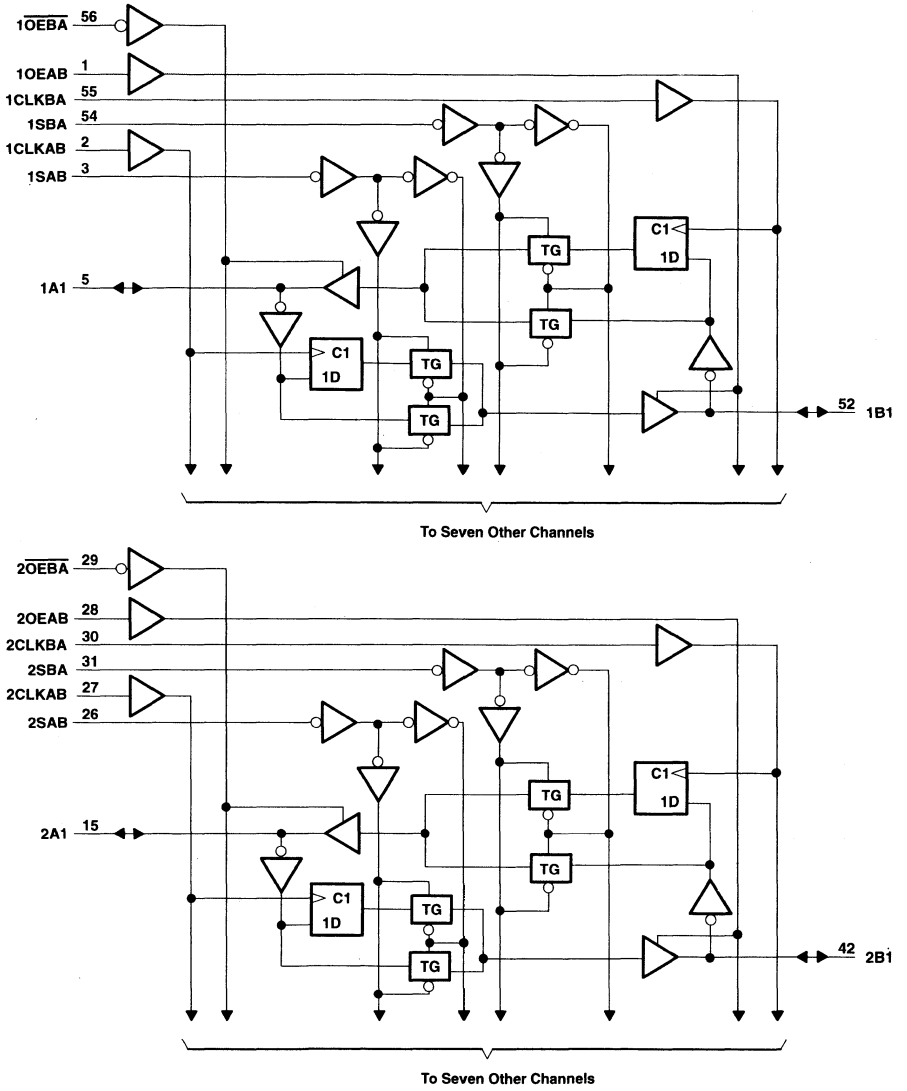
Figure 1. Bus-Management Functions

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagrams (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum package power dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		54ACT16651			74ACT16651			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current			−24			−24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
T_A	Operating free-air temperature	−55		125	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16651		74ACT16651		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = – 50 µA	4.5 V	4.4			4.4		4.4		V
			5.5 V	5.4			5.4		5.4		
		I_{OH} = – 24 mA	4.5 V	3.94			3.7		3.8		
			5.5 V	4.94			4.7		4.8		
		I_{OH} = –50 mA†	5.5 V				3.85				
		I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1		0.1	V
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		160		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4						pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 2)

		T_A = 25°C		54ACT16651		74ACT16651		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	90	0	90	0	90	MHz
t_w	Pulse duration, CLKAB or CLKBA high or low	5.5		5.5		5.5		ns
t_{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	5.3		5.3		5.3		ns
t_h	Hold time, A after CLKAB↑ or B after CLKBA↑	1		1		1		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 2)

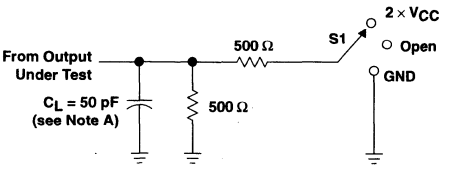
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16651		74ACT16651		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			90			90		90		MHz
t_{PLH}	A or B	B or A	3	6.6	10	3	12.2	3	11.3	ns
t_{PHL}			4.6	8	10.6	4.6	12.7	4.6	11.9	
t_{PLH}	CLKBA or CLKAB	A or B	5.4	9.1	12	5.4	14.8	5.4	13.7	ns
t_{PHL}			5.4	9.1	12	5.4	14.6	5.4	13.6	
t_{PLH}	SBA or SAB (with A or B high)	A or B	4.6	7.9	10.5	4.6	13.1	4.6	12.1	ns
t_{PHL}			5.4	10.9	15.5	5.4	19.6	5.4	17.8	
t_{PLH}	SBA or SAB (with A or B low)	A or B	5	10.4	14.9	5	19.2	5	17.3	ns
t_{PHL}			4.9	8.6	11.9	4.9	13.7	4.9	12.7	
t_{PZH}	$\overline{OEBA}$	A	3.2	7.2	10.8	3.2	13.6	3.2	12.3	ns
t_{PZL}			3.8	8	12.2	3.8	15.3	3.8	13.9	
t_{PHZ}	$\overline{OEBA}$	A	5.1	7.8	9.8	5.1	11.3	5.1	10.6	ns
t_{PLZ}			4.9	7.7	9.9	4.9	11.4	4.9	10.8	
t_{PZH}	OEAB	B	4.9	8	10.5	4.9	12.9	4.9	11.9	ns
t_{PZL}			5.4	8.8	11.8	5.4	14.7	5.4	13.5	
t_{PHZ}	OEAB	B	4.3	7.5	10.7	4.3	12	4.3	11.4	ns
t_{PLZ}			4.5	7.6	10.8	4.5	12.3	4.5	11.6	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	62	pF
		Outputs disabled		14	

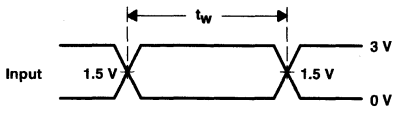
TEXAS INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION

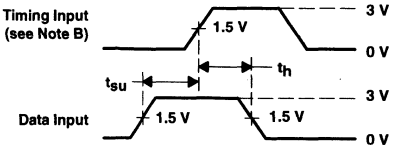


LOAD CIRCUIT

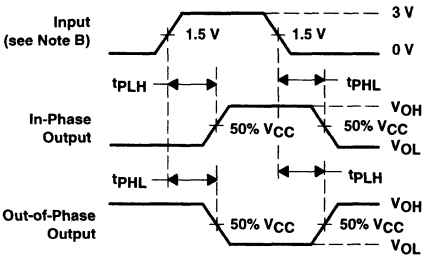
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × VCC
t_{PHZ}/t_{PZH}	GND



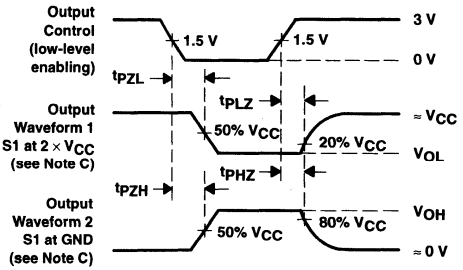
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



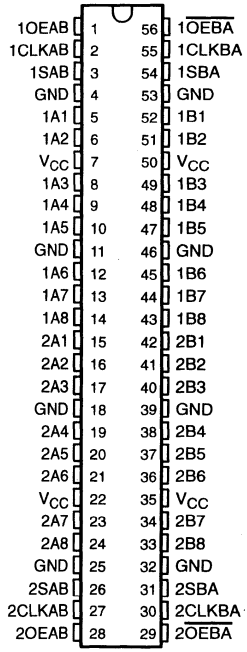
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **Independent Registers and Enables for A and B Buses**
- **Multiplexed Real-Time and Stored Data**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16652 is a 16-bit bus transceiver that consists of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The device can be used as two 8-bit transceivers or one 16-bit transceiver.

Complementary output-enable (OEAB and $\overline{\text{OEBA}}$) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 74ACT16652.

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L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	L	X	X	Input	Unspecified‡	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	L	↑	X	X	Unspecified‡	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	L	X	H	X	Input	Output	Stored A data to B bus
H	L	L	L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

† The data output functions may be enabled or disabled by a variety of level combinations at the OEAB or $\overline{OEBA}$ inputs. Data input functions are always enabled; i.e., data at the bus pins is stored on every low-to-high transition on the clock inputs.

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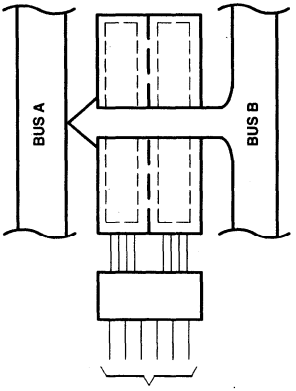
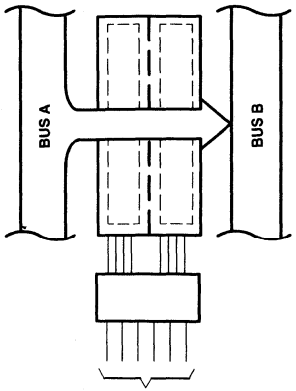
Select control = H; clocks must be staggered in order to load both registers.



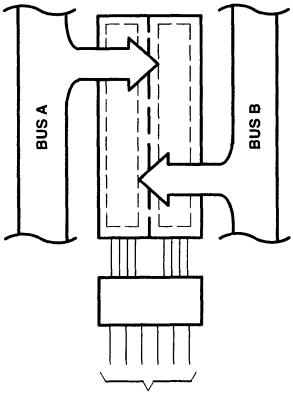
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER
BUS B TO BUS A



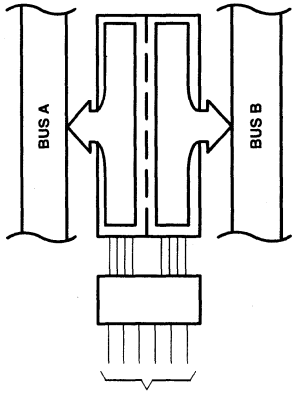
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	H	X	X	L	X

REAL-TIME TRANSFER
BUS A TO BUS B



OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

STORAGE FROM
A, B, OR A AND B

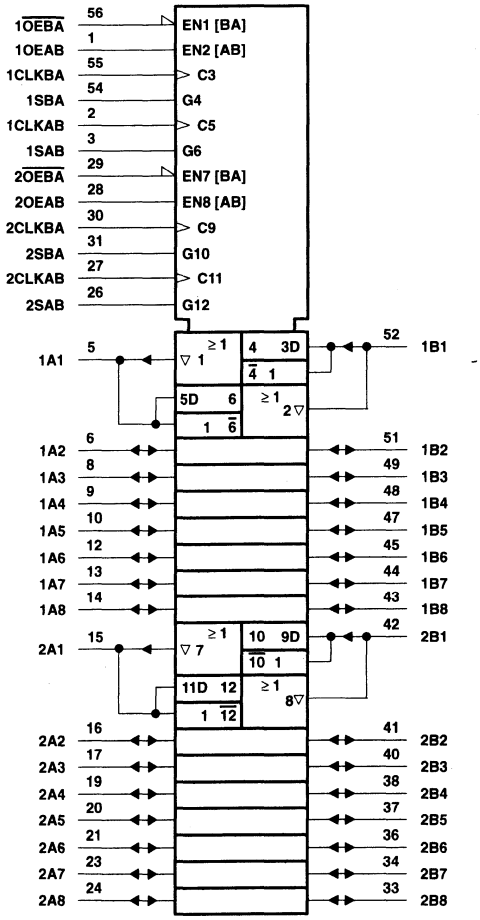


OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	L	L	L	H	H

TRANSFER STORED DATA
TO A AND/OR B

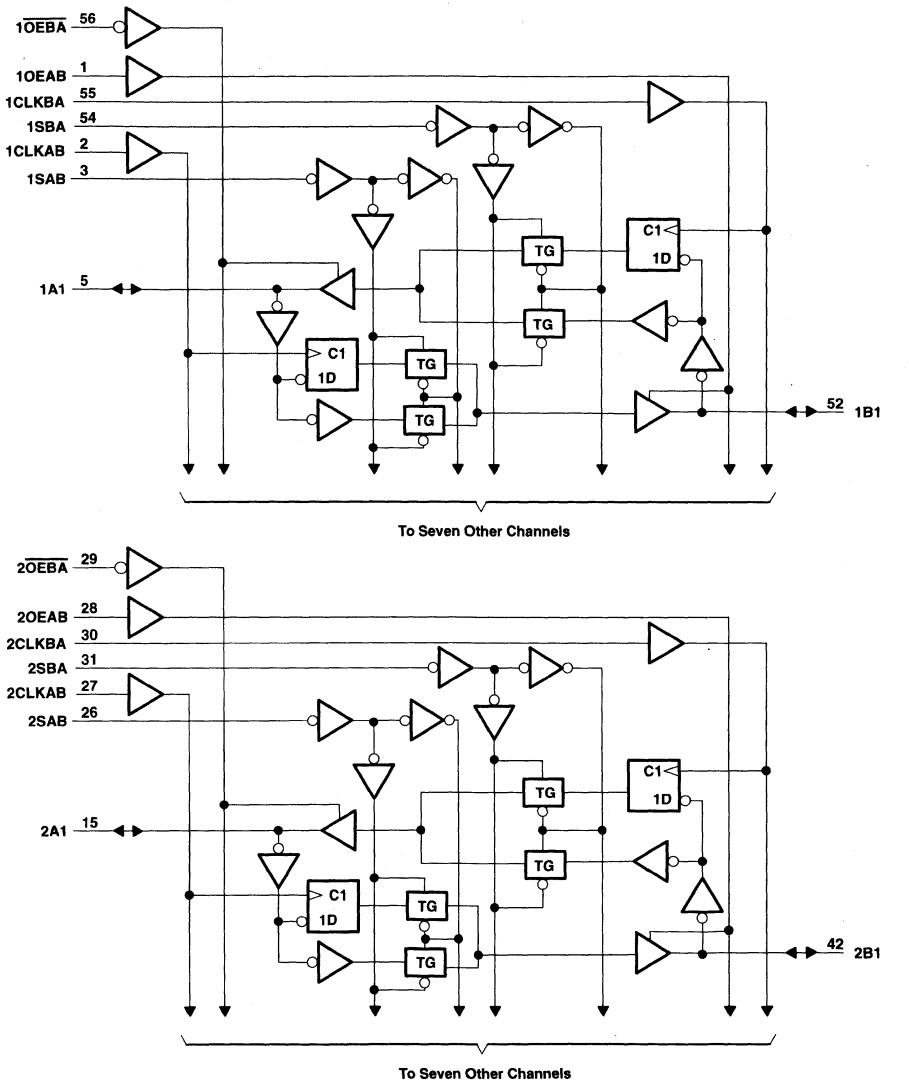
Figure 1. Bus-Management Functions

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagrams (positive logic)



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Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum package power dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = – 50 µA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = – 24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = –75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	µA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4				pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		MIN	MAX	UNIT
		MIN	MAX			
f_{clock}	Clock frequency	0	90	0	90	MHz
t_w	Pulse duration, CLKAB or CLKBA high or low	5.5		5.5		ns
t_{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5		4.5		ns
t_h	Hold time, A after CLKAB↑ or B after CLKBA↑	1		1		ns

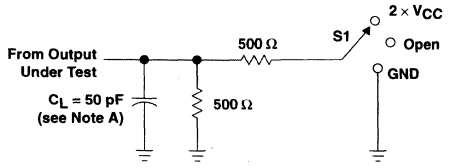
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f_{max}			90			90		MHz
t_{PLH}	A or B	B or A	3.7	7.2	9.4	3.7	10.5	ns
t_{PHL}			3	8.1	10.5	3	11.6	
t_{PLH}	CBA or CAB	A or B	4.5	8.7	11.2	4.5	12.3	ns
t_{PHL}			4.9	8.9	11.3	4.9	12.3	
t_{PLH}	SBA or SAB (with A or B high)	A or B	4.9	10.4	14.1	4.9	16	ns
t_{PHL}			4.6	8.4	10.6	4.6	11.7	
t_{PLH}	SBA or SAB (with A or B low)	A or B	3.9	7.8	10	3.9	11.2	ns
t_{PHL}			5.6	12.3	14.9	5.6	16.9	
t_{PZH}	$\overline{OEBA}$	A	3	8.1	10.5	3	11.7	ns
t_{PZL}			3.9	9.4	12	3.9	13.4	
t_{PHZ}	$\overline{OEBA}$	A	5.3	7.4	8.9	5.3	9.5	ns
t_{PLZ}			4.8	6.8	8.6	4.8	9.2	
t_{PZH}	OEAB	B	4.1	7.7	9.8	4.1	10.8	ns
t_{PZL}			5	9	11	5	12.4	
t_{PHZ}	OEAB	B	4.4	8.1	10.1	4.4	10.5	ns
t_{PLZ}			4.3	7.7	9.7	4.3	9.9	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

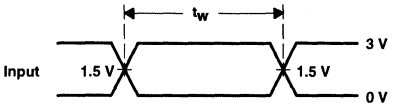
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	57	pF
		Outputs disabled		13	

PARAMETER MEASUREMENT INFORMATION

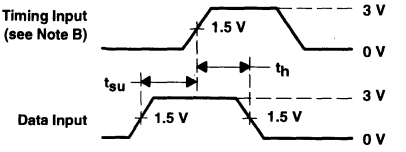


LOAD CIRCUIT

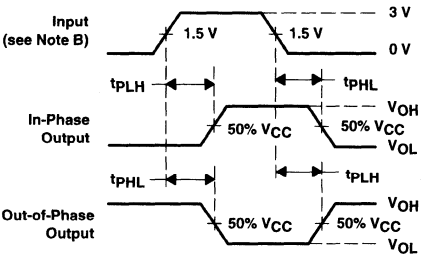
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



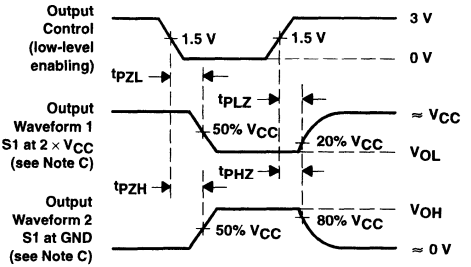
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



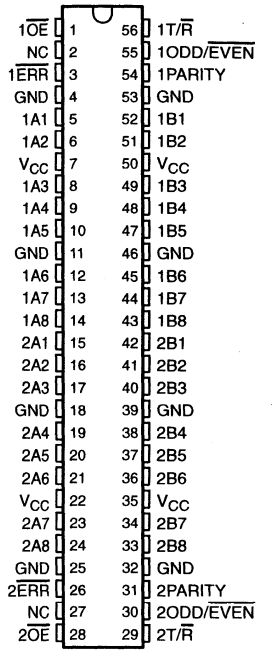
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16657 contains two noninverting octal transceiver sections with separate parity generator/checker circuits and control signals. For either section, the transmit/receive (1T/$\overline{R}$ or 2T/$\overline{R}$) input determines the direction of data flow. When 1T/$\overline{R}$ (or 2T/$\overline{R}$) is high, data flows from the 1A (or 2A) port to the 1B (or 2B) port (transmit mode); when 1T/$\overline{R}$ (or 2T/$\overline{R}$) is low, data flows from the 1B (or 2B) port to the 1A (or 2A) port (receive mode). When the output-enable (1$\overline{OE}$ or 2$\overline{OE}$) input is high, both the 1A (or 2A) and 1B (or 2B) ports are in the high-impedance state.

Odd or even parity is selected by a logic high or low level, respectively, on the 1ODD/$\overline{EVEN}$ (or 2ODD/$\overline{EVEN}$) input. 1PARITY (or 2PARITY) carries the parity bit value; it is an output from the parity generator/checker in the transmit mode and an input to the parity generator/checker in the receive mode.

In the transmit mode, after the 1A (or 2A) bus is polled to determine the number of high bits, 1PARITY (or 2PARITY) is set to the logic level that maintains the parity sense selected by the level at the 1ODD/$\overline{EVEN}$ (or 2ODD/$\overline{EVEN}$) input. For example, if 1ODD/$\overline{EVEN}$ is low (even parity selected) and there are five high bits on the 1A bus, then 1PARITY is set to the logic high level so that an even number of the nine total bits (eight 1A-bus bits plus parity bit) are high.

In the receive mode, after the 1B (or 2B) bus is polled to determine the number of high bits, the 1$\overline{ERR}$ (or 2$\overline{ERR}$) output logic level indicates whether or not the data to be received exhibits the correct parity sense. For example, if 1ODD/$\overline{EVEN}$ is high (odd parity selected), 1PARITY is high, and there are three high bits on the 1B bus, then 1$\overline{ERR}$ is low, indicating a parity error.

The 74ACT16657 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

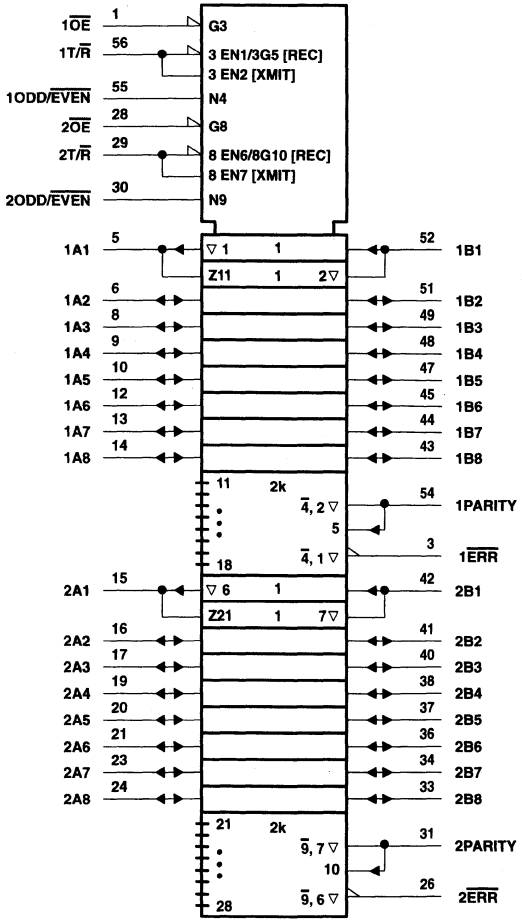
The 74ACT16657 is characterized for operation from –40°C to 85°C.

EPIC and Widebus are trademarks of Texas Instruments Incorporated.

FUNCTION TABLE

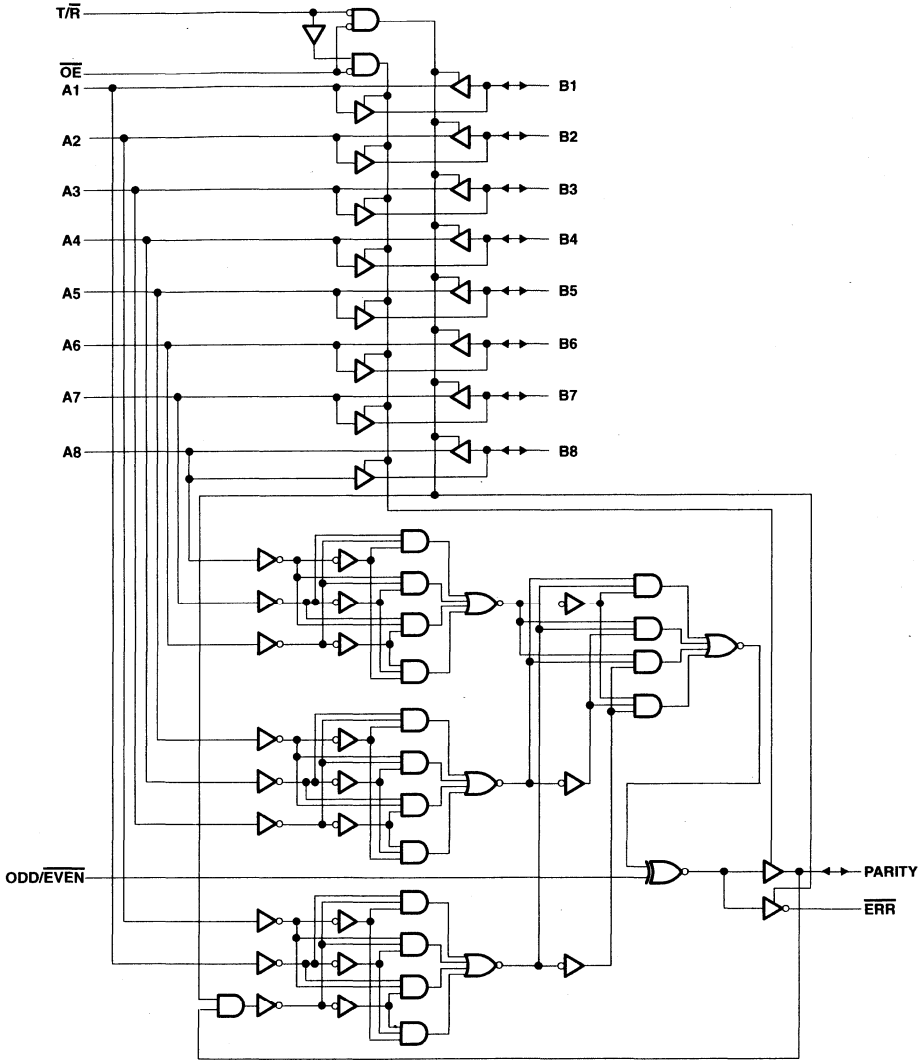
NUMBER OF A OR B INPUTS THAT ARE HIGH	INPUTS			INPUT/OUTPUT PARITY	OUTPUTS	
	$\overline{OE}$	T/$\overline{R}$	ODD/$\overline{EVEN}$		$\overline{ERR}$	OUTPUT MODE
0, 2, 4, 6, 8	L	H	H	H	Z	Transmit
	L	H	L	L	Z	Transmit
	L	L	H	H	H	Receive
	L	L	H	L	L	Receive
	L	L	L	H	L	Receive
	L	L	L	L	H	Receive
1, 3, 5, 7	L	H	H	L	Z	Transmit
	L	H	L	H	Z	Transmit
	L	L	H	H	L	Receive
	L	L	H	L	H	Receive
	L	L	L	H	H	Receive
	L	L	L	L	L	Receive
Don't care	H	X	X	Z	Z	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram, each transceiver (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±500 mA
Maximum package power dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = – 50 µA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = – 24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = – 75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	A or B ports	V_I = V_{CC} or GND	5.5 V			±0.1		±1	µA
I_{OZ}‡	Control Inputs	V_O = V_{CC} or GND	5.5 V			±0.5		±5	µA
I_{CC}		V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	V_I = V_{CC} or GND	5 V		4.5				pF
C_o	$\overline{ERR}$	V_O = V_{CC} or GND	5 V		11				pF
C_{io}	A or B ports	V_O = V_{CC} or GND	5 V		12				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

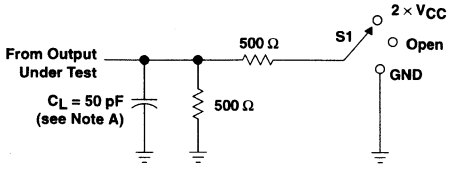
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	4.1	7.3	9.6	4.1	10.7	ns
t_{PHL}			3.2	6.8	9.8	3.2	10.6	
t_{PLH}	A	PARITY	4	8.6	12.9	4	14.3	ns
t_{PHL}			4.3	9	13.1	4.3	14.3	
t_{PLH}	ODD/$\overline{EVEN}$	PARITY, $\overline{ERR}$	3.7	8.3	12.3	3.7	13.7	ns
t_{PHL}			4.1	8.8	12.8	4.1	14.1	
t_{PLH}	B	$\overline{ERR}$	3.9	8.6	13	3.9	14.6	ns
t_{PHL}			4.3	9	13.3	4.3	14.7	
t_{PLH}	PARITY	$\overline{ERR}$	3.8	8.4	12.2	3.8	13.8	ns
t_{PHL}			4.1	8	12.8	4.1	14.2	
t_{PZH}	$\overline{OE}$	A, B, PARITY, or $\overline{ERR}$	2.6	6.1	10.1	2.6	11.3	ns
t_{PZL}			3.2	7.2	11.7	3.2	13	
t_{PHZ}	$\overline{OE}$	A, B, PARITY, or $\overline{ERR}$	5.9	8.6	10.5	5.9	11.2	ns
t_{PLZ}			5.3	8	9.8	5.3	10.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

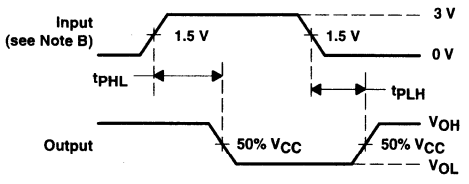
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	76	pF
		Outputs disabled		35	

PARAMETER MEASUREMENT INFORMATION

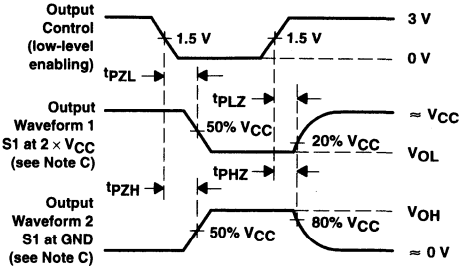


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



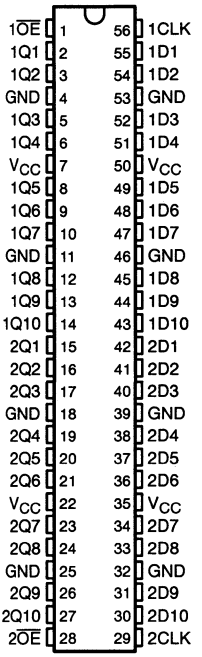
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Inputs Are TTL-Voltage Compatible**
- **Provide Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings**

54ACT16821 . . . WD PACKAGE
74ACT16821 . . . DL PACKAGE
(TOP VIEW)



description

These 20-bit flip-flops feature 3-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, parity bus interfacing, and working registers.

The 'ACT16821 can be used as two 10-bit flip-flops or one 20-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs follow the data (D) inputs. Each 10-bit flip-flop section has a buffered output-enable ($1\overline{OE}$ or $2\overline{OE}$) input that can be used to place the ten outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

$\overline{OE}$ does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74ACT16821 is packaged in theTI shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

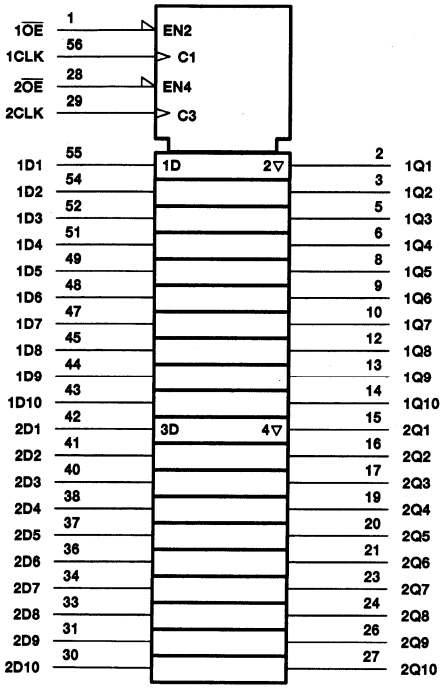
The 54ACT16821 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16821 is characterized for operation from –40°C to 85°C.

EPIC and Widebus are trademarks of Texas Instruments Incorporated.

FUNCTION TABLE
(each 10-bit flip-flop)

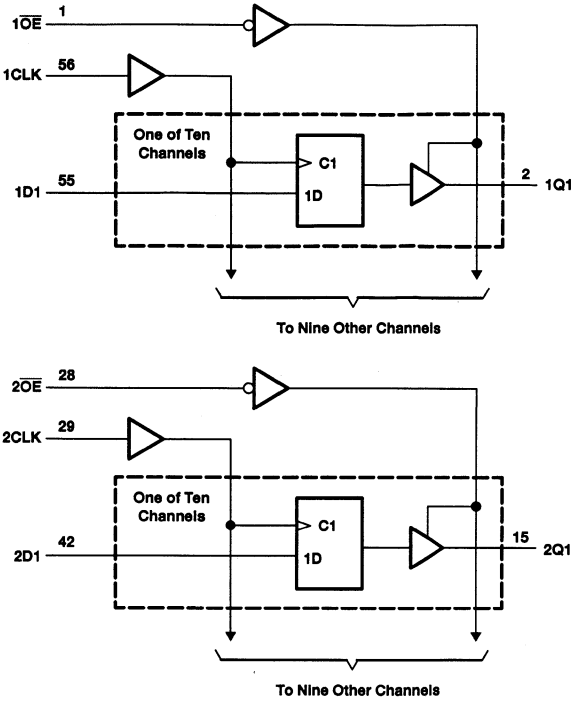
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±500 mA
Maximum package power dissipation at $T_A = 55°C$ (in still air) (see Note 2): DL package ..... 1.4 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		54ACT16821			74ACT16821			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current			–24			–24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate			10	0		10	ns/V
T_A	Operating free-air temperature	–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16821		74ACT16821		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	4.5 V	4.4			4.4		4.4		V
		5.5 V	5.4			5.4		5.4		
	I_{OH} = –24 mA	4.5 V	3.94			3.8		3.8		
		5.5 V	4.94			4.8		4.8		
	I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.44		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80		80	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1		1	mA
C_i	$V_I = V_{CC}$ or GND	5 V		3						pF
C_i	$V_O = V_{CC}$ or GND	5 V		11						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		54ACT16821		74ACT16821		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	70	0	70	0	70	MHz
t_w	Pulse duration, CLK high or low	7		7		7		ns
t_{su}	Setup time, data before CLK↑	7.5		7.5		7.5		ns
t_h	Hold time, data after CLK↑	0.5		0.5		0.5		ns

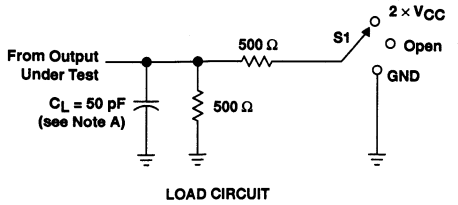
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16821		74ACT16821		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			70			70		70		MHz
t_{PLH}	CLK	Any Q	4.5	8.8	12	4.5	13.4	4.5	13.4	ns
t_{PHL}			5.2	9.5	12.6	5.2	14	5.2	14	
t_{PZH}	$\overline{OE}$	Any Q	2.8	8.6	10.8	2.8	11.9	2.8	11.9	ns
t_{PZL}			4	9.7	13.3	4	14.7	4	14.7	
t_{PHZ}	$\overline{OE}$	Any Q	5.4	8.3	10	5.4	10.7	5.4	10.7	ns
t_{PLZ}			4.7	7.6	9.3	4.7	10	4.7	10	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

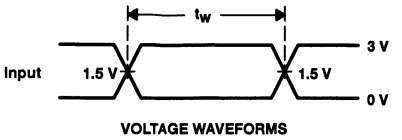
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per flip-flop	Outputs enabled	CL = 50 pF, f = 1 MHz	41	pF
		Outputs disabled		25	

PARAMETER MEASUREMENT INFORMATION

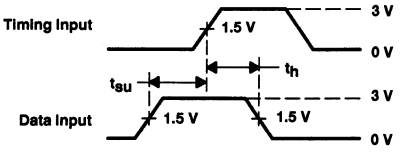


LOAD CIRCUIT

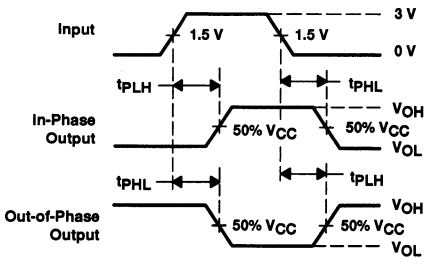
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



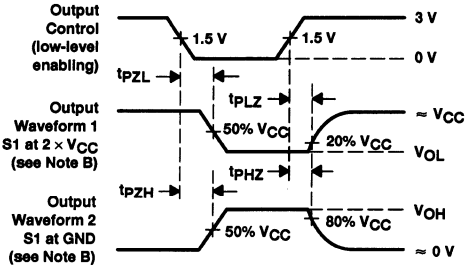
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



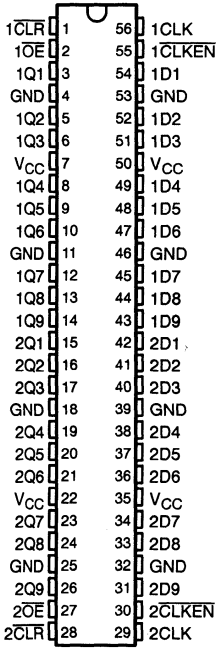
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Inputs Are TTL-Voltage Compatible**
- **Provide Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings**

54ACT16823 . . . WD PACKAGE
74ACT16823 . . . DL PACKAGE
(TOP VIEW)



description

These 18-bit flip-flops feature 3-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, parity bus interfacing, and working registers.

The 'ACT16823 can be used as two 9-bit flip-flops or one 18-bit flip-flop. With the clock-enable ($\overline{CLKEN}$) input low, the D-type flip-flops enter data on the low-to-high transitions of the clock. Taking $\overline{CLKEN}$ high disables the clock buffer, thus latching the outputs. Taking the clear ($\overline{CLR}$) input low causes the Q outputs to go low independently of the clock.

A buffered output-enable ($\overline{OE}$) input can be used to place the outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

$\overline{OE}$ does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74ACT16823 is packaged in theTI shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16823 is characterized for operation over the full military temperature range of 55°C to 125°C. The 74ACT16823 is characterized for operation from –40°C to 85°C

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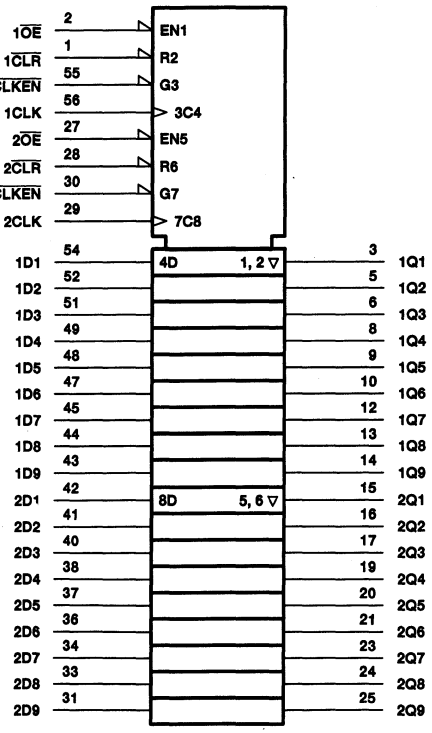
FUNCTION TABLE
(each 9-bit stage)

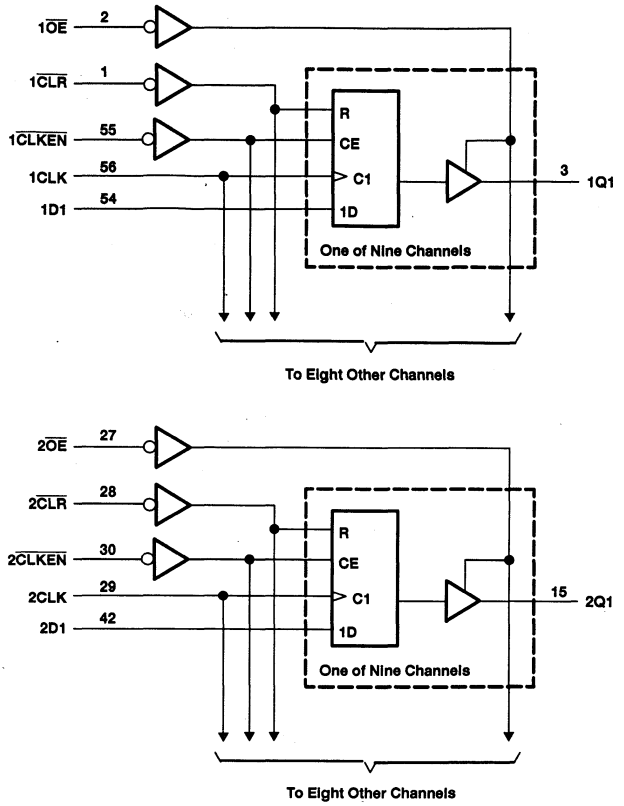
INPUTS					OUTPUT
$\overline{OE}$	$\overline{CLR}$	$\overline{CLKEN}$	CLK	D	Q
L	L	X	X	X	L
L	H	L	↑	H	H
L	H	L	↑	L	L
L	H	L	L	X	Q_0
L	H	H	X	X	Q_0
H	X	X	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±450 mA
Maximum package power dissipation at T_A = 55°C (in still air) (see Note 2): DL package ..... 1.4 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 2)

		54ACT16823			74ACT16823			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current			–24			–24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
T_A	Operating free-air temperature	–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16823		74ACT16823		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	4.5 V	4.4			4.4		4.4		V
		5.5 V	5.4			5.4		5.4		
	I_{OH} = –24 mA	4.5 V	3.94			3.8		3.8		
		5.5 V	4.94			4.8		4.8		
	I_{OH}= –75 mA†	5.5 V				3.85		3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V			0.1		0.1		0.1	V
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.44		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80		80	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1		1	mA
C_i	V_I = V_{CC} or GND	5 V		3						pF
C_o	V_O = V_{CC} or GND	5 V		12						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		54ACT16823		74ACT16823		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	90	0	90	0	90	MHz
t_w	Pulse duration	$\overline{CLR}$ low	3.3		3.3		3.3		ns
		CLK high or low	5.5		5.5		5.5		
t_{su}	Setup time before CLK↑	$\overline{CLR}$ inactive	0.5		0.5		0.5		ns
		Data	7		7		7		
		$\overline{CLKEN}$ low	3.5		3.5		3.5		
t_h	Hold time after CLK↑	Data	0.5		0.5		0.5		ns
		$\overline{CLKEN}$ high or low	2.5		2.5		2.5		

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

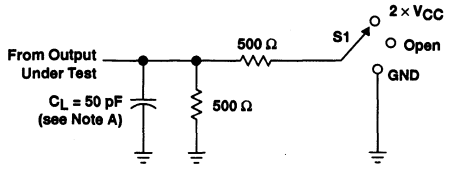
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16823		74ACT16823		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			90			90		90		MHz
t_{PLH}	CLK	Q	4.2	7.5	10.6	4.2	12.1	4.2	12.1	ns
t_{PHL}			4.8	8.3	11.5	4.8	12.9	4.8	12.9	
t_{PHL}	$\overline{CLR}$	Q	3.4	7.3	11.2	3.4	12.5	3.4	12.5	ns
t_{PZH}	$\overline{OE}$	Q	2.4	5.9	9.5	2.4	10.7	2.4	10.7	ns
t_{PZL}			3.3	7.1	11.3	3.3	12.8	3.3	12.8	
t_{PHZ}	$\overline{OE}$	Q	5.5	7.6	9.7	5.5	10.3	5.5	10.3	ns
t_{PLZ}			4.6	6.7	8.8	4.6	9.4	4.6	9.4	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER			TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance per flip-flop	Outputs enabled	C_L = 50 pF,	f = 1 MHz	42	pF
		Outputs disabled			24	

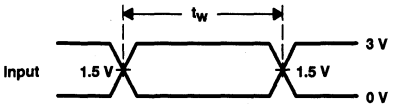
TEXAS INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION

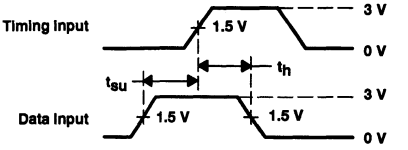


LOAD CIRCUIT

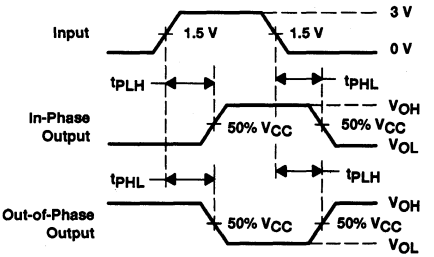
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



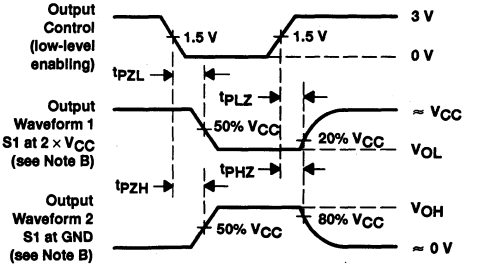
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



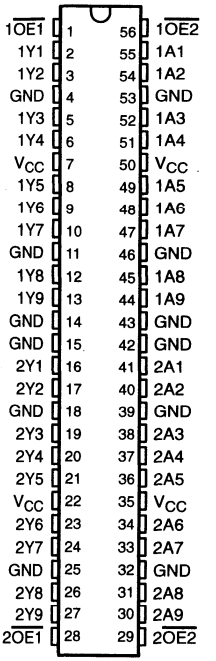
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Shrink Small-Outline 300-mil Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **Provides Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity**
- **Flow-Through Architecture Optimizes Printed-Circuit-Board (PCB) Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16825 is an 18-bit buffer or line driver designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 74ACT16825 can be used as two 9-bit buffers or one 18-bit buffer. It provides true data.

The 3-state control gate is a 2-input NOR gate so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) inputs is high, all nine affected outputs are in the high-impedance state.

The 74ACT16825 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16825 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each 9-bit section)

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

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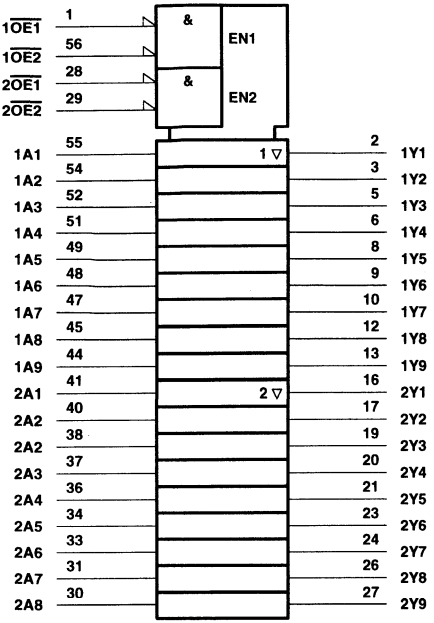
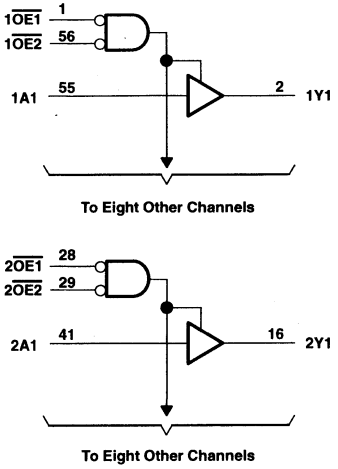
logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±450 mA
Maximum package power dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	I_{OH} = −50 μA	4.5 V	4.4			4.4		V
		5.5 V	5.4			5.4		
	I_{OH} = −24 mA	4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1	V
		5.5 V			0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	$V_I = V_{CC}$ or GND	5 V		4				pF
C_o	$V_O = V_{CC}$ or GND	5 V		16				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

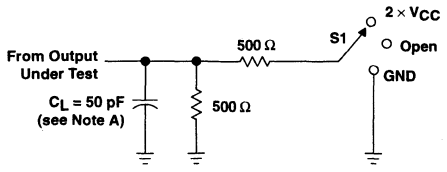
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	Y	4.1	7.5	9.3	4.1	10.5	ns
t_{PHL}			3.1	7.5	9.6	3.1	10.3	
t_{PZH}	$\overline{OE}$	Y	3.3	7.9	9.9	3.3	11	ns
t_{PZL}			4.1	9.5	12.1	4.1	13.2	
t_{PHZ}	$\overline{OE}$	Y	5.7	9	10.8	5.7	11.5	ns
t_{PLZ}			5.5	8.5	10	5.5	10.6	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

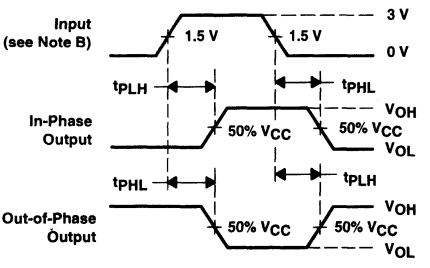
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	C_L = 50 pF, f = 1 MHz	42	pF
		Outputs disabled		12	

PARAMETER MEASUREMENT INFORMATION

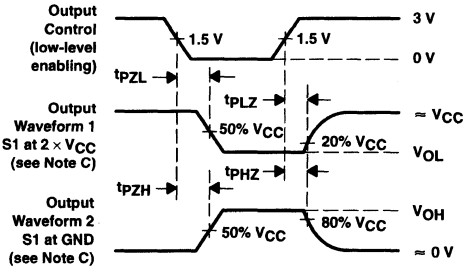


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × VCC
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



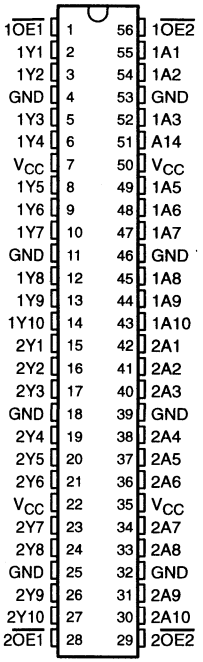
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL- or CMOS-Voltage Compatible**
- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16827 is a noninverting 20-bit buffer composed of two 10-bit sections with separate output-enable signals. For either 10-bit buffer section, the two output-enable ($1\overline{OE1}$ and $1\overline{OE2}$ or $2\overline{OE1}$ and $2\overline{OE2}$) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 10-bit buffer section are in the high-impedance state.

The 74ACT16827 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16827 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 10-bit section)

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

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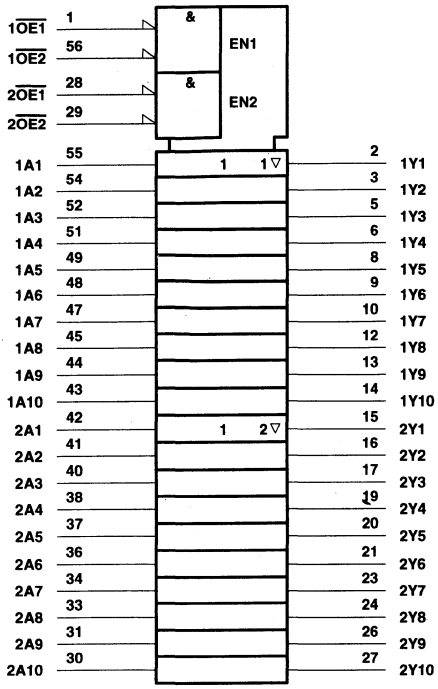
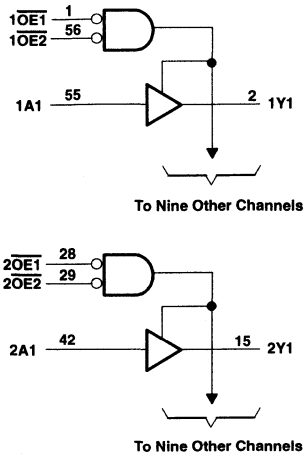
logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±500 mA
Maximum package power dissipation at $T_A = 55°C$ (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	I_{OH} = −50 μA	4.5 V	4.4			4.4		V
		5.5 V	5.4			5.4		
	I_{OH} = −24 mA	4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}	I_{OL} = 50 μA	4.5 V			0.1		0.1	V
		5.5 V			0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	μA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	$V_I = V_{CC}$ or GND	5 V		4.5				pF
C_o	$V_O = V_{CC}$ or GND	5 V		16				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

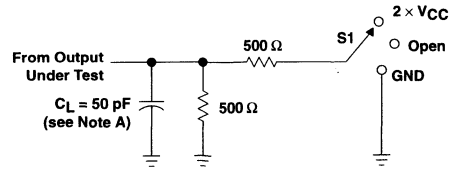
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	Y	3.6	7.4	9.8	3.6	11	ns
t_{PHL}			2.8	7.4	9.8	2.8	10.8	
t_{PZH}	$\overline{OE}$	Y	3	7.9	10.4	3	11.7	ns
t_{PZL}			4	9.6	12.4	4	14	
t_{PHZ}	$\overline{OE}$	Y	5.8	9.1	11.3	5.8	12.4	ns
t_{PLZ}			5.3	8.5	10.5	5.3	11.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

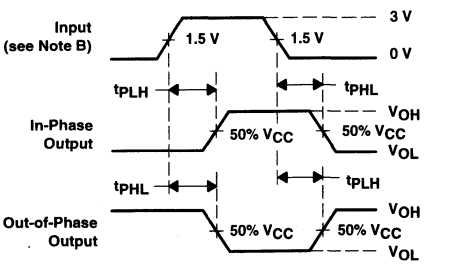
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	C_L = 50 pF, f = 1 MHz	41	pF
		Outputs disabled		10	

PARAMETER MEASUREMENT INFORMATION

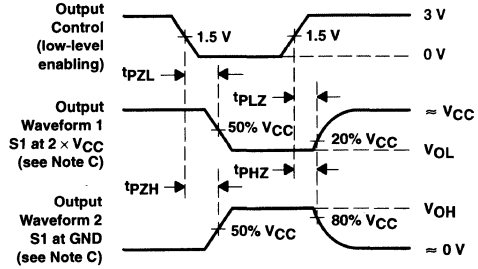


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

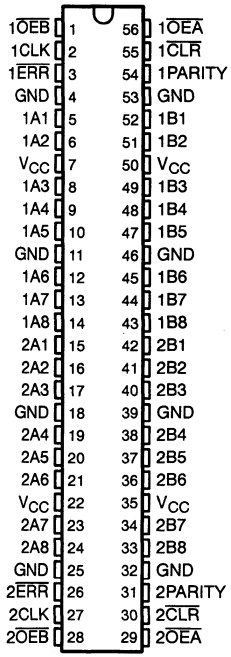
NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

SCAS166A – JUNE 1990 – REVISED APRIL 1996

- **Members of the Texas Instruments *Widebus*™ Family**
- **Inputs Are TTL-Voltage Compatible**
- **Parity Error Flag With Parity Generator/Checker**
- **Register for Storage of the Parity Error Flag**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings**

54ACT16833 . . . WD PACKAGE
74ACT16833 . . . DL PACKAGE
(TOP VIEW)



description

The 'ACT16833 consist of two noninverting 8-bit to 9-bit parity bus transceivers and are designed for communication between data buses. For each transceiver, when data is transmitted from the A bus to the B bus, an odd-parity bit is generated and output on the parity I/O pin (1PARITY or 2PARITY). When data is transmitted from the B bus to the A bus, 1PARITY or 2PARITY is configured as an input and combined with the B-input data to generate an active-low error flag if odd parity is not detected.

The error (1$\overline{ERR}$ or 2$\overline{ERR}$) output is configured as an open-collector output. The B-to-A parity error flag is clocked into 1$\overline{ERR}$ or 2$\overline{ERR}$ on the low-to-high transition of the clock (1CLK or 2CLK) input. 1$\overline{ERR}$ or 2$\overline{ERR}$ is cleared (set high) by taking the clear (1$\overline{CLR}$ or 2$\overline{CLR}$) input low.

The output-enable ($\overline{OEA}$ and $\overline{OEB}$) inputs can be used to disable the device so that the buses are effectively isolated. When both $\overline{OEA}$ and $\overline{OEB}$ are low, data is transferred from the A bus to the B bus and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

The 74ACT16833 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16833 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16833 is characterized for operation from –40°C to 85°C.

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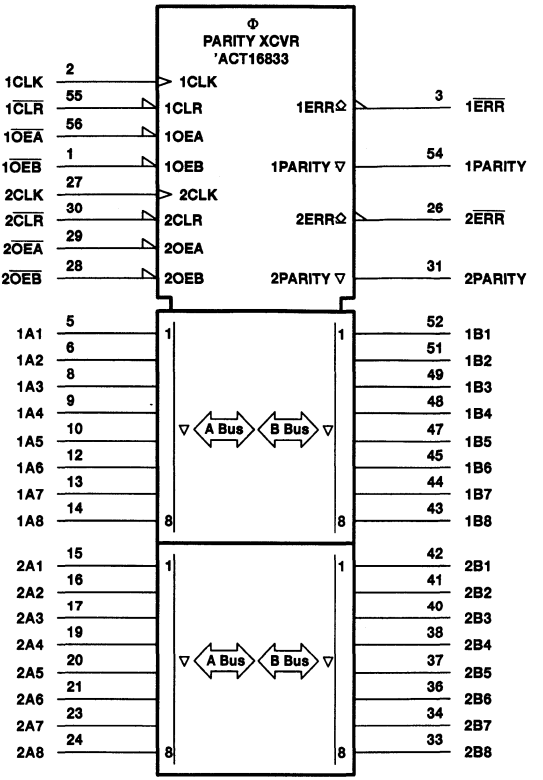
FUNCTION TABLE

INPUTS						OUTPUT AND I/O				FUNCTION
$\overline{OEB}$	$\overline{OEA}$	$\overline{CLR}$	CLK	AI Σ OF H	BI† Σ OF H	A	B	PARITY	$\overline{ERR}$‡	
L	H	X	X	Odd Even	NA	NA	A	L H	NA	A data to B bus and generate parity
H	L	H	↑	NA	Odd Even	B	NA	NA	H L	B data to A bus and check parity
X	X	L	X	X	X	X	NA	NA	H	Check error-flag register
H	H	H	No↑	X	X	Z	Z	Z	NC	Isolation§
		L	No↑	X					H	
		H	↑	Odd					H	
		H	↑	Even					L	
L	L	X	X	Odd Even	NA	NA	A	H L	NA	A data to B bus and generate inverted parity

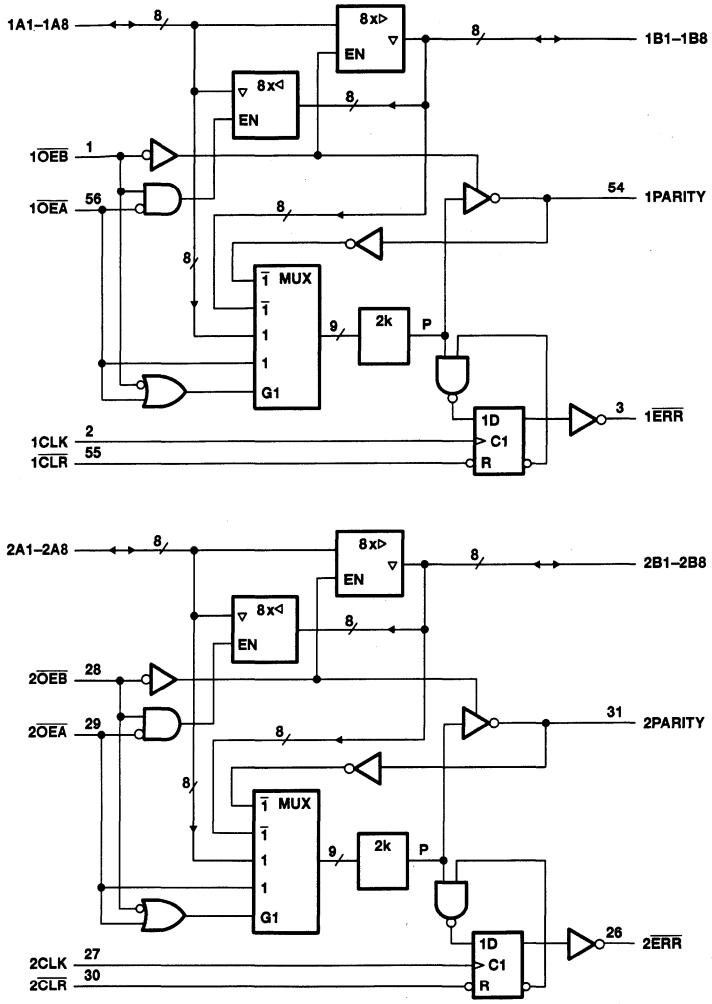
NA = not applicable, NC = no change, X = don't care
† Summation of high-level inputs includes PARITY along with Bi inputs.
‡ Output states shown assume $\overline{ERR}$ was previously high.
§ In this mode, $\overline{ERR}$ (when clocked) shows inverted parity of the A bus.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

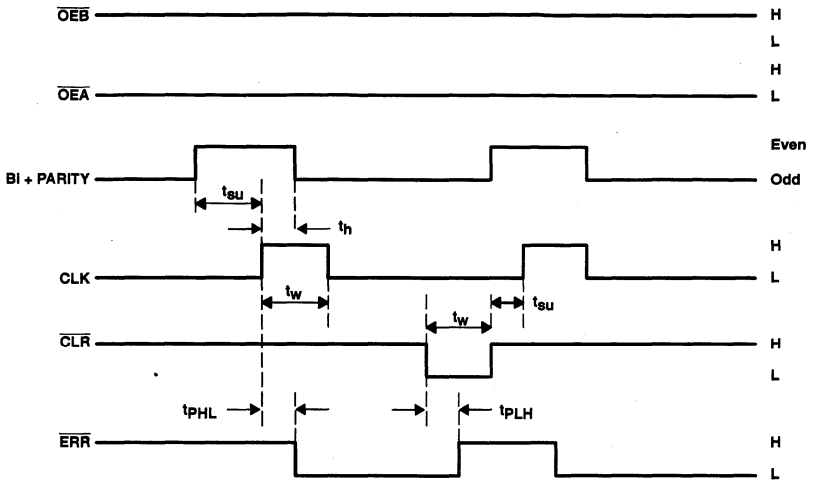


ERROR FLAG FUNCTION TABLE

INPUTS		INTERNAL TO DEVICE	OUTPUT PRE-STATE	OUTPUT	FUNCTION
$\overline{CLR}$	CLK	POINT P‡	$\overline{ERR}_{n-1}$†	$\overline{ERR}$	
H	↑	H	H	H	Sample
H	↑	X	L	L	
H	↑	L	X	L	
L	X	X	X	H	Clear

† The state of $\overline{ERR}$ before any changes at $\overline{CLR}$, CLK, or point P
‡ Location of point P is shown on local diagram.

timing waveforms, error flag



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)§

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±450 mA
Maximum power package dissipation at T_A = 55°C (in still air) (see Note 2): DL package ..... 1.4 W
Storage temperature range, T_{stg} ..... –65°C to 150°C

§ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		54ACT16833			74ACT16833			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current			–24			–24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate			10	0		10	ns/V
T_A	Operating free-air temperature	–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16833		74ACT16833		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
I_{OH}	$\overline{ERR}$	$V_O = V_{CC}$	5.5 V			0.5		5		5	µA
V_{OH}	All outputs except $\overline{ERR}$	I_{OH} = –50 µA	4.5 V	4.4			4.4		4.4		V
			5.5 V	5.4			5.4		5.4		
		I_{OH} = –24 mA	4.5 V	3.94			3.8		3.8		
			5.5 V	4.94			4.8		4.8		
		I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1		0.1	V
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
			5.5 V			0.36		0.44		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	A or B ports	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}‡	Control inputs	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		3.5						pF
C_{io}	A or B ports, PARITY	$V_O = V_{CC}$ or GND	5 V		11.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

TEXAS INSTRUMENTS

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1 and timing waveforms)

			T_A = 25°C		54ACT16833		74ACT16833		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	CLK high or low	4		4		4		ns
		$\overline{CLR}$ low	4		4		4		
t_{su}	Setup time before CLK↑	Bi + PARITY	7.5		7.5		7.5		ns
		$\overline{CLR}$ inactive	1.5		1.5		1.5		
t_h	Hold time, Bi + PARITY low after CLK↑		0		0		0		ns

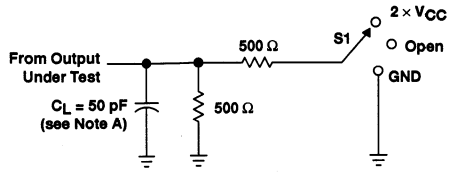
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1 and timing waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16833		74ACT16833		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	4	7.2	9.2	4	10.4	4	10.4	ns
t_{PHL}			3.2	6.6	9.6	3.2	10.7	3.2	10.7	
t_{PLH}	A	PARITY	3.9	7.9	12	3.9	13.5	3.9	13.5	ns
t_{PHL}			4.2	8.3	12.4	4.2	13.8	4.2	13.8	
t_{PZH}	$\overline{OEB}$ or $\overline{OEA}$	A or B	3.1	6.7	10.1	3.1	11.2	3.1	11.2	ns
t_{PZL}			3.8	7.9	11.6	3.8	13	3.8	13	
t_{PHZ}	$\overline{OEB}$ or $\overline{OEA}$	A or B	5.5	7.8	10	5.5	10.8	5.5	10.8	ns
t_{PLZ}			5	7.1	9.3	5	10.1	5	10.1	
t_{PLH}	$\overline{CLR}$	$\overline{ERR}$	10.7	13.1	15.4	10.7	15.8	10.7	15.8	ns
t_{PHL}	CLK		4.6	7.8	10.3	4.6	11.6	4.6	11.6	
t_{PLH}	$\overline{OEA}$	PARITY	4	8	11.8	4	13.2	4	13.2	ns
t_{PHL}			4.3	8.5	12.3	4.3	13.6	4.3	13.6	
t_{PZH}	$\overline{OEB}$	PARITY	2.6	5.7	8.5	2.6	9.5	2.6	9.5	ns
t_{PZL}			3.4	6.8	9.8	3.4	10.7	3.4	10.7	
t_{PHZ}	$\overline{OEB}$	PARITY	5.6	7.9	9.5	5.6	10.2	5.6	10.2	ns
t_{PLZ}			5.1	7.2	9.1	5.1	9.7	5.1	9.7	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

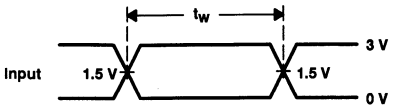
PARAMETER				TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	A to B	CL = 50 pF, f = 1 MHz	64	pF
			B to A		72	
		Outputs disabled	A to B		6	
			B to A		10.5	

PARAMETER MEASUREMENT INFORMATION

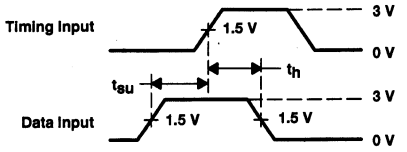


LOAD CIRCUIT

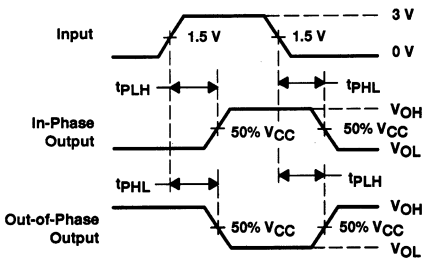
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



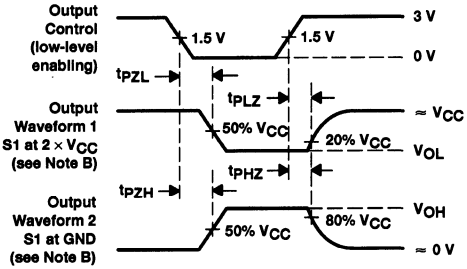
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



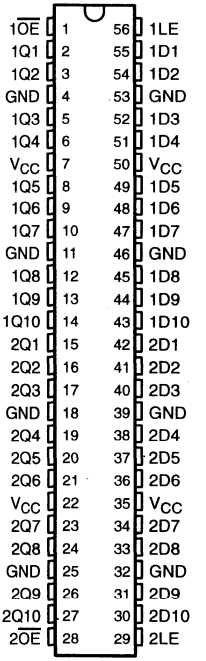
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines Directly**
- **Provide Extra Bus Driving/Latches Necessary for Wider Address/Data Paths or Buses With Parity**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

This 20-bit latch features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The 74ACT16841 can be used as two 10-bit latches or one 20-bit latch. The twenty latches are transparent D-type. While the latch-enable (1LE or 2LE) input is high, the Q outputs of the corresponding 10-bit latch follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels that were set up at the D inputs.

A buffered output-enable ($1\overline{OE}$ or $2\overline{OE}$) input can be used to place the outputs of the corresponding 10-bit latch in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

The output-enable input does not affect the internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74ACT16841 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16841 is characterized for operation from −40°C to 85°C.

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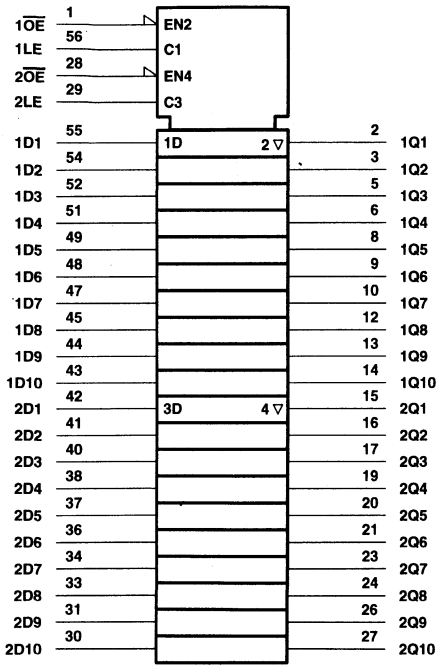
FUNCTION TABLE
(each 10-bit latch)

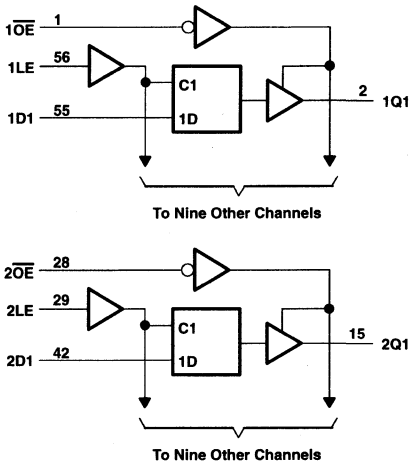
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±500 mA
Maximum package power dissipation at $T_A = 55°C$ (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	I_{OH} = −50 µA	4.5 V	4.4			4.4		V
		5.5 V	5.4			5.4		
	I_{OH} = −24 mA	4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V			0.1		0.1	V
		5.5 V			0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	µA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	$V_I = V_{CC}$ or GND	5 V		3				pF
C_o	$V_O = V_{CC}$ or GND	5 V		11				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
t_w	Pulse duration, LE high		4		4		ns
t_{su}	Setup time, data before LE↓		1.5		1.5		ns
t_h	Hold time, data after LE↓	High	3		3		ns
		Low	4.5		4.5		

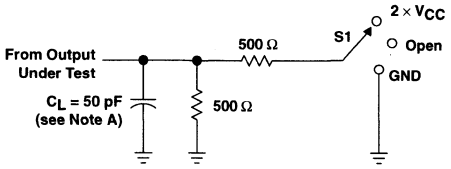
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ±0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	D	Q	4	7.1	10.3	4	11.8	ns
t_{PHL}			3.2	6.9	11	3.2	12.2	
t_{PLH}	LE	Q	4.5	7.7	11.3	4.5	12.7	ns
t_{PHL}			4.3	7.8	11.4	4.3	12.7	
t_{PZH}	$\overline{OE}$	Q	3.1	6.4	10.1	3.1	11.3	ns
t_{PZL}			3.8	7.6	12.1	3.8	13.7	
t_{PHZ}	$\overline{OE}$	Q	4	7.3	9.5	4	10.2	ns
t_{PLZ}			4	6.8	8.9	4	9.6	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

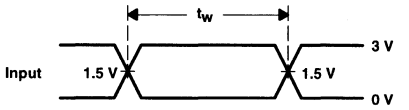
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	C_L = 50 pF, f = 1 MHz	41	pF
		Outputs disabled		10	

PARAMETER MEASUREMENT INFORMATION

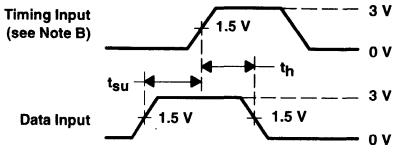


LOAD CIRCUIT

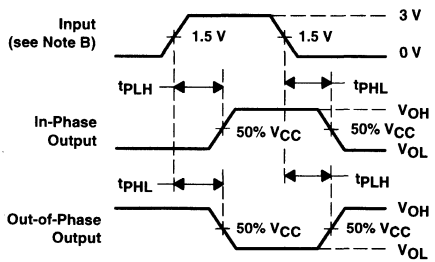
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



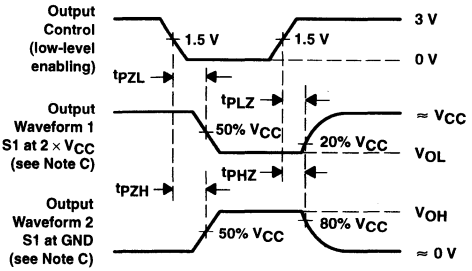
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
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- **Flow-Through Architecture Optimizes PCB Layout**
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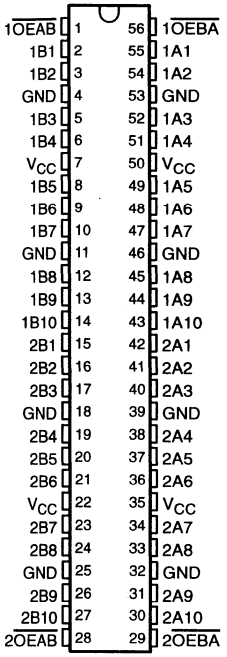
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16861 is a noninverting 20-bit transceiver designed for asynchronous communication between data buses. The control function implementation minimizes external timing requirements.

The 74ACT16861 can be used as two 10-bit transceivers or one 20-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

The 74ACT16861 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

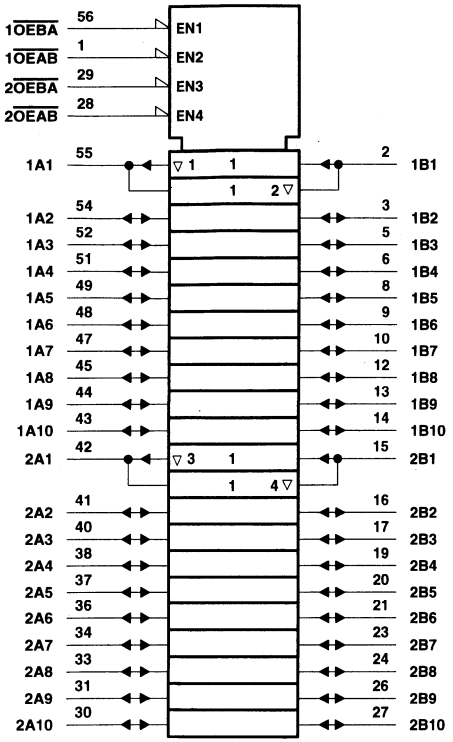
The 74ACT16861 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 10-bit section)

INPUTS		OPERATION
$\overline{OEAB}$	$\overline{OEBA}$	
L	L	Latch A and B (A = B)
L	H	A to B
H	L	B to A
H	H	Isolation

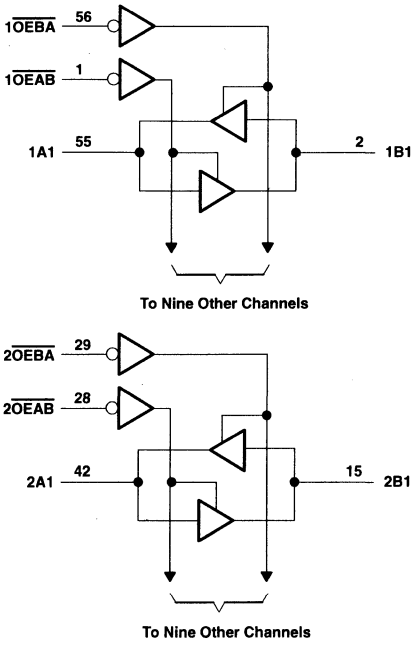
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



TEXAS INSTRUMENTS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±500 mA
Maximum package power dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = – 50 μA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = – 24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = –75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 μA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = – 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	V_I = V_{CC} or GND	5.5 V			±0.1		±1	μA
I_{OZ}‡	A or B ports	V_O = V_{CC} or GND	5.5 V			±0.5		±5	μA
I_{CC}		V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80	μA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	V_I = V_{CC} or GND	5 V		4.5				pF
C_{io}	A or B ports	V_O = V_{CC} or GND	5 V		17				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

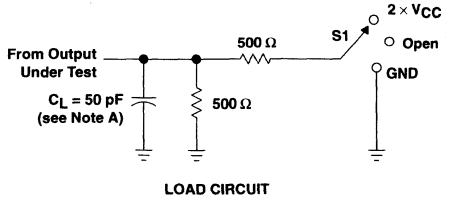
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	3.1	6.5	9.2	3.1	10.4	ns
t_{PHL}			2.9	7.5	10	2.9	11.1	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	2.4	6.6	9	2.4	10	ns
t_{PZL}			3.7	8.5	11.5	3.7	12.7	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	4.9	7.4	9.8	4.9	10.7	ns
t_{PLZ}			4.5	6.9	9.3	4.5	10	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

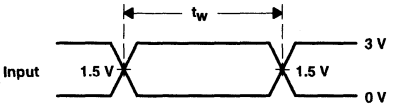
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	64	pF
		Outputs disabled		14	

PARAMETER MEASUREMENT INFORMATION

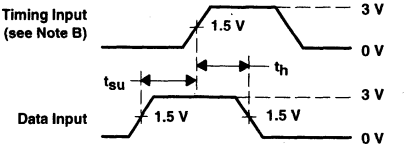


LOAD CIRCUIT

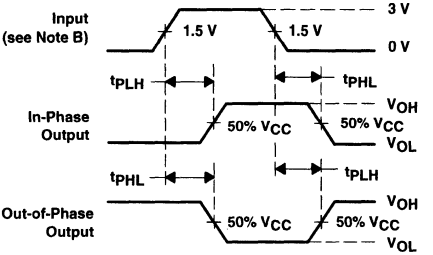
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × VCC
t_{PHZ}/t_{PZH}	GND



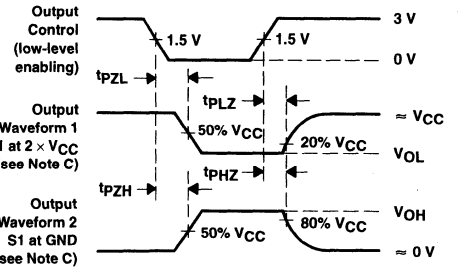
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



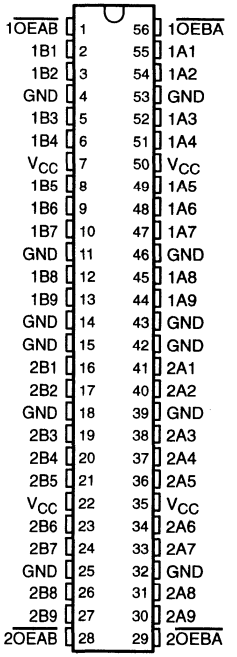
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

54ACT16863 . . . WD PACKAGE
74ACT16863 . . . DL PACKAGE
(TOP VIEW)



description

The 'ACT16863 is an 18-bit noninverting transceiver designed for asynchronous communication between data buses. The control function implementation minimizes external timing requirements.

The 'ACT16863 can be used as two 9-bit transceivers or one 18-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs.

The 74ACT16863 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16863 is characterized for operation over the full military temperature range of −55°C to 125°C. The 74ACT16863 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE
(each 9-bit section)

INPUTS		OPERATION
$\overline{OEAB}$	$\overline{OEBA}$	
H	L	B data to A bus
L	H	A data to B bus
H	H	Isolation

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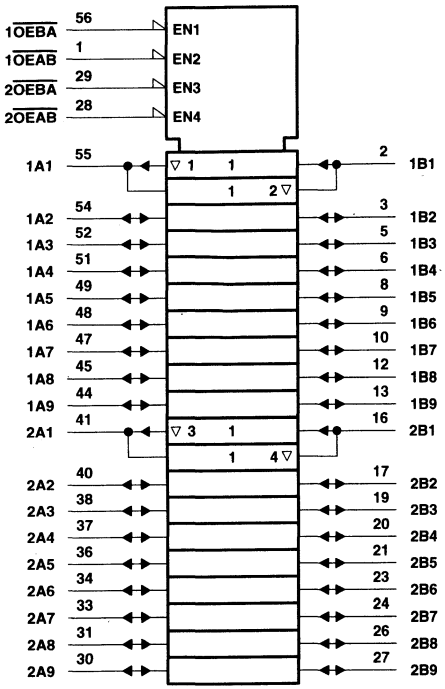
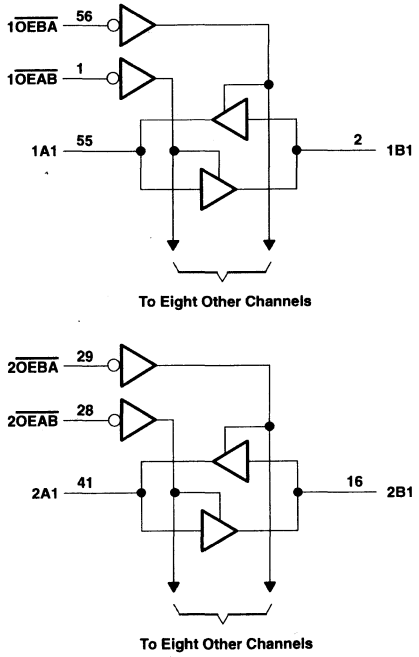
logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ..... ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ..... ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±450 mA
Maximum package power dissipation at $T_A = 55°C$ (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		54ACT16863			74ACT16863			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current			−24			−24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
T_A	Operating free-air temperature	−55		125	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54ACT16863		74ACT16863		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = − 50 µA	4.5 V	4.4			4.4		4.4		V
			5.5 V	5.4			5.4		5.4		
		I_{OH} = − 24 mA	4.5 V	3.94			3.7		3.8		
			5.5 V	4.94			4.7		4.8		
		I_{OH} = −50 mA†	5.5 V				3.85				
		I_{OH} = −75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1		0.1	V
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		160		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4.5						pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		17						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

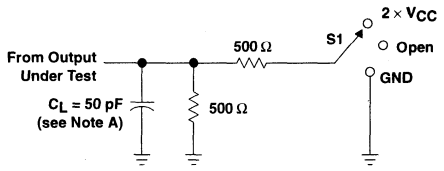
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54ACT16863		74ACT16863		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	4.1	7	9.9	4.1	12.1	4.1	11.1	ns
t_{PHL}			3.1	6.4	10.6	3.1	12.5	3.1	11.8	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	3	5.9	9.6	3	11.5	3	10.6	ns
t_{PZL}			3.9	7.4	12.3	3.9	14.7	3.9	13.6	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	5.7	8.2	10.6	5.7	12.3	5.7	11.6	ns
t_{PLZ}			5.4	7.7	10	5.4	11.6	5.4	11	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

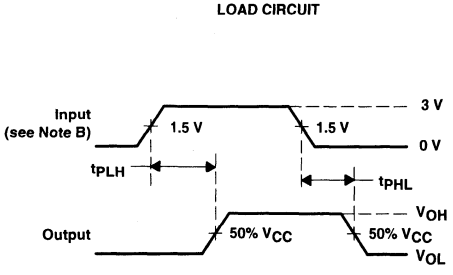
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	62	pF
		Outputs disabled		13	

PARAMETER MEASUREMENT INFORMATION

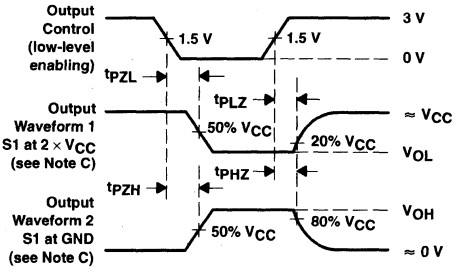


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

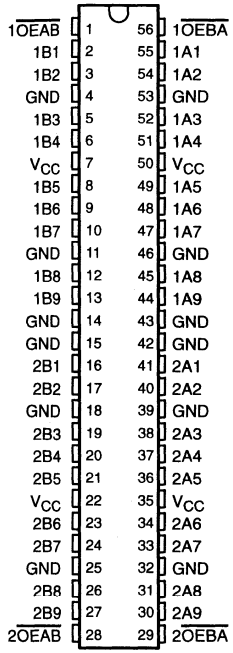
NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

TEXAS INSTRUMENTS

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 74ACT16864 is an 18-bit inverting transceiver designed for asynchronous communication between data buses. The control function implementation minimizes external timing requirements.

The 74ACT16864 can be used as two 9-bit transceivers or one 18-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs.

The 74ACT16864 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16864 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 9-bit section)

INPUTS		OPERATION
$\overline{OEAB}$	$\overline{OEBA}$	
H	L	$\overline{B}$ data to A bus
L	H	$\overline{A}$ data to B bus
H	H	Isolation

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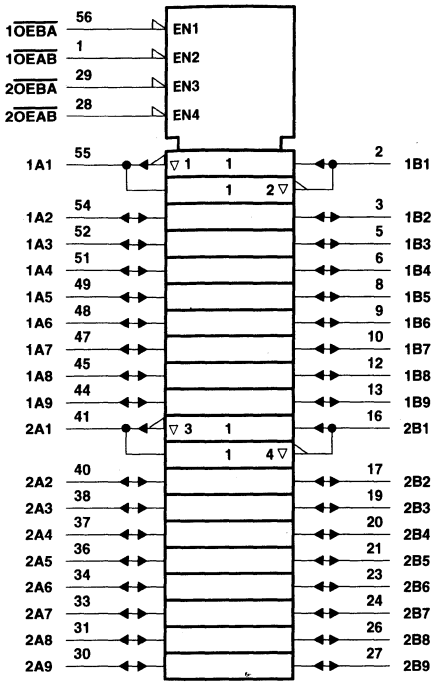
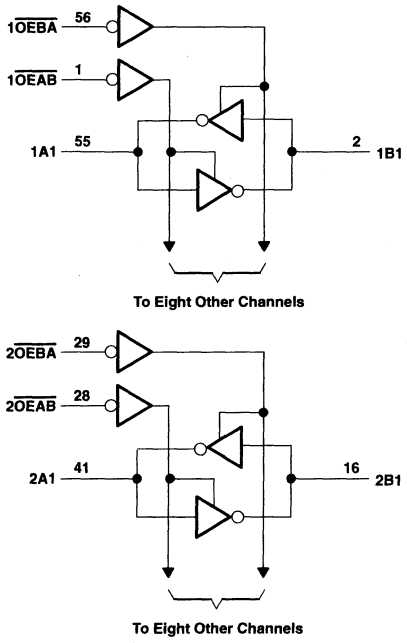
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±450 mA
Maximum package power dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = − 50 μA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = − 24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 μA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	V_I = V_{CC} or GND	5.5 V			±0.1		±1	μA
I_{OZ}‡	A or B ports	V_O = V_{CC} or GND	5.5 V			±0.5		±5	μA
I_{CC}		V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80	μA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	V_I = V_{CC} or GND	5 V		4.5				pF
C_{io}	A or B ports	V_O = V_{CC} or GND	5 V		17				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

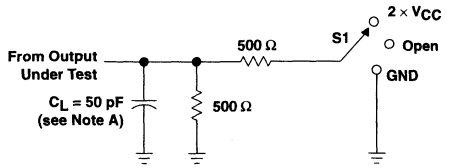
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1.6	7	8.9	1.6	10.2	ns
t_{PHL}			3.7	8.1	10	3.7	11.3	
t_{PZH}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	2.2	8.2	10.1	2.2	11.1	ns
t_{PZL}			3.1	10.2	12.4	3.1	13.8	
t_{PHZ}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	5.1	8.6	10.1	5.1	10.8	ns
t_{PLZ}			5	8.3	9.7	5	10.3	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

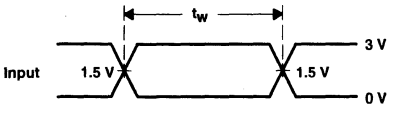
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	56	pF
		Outputs disabled		9	

PARAMETER MEASUREMENT INFORMATION

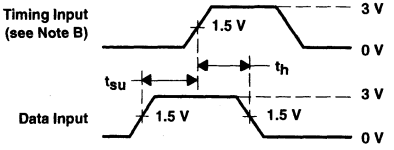


LOAD CIRCUIT

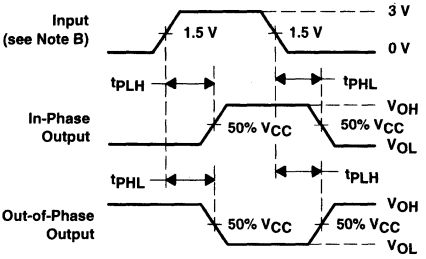
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



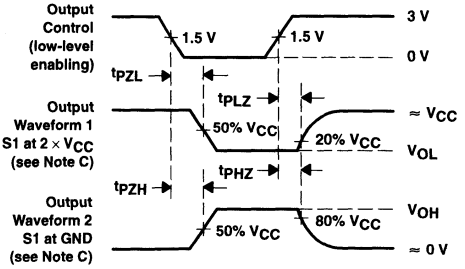
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



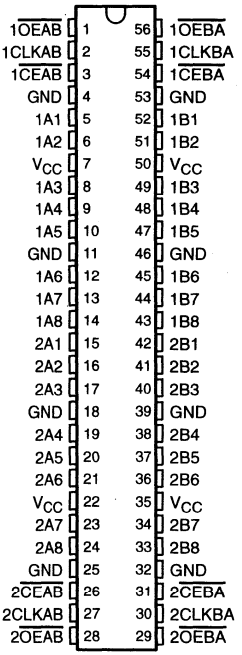
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Member of the Texas Instruments *Widebus*™ Family**
- **Packaged in Plastic 300-mil Shrink Small-Outline Package Using 25-mil Center-to-Center Pin Spacings**
- **Inputs Are TTL-Voltage Compatible**
- **Noninverting Outputs**
- **Two 16-Bit, Back-to-Back Registers Store Data Flowing in Both Directions**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

DL PACKAGE
(TOP VIEW)



description

The 'ACT16952 is a 16-bit registered transceiver that contains two sets of D-type flip-flops for temporary storage of data flowing in either direction. It can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable ($\overline{CEAB}$ or $\overline{CEBA}$) input is low. Taking the output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) input low accesses the data on either port. To avoid false clocking of the flip-flops, $\overline{CEAB}$ (or $\overline{CEBA}$) should not be switched from low to high while CLKAB (or CLKBA) is low.

The 74ACT16952 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 74ACT16952 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

INPUTS				OUTPUT
$\overline{CEAB}$	CLKAB	$\overline{OEAB}$	A	B
H	X	L	X	B_0‡
X	H	L	X	B_0‡
L	↑	L	L	L
L	↑	L	H	H
X	X	H	X	Z

† A-to-B data flow is shown; B-to-A data flow is similar but uses $\overline{CEBA}$, CLKBA, and $\overline{OEBA}$.
‡ Level of B before the indicated steady-state input conditions were established.

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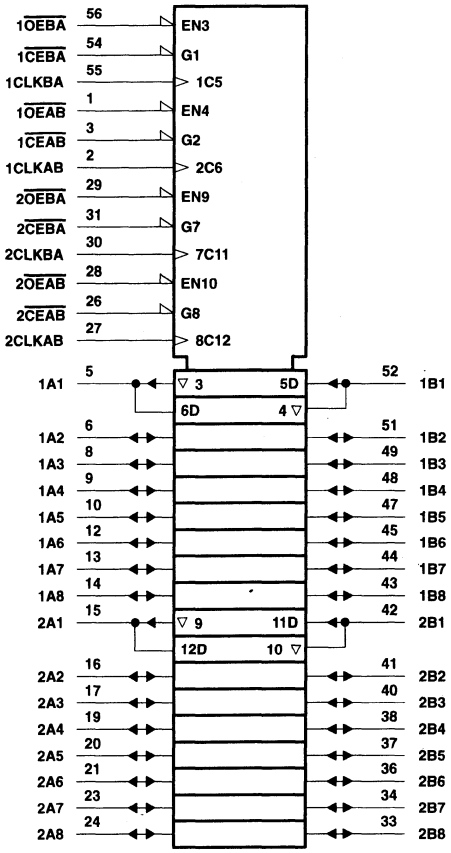
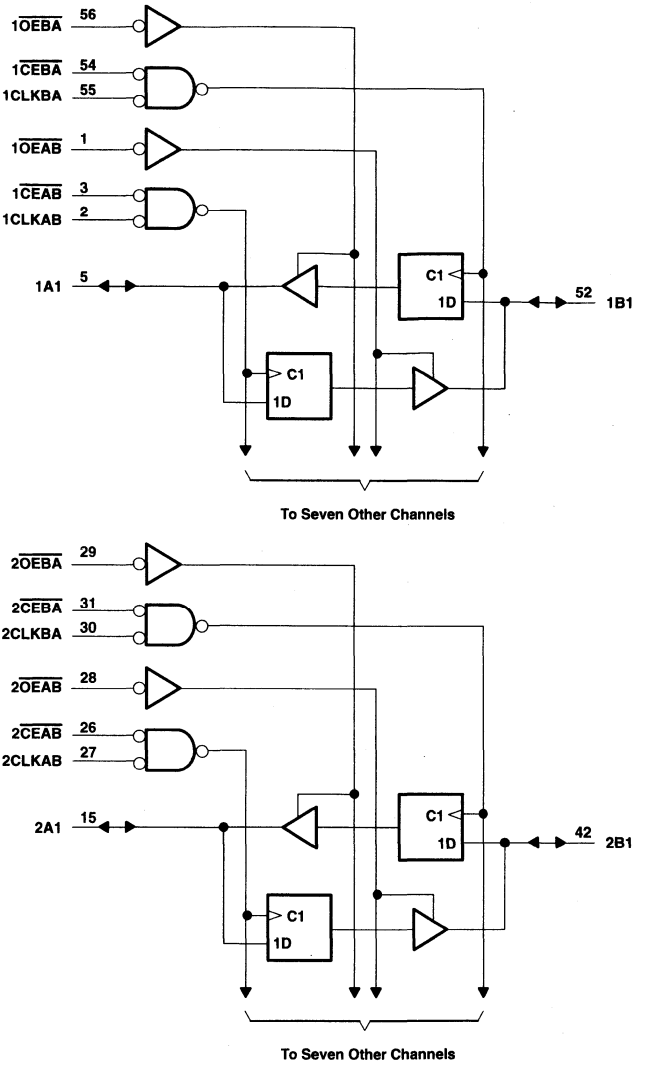
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) ..... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) ..... ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ..... ±50 mA
Continuous current through V_{CC} or GND ..... ±400 mA
Maximum package power dissipation at T_A = 55°C (in still air) ..... 1 W
Storage temperature range ..... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}		I_{OH} = –50 µA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I_{OH} = –24 mA	4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
		I_{OH} = –50 mA†	5.5 V						
		I_{OH} = –75 mA†	5.5 V				3.85		
V_{OL}		I_{OL} = 50 µA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I_{OL} = 24 mA	4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
		I_{OL} = 50 mA†	5.5 V						
		I_{OL} = 75 mA†	5.5 V					1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	µA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	µA
ΔI_{CC}§		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		3				pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 0.5 V ± 0.5 V (unless otherwise noted)

			T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
f_{clock}	Clock frequency		0	75	0	75	MHz
t_w	Pulse duration, CLK high or low		6.7		6.7		ns
t_{su}	Setup time before CLK↑	Data	5		5		ns
		$\overline{CEAB}$ or $\overline{CEBA}$	6.5		6.5		
t_h	Hold time after CLK↑	Data	1		1		ns
		$\overline{CEAB}$ or $\overline{CEBA}$	0		0		

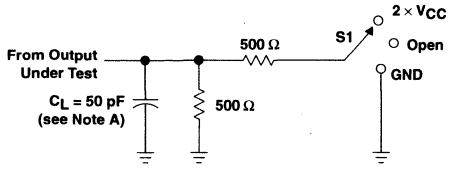
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f_{max}			75			75		MHz
t_{PLH}	CLK	A or B	4.7	8.5	10.7	4.7	11.8	ns
t_{PHL}			4.9	8.7	10.5	4.9	11.7	
t_{PLH}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	4.7	8.5	10.7	4.7	11.8	ns
t_{PHL}			4.9	8.7	10.5	4.9	11.7	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	3.4	8.1	10.2	3.4	11.2	ns
t_{PZL}			4.2	9.6	11.8	4.2	13	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	5.2	7.5	8.9	5.2	9.4	ns
t_{PLZ}			4.5	6.7	8.2	4.5	8.7	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

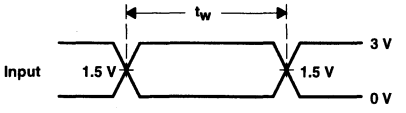
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	55	pF
		Outputs disabled		34	

PARAMETER MEASUREMENT INFORMATION

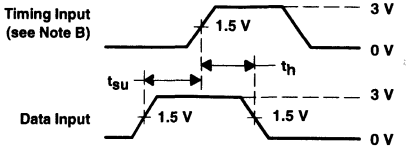


LOAD CIRCUIT

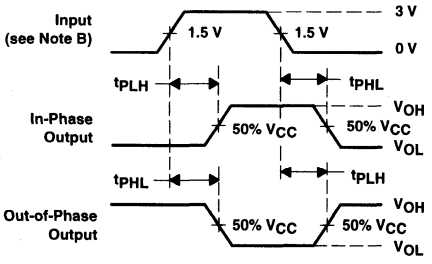
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × VCC
t_{PHZ}/t_{PZH}	GND



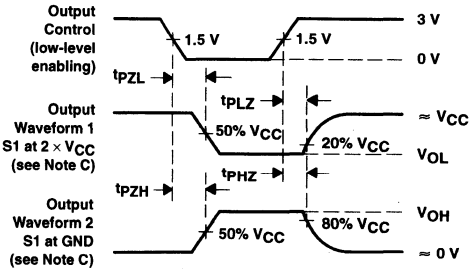
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

6 Application Reports

Package Thermal Considerations

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Advanced System Logic – Semiconductor Group

SCZA002B

Contents

List of Illustrations

Abstract

To meet current and future system requirements of increasing speed and decreasing size, integrated circuit manufacturers are pushing the edge on existing packaging technology. A component's performance is determined by process technology and the thermal limitations of its package. As a leader in package technology, Texas Instruments (TI) has introduced a number of fine-pitch packages and is acutely aware of the thermal considerations that must be examined by systems designers. This paper is intended to create awareness and understanding of thermal issues and to explore factors that influence thermal performance.

Introduction

Thermal awareness became an industry concern when surface-mount (SMT) packages began replacing through-hole (DIP) packages in PCB designs. Circuits operating at the same power enclosed in a smaller package meant higher power. To add to the issue, systems required increased throughput, which resulted in higher frequencies, increasing the power density even further. Not only are these same concerns haunting designers today, they are progressively getting more severe.

Figure 1 shows part of the reason for increased attention to thermal issues. As a baseline for comparison, the 24-pin small-outline integrated circuit (SOIC) is shown along with several fine-pitch packages supplied by TI, including the 24-pin SSOP (shrink small outline), 48-pin SSOP, and the 100-pin TQFP (thin quad flat pack). The 24-pin SSOP (8, 9, and 10 bits) allows for the same circuit functionality of the 24-pin SOIC to be packaged in less than half the area, while the 48-pin SSOP (16, 18, and 20 bits) occupies just slightly more area but has twice the functionality of the 24-pin SOIC. This same phenomena is expanded even further with the 100-pin TQFP (32 and 36 bits), which is the functional equivalent of four 24-pin or two 48-pin devices, with additional board savings over that of the SSOP packages. As the trend in packaging technology continues toward smaller packages, attention must be focused on the thermal issues that are created.

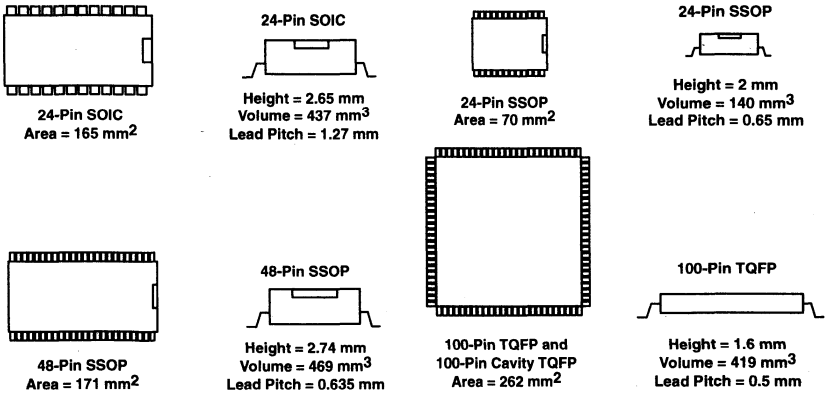


Figure 1. Advanced Packages

Reliability

The overriding effect of increased power densities in integrated circuits is a decrease in overall system reliability. A direct relationship exists between junction temperature and reliability.

Table 1 provides an example of a device with an initial junction temperature of 150°C and the calculated failure-rate decrease as the in-use junction temperature is lowered. The data in Table 1 indicates that lower junction temperature results in increased system reliability.

Table 1

TEMPERATURE °C	% FR†
150	96
140	80
130	46
120	11
110	1
100	0.02

† Failure rate at 100,000 hours

A better understanding of the factors that contribute to junction temperature (T_J) provides a system designer with more flexibility when attempting to solve thermal issues. Device junction temperature is determined by equation 1:

$$T_J = T_A + [\Theta_{JA} \times P_T] \quad (1)$$

Where:

T_J = junction (die) temperature (°C)
T_A = ambient temperature (°C)
Θ_{JA} = thermal resistance of the package from the junction to the ambient (°C/W)
P_T = total power of the device (W)

Junction temperature can be altered by lower chip power consumption, longer trace length, heat sinks, forced air flow, package mold compound, lead-frame size and material, surface area, and die size. Some of these are mechanically inherent to a particular package while others are controlled by the designer and are application specific. Understanding which variables can be influenced by practicing good thermal-design techniques requires a more detailed investigation of power considerations as well as thermal-resistance measurements.

Power Consumption

One way to lower the junction temperature (T_J) of a device, thus improving reliability, is to lower the power consumption. A variety of options are available to help achieve this, such as low-power process technologies, reduced output swing, and reduced power-supply voltage. A closer look at the power performance and advantages of several popular logic families can assist the designer when choosing what best fits his/her needs.

The choices available from TI for high-speed bus interfaces range from standard bipolar (F) to advanced CMOS (ACL/ACT) to state-of-the-art BiCMOS (BCT) and advanced BiCMOS (ABT). Figures 2 through 4 show comparisons of current (I_{CC}) consumption of '244 functions for these technologies across frequency. As expected, the bipolar device consumes more current than the CMOS device at lower frequencies, but as frequency increases, this relationship no longer holds true. In fact, there is a region in the frequency range where the CMOS device consumes more current than the bipolar device. The point where they are equal is referred to as the crossover frequency.

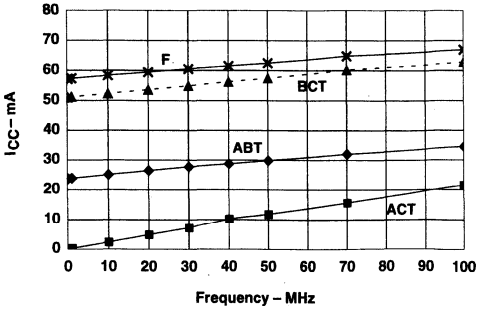


Figure 2. I_{CC} Versus Frequency (One Switching, Unused Outputs Low)

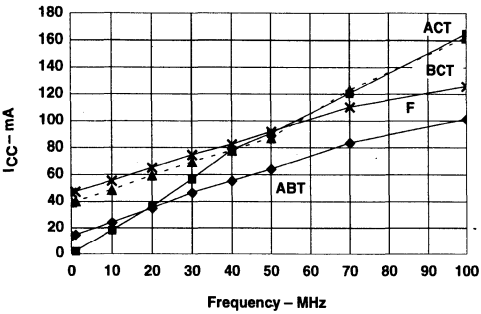


Figure 3. I_{CC} Versus Frequency (All Outputs Switching)

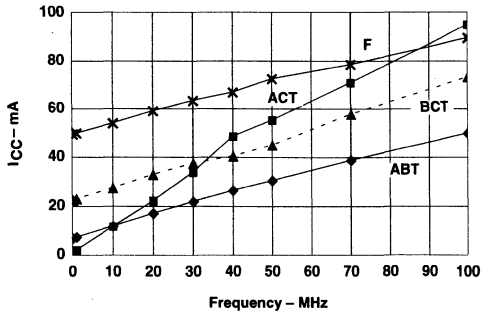


Figure 4. I_{CC} Versus Frequency (All Switching, 50% Duty Cycle Enabled)

Typical applications for bus-interface devices require them to be disabled or in the standby mode during certain periods of time, for instance, while other devices access the bus. This can result in a large decrease in current consumption for ABT, BCT, and ACT devices, which have low-standby current. These values are given in the data sheets as I_{CC} for ACT and I_{CCZ} for ABT (250 μA) and BCT (≅ 10 mA). Current-consumption data versus percent duty cycle enabled is shown in Figure 5. The frequency of the data is held constant at 25 MHz and all outputs are switching.

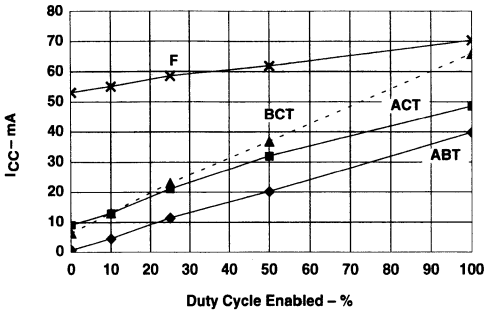


Figure 5. I_{CC} Versus Duty Cycle Enabled (25 MHz)

The power-consumption data provided is limited to a small range of variations. However, using this data, along with standard formulas, power consumption can be calculated for specific applications.

Power Calculations

When calculating the total power consumption of a circuit, both the static and the dynamic currents must be taken into account. Both bipolar and BiCMOS devices have varying static-current levels, depending on the state of the output (I_{CCL}, I_{CCH}, or I_{CCZ}), while a CMOS device has a single value for I_{CC}. These values can be found in the individual data sheets. ACT and ABT inputs, when driven at TTL levels, also consume additional current because they may not be driven all the way to V_{CC} or GND; therefore, the input transistors are not completely turned off. This value is known as ΔI_{CC} and is provided in the data sheet.

Dynamic power consumption results from charging and discharging of both internal parasitic capacitances and external load capacitance. The parameter for ACT and AC devices that accounts for the parasitic capacitances is known as C_{pd}. It is obtained using equation 2 and is found in the data sheet.

$$C_{pd} = [I_{CC}\,(\text{dynamic})/(V_{CC} \times f_i)] - C_L \qquad (2)$$

Where:

f_i = input frequency (Hz)
V_{CC} = supply voltage (V)
C_L = load capacitance (F)
I_{CC} = measured value of current into the device

Although a C_{pd} value is not provided for ABT, BCT, or F devices, the I_{CC} versus frequency curves display essentially the same information. The slope of the curve provides a value in the form of mA/(MHz × bit), which when multiplied by the number of outputs switching and the desired frequency, provides the dynamic power dissipated by the device without the load current.

Equations 3 through 7 can be used to calculate total power for CMOS, bipolar, and BiCMOS devices:

$$P_T = P_{S(static)} + P_{D(dynamic)} \quad (3)$$

CMOS

AC (CMOS-level inputs)

$$P_S = V_{CC} \times I_{CC}$$
$$P_D = [(C_{pd} + C_L) \times V_{CC}^2 \times f_1] N_{sw} \quad (4)$$

ACT (TTL-level inputs)

$$P_S = V_{CC} [I_{CC} + (N_{TTL} \times \Delta I_{CC} \times DC_d)]$$
$$P_D = [(C_{pd} + C_L) \times V_{CC}^2 \times f_1] N_{sw} \quad (5)$$

BiCMOS/Bipolar

$$P_S = V_{CC} [DC_{en}(N_H \times I_{CCH}/N_T + N_L \times I_{CCL}/N_T) + (1-DC_{en})Iccz] + (N_{TTL} \times \Delta I_{CC} \times DC_d) \quad (6)$$

Note: $\Delta I_{CC} = 0$ for bipolar devices

$$P_D = [DC_{en} \times N_{sw} \times V_{CC} \times f_1 \times (V_{OH} - V_{OL}) \times C_L] + [DC_{en} \times N_{sw} \times V_{CC} f_2 \times (mA/MHz \times bit)] \times 10^{-3} \quad (7)$$

Where:

V_{CC}	=	Supply voltage (V)
I_{CC}	=	Power-supply current (A) (from the data sheet)
I_{CCL}	=	Power-supply current (A) when outputs are in low state (from the data sheet)
I_{CCH}	=	Power-supply current (A) when outputs are in high state (from the data sheet)
I_{CCZ}	=	Power-supply current (A) when outputs are in high-impedance state (from the data sheet)
ΔI_{CC}	=	Power-supply current (A) when inputs are at a TTL level (from the data sheet)
DC_{en}	=	% duty cycle enabled (50% = 0.5)
DC_d	=	% duty cycle of the data (50% = 0.5)
N_H	=	Number of outputs in high state
N_L	=	Number of outputs in low state
N_{sw}	=	Total number of outputs switching
N_T	=	Total number of outputs
f_1	=	Operating frequency (Hz)
f_2	=	Operating frequency (MHz)
V_{OH}	=	Output voltage (V) in high state
V_{OL}	=	Output voltage (V) in low state
C_L	=	External load capacitance (F)
mA/(MHz × bit)	=	Slope of the I_{CC} versus frequency curve

Thermal-Resistance Values

Design trends requiring board size reduction have made way for circuit manufacturers to produce fine-pitch packages that appear to threaten the reliability of systems due to further thermal constraints. As a leader in packaging technology, TI has done considerable research into the validity of traditional thermal measurements and data provided by circuit manufacturers.

Unlike data-sheet parameters, where the industry has adopted a standard load for measurement (50 pf, 500 Ω), the measurement of Θ_{JA} has no standard to which all manufacturers comply. The problem facing the designer wishing to make comparisons of thermal data from several manufacturers is that this could be an apples-to-oranges type comparison. As a result, a software package has been developed at TI to allow designers to obtain thermal data based on their specific application.

The validity and usefulness of the traditional approach to presenting Θ_{JA} values became a pressing issue when TI and another manufacturer measured an identical package and obtained results that varied by 40%. Extensive research led to the conclusion that the methodology used to measure Θ_{JA} did not cause the discrepancy but the physical aspects such as trace length, trace width, number of devices per board, and proximity of the other devices did.

To demonstrate the extreme impact of trace length alone, Figure 6 shows the Θ_{JA} values for TI's 48-pin SSOP at 0 LFMP and 250 LFMP with varying trace lengths. The 48-pin SSOP is shown in Figure 1 for a side-by-side comparison with the standard 24-pin SOIC, the 24-pin SSOP, and the 100-pin TQFP. The data in Figure 6 clearly shows the need for more complete thermal data, not simply a single data point.

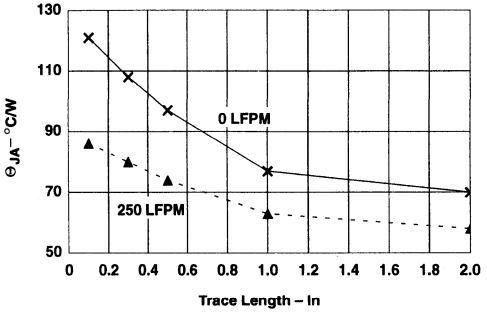


Figure 6. 48-Pin SSOP Θ_{JA} Versus Trace Length

There are other methods to lower the Θ_{JA} of a device. Using heat sinks or blowing air across a device certainly improves the ability to remove heat from its surface. Figure 7 provides Θ_{JA} data for the 48-pin SSOP with trace lengths of 200 mils and 1 inch while varying the amount of air flow. Although many applications tend to limit the amount of air flow, excellent benefits are possible with increased air flow.

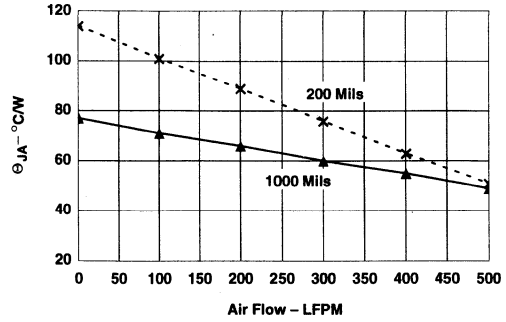
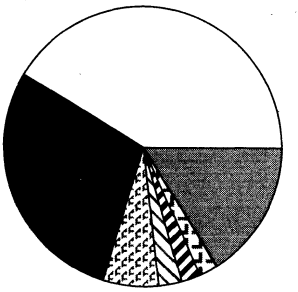


Figure 7. 48-Pin SSOP Θ_{JA} Versus Air Flow

Several variables that have a direct effect on Θ_{JA} values were compared and results are shown in Figure 8. Surprisingly, the major contributing factor is trace length, not air flow. Once again, this validates the need for improvement not necessarily in the test methodology used to calculate Θ_{JA} values, but certainly in the way those values are provided.



VARIABLE	RANGE	% CONTRIBUTION
Trace Length	75 mils – 2000 mils	41.4
Air Flow	0 LFM – 500 LFM	28.8
Board Extension After Trace	0 mils – 400 mils	6.5
Board Extension After Package End	0 mils – 755 mils	2.6
Trace Thickness	1 oz – 2 oz	2.2
Trace Width	3 mils – 15 mils	2.1
Power	0.5 W – 1.5 W	0.1
Total Interactions Between Factors		16.3

Figure 8. 48-/56-Pin SSOP K-Factor Board Modeling

TI provides Θ_{JA} values for a variety of packages (including the SOIC, SSOP, and QSOP) in a user-friendly software package. The program allows designers to specify their conditions, such as trace length, air flow, proximity of other devices, and trace width in order to obtain realistic thermal solutions.

Summary

How a system can avoid being a reliability nightmare in today's world where:

- Eight-bit devices are being replaced by 16 and 32 bits in a single package, increasing the power.
- Higher operating frequencies add to the increase in power.
- Fine-pitch packages are reducing the amount of available surface area to remove heat from a device.

Semiconductor manufacturers must take the first step and provide realistic and useful thermal information that will provide designers key variables to focus on for thermal management.

References

Thermal Software

Contact the factory at (903) 868-7682.

Power Dissipation

Advanced CMOS Logic Designer's Handbook, Texas Instruments Incorporated, 1988, literature number SCAA001B SSOP Designer's Handbook, Texas Instruments Incorporated, 1991, literature number SCYA001

Overview of IEEE Standard 91-1984

Explanation of Logic Symbols

Semiconductor Group

SDYZ001A

Contents

List of Tables

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1 Introduction

The International Electrotechnical Commission (IEC) has been developing a very powerful symbolic language that can show the relationship of each input of a digital logic circuit to each output without showing explicitly the internal logic. At the heart of the system is dependency notation, which will be explained in Section 4.

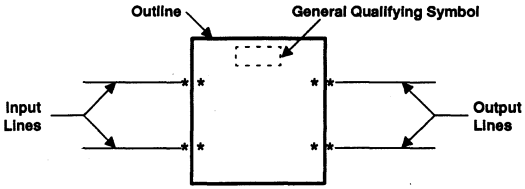
The system was introduced in the USA in a rudimentary form in IEEE/ANSI Standard Y32.14-1973. Lacking at that time a complete development of dependency notation, it offered little more than a substitution of rectangular shapes for the familiar distinctive shapes for representing the basic functions of AND, OR, negation, etc. This is no longer the case.

Internationally, Working Group 2 of IEC Technical Committee TC-3 has prepared a new document (Publication 617-12) that consolidates the original work started in the mid 1960s and published in 1972 (Publication 117-15) and the amendments and supplements that have followed. Similarly for the USA, IEEE Committee SCC 11.9 has revised the publication IEEE Std 91/ANSI Y32.14. Now numbered simply IEEE Std 91-1984, the IEEE standard contains all of the IEC work that has been approved, and also a small amount of material still under international consideration. Texas Instruments is participating in the work of both organizations and this document introduces new logic symbols in accordance with the new standards. When changes are made as the standards develop, future editions will take those changes into account.

The following explanation of the new symbolic language is necessarily brief and greatly condensed from what the standards publications will contain. This is not intended to be sufficient for those people who will be developing symbols for new devices. It is primarily intended to make possible the understanding of the symbols used in various data books, and the comparison of the symbols with logic diagrams, functional block diagrams, and/or function tables will further help that understanding.

2 Symbol Composition

A symbol comprises an outline or a combination of outlines together with one or more qualifying symbols. The shape of the symbols is not significant. As shown in Figure 1, general qualifying symbols are used to tell exactly what logical operation is performed by the elements. Table 1 shows general qualifying symbols defined in the new standards. Input lines are placed on the left and output lines are placed on the right. When an exception is made to that convention, the direction of signal flow is indicated by an arrow, as shown in Figure 1.



* Possible positions for qualifying symbols relating to inputs and outputs

Figure 1. Symbol Composition

All outputs of a single, unsubdivided element always have identical internal logic states determined by the function of the element, except when otherwise indicated by an associated qualifying symbol or label inside the element.

The outlines of elements may be abutted or embedded, in which case the following conventions apply. There is no logic connection between the elements when the line common to their outlines is in the direction of signal flow. There is at least one logic connection between the elements when the line common to their outlines is perpendicular to the direction of signal flow. The number of logic connections between elements will be clarified by the use of qualifying symbols, and this is discussed further under that topic. If no indications are shown on either side of the common line, it is assumed there is only one connection.

When a circuit has one or more inputs that are common to more than one element of the circuit, the common-control block may be used. This is the only distinctively shaped outline used in the IEC system. Figure 2 shows that, unless otherwise qualified by dependency notation, an input to the common-control block is an input to each of the elements below the common-control block.

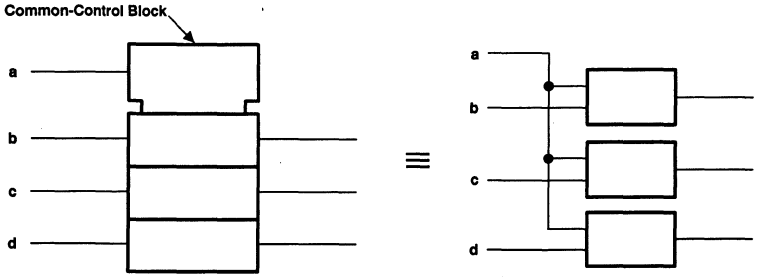
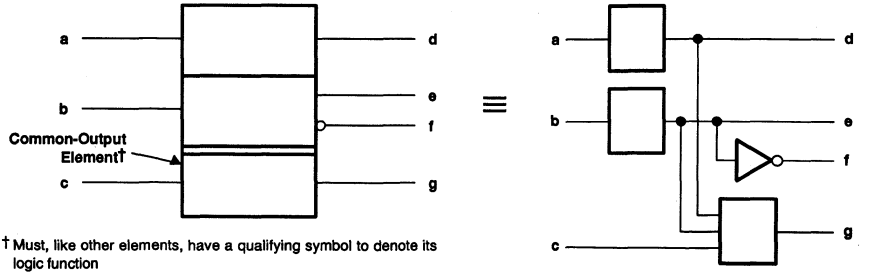


Figure 2. Common-Control Block

A common output depending on all elements of the array can be shown as the output of a common-output element. Its distinctive visual feature is the double line at its top. In addition, the common-output element may have other inputs as shown in Figure 3. The function of the common-output element must be shown by use of a general qualifying symbol.



† Must, like other elements, have a qualifying symbol to denote its logic function

Figure 3. Common-Output Element

3 Qualifying Symbols

3.1 General Qualifying Symbols

Table 1 shows general qualifying symbols defined by IEEE Standard 91. These characters are placed near the top center or the geometric center of a symbol or symbol element to define the basic function of the device represented by the symbol or of the element.

Table 1. General Qualifying Symbols†

SYMBOL	DESCRIPTION
&	AND gate or function
≥1	OR gate or function. The symbol was chosen to indicate that at least one active input is needed to activate the output.
=1	Exclusive OR. One and only one input must be active to activate the output.
=	Logic identity. All inputs must stand at the same state.
2k	An even number of inputs must be active.
2k + 1	An odd number of inputs must be active.
1	The one input must be active.
▷ or ◁	A buffer or element with more than usual output capability. Symbol is oriented in the direction of signal flow.
⊓	Schmitt trigger; element with hysteresis
X/Y	Coder, code converter (DEC/BCD, BIN/OUT, BIN/7-SEG, etc.)
MUX	Multiplexer/data selector
DMUX or DX	Demultiplexer
Σ	Adder
P–Q	Subtracter
CPG	Look-ahead carry generator
π	Multiplier
COMP	Magnitude comparator
ALU	Arithmetic logic unit
⎍	Retriggerable monostable
1 ⎍	Nonretriggerable monostable (one shot)
G ⎍⎍	Astable element. Showing waveform is optional.
!G ⎍⎍	Synchronously starting astable
G! ⎍⎍	Astable element that stops with a completed pulse
SRGm	Shift register. m = number of bits
CTRm	Counter. m = number of bits; cycle length = 2^m
CTR DIVm	Counter with cycle length = m
RCTRm	Asynchronous (ripple-carry) counter; cycle length = 2^m
ROM	Read-only memory
RAM	Random-access read/write memory
FIFO	First-in, first-out memory
I = 0	Element powers up cleared to 0 state
I = 1	Element powers up set to 1 state
Φ	Highly complex function; *gray-box* symbol with limited detail shown under special rules

† Not all of the general qualifying symbols have been used in TI's data books, but they are included here for completeness.

3.2 Qualifying Symbols for Inputs and Outputs

Qualifying symbols for inputs and outputs are shown in Table 2 and are familiar to most users, with the possible exception of the logic polarity symbol for directly indicating active-low inputs and outputs (negation). The older logic negation indicator means that the external 0 state produces the internal 1 state. The internal 1 state means the active state. Logic negation may be used in pure logic diagrams; in order to tie the external 1 and 0 logic states to the levels high (H) and low (L), a statement of whether positive logic (1 = H, 0 = L) or negative logic (1 = L, 0 = H) is being used is required or must be assumed. Logic polarity indicators eliminate the need for calling out the logic convention and are used in various data books in the symbology for actual devices. The presence of the triangular polarity indicator indicates that the L logic level produces the internal 1 state (active state) or that, in the case of an output, the internal 1 state produces the external L level. Note how the active direction of transition for a dynamic input is indicated in positive logic, negative logic, and with polarity indication.

The internal connections between logic elements abutted together in a symbol may be indicated by the symbols shown in Table 2. Each logic connection may be shown by the presence of qualifying symbols at one or both sides of the common line and, if confusion can arise about the numbers of connections, use can be made of one of the internal connection symbols.

Table 2. Qualifying Symbols for Inputs and Outputs

SYMBOL	DESCRIPTION
	Logic negation at input. External 0 produces internal 1.
	Logic negation at output. Internal 1 produces external 0.
	Active-low input. Equivalent to  in positive logic.
	Active-low output. Equivalent to  in positive logic.
	Active-low input in the case of right-to-left signal flow
	Active-low output in the case of right-to-left signal flow
	Signal flow from right to left. If not otherwise indicated, signal flow is from left to right.
	Bidirectional signal flow
	Dynamic inputs active on indicated transition **Positive Logic**: 1→0; not used; 0→1 **Negative Logic**: 1→0; not used; 0→1 **Polarity Indication**: not used; H→L; L→H
	Nonlogic connection. A label inside the symbol usually defines the nature of this pin.
	Input for analog signals (on a digital symbol) (see Figure 14)
	Input for digital signals (on an analog symbol) (see Figure 14)
	Internal connection. 1 state on left produces 1 state on right.
	Negated internal connection. 1 state on left produces 0 state on right.
	Dynamic internal connection. Transition from 0 to 1 on left produces transitory 1 state on right.
	Internal input (virtual input). It always stands at its internal 1 state unless affected by an overriding dependency relationship.
	Internal output (virtual output). Its effect on an internal input to which it is connected is indicated by dependency notation.

The internal (virtual) input is an input originating somewhere else in the circuit and is not connected directly to a terminal. The internal (virtual) output is likewise not connected directly to a terminal. The application of internal inputs and outputs requires an understanding of dependency notation, which is explained in Section 4.

In an array of elements, if the same general qualifying symbol and the same qualifying symbols associated with inputs and outputs would appear inside each of the elements of the array, these qualifying symbols usually are shown only in the first element. This is done to reduce clutter and to save time in recognition. Similarly, large identical elements that are subdivided into smaller elements may each be represented by an unsubdivided outline.

3.3 Symbols Inside the Outline

Table 3 shows some symbols used inside the outline. Note particularly that open-collector (open-drain), open-emitter (open-source), and 3-state outputs have distinctive symbols. An EN input affects all the external outputs of the element in which it is placed, plus the external outputs of any elements shown to be influenced by that element. It has no effect on inputs. When an enable input affects only certain outputs, affects outputs located outside the indicated influence of the element in which the enable input is placed, and/or affects one or more inputs, a form of dependency notation indicates this (see 4.10). The effects of the EN input on the various types of outputs are shown.

It is particularly important to note that a D input is always the data input of a storage element. At its internal 1 state, the D input sets the storage element to its 1 state, and at its internal 0 state it resets the storage element to its 0 state.

The binary grouping symbol is explained more fully in Section 8. Binary-weighted inputs are arranged in order and the binary weights of the least-significant and the most-significant lines are indicated by numbers. In this document, weights of input and output lines are represented by powers of two, usually only when the binary grouping symbol is used, otherwise, decimal numbers are used. The grouped inputs generate an internal number on which a mathematical function can be performed or that can be an identifying number for dependency notation (Figure 28). A frequent use is in addresses for memories.

Reversed in direction, the binary grouping symbol can be used with outputs. The concept is analogous to that for the inputs, and the weighted outputs indicate the internal number assumed to be developed within the circuit.

Other symbols are used inside the outlines in accordance with the IEC/IEEE standards, but are not shown here. Generally, these are associated with arithmetic operations and are self-explanatory.

When nonstandardized information is shown inside an outline, it is usually enclosed in square brackets [ ]. The square brackets are omitted when associated with a nonlogic input, which is indicated by an X superimposed on the connection line outside the symbol.

Table 3. Symbols Inside the Outline

SYMBOL	DESCRIPTION
¬	Postponed output (of a pulse-triggered flip-flop). The output changes when input initiating change (e.g., a C input) returns to its initial external state or level (see Section 5).
⎍	Bi-threshold input (input with hysteresis)
⏛	N-P-N open-collector or similar output that can supply a relatively low-impedance L level when not turned off. Requires external pullup. Capable of positive-logic wired-AND connection.
⏚	Passive pullup output is similar to N-P-N open-collector output but is supplemented with a built-in passive pullup.
⏛	N-P-N open-emitter or similar output that can supply a relatively low-impedance H level when not turned off. Requires external pulldown. Capable of positive-logic wired-OR connection.
⏚	Passive pulldown output is similar to N-P-N open-emitter output but is supplemented with a built-in passive pulldown.
▽	3-state output
▷	Output with more than usual output capability (symbol is oriented in the direction of signal flow)
EN	Enable input. When at its internal 1 state, all outputs are enabled. When at its internal 0 state, open-collector and open-emitter outputs are off, 3-state outputs are at normally defined internal logic states and at external high-impedance state, and all other outputs (e.g., totem-poles) are at the internal 0 state.
J, K, R, S	Usual meanings associated with flip-flops (e.g., R = reset to 0, S = reset to 1)
T	Toggle input causes internal state of output to change to its complement.
D	Data input to a storage element equivalent to: S, R
m, m	Shift right (left) inputs, m = 1, 2, 3, etc. If m = 1, it usually is not shown.
+m, −m	Counting up (down) inputs, m = 1, 2, 3, etc. If m = 1, it usually is not shown.
0, m	Binary grouping. m is highest power of 2.
CT=15	The contents-setting input, when active, causes the content of a register to take on the indicated value.
CT=9	The content output is active if the content of the register is as indicated.
	Input line grouping . . . indicates two or more terminals used to implement a single logic input. X, X̄, E
"1"	Fixed-state output always stands at its internal 1 state.

4 Dependency Notation

4.1 General Explanation

Dependency notation is the powerful tool that sets the IEC symbols apart from previous systems and makes compact, meaningful symbols possible. It provides the means of denoting the relationship between inputs, outputs, or inputs and outputs without actually showing all the elements and interconnections involved. The information provided by dependency notation supplements that provided by the qualifying symbols for an element's function.

In the convention for the dependency notation, the terms *affecting* and *affected* are used. In cases where it is not evident which inputs must be considered as being the affecting or the affected ones (e.g., if they stand in an AND relationship), the choice may be made in any convenient way.

So far, 11 types of dependency have been defined and all of these are used in various TI data books. X dependency is used mainly with CMOS circuits. They are listed below in the order in which they are presented and are summarized in Table 4.

SECTION	DEPENDENCY TYPE OR OTHER SUBJECT
4.2	G, AND
4.3	General Rules for Dependency Notation
4.4	V, OR
4.5	N, Negate (Exclusive-OR)
4.6	Z, Interconnection
4.7	X, Transmission
4.8	C, Control
4.9	S, Set and R, Reset
4.10	EN, Enable
4.11	M, Mode
4.12	A, Address

4.2 G (AND) Dependency

A common relationship between two signals is to have them ANDed together. This traditionally has been shown by explicitly drawing an AND gate with the signals connected to the inputs of the gate. The 1972 IEC publication and the 1973 IEEE/ANSI standard showed several ways to represent this AND relationship using dependency notation. While ten other forms of dependency have since been defined, the ways to invoke AND dependency are now reduced to one.

In Figure 4, input **b** is ANDed with input **a** and the complement of **b** is ANDed with **c**. The letter G has been chosen to indicate AND relationships and is placed at input **b**, inside the symbol. A number considered appropriate by the symbol designer (1 has been used here) is placed after the letter G and also at each affected input. Note the bar over the 1 at input **c**.

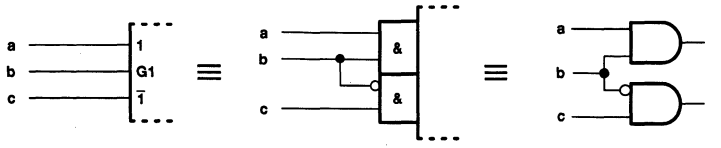


Figure 4. G Dependency Between Inputs

In Figure 5, output **b** affects input **a** with an AND relationship. The lower example shows that it is the internal logic state of **b** unaffected by the negation sign that is ANDed. Figure 6 shows input **a** to be ANDed with a dynamic input **b**.

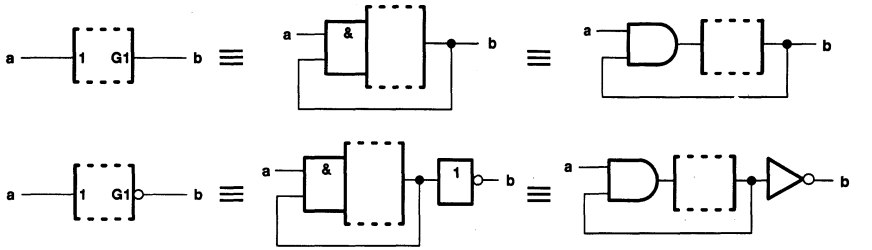


Figure 5. G Dependency Between Outputs and Inputs

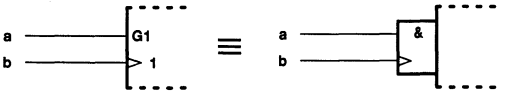


Figure 6. G Dependency With a Dynamic Input

The rules for G dependency can be summarized thus:

- When a Gm input or output (m is the number) stands at its internal 1 state, all inputs and outputs affected by Gm stand at their normally defined internal logic states.
- When the Gm input or output stands at its 0 state, all inputs and outputs affected by Gm stand at their internal 0 states.

4.3 Conventions for the Application of Dependency Notation In General

The rules for applying dependency relationships in general follow the same pattern as was illustrated for G dependency. Application of dependency notation is accomplished by:

1. labeling the input (or output) *affecting* other inputs or outputs with the letter symbol indicating the relationship involved (e.g., G for AND) followed by an identifying number, appropriately chosen, and
2. labeling each input or output *affected* by that affecting input (or output) with that same number.

If it is the complement of the internal logic state of the affecting input or output that does the affecting, then a bar is placed over the identifying numbers at the affected inputs or outputs (Figure 4).

If two affecting inputs or outputs have the same letter and same identifying number, they stand in an OR relationship to each other (Figure 7).

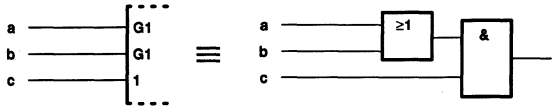


Figure 7. ORed Affecting Inputs

If the affected input or output requires a label to denote its function (e.g., D), this label is *prefixed* by the identifying number of the affecting input (Figure 15).

If an input or output is affected by more than one affecting input, the identifying numbers of each of the affecting inputs appear in the label of the affected one, separated by commas. The normal reading order of these numbers is the same as the sequence of the affecting relationships (Figure 15).

If the labels denoting the functions of affected inputs or outputs must be numbers (e.g., outputs of a coder), the identifying numbers to be associated with both affecting inputs and affected inputs or outputs are replaced by another character selected to avoid ambiguity, e.g., Greek letters (Figure 8).

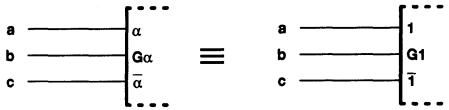


Figure 8. Substitution for Numbers

4.4 V (OR) Dependency

The symbol denoting OR dependency is the letter V (Figure 9).

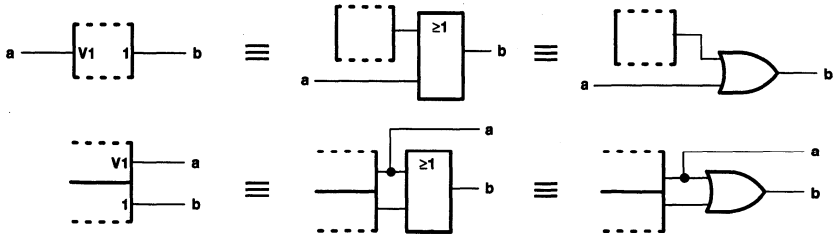
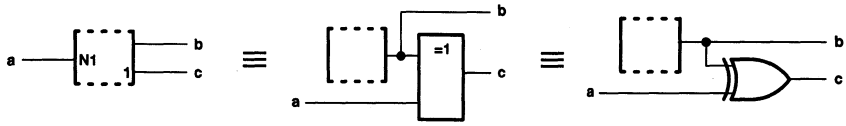


Figure 9. V (OR) Dependency

When a Vm input or output stands at its internal 1 state, all inputs and outputs affected by Vm stand at their internal 1 states. When the Vm input or output stands at its internal 0 state, all inputs and outputs affected by Vm stand at their normally defined internal logic states.

4.5 N (Negate) (Exclusive-OR) Dependency

The symbol denoting negate dependency is the letter N (Figure 10).



If a = 0, then c = b, if a = 1, then c = b

Figure 10. N (Negate) (Exclusive-OR) Dependency

Each input or output affected by an Nm input or output stands in an exclusive-OR relationship with the Nm input or output.

When an Nm input or output stands at its internal 1 state, the internal logic state of each input and each output affected by Nm is the complement of what it otherwise would be. When an Nm input or output stands at its internal 0 state, all inputs and outputs affected by Nm stand at their normally defined internal logic states.

4.6 Z (Interconnection) Dependency

The symbol denoting interconnection dependency is the letter Z.

Interconnection dependency is used to indicate the existence of internal logic connections between inputs, outputs, internal inputs, and/or internal outputs.

The internal logic state of an input or output affected by a Zm input or output is the same as the internal logic state of the Zm input or output, unless modified by additional dependency notation (Figure 11).

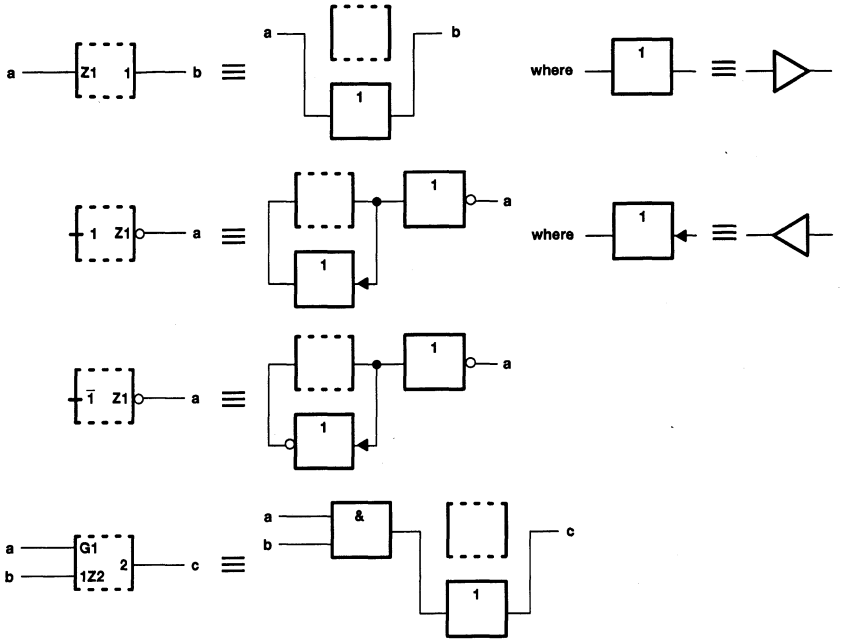


Figure 11. Z (Interconnection) Dependency

4.7 X (Transmission) Dependency

The symbol denoting transmission dependency is the letter X.

Transmission dependency is used to indicate controlled bidirectional connections between affected input/output ports (Figure 12).

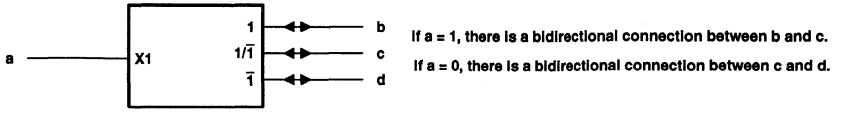


Figure 12. X (Transmission) Dependency

When an Xm input or output stands at its internal 1 state, all I/O ports affected by this Xm input or output are bidirectionally connected and stand at the same internal logic state or analog signal level. When an Xm input or output stands at its internal 0 state, the connection associated with this set of dependency notation does not exist.

Although the transmission paths represented by X dependency are inherently bidirectional, use is not always made of this property. This is analogous to a piece of wire, that may be constrained to carry current in only one direction. If this is the case in a particular application, then the directional arrows shown in Figures 12, 13, and 14 would be omitted.

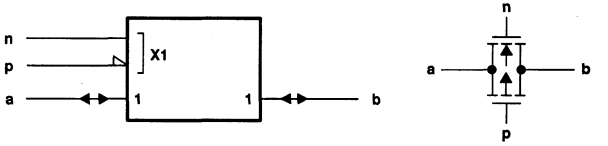


Figure 13. CMOS Transmission Gate Symbol and Schematic

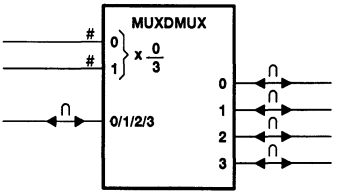


Figure 14. Analog Data Selector (Multiplexer/Demultiplexer)

4.8 C (Control) Dependency

The symbol denoting control dependency is the letter C.

Control inputs typically are used to enable or disable the data (D, J, K, R, or S) inputs of storage elements. They may take on their internal 1 states (be active) either statically or dynamically. In the latter case, the dynamic input symbol is used as shown in the third example of Figure 15.

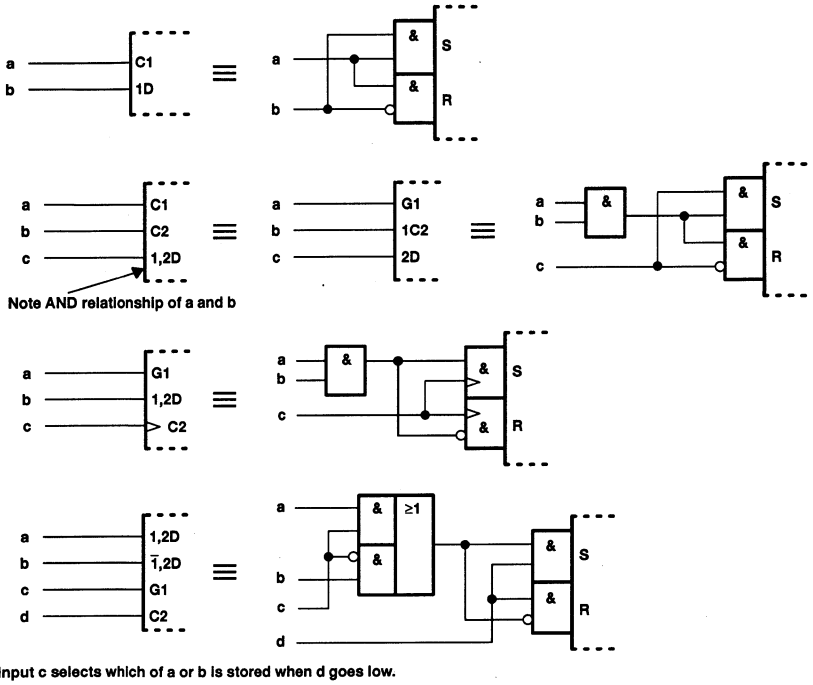


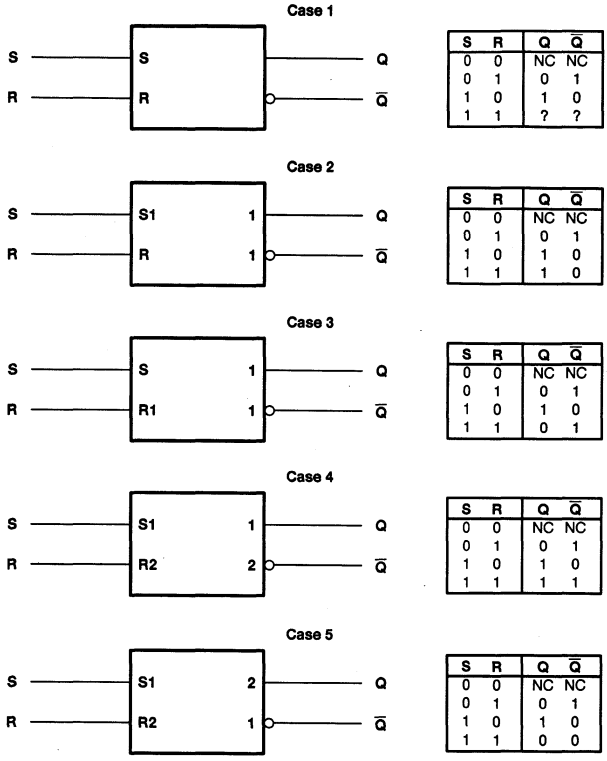
Figure 15. C (Control) Dependency

When a Cm input or output stands at its internal 1 state, the inputs affected by Cm have their normally defined effect on the function of the element, i.e., these inputs are enabled. When a Cm input or output stands at its internal 0 state, the inputs affected by Cm are disabled and have no effect on the function of the element.

4.9 S (Set) and R (Reset) Dependencies

The symbol denoting set dependency is the letter S. The symbol denoting reset dependency is the letter R.

Set and reset dependencies are used if it is necessary to specify the effect of the combination R = S = 1 on a bistable element. Case 1 in Figure 16 does not use S or R dependency.



S	R	Q	$\overline{Q}$
0	0	NC	NC
0	1	0	1
1	0	1	0
1	1	?	?

S	R	Q	$\overline{Q}$
0	0	NC	NC
0	1	0	1
1	0	1	0
1	1	1	0

S	R	Q	$\overline{Q}$
0	0	NC	NC
0	1	0	1
1	0	1	0
1	1	0	1

S	R	Q	$\overline{Q}$
0	0	NC	NC
0	1	0	1
1	0	1	0
1	1	1	1

S	R	Q	$\overline{Q}$
0	0	NC	NC
0	1	0	1
1	0	1	0
1	1	0	0

0 = external 0 state, 1 = external 1 state, NC = no change, ? = unspecified

Figure 16. S (Set) and R (Reset) Dependencies

When an Sm input is at its internal 1 state, outputs affected by the Sm input react, regardless of the state of an R input, as they normally would react to the combination S = 1, R = 0. See cases 2, 4, and 5 in Figure 16.

When an Rm input is at its internal 1 state, outputs affected by the Rm input react, regardless of the state of an S input, as they normally would react to the combination S = 0, R = 1. See cases 3, 4, and 5 in Figure 16.

When an Sm or Rm input is at its internal 0 state, it has no effect.

Note that the noncomplementary output patterns in cases 4 and 5 are only pseudo stable. The simultaneous return of the inputs to S = R = 0 produces an unforeseeable stable and complementary output pattern.

4.10 EN (Enable) Dependency

The symbol denoting enable dependency is the combination of letters EN.

The ENm input has the same effect on outputs as an EN input, see 3.1, but it affects only those outputs labeled with the identifying number m. It also affects those inputs labeled with the identifying number m. By contrast, an EN input affects all outputs and no inputs. The effect of an ENm input on an affected input is identical to that of a Cm input (Figure 17).

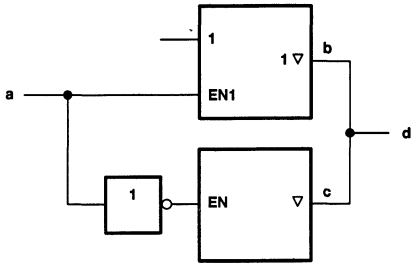


Figure 17. EN (Enable) Dependency

When an ENm input stands at its internal 1 state, the inputs affected by ENm have their normally defined effect on the function of the element and the outputs affected by this input stand at their normally defined internal logic states, i.e., these inputs and outputs are enabled.

When an ENm input stands at its internal 0 state, the inputs affected by ENm are disabled and have no effect on the function of the element, and the outputs affected by ENm are also disabled. Open-collector outputs are turned off, 3-state outputs stand at their normally defined internal logic states but externally exhibit high impedance, and all other outputs (e.g., totem-pole outputs) stand at their internal 0 states.

4.11 M (Mode) Dependency

The symbol denoting mode dependency is the letter M.

Mode dependency is used to indicate that the effects of particular inputs and outputs of an element depend on the mode in which the element is operating.

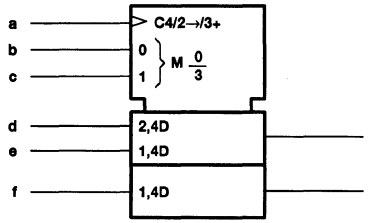
If an input or output has the same effect in different modes of operation, the identifying numbers of the relevant affecting Mm inputs will appear in the label of that affected input or output between parentheses and separated by solidi (Figure 22).

4.11.1 M Dependency Affecting Inputs

M dependency affects inputs the same as C dependency. When an Mm input or Mm output stands at its internal 1 state, the inputs affected by this Mm input or Mm output have their normally defined effect on the function of the element, i.e., the inputs are enabled.

When an Mm input or Mm output stands at its internal 0 state, the inputs affected by this Mm input or output have no effect on the function of the element. When an affected input has several sets of labels separated by solidi (e.g., C4/2→/3+), any set in which the identifying number of the Mm input or Mm output appears has no effect and is to be ignored. This represents disabling of some of the functions of a multifunction input.

The circuit in Figure 18 has two inputs, **b** and **c**, that control which one of four modes (0, 1, 2, or 3) will exist at any time. Inputs **d**, **e**, and **f** are D inputs subject to dynamic control (clocking) by the **a** input. The numbers 1 and 2 are in the series chosen to indicate the modes so inputs **e** and **f** are only enabled in mode 1 (for parallel loading) and input **d** is only enabled in mode 2 (for serial loading). Note that input **a** has three functions. It is the clock for entering data. In mode 2, it causes right shifting of data, which means a shift away from the control block. In mode 3, it causes the contents of the register to be incremented by one count.



Note that all operations are synchronous.

In mode 0 (b = 0, c = 0), the outputs remain at their existing states as none of the inputs has an effect.

In mode 1 (b = 1, c = 0), parallel loading takes place through inputs e and f.

In mode 2 (b = 0, c = 1), shifting down and serial loading through input d take place.

In mode 3 (b = c = 1), counting up by increment of one per clock pulse takes place.

Figure 18. M (Mode) Dependency Affecting Inputs

4.11.2 M Dependency Affecting Outputs

When an Mm input or output stands at its internal 1 state, the affected outputs stand at their normally defined internal logic states, i.e., the outputs are enabled.

When an Mm input or output stands at its internal 0 state, at each affected output any set of labels containing the identifying number of the Mm input or Mm output has no effect and is to be ignored. When an output has several different sets of labels separated by solidi (e.g., 2,4/3,5), only those sets in which the identifying number of this Mm input or Mm output appears are to be ignored.

Figure 19 shows a symbol for a device whose output can behave like either a 3-state output or an open-collector output, depending on the signal applied to input **a**. Mode 1 exists when input **a** stands at its internal 1 state and, in that case, the 3-state symbol applies and the open-element symbol has no effect. When **a** = 0, mode 1 does not exist, so the 3-state symbol has no effect and the open-element symbol applies.

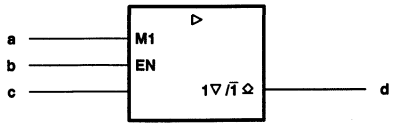


Figure 19. Type of Output Determined by Mode

In Figure 20, if input **a** stands at its internal 1 state, establishing mode 1, output **b** stands at its internal 1 state only when the content of the register equals 9. Since output **b** is located in the common-control block with no defined function outside of mode 1, the state of this output outside of mode 1 is not defined by the symbol.

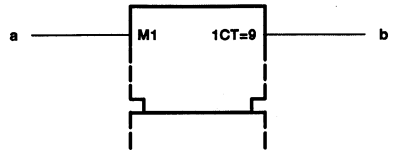


Figure 20. An Output of the Common-Control Block

In Figure 21, if input **a** stands at its internal 1 state, establishing mode 1, output **b** stands at its internal 1 state only when the content of the register equals 15. If input **a** stands at its internal 0 state, output **b** stands at its internal 1 state only when the content of the register equals 0.

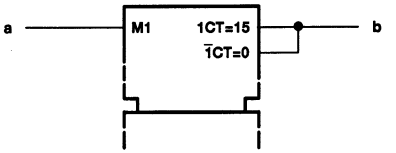


Figure 21. Determining an Output's Function

In Figure 22, inputs **a** and **b** are binary weighted to generate the numbers 0, 1, 2, or 3. This determines which one of the four modes exists.

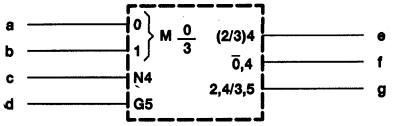


Figure 22. Dependent Relationships Affected by Mode

At output **e**, the label set causing negation (if **c** = 1) is effective only in modes 2 and 3. In modes 0 and 1, this output stands at its normally defined state as if it had no labels. At output **f**, the label set has effect when the mode is not 0, so output **e** is negated (if **c** = 1) in modes 1, 2, and 3. In mode 0, the label set has no effect, so the output stands at its normally defined state. In this example, $\overline{0}$,4 is equivalent to (1/2/3)4. At output **g** there are two label sets. The first set, causing negation (if **c** = 1), is effective only in mode 2. The second set, subjecting **g** to AND dependency on **d**, has effect only in mode 3.

Note that in mode 0 none of the dependency relationships has any effect on the outputs, so **e**, **f**, and **g** stand at the same state.

4.12 A (Address) Dependency

The symbol denoting address dependency is the letter A.

Address dependency provides a clear representation of those elements, particularly memories, that use address control inputs to select specified sections of multidimensional arrays. Such a section of a memory array usually is called a word. The purpose of address dependency is to allow a symbolic presentation of the entire array. An input of the array shown at a particular element of this general section is common to the corresponding elements of all selected sections of the array. An output of the array shown at a particular element of this general section is the result of the OR function of the outputs of the corresponding elements of selected sections.

Inputs that are not affected by any affecting address input have their normally defined effect on all sections of the array, whereas, inputs affected by an address input have their normally defined effect only on the section selected by that address input.

An affecting address input is labeled with the letter A, followed by an identifying number that corresponds with the address of the particular section of the array selected by this input. Within the general section presented by the symbol, inputs and outputs affected by an Am input are labeled with the letter A, which stands for the identifying numbers, i.e., the addresses of the particular sections.

Figure 23 shows a 3-word by 2-bit memory having a separate address line for each word, and uses EN dependency to explain the operation. To select word 1, input **a** is taken to its 1 state, which establishes mode 1. Data can now be clocked in the inputs marked 1,4D. Unless words 2 and 3 are also selected, data cannot be clocked in at the inputs marked 2,4D and 3,4D. The outputs will be the OR functions of the selected outputs, i.e., only those enabled by the active EN functions.

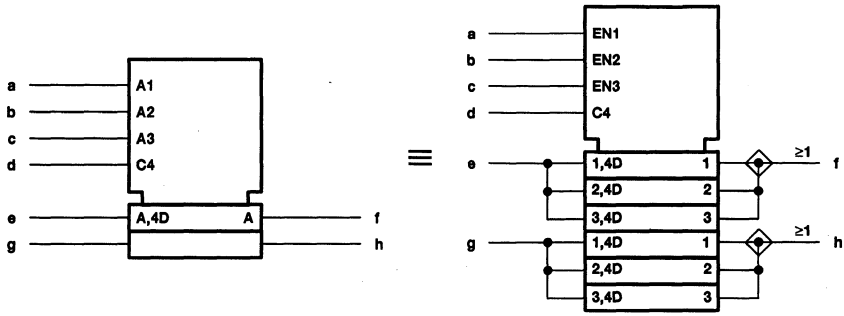


Figure 23. A (Address) Dependency

The identifying numbers of affecting address inputs correspond with the addresses of the sections selected by these inputs. They need not necessarily differ from those of other affecting dependency inputs (e.g., G, V, N, . . .) because in the general section presented by the symbol they are replaced by the letter A.

If there are several sets of affecting Am inputs for the purpose of independent and possibly simultaneous access to sections of the array, then the letter A is modified to 1A, 2A, etc. Because they have access to the same sections of the array, these sets of A inputs may have the same identifying numbers.

Figure 24 is another illustration of the concept.

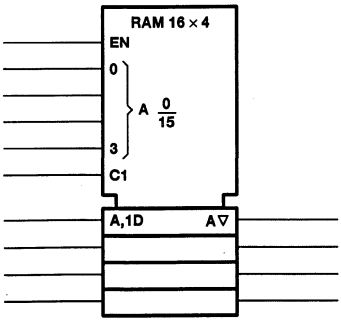


Figure 24. Array of 16 Sections of Four Transparent Latches With 3-State Outputs Comprising a 16-Word × 4-Bit Random-Access Memory

Table 4. Summary of Dependency Notation

TYPE OF DEPENDENCY	LETTER SYMBOL†	AFFECTING INPUT AT ITS 1 STATE	AFFECTING INPUT AT ITS 0 STATE
Address	A	Permits action (address selected)	Prevents action (address not selected)
Control	C	Permits action	Prevents action
Enable	EN	Permits action	Prevents action of inputs ◇outputs off ▽outputs at external high impedance, no change in internal logic state. Other outputs at internal 0 state.
AND	G	Permits action	Imposes 0 state
Mode	M	Permits action (mode selected)	Prevents action (mode not selected)
Negate (Exclusive-OR)	N	Complements state	No effect
Reset	R	Affected output reacts as it would to S = 0, R = 1	No effect
Set	S	Affected output reacts as it would to S = 1, R = 0	No effect
OR	V	Imposes 1 state	Permits action
Transmission	X	Bidirectional connection exists	Bidirectional connection does not exist
Interconnection	Z	Imposes 1 state	Imposes 0 state

† These letter symbols appear at the *affecting* input (or output) and are followed by a number. Each input (or output) *affected* by that input is labeled with that same number. When the labels EN, R, and S appear at inputs without the following numbers, the descriptions above do not apply. The action of these inputs is described under Section 3.3.

5 Bistable Elements

The dynamic input symbol, the postponed output symbol, and dependency notation provide the tools to differentiate four main types of bistable elements and make synchronous and asynchronous inputs easily recognizable (Figure 25). The first column shows the essential distinguishing features; the other columns show examples.

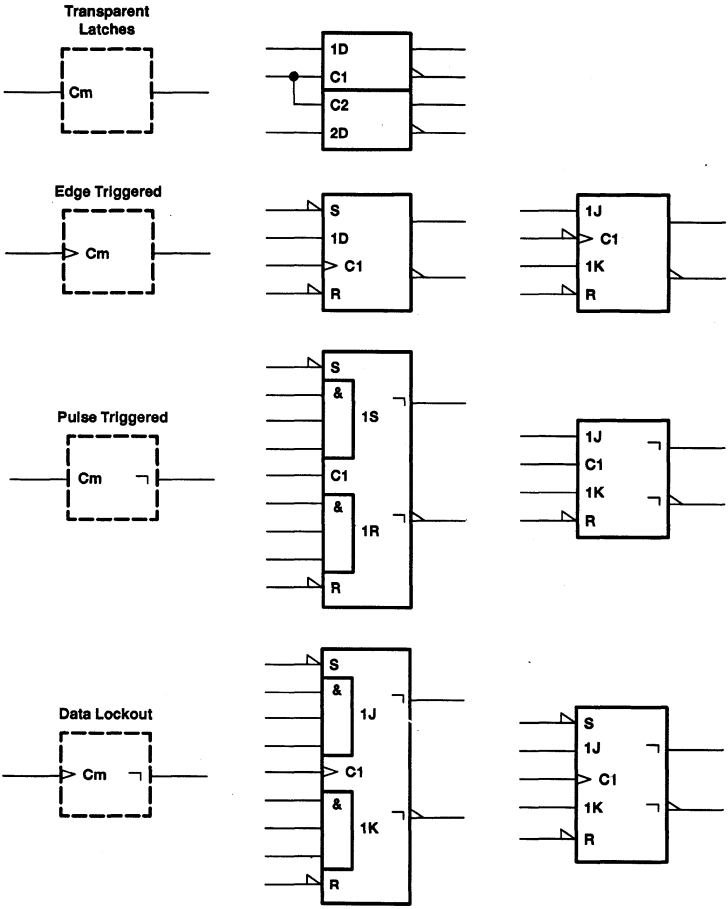


Figure 25. Four Types of Bistable Circuits

Transparent latches have a level-operated control input. The D input is active as long as the C input is at its internal 1 state. The outputs respond immediately. Edge-triggered elements accept data from D, J, K, R, or S inputs on the active transition of C. Pulse-triggered elements require the setup of data before the start of the control pulse; the C input is considered static since the data must be maintained as long as C is at its 1 state. The output is postponed until C returns to its 0 state. The data lock-out element is similar to the pulse-triggered version except that the C input is considered dynamic, in that shortly after C goes through its active transition, the data inputs are disabled and data does not have to be held. However, the output is still postponed until the C input returns to its initial external level.

Notice that synchronous inputs can be readily recognized by their dependency labels (1D, 1J, 1K, 1S, 1R) compared to the asynchronous inputs (S, R), which are not dependent on the C inputs.

6 Coders

The general symbol for a coder or code converter is shown in Figure 26. X and Y may be replaced by appropriate indications of the code used to represent the information at the inputs and at the outputs, respectively.

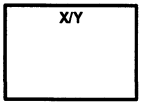


Figure 26. Coder General Symbol

Indication of code conversion is based on the following rule:

> Depending on the input code, the internal logic states of the inputs determine an internal value. This value is reproduced by the internal logic states of the outputs, depending on the output code.

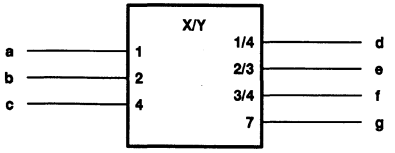
The indication of the relationships between the internal logic states of the inputs and the internal value is accomplished by:

1. labeling the inputs with numbers. In this case the internal value equals the sum of the weights associated with those inputs that stand at their internal 1 state, or by
2. replacing X by an appropriate indication of the input code and labeling the inputs with characters that refer to this code.

The relationships between the internal value and the internal logic states of the outputs are indicated by:

1. labeling each output with a list of numbers representing those internal values that lead to the internal 1 state of that output. These numbers shall be separated by solidi, as shown in Figure 27. This labeling may also be applied when Y is replaced by a letter denoting a type of dependency (see Section 7). If a continuous range of internal values produces the internal 1 state of an output, this can be indicated by two numbers that are inclusively the beginning and the end of the range, with these two numbers separated by three dots (e.g., 4 . . . 9 = 4/5/6/7/8/9) or by
2. replacing Y by an appropriate indication of the output code and labeling the outputs with characters that refer to this code, as shown in Figure 28.

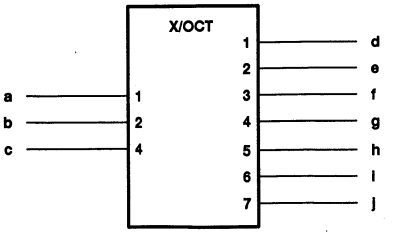
Alternatively, the general symbol may be used, together with an appropriate reference to a table, in which the relationship between the inputs and outputs is indicated. This is a recommended way to symbolize a PROM after it has been programmed.



FUNCTION TABLE

INPUTS			OUTPUTS			
c	b	a	g	f	e	d
0	0	0	0	0	0	0
0	0	1	0	0	0	1
0	1	0	0	0	1	0
0	1	1	0	1	1	0
1	0	0	0	1	0	1
1	0	1	0	0	0	0
1	1	0	0	0	0	0
1	1	1	1	0	0	0

Figure 27. An X/Y Code Converter



FUNCTION TABLE

INPUTS			OUTPUTS						
c	b	a	j	i	h	g	f	e	d
0	0	0	0	0	0	0	0	0	0
0	0	1	0	0	0	0	0	0	1
0	1	0	0	0	0	0	0	1	0
0	1	1	0	0	0	0	1	0	0
1	0	0	0	0	0	1	0	0	0
1	0	1	0	0	1	0	0	0	0
1	1	0	0	1	0	0	0	0	0
1	1	1	1	0	0	0	0	0	0

Figure 28. An X/Octal Code Converter

7 Use of a Coder to Produce Affecting Inputs

It often occurs that a set of affecting inputs for dependency notation is produced by decoding the signals on certain inputs to an element. In such a case, use can be made of the symbol for a coder as an embedded symbol (Figure 29).

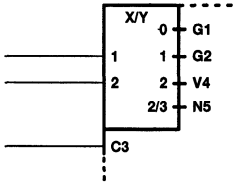


Figure 29. Producing Various Types of Dependencies

If all affecting inputs produced by a coder are of the same type and their identifying numbers are shown at the outputs of the coder, Y (in the qualifying symbol X/Y) may be replaced by the letter denoting the type of dependency. The indications of the affecting inputs should then be omitted (Figure 30).

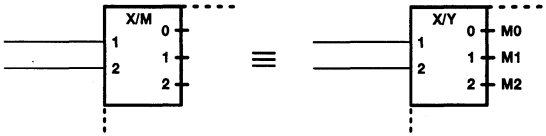


Figure 30. Producing One Type of Dependency

8 Use of Binary Grouping to Produce Affecting Inputs

If all affecting inputs produced by a coder are of the same type and have consecutive identifying numbers not necessarily corresponding with the numbers that would have been shown at the outputs of the coder, use can be made of the binary grouping symbol. k external lines effectively generate 2^k internal inputs. The bracket is followed by the letter denoting the type of dependency, followed by m1/m2. The m1 is to be replaced by the smallest identifying number and the m2 by the largest one, as shown in Figure 31.

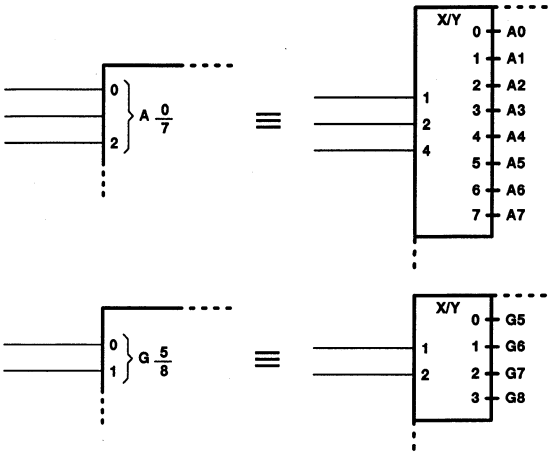


Figure 31. Use of the Binary Grouping Symbol

9 Sequence of Input Labels

If an input having a single functional effect is affected by other inputs, the qualifying symbol (if there is any) for that functional effect is preceded by the labels corresponding to the affecting inputs. The left-to-right order of these preceding labels is the order in which the effects or modifications must be applied. The affected input has no functional effect on the element if the logic state of any one of the affecting inputs, considered separately, would cause the affected input to have no effect, regardless of the logic states of other affecting inputs.

If an input has several different functional effects or has several different sets of affecting inputs, depending on the mode of action, the input may be shown as often as required. However, there are cases in which this method of presentation is not advantageous. In those cases the input may be shown once with the different sets of labels separated by solidi (Figure 32). No meaning is attached to the order of these sets of labels. If one of the functional effects of an input is that of an unlabeled input to the element, a solidus precedes the first set of labels shown.

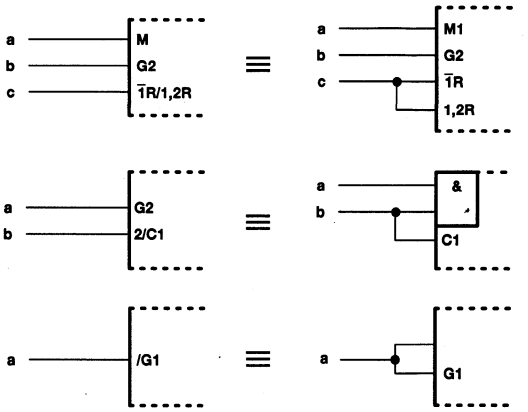


Figure 32. Input Labels

If all inputs of a combinational element are disabled (caused to have no effect on the function of the element), the internal logic states of the outputs of the element are not specified by the symbol. If all inputs of a sequential element are disabled, the content of this element is not changed and the outputs remain at their existing internal logic states.

Labels may be factored using algebraic techniques (Figure 33).

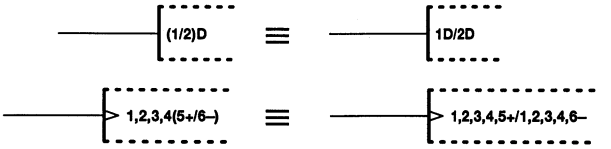


Figure 33. Factoring Input Labels

10 Sequence of Output Labels

If an output has a number of different labels, regardless of whether they are identifying numbers of affecting inputs or outputs or not, these labels are shown in the following order:

1. If the postponed output symbol has to be shown, this comes first, if necessary, preceded by the indications of the inputs to which it must be applied
2. Followed by the labels indicating modifications of the internal logic state of the output, such that the left-to-right order of these labels corresponds with the order in which their effects must be applied
3. Followed by the label indicating the effect of the output on inputs and other outputs of the element.

Symbols for open circuit or 3-state outputs, where applicable, are placed just inside the outside boundary of the symbol, adjacent to the output line (Figure 34).

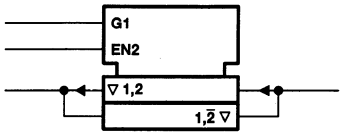


Figure 34. Placement of 3-State Symbols

If an output needs several different sets of labels that represent alternative functions (e.g., depending on the mode of action), these sets may be shown on different output lines that must be connected outside the outline. However, there are cases in which this method of presentation is not advantageous. In those cases, the output may be shown once, with the different sets of labels separated by solidi (Figure 35).

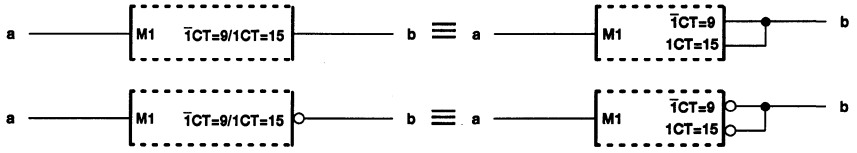


Figure 35. Output Labels

Two adjacent identifying numbers of affecting inputs in a set of labels that are not already separated by a nonnumeric character should be separated by a comma.

If a set of labels of an output not containing a solidus contains the identifying number of an affecting Mm input standing at its internal 0 state, this set of labels has no effect on that output.

Labels may be factored using algebraic techniques (Figure 36).

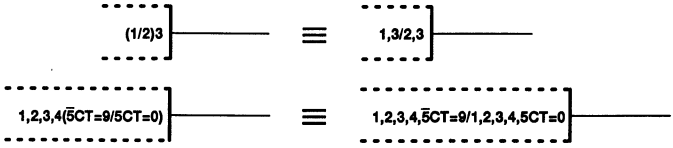
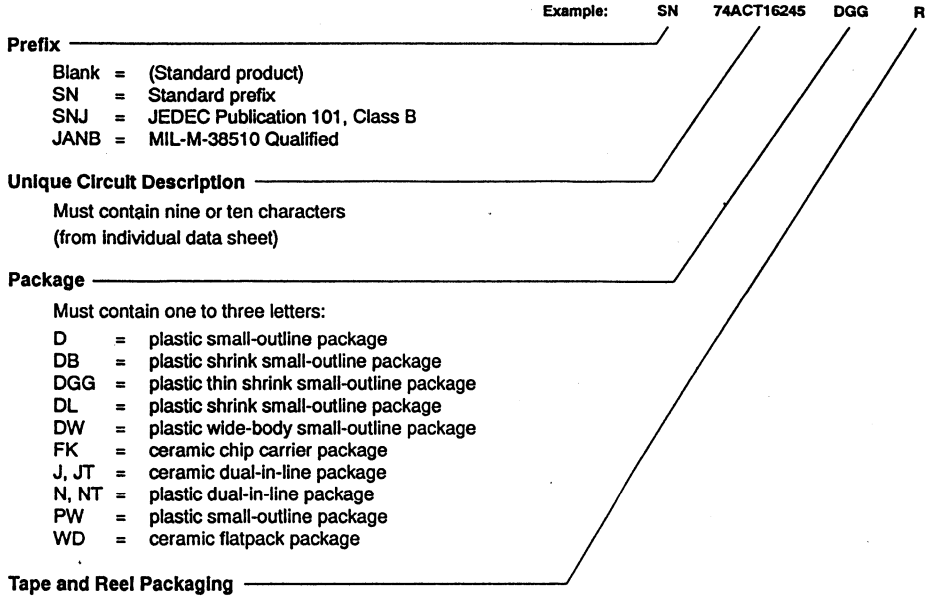


Figure 36. Factoring Output Labels

7 Mechanical Data

Electrical characteristics presented in this data book, unless otherwise noted, apply for the circuit type(s) listed in the page heading regardless of package. The availability of a circuit function in a particular package is denoted by an alphabetical reference above the pin-connection diagram(s). These alphabetical references refer to mechanical outline drawings shown in this section.

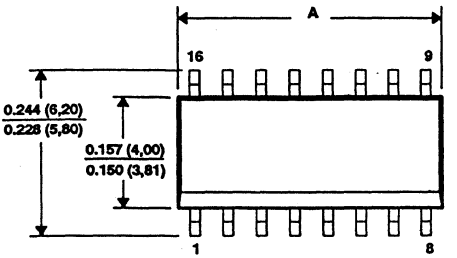
Factory orders for circuits described in this catalog should include a four-part type number as explained in the following example.



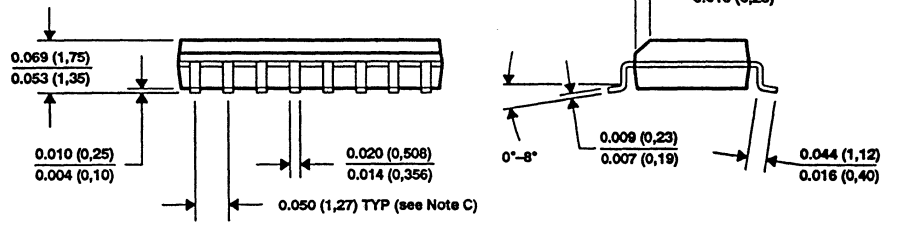
JULY 1993

D/R-PDSO-G** PLASTIC NARROW-BODY SMALL-OUTLINE PACKAGE

16-PIN SHOWN



DIM \ PINS**	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)



4040047/A–07/93

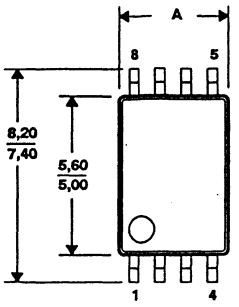
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Leads are within 0.005 (0,127) radius of true postion at maximum material condition.
D. Body dimensions do not include mold flash or protrusion.
E. Mold protrusion shall not exceed 0.006 (0,15).
F. Maximum deviation from coplanarity is 0.004 (0,10).

JULY 1993

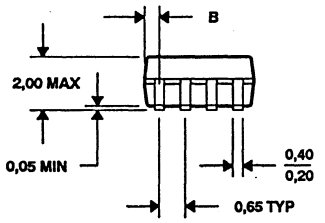
DB/R-PDSO-G**

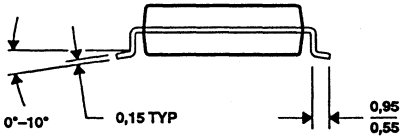
PLASTIC SMALL-OUTLINE PACKAGE

8-PIN SHOWN



DIM \ PINS**	8	14	16	20	24	28	30	38
A MAX	3,30	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	2,70	5,90	5,90	6,90	7,90	9,90	9,90	12,30
B MAX	0,68	1,30	0,98	0,83	0,68	1,03	0,70	0,60



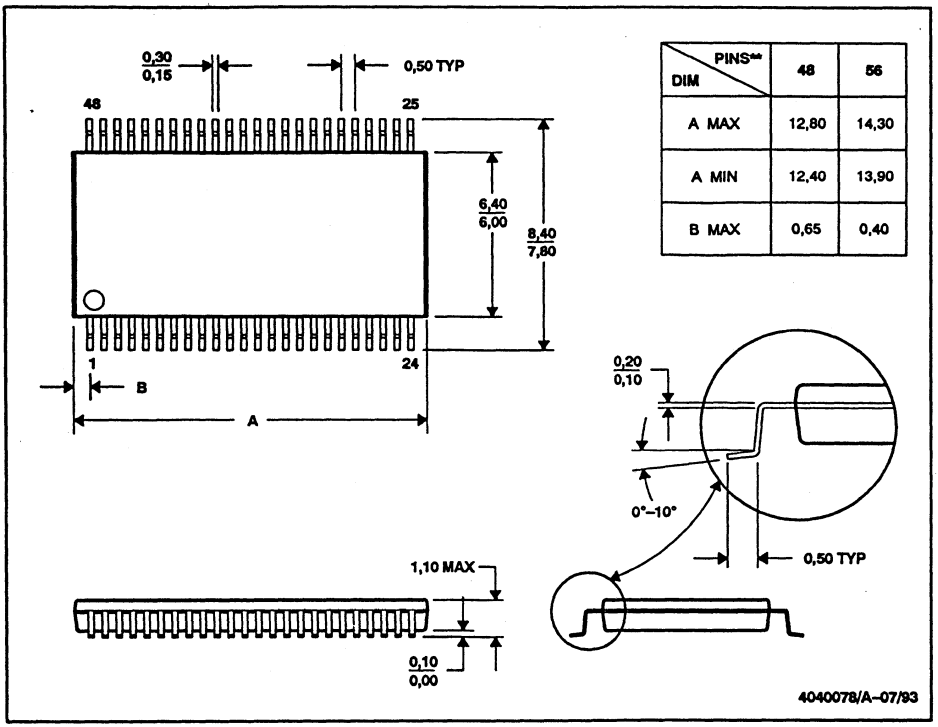


4040065/A–07/93

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions include mold flash or protrusion.

JULY 1993

DGG/R-PDSO-G** **300-MIL THIN SHRINK SMALL-OUTLINE PACKAGE**



DIM \ PINS**	48	56
A MAX	12,80	14,30
A MIN	12,40	13,90
B MAX	0,65	0,40

4040078/A–07/93

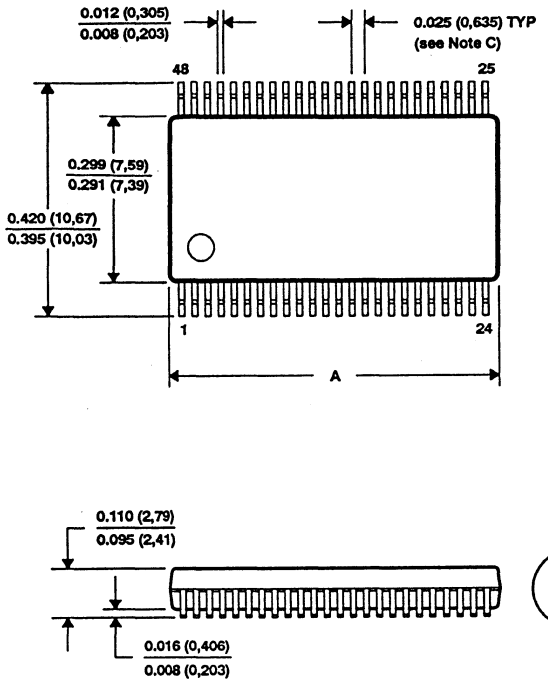
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions include mold flash or protrusion.

JUNE 1993

DL/R-PDSO-G**

PLASTIC SHRINK SMALL-OUTLINE PACKAGE

48-PIN SHOWN



DIM \ PINS**	28	48	56
A MAX	0.380 (9,65)	0.630 (16,00)	0.730 (18,54)
A MIN	0.370 (9,40)	0.620 (15,75)	0.720 (18,29)

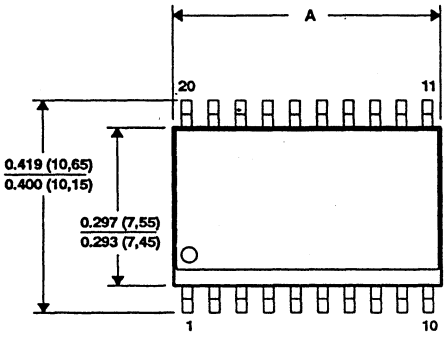
4040048/A–07/93

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Leads are within 0.0035 (0,089) radius of true postion at maximum material condition.
D. Body dimensions do not include mold flash , protrusion or gate burr.
E. Mold flash or protrusion or gate burr shall not exceed 0.015 (0,381).
F. Lead tips coplanar within 0.004 (0,102).
G. Lead length measured from lead top to point 0.010 (0,254) above seating plane.

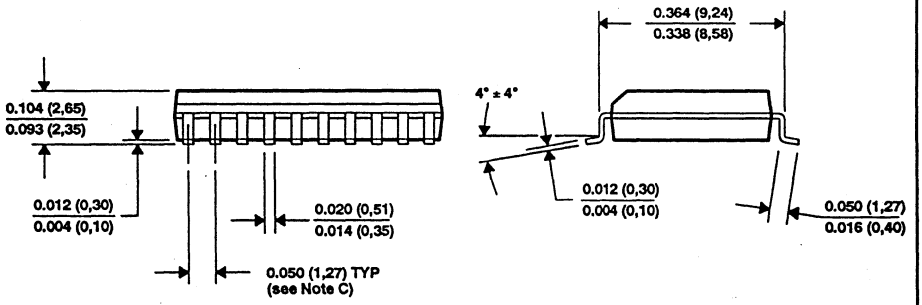
JULY 1993

DW/R-PDSO-G**
20-PIN SHOWN

PLASTIC WIDE-BODY SMALL-OUTLINE PACKAGE



DIM \ PINS**	16	20	24	28
A MIN	0.400 (10,16)	0.500 (12,70)	0.602 (15,29)	0.696 (17,68)
A MAX	0.408 (10,36)	0.508 (12,90)	0.610 (15,49)	0.704 (17,88)



4040000/A–07/93

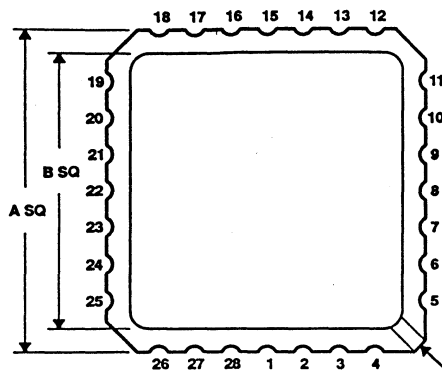
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Leads are within 0.10 (0,25) radius of true postion at maximum material condition.
D. Body dimensions do not include mold flash or protrusion.
E. Mold flash or protrusion shall not exceed 0.006 (0,15).
F. Lead tips coplanar within ±0.004 (±0,10) exclusive of solder.

JULY 1993

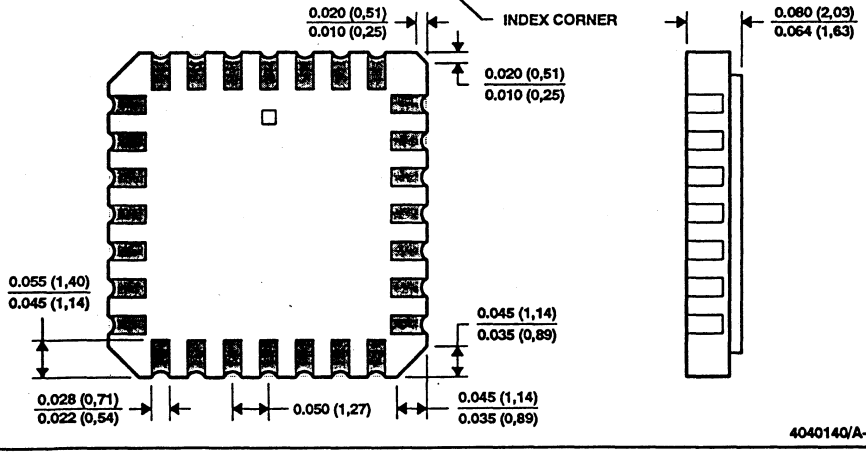
FK/S-CQCC–N**

CERAMIC CHIP CARRIER

28 PIN SHOWN



JEDEC OUTLINE DESIGNATION	NUMBERS OF ** TERMINALS	A		B	
		MIN	MAX	MIN	MAX
MS004CB	20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
MS004CC	28	0.422 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
MS004CD	44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
MS004CE	52	0.730 (18,78)	0.761 (19,32)	0.485 (12,58)	0.560 (14,22)
MS004CF	68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
MS004CG	84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/A–07/93

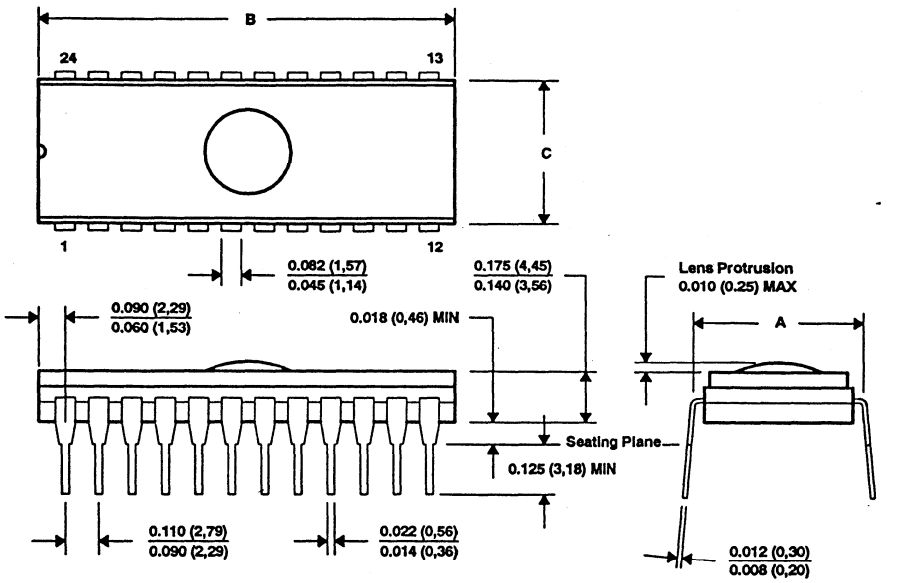
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Three–layer ceramic base with a metal lid and braze seal.
D. FK package terminal assignments conform to JEDEC Standards 1,2 and 11.
E. The packages are intended for surface mounting on solder lands on 0.050 (1,27) centers.

JULY 1993

J/R-CDIP–T**

600 MIL CERAMIC DUAL IN-LINE PACKAGE

24 PIN SHOWN



DIM \ PINS		24 NARR	24 WIDE	28 NARR	28 WIDE	32 NARR	32 WIDE	40 NARR	40 WIDE
A	MAX	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)
	MIN	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)
B	MAX	1.265(32,13)	1.265(32,13)	1.465(37,21)	1.465(37,21)	1.668(42,37)	1.668(42,37)	2.068(52,53)	2.068(52,53)
	MIN	1.235(31,37)	1.235(31,37)	1.435(36,45)	1.435(36,45)	1.632(41,45)	1.632(41,45)	2.032(51,61)	2.032(51,61)
C	MAX	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)
	MIN	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)

4040084/A–07/93

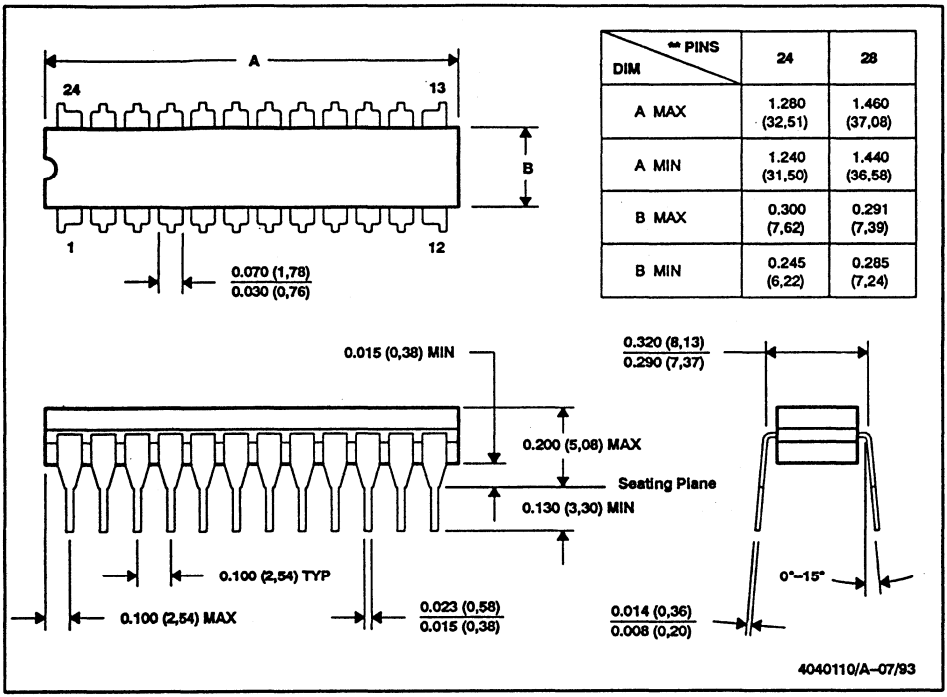
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

JULY 1993

JT/R-GDIP–T**

CERAMIC DUAL IN-LINE PACKAGE

24 PIN SHOWN



DIM \ ** PINS	24	28
A MAX	1.280 (32,51)	1.460 (37,08)
A MIN	1.240 (31,50)	1.440 (36,58)
B MAX	0.300 (7,62)	0.291 (7,39)
B MIN	0.245 (6,22)	0.285 (7,24)

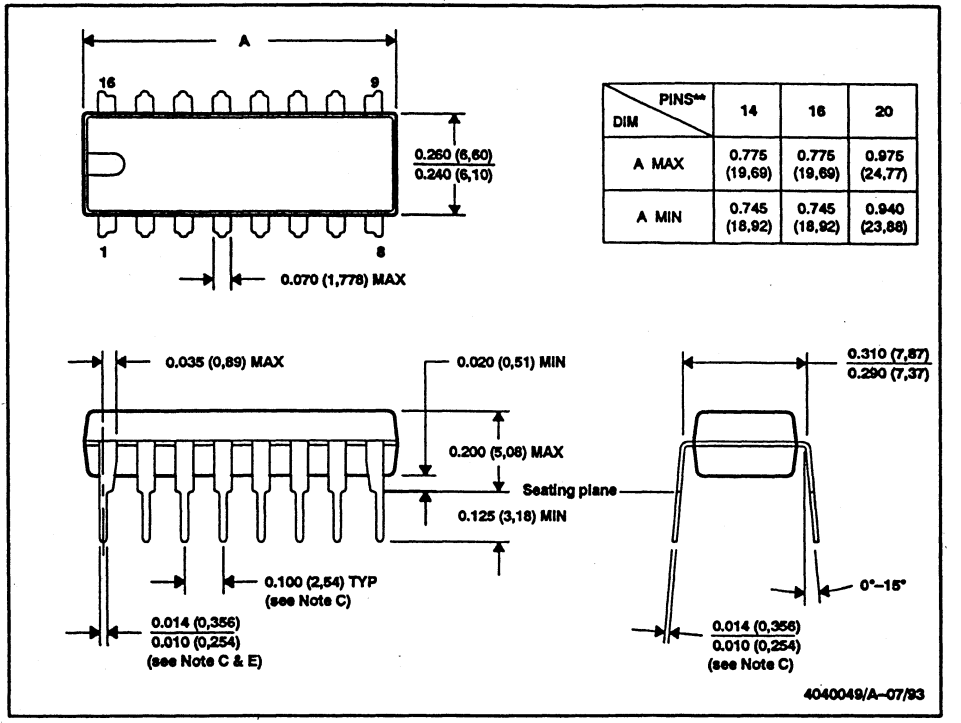
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is glass seal.

JULY 1993

N/R-PDIP-T**

PLASTIC DUAL-IN-LINE PACKAGE

16-PIN SHOWN



DIM \ PINS**	14	16	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.975 (24,77)
A MIN	0.745 (18,92)	0.745 (18,92)	0.940 (23,88)

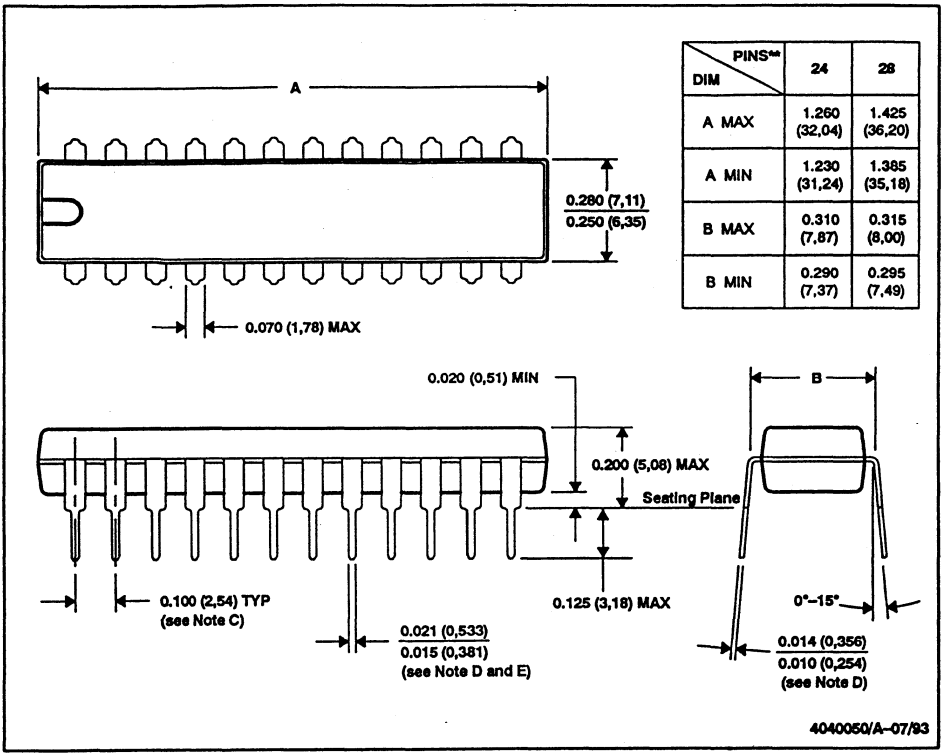
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Each pin centerline is located within 0.010 (0,254) of its true longitudinal position.
D. This dimension does not apply for solder dipped leads.
E. For solder dipped leads, dipping area of the leads extends from the lead tip to at least 0.020 (0,51) above seating plane.

JULY 1993

NT/R-PDIP-T**

PLASTIC DUAL-IN-LINE PACKAGE

24-PIN SHOWN



DIM \ PINS**	24	28
A MAX	1.260 (32,04)	1.425 (36,20)
A MIN	1.230 (31,24)	1.385 (35,18)
B MAX	0.310 (7,87)	0.315 (8,00)
B MIN	0.290 (7,37)	0.295 (7,49)

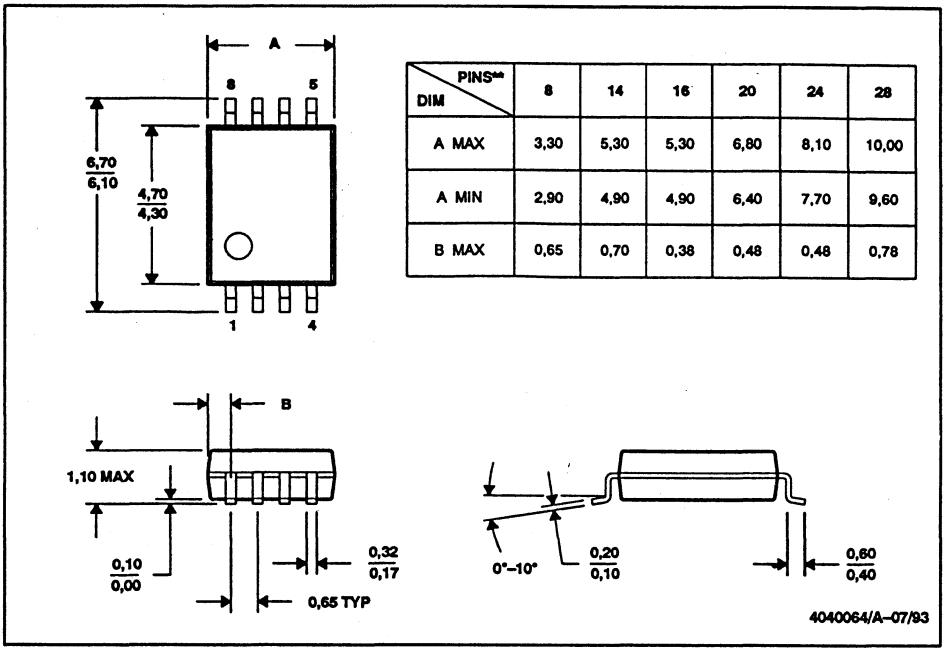
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Each pin centerline is located within 0.010 (0,254) of its true longitudinal position.
D. This dimension does not apply for solder dipped leads.
E. For solder dipped leads, dipping area of the leads extends from the lead tip to at least 0.020 (0,51) above seating plane.

JULY 1993

PW/R-PDSO-G**

PLASTIC SMALL-OUTLINE PACKAGE

8-PIN SHOWN



DIM \ PINS**	8	14	16	20	24	28
A MAX	3,30	5,30	5,30	6,80	8,10	10,00
A MIN	2,90	4,90	4,90	6,40	7,70	9,60
B MAX	0,65	0,70	0,38	0,48	0,48	0,78

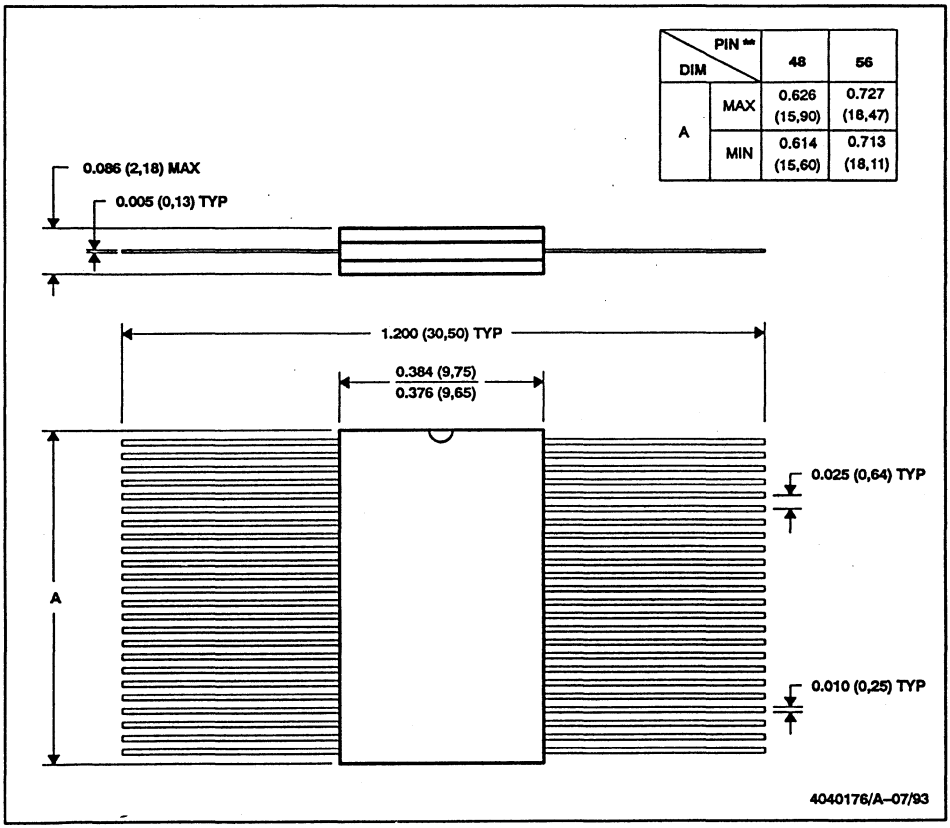
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Drawing source: SCJ Package handbook, 1990

JULY 1993

WD/R-GDFP–F**

CERAMIC FLATPACK

48 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

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